# STM32MP153C/F

## Arm® dual Cortex®-A7 800 MHz + Cortex®-M4 MPU, TFT, 37 comm. interfaces, 29 timers, adv. analog, crypto

**Datasheet - production data**

## Features

### Core

- 32-bit dual-core Arm® Cortex®-A7
  - L1 32-Kbyte I / 32-Kbyte D for each core
  - 256-Kbyte unified level 2 cache
  - Arm® NEON™ and Arm® TrustZone®
- 32-bit Arm® Cortex®-M4 with FPU/MPU
  - Up to 209 MHz (Up to 703 CoreMark®)

### Memories

- External DDR memory up to 1 Gbyte
  - up to LPDDR2/LPDDR3-1066 16/32-bit
  - up to DDR3/DDR3L-1066 16/32-bit
- 708 Kbytes of internal SRAM: 256 Kbytes of AXI SYSRAM + 384 Kbytes of AHB SRAM + 64 Kbytes of AHB SRAM in Backup domain and 4 Kbytes of SRAM in Backup domain
- Dual mode Quad-SPI memory interface
- Flexible external memory controller with up to 16-bit data bus: parallel interface to connect external ICs and SLC NAND memories with up to 8-bit ECC

### Security/safety

- Secure boot, TrustZone® peripherals, active tamper
- Cortex®-M4 resources isolation

### Reset and power management

- 1.71 V to 3.6 V I/Os supply (5 V-tolerant I/Os)
- POR, PDR, PVD and BOR
- On-chip LDOs (RETRAM, BKPSRAM, USB 1.8 V, 1.1 V)
- Backup regulator (~0.9 V)
- Internal temperature sensors
- Low-power modes: Sleep, Stop and Standby

LFBGA448 (18 × 18mm)
LFBGA354 (16 × 16mm)
Pitch 0.8mm

TFBGA361 (12 × 12 mm)
TFBGA257 (10 × 10 mm)
min Pitch 0.5mm

- DDR memory retention in Standby mode
- Controls for PMIC companion chip

### Low-power consumption

- Total current consumption down to 2 µA (Standby mode, no RTC, no LSE, no BKPSRAM, no RETRAM)

### Clock management

- Internal oscillators: 64 MHz HSI oscillator, 4 MHz CSI oscillator, 32 kHz LSI oscillator
- External oscillators: 8-48 MHz HSE oscillator, 32.768 kHz LSE oscillator
- 5 × PLLs with fractional mode

### General-purpose input/outputs

- Up to 176 I/O ports with interrupt capability
  - Up to 8 secure I/Os
  - Up to 6 Wakeup, 3 tampers, 1 active tamper

### Interconnect matrix

- 2 bus matrices
  - 64-bit Arm® AMBA® AXI interconnect, up to 266 MHz
  - 32-bit Arm® AMBA® AHB interconnect, up to 209 MHz

### 3 DMA controllers to unload the CPU

- 48 physical channels in total
- 1 × high-speed general-purpose master direct memory access controller (MDMA)



This is information on a product in full production. www.st.com

- 2 × dual-port DMAs with FIFO and request router capabilities for optimal peripheral management

### Up to 37 communication peripherals

- 6 × $I^2C$ FM+ (1 Mbit/s, SMBus/PMBus)
- 4 × UART + 4 × USART (12.5 Mbit/s, ISO7816 interface, LIN, IrDA, SPI slave)
- 6 × SPI (50 Mbit/s, including 3 with full duplex $I^2S$ audio class accuracy via internal audio PLL or external clock)
- 4 × SAI (stereo audio: $I^2S$, PDM, SPDIF Tx)
- SPDIF Rx with 4 inputs
- HDMI-CEC interface
- MDIO Slave interface
- 3 × SDMMC up to 8-bit (SD / *e*•MMC™ / SDIO)
- 2 × CAN controllers supporting CAN FD protocol, out of which one supports time-triggered CAN (TTCAN)
- 2 × USB 2.0 high-speed Host + 1 × USB 2.0 full-speed OTG simultaneously
  - or 1 × USB 2.0 high-speed Host + 1 × USB 2.0 high-speed OTG simultaneously
- 10/100M or Gigabit Ethernet GMAC
  - IEEE 1588v2 hardware, MII/RMII/GMII/RGMII
- 8- to 14-bit camera interface up to 140 Mbyte/s

### 6 analog peripherals

- 2 × ADCs with 16-bit max. resolution (12 bits up to 4.5 Msps, 14 bits up to 4 Msps, 16 bits up to 3.6 Msps)
- 1 × temperature sensor
- 2 × 12-bit D/A converters (1 MHz)
- 1 × digital filters for sigma delta modulator (DFSDM) with 8 channels/6 filters
- Internal or external ADC/DAC reference $V_{REF+}$

### Graphics

- LCD-TFT controller, up to 24-bit // RGB888
  - up to WXGA (1366 × 768) @60 fps
  - Two layers with programmable colour LUT

### Up to 29 timers and 3 watchdogs

- 2 × 32-bit timers with up to 4 IC/OC/PWM or pulse counter and quadrature (incremental) encoder input
- 2 × 16-bit advanced motor control timers
- 10 × 16-bit general-purpose timers (including 2 basic timers without PWM)
- 5 × 16-bit low-power timers
- RTC with sub-second accuracy and hardware calendar
- 2 × 4 Cortex®-A7 system timers (secure, non-secure, virtual, hypervisor)
- 1 × SysTick M4 timer
- 3 × watchdogs (2 × independent and window)

### Hardware acceleration

- AES 128, 192, 256, TDES
- HASH (MD5, SHA-1, SHA224, SHA256), HMAC
- 2 × true random number generator (3 oscillators each)
- 2 × CRC calculation unit

### Debug mode

- Arm® CoreSight™ trace and debug: SWD and JTAG interfaces
- 8-Kbyte embedded trace buffer

### 3072-bit fuses including 96-bit unique ID, up to 1184-bit available for user

### All packages are ECOPACK2 compliant

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# 1 Introduction

This datasheet provides the ordering information and mechanical device characteristics of the STM32MP153C/F microprocessors.

This document should be read in conjunction with the STM32MP153 reference manual (RM0442), available from the STMicroelectronics website *www.st.com*.

For information on the Arm®(a) Cortex®-A7 and Cortex®-M4 cores, refer to the Cortex®-A7 and Cortex®-M4 *Technical Reference Manuals*.

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# 2 Description

The STM32MP153C/F devices are based on the high-performance dual-core Arm® Cortex®-A7 32-bit RISC core operating at up to 800 MHz. The Cortex-A7 processor includes a 32-Kbyte L1 instruction cache for each CPU, a 32-Kbyte L1 data cache for each CPU and a 256-Kbyte level2 cache. The Cortex-A7 processor is a very energy-efficient application processor designed to provide rich performance in high-end wearables, and other low-power embedded and consumer applications. It provides up to 20% more single thread performance than the Cortex-A5 and provides similar performance than the Cortex-A9.

The Cortex-A7 incorporates all features of the high-performance Cortex-A15 and Cortex-A17 processors, including virtualization support in hardware, NEON™, and 128-bit AMBA®4 AXI bus interface.

The STM32MP153C/F devices also embed a Cortex® -M4 32-bit RISC core operating at up to 209 MHz frequency. Cortex-M4 core features a floating point unit (FPU) single precision which supports Arm® single-precision data-processing instructions and data types. The Cortex® -M4 supports a full set of DSP instructions and a memory protection unit (MPU) which enhances application security.

The STM32MP153C/F devices provide an external SDRAM interface supporting external memories up to 8-Gbit density (1 Gbyte), 16 or 32-bit LPDDR2/LPDDR3 or DDR3/DDR3L up to 533 MHz.

The STM32MP153C/F devices incorporate high-speed embedded memories with 708 Kbytes of Internal SRAM (including 256 Kbytes of AXI SYSRAM, 3 banks of 128 Kbytes each of AHB SRAM, 64 Kbytes of AHB SRAM in backup domain and 4 Kbytes of SRAM in backup domain), as well as an extensive range of enhanced I/Os and peripherals connected to APB buses, AHB buses, a 32-bit multi-AHB bus matrix and a 64-bit multi layer AXI interconnect supporting internal and external memories access.

All the devices offer two ADCs, two DACs, a low-power RTC, 12 general-purpose 16-bit timers, two PWM timers for motor control, five low-power timers, a true random number generator (RNG), and a cryptographic acceleration cell. The devices support six digital filters for external sigma delta modulators (DFSDM). They also feature standard and advanced communication interfaces.

- Standard peripherals
  - Six $I^2Cs$
  - Four USARTs and four UARTs
  - Six SPIs, three $I^2Ss$ full-duplex master/slave. To achieve audio class accuracy, the $I^2S$ peripherals can be clocked via a dedicated internal audio PLL or via an external clock to allow synchronization.
  - Four SAI serial audio interfaces
  - One SPDIF Rx interface
  - Management data input/output slave (MDIOS)
  - Three SDMMC interfaces
  - An USB high-speed Host with two ports two high-speed PHYs and a USB OTG high-speed with full-speed PHY or high-speed PHY shared with second port of USB Host.
  - Two FDCAN interface, including one supporting TTCAN mode
  - A Gigabit Ethernet interface
  - HDMI-CEC
- Advanced peripherals including
  - A flexible memory control (FMC) interface
  - A Quad-SPI Flash memory interface
  - A camera interface for CMOS sensors
  - An LCD-TFT display controller

Refer to *Table 1: STM32MP153C/F features and peripheral counts* for the list of peripherals available on each part number.

A comprehensive set of power-saving mode allows the design of low-power applications.

The STM32MP153C/F devices are proposed in 4 packages ranging from 257 to 448 balls with pitch 0.5 mm to 0.8 mm. The set of included peripherals changes with the device chosen.

These features make the STM32MP153C/F suitable for a wide range of consumer, industrial, white goods and medical applications.

shows the general block diagram of the device family.

**Table 1. STM32MP153C/F features and peripheral counts**

| Features | | | STM32MP153CADxx STM32MP153FADxx | STM32MP153CABxx STM32MP153FABxx | STM32MP153CACxx STM32MP153FACxx | STM32MP153CAAxx STM32MP153FAAxx | Miscellaneous |
|---|---|---|---|---|---|---|---|
| | | | TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | |
| Package | | Body size (mm) | 10x10 | 16x16 | 12x12 | 18x18 | - |
| | | Pitch (mm) | 0.5(1) | 0.8 | 0.5(1) | 0.8 | |
| | | Ball size (mm) | 0.30 | 0.40 | 0.30 | 0.40 | |
| | | Thickness (mm) | <1.2 | <1.4 | <1.2 | <1.4 | |
| | | Ball count | 257 | 354 | 361 | 448 | |
| CPU | | | Dual-core Cortex-A7 FPU Neon TrustZone | | | | - |
| | | Caches size | 2 × 32-Kbyte L1 data cache | | | | |
| | | | 2 × 32-Kbyte L1 instruction cache | | | | |
| | | | 256-Kbyte level 2 unified coherent cache | | | | |
| | | Frequency | STM32MP153C: 2 × 650 MHz<br>STM32MP153F: 2 × 800 MHz | | | | |
| MCU core | | | Cortex-M4 FPU | | | | - |
| | | Frequency | 209 MHz | | | | |
| ROM | | | 128 Kbytes (secure) | | | | - |
| Embedded SRAM | | CPU system | 256 Kbytes (securable) | | | | 708 Kbytes |
| | | MCU subsystem | 384 Kbytes | | | | |
| | | MCU retention | 64 Kbytes | | | | |
| | | Backup | 4 Kbytes (securable, tamper protected) | | | | |
| SDRAM (securable) | LPDDR2/3 | 16-bit 533 MHz | Up to 1 Gbyte, single rank | | | | - |
| | | 32-bit 533 MHz | - | - | | | |
| | DDR3/3L | 16-bit 533 MHz | Up to 1 Gbyte, single rank | | | | |
| | | 32-bit 533 MHz | - | - | | | |
| Backup registers | | | 128 bytes (32x32-bit, securable, tamper protected) | | | | - |

**Table 1. STM32MP153C/F features and peripheral counts (continued)**

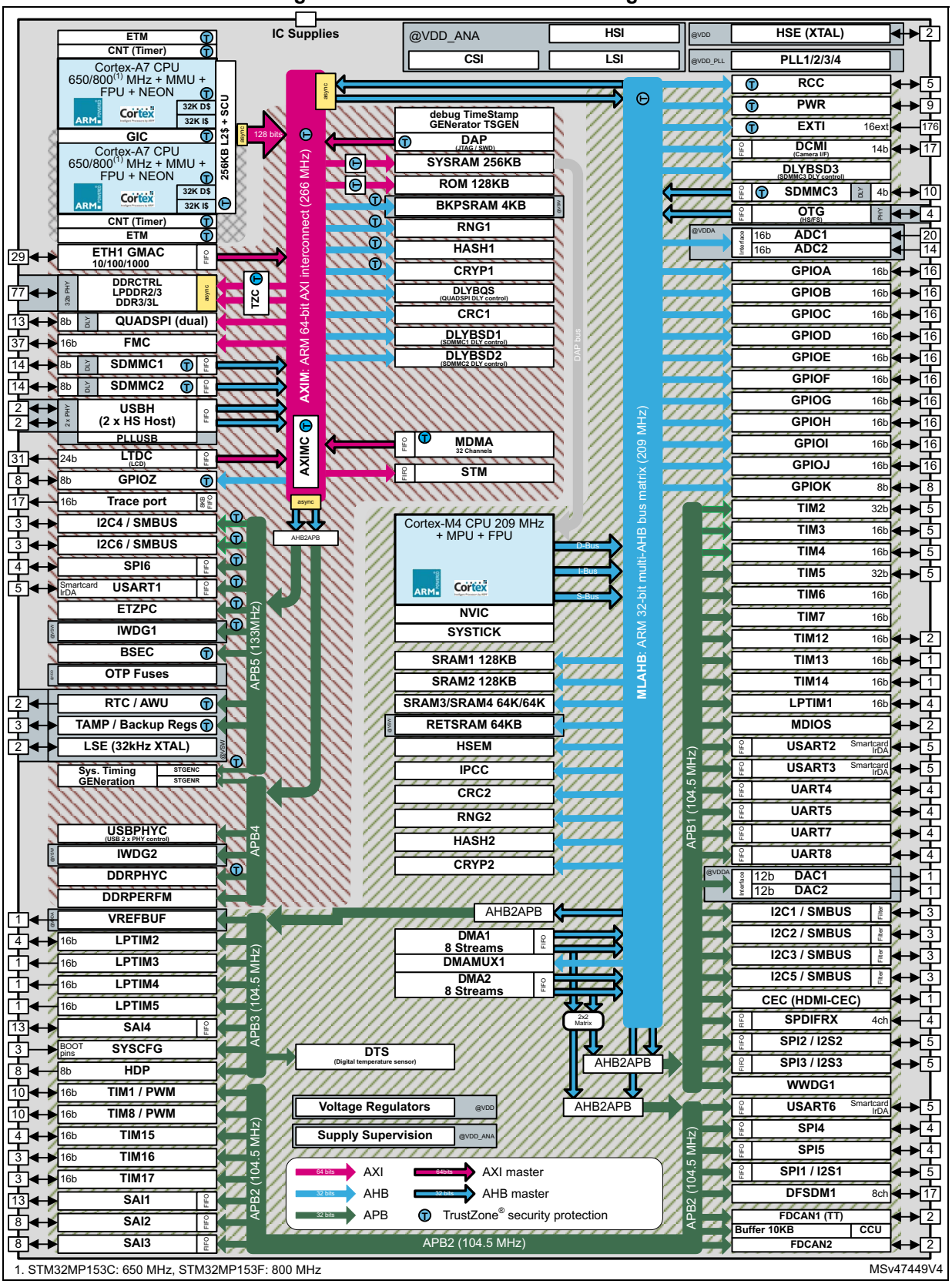
| Features | | | STM32MP153CADxx STM32MP153FADxx | STM32MP153CABxx STM32MP153FABxx | STM32MP153CACxx STM32MP153FACxx | STM32MP153CAAxx STM32MP153FAAxx | Miscellaneous |
|---|---|---|---|---|---|---|---|
| | | | TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | |
| Timers | Advanced | 16 bits | 2 | | | | 29 timers |
| | General purpose | 16 bits | 8 | | | | |
| | | 32 bits | 2 | | | | |
| | Basic | 16 bits | 2 | | | | |
| | Low power | 16 bits | 5 | | | | |
| | A7 timers | 64 bits | 2 × 4 (secure, non-secure, virtual, hypervisor) | | | | |
| | M4 SysTick | 24 bits | 1 | | | | |
| | RTC/AWU | | 1 (securable) | | | | |
| Watchdog | | | 3 (independent, independent secure, window) | | | | - |
| Communication peripherals | SPI | | 6 (1 securable) | | | | - |
| | | Having I2S | 3 | | | | |
| | I2C (with SMB/PMB support) | | 6 (2 securable) | | | | - |
| | USART (smartcard, SPI, IrDA, LIN) + UART (IrDA, LIN) | | 4 + 4 (including 1 securable USART) some can be a boot source | | | | Boot |
| | SAI | | 4 (up to 8 audio channels), with I2S master/slave, PCM input, SPDIF-TX | | | | Boot |
| | USB | EHCI/OHCI Host | 2 ports | | | | - |
| | | | Embedded HS PHY with BCD | | | | - |
| | | OTG HS/FS (dual role port) | Yes, embedded FS or HS PHY with BCD, can be a boot source | | | | Boot |
| | | Embedded PHYs | 3 (2 × high-speed + 1 × full-speed) | | | | - |
| | SPDIF-RX | | 4 inputs | | | | - |
| | FDCAN | | 2 (1 × TTCAN), clock calibration, 10 Kbyte shared buffer | | | | - |
| | HDMI-CEC | | 1 | | | | - |
| | Including the following securable | | 1 × USART, 1 × SPI, 2 × I2C | | 1 × USART, 1 × SPI, 2 × I2C on securable GPIOs | | - |
| **SDMMC (SD, SDIO, *e*•MMC)** | | | 3 (8 + 8 + 4 bits), *e*•MMC or SD can be a boot source | | | | Boot |
| **QuadSPI** | | | Yes (dual-quad), can be a boot source | | | | Boot |

**Table 1. STM32MP153C/F features and peripheral counts (continued)**

| Features | | | STM32MP153CADxx STM32MP153FADxx TFBGA257 | STM32MP153CABxx STM32MP153FABxx LFBGA354 | STM32MP153CACxx STM32MP153FACxx TFBGA361 | STM32MP153CAAxx STM32MP153FAAxx LFBGA448 | Miscellaneous |
|---|---|---|---|---|---|---|---|
| **FMC** | Parallel address/data 8/16-bit | | - | | 4 × CS, up to 4 × 64 Mbyte | | No boot |
| | Parallel AD-Mux 8/16-bit | | 4 × CS, up to 4 × 64 Mbytes | | | | |
| | NAND 8/16-bit | | Yes, 1 × CS, SLC, BCH4/8, can be a boot source | | | | Boot |
| **Gigabit Ethernet** | | | - | | MII, RMII, GMII, RGMII with PTP and EEE | | - |
| **10/100M Ethernet** | | | MII, RMII with PTP and EEE | | | | |
| **LCD-TFT** | Parallel interface | | up to 24-bit data (up to 1366×768 60 fps) | | | | - |
| **DMA** | | | 3 instances (1 securable), 48 physical channels in total | | | | - |
| **Cryptography** | | | DES, TDES, AES-256 dual instances (secure and non-secure) | | | | - |
| **Hash** | | | SHA-256, MD5, HMAC dual instances (secure and non-secure) | | | | - |
| **True random number generator** | | | True-RNG, dual instances (secure and non-secure) | | | | - |
| **Fuses (one-time programmable)** | | | 3072 effective bits (secure, >1500 bits available for user) | | | | - |
| **Camera interface** | Bus width | | 14-bit | | | | - |
| **GPIOs with interrupt (total count)** | | | 98 | | 148 | 176 | - |
| | Securable GPIOs | | - | | 8 | | |
| | Wakeup pins | | 4 | | 6 | | |
| | Tamper pins (active tamper) | | 2 (1) | | 3 (1) | | |
| **DFSDM** | | | 8 input channels with 6 filters | | | | - |
| **Up to** | **16-bit synchronized ADC** | | 2 (up to 3.6/4/4.5/5/6 Msps on 16/14/12/10/8-bit each) | | | | - |
| | Low noise 16 bit (differential) | | - | | 2 (1) | | |
| | 16 bit (differential) | | 17 (7) | | 20 (9) | | |
| | ADC channels in total(2) | | 17 | | 22 | | |
| **12-bit DAC** | | | 2 | | | | - |
| **Internal ADC/DAC VREF** | | | 1.5 V, 1.8 V, 2.048 V, 2.5 V or VREF+ input | | | | - |
| | VREF+ input pin | | Yes | | | | |

1. With inner matrix balls having 0.65 mm pitch to allow optimized PCB routing for supplies.
2. In addition, there is also 6 internal channels for temperature, internal voltage reference, $V_{DDCORE}$, $V_{BAT}$/4, DAC1 or DAC2 acquisitions.

**Figure 1. STM32MP153C/F block diagram**




1. STM32MP153C: 650 MHz, STM32MP153F: 800 MHz

MSv47449V4

# 3 Functional overview

## 3.1 Dual-core Arm® Cortex®-A7 subsystem

### 3.1.1 Features

- ARMv7-A architecture
- 32-Kbyte L1 instruction cache for each CPU
- 32-Kbyte L1 data cache for each CPU
- 256-Kbyte level2 cache
- Arm® + Thumb®-2 instruction set
- Arm® TrustZone® security technology
- Arm® NEON™ Advanced SIMD
- DSP and SIMD extensions
- VFPv4 floating-point
- Hardware virtualization support
- Embedded trace module (ETM)
- Integrated generic interrupt controller (GIC) with 256 shared peripheral interrupts
- Integrated generic timer (CNT)

### 3.1.2 Overview

The Cortex-A7 processor is a very energy-efficient applications processor designed to provide rich performance in high-end wearables, and other low-power embedded and consumer applications. It provides up to 20 % more single thread performance than the Cortex-A5 and provides similar performance than the Cortex-A9.

The Cortex-A7 incorporates all features of the high-performance Cortex-A15 and Cortex-A17 processors, including virtualization support in hardware, NEON™, and 128-bit AMBA®4 AXI bus interface.

The Cortex-A7 processor builds on the energy-efficient 8-stage pipeline of the Cortex-A5 processor. It also benefits from an integrated L2 cache designed for low-power, with lower transaction latencies and improved OS support for cache maintenance. On top of this, there is improved branch prediction and improved memory system performance, with 64-bit load-store path, 128-bit AMBA 4 AXI buses and increased TLB size (256 entry, up from 128 entry for Cortex-A9 and Cortex-A5), increasing performance for large workloads such as web browsing.

#### Thumb-2 technology

Delivers the peak performance of traditional Arm® code while also providing up to a 30 % reduction in memory requirement for instructions storage.

#### TrustZone technology

Ensures reliable implementation of security applications ranging from digital rights management to electronic payment. Broad support from technology and industry partners.

### NEON

NEON technology can accelerate multimedia and signal processing algorithms such as video encode/decode, 2D/3D graphics, gaming, audio and speech processing, image processing, telephony, and sound synthesis. The Cortex-A7 provides an engine that offers both the performance and functionality of the Cortex-A7 floating-point unit (FPU) and an implementation of the NEON advanced SIMD instruction set for further acceleration of media and signal processing functions. The NEON extends the Cortex-A7 processor FPU to provide a quad-MAC and additional 64-bit and 128-bit register set supporting a rich set of SIMD operations over 8-, 16- and 32-bit integer and 32-bit floating-point data quantities.

### Hardware virtualization

Highly efficient hardware support for data management and arbitration, whereby multiple software environments and their applications are able to simultaneously access the system capabilities. This enables the realization of devices that are robust, with virtual environments that are well isolated from each other.

### Optimized L1 caches

Performance and power optimized L1 caches combine minimal access latency techniques to maximize performance and minimize power consumption. There is also the option of cache coherence for enhanced inter-processor communication, or support of a rich SMP capable OS for simplified multicore software development.

### Integrated L2 cache controller

Provides low-latency and high-bandwidth access to cached memory in high-frequency, or to reduce the power consumption associated with off-chip memory access.

### Cortex-A7 floating-point unit (FPU)

The FPU provides high-performance single and double precision floating-point instructions compatible with the Arm VFPv4 architecture that is software compatible with previous generations of Arm floating-point coprocessor.

### Snoop control unit (SCU)

The SCU is responsible for managing the interconnect, arbitration, communication, cache to cache and system memory transfers, cache coherence and other capabilities for the processor.

This system coherence also reduces software complexity involved in maintaining software coherence within each OS driver.

### Generic interrupt controller (GIC)

Implementing the standardized and architected interrupt controller, the GIC provides a rich and flexible approach to inter-processor communication and the routing and prioritization of system interrupts.

Supporting up to 288 independent interrupts, under software control, each interrupt can be distributed across A7 cores, hardware prioritized, and routed between the operating system and TrustZone software management layer.

This routing flexibility and the support for virtualization of interrupts into the operating system, provides one of the key features required to enhance the capabilities of a solution utilizing a hypervisor.

## 3.2 Arm® Cortex®-M4 with FPU

The Arm® Cortex®-M4 with FPU core is a 32-bit RISC processor that features exceptional code-efficiency, delivering the high-performance expected from an Arm core in the memory size usually associated with 8- and 16-bit devices.

The processor supports a set of DSP instructions which allow efficient signal processing and complex algorithm execution.

Its single precision FPU (floating point unit) speeds up software development by using metalanguage development tools, while avoiding saturation.

*Note: Cortex-M4 with FPU core is binary compatible with the Cortex-M3 core.*

### Memory protection unit (MPU)

The memory protection unit (MPU) manages the Cortex®-M4 access rights and the attributes of the system resources. It has to be programmed and enabled before use. Its main purposes are to prevent an untrusted user program to accidentally corrupt data used by the OS and/or by a privileged task, but also to protect data processes or read-protect memory regions.

The MPU defines access rules for privileged accesses and user program accesses. It allows the definition of up to 16 protected regions that can in turn be divided into up to 8 independent subregions, where region address, size, and attributes can be configured. The protection area ranges from 32 bytes to 4 Gbytes of addressable memory.

When an unauthorized access is performed, a memory management exception is generated.

## 3.3 Memories

### 3.3.1 External SDRAM

The STM32MP153C/F devices embed a controller for external SDRAM which support the following devices

- LPDDR2 or LPDDR3, 16- or 32-bit data, up to 1 Gbyte, up to 533 MHz clock.
- DDR3 or DDR3L, 16- or 32-bit data, up to 1 Gbyte, up to 533 MHz clock.

### 3.3.2 Embedded SRAM

All devices feature:

- SYSRAM in MPU domain: 256 Kbytes
- SRAM1 in MCU domain: 128 Kbytes
- SRAM2 in MCU domain: 128 Kbytes
- SRAM3 in MCU domain: 64 Kbytes
- SRAM4 in MCU domain: 64 Kbytes
- RETRAM (retention RAM): 64 Kbytes

  The content of this area can be retained in Standby or $V_{BAT}$ mode.
- BKPSRAM (backup SRAM): 4 Kbytes

  The content of this area is protected against possible unwanted write accesses, and can be retained in Standby or $V_{BAT}$ mode.

  BKPSRAM can be defined (in ETZPC) as accessible by secure software only.

## 3.4 DDR3/DDR3L/LPDDR2/LPDDR3 controller (DDRCTRL)

DDRCTRL combined with DDRPHYC provides a complete memory interface solution for DDR memory subsystem.

- Two 64-bit AMBA 4 AXI4 ports interface (XPI)
- AXI clock asynchronous to the controller
- Supported standards:
  - JEDEC DDR3 SDRAM specification, JESD79-3E for DDR3/3L with 32-bit interface
  - JEDEC LPDDR2 SDRAM specification, JESD209-2E for LPDDR2 with 32-bit interface
  - JEDEC LPDDR3 SDRAM specification, JESD209-3B for LPDDR3 with 32-bit interface
- Advanced scheduler and SDRAM command generator
- Programmable full data width (32-bit) or half data width (16-bit)
- Advanced QoS support with 3 traffic class on read and 2 traffic classes on write
- Options to avoid starvation of lower priority traffic
- Guaranteed coherency for write-after-read (WAR) and read-after-write (RAW) on AXI ports
- Programmable support for burst length options (4, 8,16)
- Write combine to allow multiple writes to the same address to be combined into a single write
- Single rank configuration
- Supports automatic SDRAM power-down entry and exit caused by lack of transaction arrival for programmable time
- Supports automatic clock stop (LPDDR2/3) entry and exit caused by lack of transaction arrival
- Supports automatic low power mode operation caused by lack of transaction arrival for programmable time via hardware low power interface
- Programmable paging policy
- Supports automatic or under software control self-refresh entry and exit
- Support for deep power-down entry and exit under software control (LPDDR2)
- Support for explicit SDRAM mode register updates under software control
- Flexible address mapper logic to allow application specific mapping of row, column, bank bits
- User-selectable refresh control options
- DDRPERFM associated block to help for performance monitoring and tuning

DDRCTRL and DDRPHYC can be defined (in ETZPC) as accessible by secure software only.

## 3.5 TrustZone address space controller for DDR (TZC)

TZC is used to filter read/write accesses to DDR controller according to TrustZone rights and according to non-secure master (NSAID) on up to 9 programmable regions.

- Configuration is supported by trusted software only
- 2 filter units working concurrently
- 9 regions:
  - region 0 is always enabled and covers the whole address range.
  - regions 1 to 8 have programmable base/end address and can be assigned to any one or both filters.
- Secure and non-secure access permissions programmed per region
- Non-secure accesses are filtered according to NSAID
- Regions controlled by same filter must not overlap
- Fail modes with error and/or interrupt
- Acceptance capability = 256
- Gate keeper logic to enable and disable of each filter
- Speculative accesses

## 3.6 Boot modes

At startup, the boot source used by the internal BootROM is selected by the BOOT pin and OTP bytes.

**Table 2. Boot modes**

| BOOT2 | BOOT1 | BOOT0 | Initial boot mode | Comments |
|---|---|---|---|---|
| 0 | 0 | 0 | UART and USB(1) | Wait incoming connection on:<br>– USART2/3/6 and UART4/5/7/8 on default pins<br>– USB high-speed device(2) |
| 0 | 0 | 1 | Serial NOR Flash(3) | Serial NOR Flash on QUADSPI(4) |
| 0 | 1 | 0 | *e*•MMC(3) | *e*•MMC on SDMMC2 (default)(4)(5) |
| 0 | 1 | 1 | NAND Flash(3) | SLC NAND Flash on FMC |
| 1 | 0 | 0 | Reserved (NoBoot) | Used to get debug access without boot from Flash memory |
| 1 | 0 | 1 | SD card(3) | SD card on SDMMC1 (default)(4)(5) |
| 1 | 1 | 0 | UART and USB(1)(3) | Wait incoming connection on:<br>– USART2/3/6 and UART4/5/7/8 on default pins<br>– USB high-speed device on OTG_HS_DP/DM pins(2) |
| 1 | 1 | 1 | Serial NAND Flash(3) | Serial NAND Flash on QUADSPI(4) |

1. can be disabled by OTP settings.
2. USB requires 24 MHz HSE clock/crystal if OTP is not programmed for different frequency.
3. Boot source can be changed by OTP settings (e.g. initial boot on SD card, then *e*•MMC with OTP settings).
4. Default pins can be altered by OTP.
5. Alternatively, another SDMMC1 or SDMMC2 interface than this default can be selected by OTP.

## 3.7 Power supply management

### 3.7.1 Power supply scheme

- The $V_{DD}$ is the main supply for I/Os and internal part kept powered during Standby mode. Useful voltage range is 1.71 V to 3.6 V (e.g. 1.8 V, 2.5 V, 3.0 V or 3.3 V typ.)
  - $V_{DD_PLL}$ and $V_{DD_ANA}$ must be star-connected to $V_{DD}$.
- The $V_{DDCORE}$ is the main digital voltage and is usually shutdown during Standby mode. Voltage range during Run mode is 1.18 V to 1.25/1.38 V (1.2/1.34 V typ.), see *Table 13: General operating conditions*.
- The VBAT pin can be connected to the external battery (1.2 V < $V_{BAT}$ < 3.6 V). If no external battery is used, it is mandatory to connect this pin to $V_{DD}$.
- The VDDA pin is the analog (ADC/DAC/VREF), supply voltage range is 1.71 V to 3.6 V. DAC can only be used when $V_{DDA}$ is above or equal 1.8 V. Using Internal $V_{REF+}$ requires $V_{DDA}$ equal to or higher than $V_{REF+}$ + 0.3 V.
- The VDDA1V8_REG pin is the output of internal regulator and connected internally to USB PHY and USB PLL. Internal $V_{DDA1V8_REG}$ regulator is enabled by default and can be controlled by software. It is always shut down during Standby mode.

  There is specific BYPASS_REG1V8 pin that must be connected either to $V_{SS}$ or $V_{DD}$ to activate or deactivate the voltage regulator. It is mandatory to bypass the 1.8 V regulator when $V_{DD}$ is below 2.25 V (BYPASS_REG1V8 = $V_{DD}$). In that case, VDDA1V8_REG pin must be connected to $V_{DD}$ (if below 1.98 V) or to a dedicated 1.65 V - 1.98 V supply (1.8 V typ.).
- 
- VDDA1V1_REG pin is the output of internal regulator connected internally to USB PHY. Internal $V_{DDA1V1_REG}$ regulator is enabled by default and can be controlled by software. It is always shut down during Standby mode.
- $V_{DD3V3_USBHS}$ and $V_{DD3V3_USBFS}$ are respectively the USB high-speed and full-speed PHY supply. Voltage range is 3.07 V to 3.6 V. $V_{DD3V3_USBFS}$ is used to supply OTG_VBUS and ID pins. So, $V_{DD3V3_USBFS}$ must be supplied as well when USB high-speed OTG device is used. If not used, must be connected to $V_{DD}$.

**Caution:** $V_{DD3V3_USBHS}$ must not be present unless $V_{DDA1V8_REG}$ is present, otherwise permanent STM32MP153C/F damage could occur. Must be ensured by PMIC ranking order or with external component in case of discrete component power supply implementation.

- $V_{DDQ_DDR}$ is the DDR IO supply.
  - Voltage range is 1.425 V to 1.575 V for interfacing DDR3 memories (1.5 V typ.).
  - Voltage range is 1.283 V to 1.45 V for interfacing DDR3L memories (1.35 V typ.).
  - Voltage range is 1.14 V to 1.3 V for interfacing LPDDR2 or LPDDR3 memories (1.2 V typ.).

During power-up and power-down phases, the following power sequence requirements must be respected:

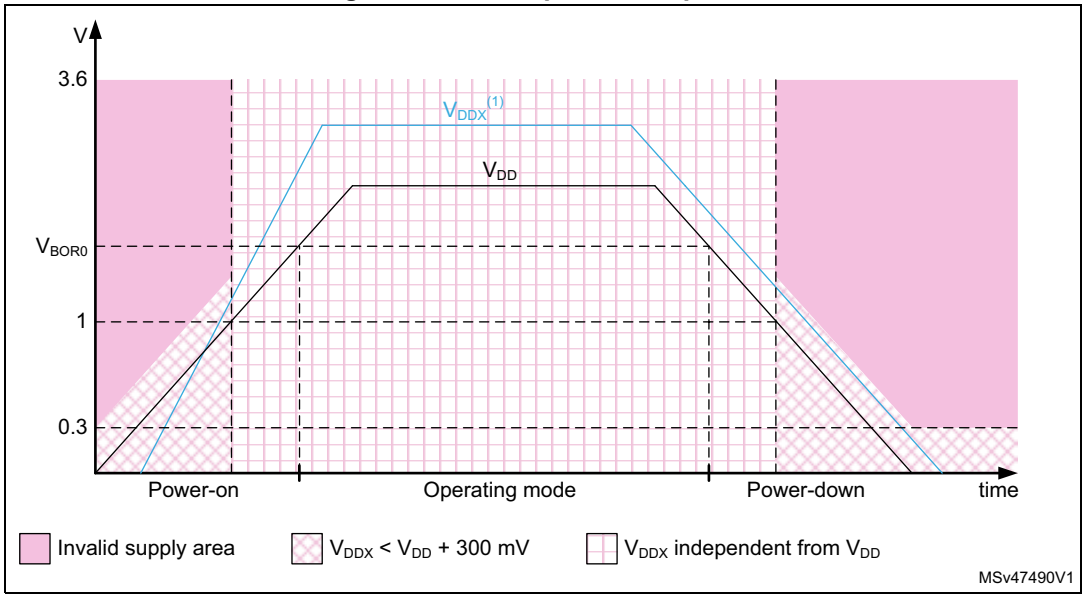
• When $V_{DD}$ is below 1 V, other power supplies ($V_{DDCORE}$, $V_{DDA}$, $V_{DDA1V8_REG}$, $V_{DDA1V1_REG}$, $V_{DD3V3_USBHS/FS}$, $V_{DDQ_DDR}$) must remain below $V_{DD}$ + 300 mV.

• When $V_{DD}$ is above 1 V, all power supplies are independent.

During the power-down phase, $V_{DD}$ can temporarily become lower than other supplies only if the energy provided to the STM32MP153C/F device remains below 1 mJ; this allows

external decoupling capacitors to be discharged with different time constants during the power- down transient phase.

**Figure 2. Power-up/down sequence**




1. $V_{DDX}$ refers to any power supply among $V_{DDCORE}$, $V_{DDA}$, $V_{DDA1V8_REG}$, , $V_{DDA1V1_REG}$, $V_{DD3V3_USBHS/FS}$, $V_{DDQ_DDR}$.

### 3.7.2 Power supply supervisor

The devices have an integrated power-on reset (POR)/ power-down reset (PDR) circuitry coupled with a Brownout reset (BOR) circuitry:

- Power-on reset (POR)

  The POR supervisor monitors $V_{DD}$ power supply and compares it to a fixed threshold. The devices remain in reset mode when $V_{DD}$ is below this threshold,
- Power-down reset (PDR)

  The PDR supervisor monitors $V_{DD}$ power supply. A reset is generated when $V_{DD}$ drops below a fixed threshold.

  The PDR supervisor can be enabled/disabled through PDR_ON pin.
- Brownout reset (BOR)

  The BOR supervisor monitors $V_{DD}$ power supply. Three BOR thresholds (from 2.1 to 2.7 V) can be configured through option bytes. A reset is generated when $V_{DD}$ drops below this threshold.
- Power-on reset $V_{DDCORE}$ (POR_VDDCORE)

  The POR_VDDCORE supervisor monitors $V_{DDCORE}$ power supply and compares it to a fixed threshold. The $V_{DDCORE}$ domain remain in reset mode when $V_{DDCORE}$ is below this threshold,
- Power-down reset $V_{DDCORE}$ (PDR_VDDCORE)

  The PDR_VDDCORE supervisor monitors $V_{DDCORE}$ power supply. A $V_{DDCORE}$ domain reset is generated when $V_{DDCORE}$ drops below a fixed threshold.

  The PDR_VDDCORE supervisor can be enabled/disabled through PDR_ON_CORE pin.

## 3.8 Low-power strategy

There are several ways to reduce power consumption on STM32MP153C/F:

- Decrease dynamic power consumption by slowing down the CPU clocks and/or the bus matrix clocks and/or controlling individual peripheral clocks.
- Save power consumption when the CPU is IDLE, by selecting among the available low-power mode according to the user application needs. This allows the best compromise between short startup time, low-power consumption, as well as available wakeup sources, to be achieved.

The CPUs feature several low-power modes:

- CSleep (CPU clock stopped)
- CStop (CPU sub-system clock stopped)
- Stop (bus matrix clocks stalled, the oscillators can be stopped)
- CStandby (MPU sub-system clock stopped and wakeup via reset)
- Standby (system powered down)
- LP-Stop and LPLV-Stop (bus matrix clocks stalled, the oscillators can be stopped, low-power mode signaled to external regulator)

CSleep and CStop low-power modes are entered by the CPU when executing the WFI (wait for interrupt) or WFE (Wait for Event) instructions, or when the SLEEPONEXIT bit of the Cortex-M4 core is set after returning from an interrupt service routine.

If part of the domain is not in low-power mode, the domain remains in the current mode.

Finally the system can enter Stop or Standby when all EXTI wakeup sources are cleared and the CPUs are in CStop or CStandby mode.

**Table 3. System versus domain power mode**

| System power mode | MPU | MCU |
|---|---|---|
| Run mode | CRun or CSleep | CRun or CSleep |
| | CStop or CStandby | |
| | CRun or CSleep | CStop |
| Stop mode<br>LP-Stop mode<br>LPLV-Stop mode | CStop or CStandby | CStop |
| Standby mode | CStandby or (CStop and<br>MPU PDDS = 1 and MPU CSTBYDIS = 1) | CStop and<br>MCU PDDS = 1 |

## 3.9 Reset and clock controller (RCC)

The clock and reset controller manages the generation of all the clocks, as well as the clock gating and the control of the system and peripheral resets. It provides a high flexibility in the choice of clock sources and allows application of clock ratios to improve the power consumption. In addition, on some communication peripherals that are capable to work with two different clock domains (either a bus interface clock or a kernel peripheral clock), the system frequency can be changed without modifying the baudrate.

### 3.9.1 Clock management

The devices embed four internal oscillators, two oscillators with external crystal or resonator, three internal oscillators with fast startup time and four PLLs.

The RCC receives the following clock source inputs:

- Internal oscillators:
  - 64 MHz HSI clock (1% accuracy)
  - 4 MHz CSI clock
  - 32 kHz LSI clock
- External oscillators:
  - 8-48 MHz HSE clock
  - 32.768 kHz LSE clock

The RCC provides four PLLs:

- The PLL1 is dedicated to the MPU clocking
- The PLL2 provides:
  - The clocks for the AXI-SS (including APB4, APB5, AHB5 and AHB6 bridges)
  - The clocks for the DDR interface
- The PLL3 provides:
  - The clocks for the MCU, and its bus matrix (including the APB1, APB2, APB3, AHB1, AHB2, AHB3 and AHB4)
  - The kernel clocks for peripherals
- The PLL4 is dedicated to the generation of the kernel clocks for various peripherals

The system starts on the HSI clock. The user application can then select the clock configuration.

### 3.9.2 System reset sources

The power-on reset initializes all registers while the system reset reinitializes the system except for the debug, part of the RCC and power controller status registers, as well as the backup power domain.

An application reset is generated from one of the following sources:

- a reset from NRST pad
- a reset from POR and PDR signal (generally called power-on reset)
- a reset from BOR (generally called brownout)
- a reset from the independent watchdogs 1
- a reset from the independent watchdogs 2
- a software reset from the Cortex-M4 (MCU)
- a software reset from the Cortex-A7 (MPU)
- a failure on HSE, when the clock security system feature is activated

A system reset is generated from one of the following sources:

- An application reset,
- A reset from POR_VDDCORE signal,
- Every time the system exits from Standby.

## 3.10 Hardware semaphore (HSEM)

The HW semaphore block provides 64 (32-bit) register-based semaphores.

The semaphores can be used to ensure synchronization between different processes running on a core and between different cores. The HSEM provides a non blocking mechanism to lock semaphores in an atomic way. The following functions are provided:

- Locking a semaphore can be done in 2 ways:
  - 2-step lock: by writing CoreID and ProcessID to the semaphore, followed by a read check.
  - 1-step lock: by reading the CoreID from the semaphore.
- Interrupt generation when a semaphore is freed.
  - Each semaphore may generated an interrupt on one of the interrupt lines.
- Semaphore clear protection.
  - A semaphore is only cleared when CoreID and ProcessID matches.
- Global semaphore clear per CoreID.

## 3.11 Inter-processor communication controller (IPCC)

The inter-processor communication controller (IPCC) is used for communicating data between two processors.

The IPCC block provides a non blocking signaling mechanism to post and retrieve communication data in an atomic way. It provides the signaling for four channels:

- two channels in the direction from processor 1 to processor 2
- two channels in the opposite direction.

It is then possible to have two different communication types in each direction.

The IPCC communication data must be located in a common memory, which is not part of the IPCC block.

### 3.11.1 IPCC main features

- Status signaling for the four channels
  - Channel occupied/free flag, also used as lock
- Two interrupt lines per processor
  - One for RX channel occupied (communication data posted by sending processor)
  - One for TX channel free (communication data retrieved by receiving processor)
- Interrupt masking per channel
  - Channel occupied mask
  - Channel free mask
- Two channel operation modes
  - Simplex (each channel has its own communication data memory location)
  - Half duplex (a single channel in associated to a bidirectional communication data information memory location)

## 3.12 General-purpose input/outputs (GPIOs)

Each of the GPIO pins can be configured by software as output (push-pull or open-drain, with or without pull-up or pull-down), as input (with or without pull-up or pull-down) or as peripheral alternate function. Most of the GPIO pins are shared with digital or analog alternate functions. All GPIOs are high-current-capable and have speed selection to better manage internal noise, power consumption and electromagnetic emission.

After reset, all GPIOs are in analog mode to reduce power consumption.

The I/O configuration can be locked if needed by following a specific sequence in order to avoid spurious writing to the I/Os registers.

Additionally, GPIO pins on port Z can be individually set as secure, which would mean that software accesses to these GPIOs and associated peripherals defined as secure are restricted to secure software running on Cortex-A7.

## 3.13 TrustZone protection controller (ETZPC)

ETZPC is used to configure TrustZone security of bus masters and slaves with programmable-security attributes (securable resources) such as:

- On-chip SYSRAM with programmable secure region size
- AHB and APB peripherals to be made secure

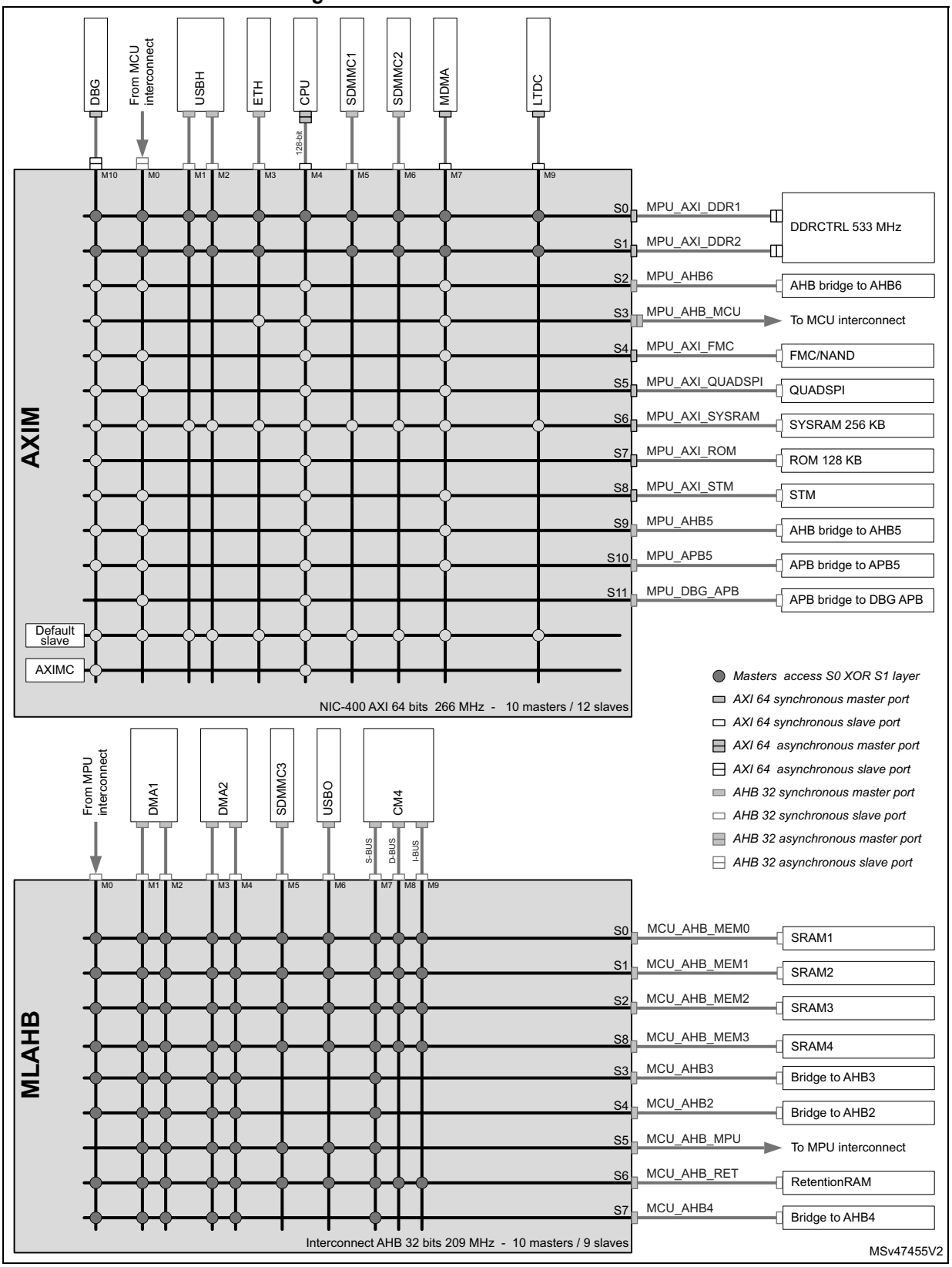
Notice that by default, SYSRAM and peripheral are set to secure access only, so, not accessible by non-secure masters such as Cortex-M4 or DMA1/DMA2.

ETZPC can also allocate peripherals and SRAM to be accessible only by the Cortex-M4 and/or DMA1/DMA2. This ensures the safe execution of the Cortex-M4 firmware, protected from other masters (e.g. Cortex-A7) unwanted accesses.

## 3.14 Bus-interconnect matrix

The devices feature an AXI bus matrix, one main AHB bus matrix and bus bridges that allow bus masters to be interconnected with bus slaves (see *Figure 3*, the dots represent the enabled master/slave connections).

**Figure 3. STM32MP153C/F bus matrix**



## 3.15 DMA controllers

The devices features three DMA modules to unload CPU activity:

- A master direct memory access (MDMA)

  The MDMA is a high-speed DMA controller, which is in charge of all types of memory transfers (peripheral to memory, memory to memory, memory to peripheral), without any CPU action. It features a master AXI interface.

  The MDMA is located in MPU domain. It is able to interface with the other DMA controllers located in MCU domain to extend the standard DMA capabilities, or can manage peripheral DMA requests directly.

  Each of the 32 channels can perform block transfers, repeated block transfers and linked list transfers.

  The MDMA can be set to make secure transfers to secured memories.
- Two DMA controllers (DMA1, DMA2), located in MCU domain. Each controller is a dual-port AHB, for a total of 16 DMA channels to perform FIFO-based block transfers.

The DMAMUX is an extension of the DMA1 and DMA2 controllers. It multiplexes and routes the DMA peripheral requests to the DMA1 or DMA2 controllers, with a high flexibility, maximizing the number of DMA requests that run concurrently, as well as generating DMA requests from peripheral output trigger or DMA event.

## 3.16 Nested vectored interrupt controller (NVIC)

The devices embed a nested vectored interrupt controller able to manage 16 priority levels, and handle up to 150 maskable interrupt channels plus the 16 interrupt lines of the Cortex®-M4 with FPU core.

- Closely coupled NVIC gives low-latency interrupt processing
- Interrupt entry vector table address passed directly to the core
- Allows early processing of interrupts
- Processing of late arriving, higher-priority interrupts
- Support tail chaining
- Processor context automatically saved
- Interrupt entry restored on interrupt exit with no instruction overhead

This hardware block provides flexible interrupt management features with minimum interrupt latency.

## 3.17 Extended interrupt and event controller (EXTI)

The extended interrupt and event controller (EXTI) manages individual CPU and system wakeup through configurable and direct event inputs. It provides wake-up requests to the power control, and generates an interrupt request to the CPUs NVIC or GIC and events to the CPUs event inputs. For each CPU an additional event generation block (EVG) is needed to generate the CPU event signal.

The EXTI wake-up requests allow the system to be woken up from Stop mode, and the CPUs to be woken up from CStop and CStandby modes.

The interrupt request and event request generation can also be used in Run mode.

The block also includes the EXTI IOport selection.

Each interrupt or event can be set as secure in order to restrict access to secure software only.

## 3.18 Cyclic redundancy check calculation unit (CRC1, CRC2)

The CRC (cyclic redundancy check) calculation unit is used to get a CRC code using a programmable polynomial.

Among other applications, CRC-based techniques are used to verify data transmission or storage integrity. In the scope of the EN/IEC 60335-1 standard, they offer a means of verifying the Flash memory integrity. The CRC calculation unit helps computing a signature of the software during runtime, to be compared with a reference signature generated at link-time and stored at a given memory location.

## 3.19 Flexible memory controller (FMC)

The FMC controller main features are the following:

- Interface with static-memory mapped devices including:
  - NOR Flash memory
  - Static or pseudo-static random access memory (SRAM, PSRAM)
  - NAND Flash memory with 4-bit/8-bit BCH hardware ECC
- 8-,16-bit data bus width
- Independent chip select control for each memory bank
- Independent configuration for each memory bank
- Write FIFO

## 3.20 Dual Quad-SPI memory interface (QUADSPI)

The QUADSPI is a specialized communication interface targeting single, dual or quad SPI Flash memories. It can operate in any of the three following modes:

- indirect mode: all the operations are performed using the QUADSPI registers
- status polling mode: the external Flash memory status register is periodically read and an interrupt can be generated in case of flag setting
- memory-mapped mode: the external Flash memory is mapped to the address space and is seen by the system as if it was an internal memory

Both throughput and capacity can be increased two-fold using dual-flash mode, where two Quad-SPI Flash memories are accessed simultaneously.

QUADSPI is coupled with a delay block (DLYBQS) allowing the support of external data frequency above 100 MHz.

## 3.21 Analog-to-digital converters (ADCs)

The STM32MP153C/F devices embed two analog-to-digital converters, which resolution can be configured to 16, 14, 12, 10 or 8 bits. Each ADC shares up to 20 external channels, performing conversions in the single-shot or scan mode. In scan mode, automatic conversion is performed on a selected group of analog inputs.

Additional logic functions embedded in the ADC interface allow:

- simultaneous ADC1/ADC2 conversion
- interleaved ADC1/ADC2 conversion.

The ADC can be served by the DMA controller, thus allowing the automatic transfer of ADC converted values to a destination location without any software action.

In addition, an analog watchdog feature can accurately monitor the converted voltage of one, some or all selected channels. An interrupt is generated when the converted voltage is outside the programmed thresholds.

In order to synchronize A/D conversion and timers, the ADCs can be triggered by any of TIM1, TIM2, TIM3, TIM4, TIM6, TIM8, TIM15, LPTIM1, LPTIM2 and LPTIM3 timers.

## 3.22 Temperature sensor

The STM32MP153C/F devices embed a temperature sensor that generates a voltage ($V_{TS}$) that varies linearly with the temperature. This temperature sensor is internally connected to ADC2_INP12. It can measure the device ambient temperature ranging from –40 to +125 °C with a precision of ±2%.

The temperature sensor has a good linearity, but it has to be calibrated to obtain a good overall accuracy of the temperature measurement. As the temperature sensor offset varies from chip to chip due to process variation, the uncalibrated internal temperature sensor is suitable for applications that detect temperature changes only. To improve the accuracy of the temperature sensor measurement, each device is individually factory-calibrated by ST. The temperature sensor factory calibration data are stored by ST in the OTP area, which is accessible in read-only mode.

## 3.23 Digital temperature sensor (DTS)

The device embeds a frequency output temperature sensor. This block counts the frequency based on the LSE or PCLK to provide the temperature information.

Following functions can be supported:

- Interrupt generation by temperature threshold.
- Wakeup signal generation by temperature threshold.

## 3.24 $V_{BAT}$ operation

The $V_{BAT}$ power domain contains the RTC, the backup registers, the retention RAM and the backup SRAM.

In order to optimize battery duration, this power domain is supplied by $V_{DD}$ when available or by the voltage applied on VBAT pin (when $V_{DD}$ supply is not present). $V_{BAT}$ power is switched when the PDR detects that $V_{DD}$ has dropped below the PDR level.

The voltage on the VBAT pin could be provided by an external battery, a supercapacitor or directly by $V_{DD}$. In the later case, VBAT mode is not functional.

$V_{BAT}$ operation is activated when $V_{DD}$ is not present.

The $V_{BAT}$ pin supplies the RTC, the backup registers, the retention RAM and the backup SRAM.

*Note: None of these events: external interrupts, TAMP event, or RTC alarm/events are able to directly restore the $V_{DD}$ supply and force the STM32MP153C/F device out of the $V_{BAT}$ operation. Nevertheless, TAMP events and RTC alarm/events can be used to generate a signal to an external circuitry (typically a PMIC) that can restore the STM32MP153C/F $V_{DD}$ supply.*

*When PDR_ON pin is connected to $V_{SS}$ (internal reset OFF), the $V_{BAT}$ functionality is no more available and VBAT pin must be connected to $V_{DD}$.*

## 3.25 Digital-to-analog converters (DAC1, DAC2)

The two 12-bit buffered DAC channels can be used to convert two digital signals into two analog voltage signal outputs.

This dual digital interface supports the following features:

- Two DAC converters: one for each output channel
- 8-bit or 12-bit monotonic output
- Left or right data alignment in 12-bit mode
- Synchronized update capability
- Noise-wave generation
- Triangular-wave generation
- Sample and hold mode to reduce the power consumption
- Dual DAC channel independent or simultaneous conversions
- DMA capability for each channel including DMA underrun error detection
- External triggers for conversion
- input voltage reference $V_{REF+}$ or internal VREFBUF reference.

The DAC channels are triggered through the timer update outputs that are also connected to different DMA streams.

## 3.26 Voltage reference buffer (VREFBUF)

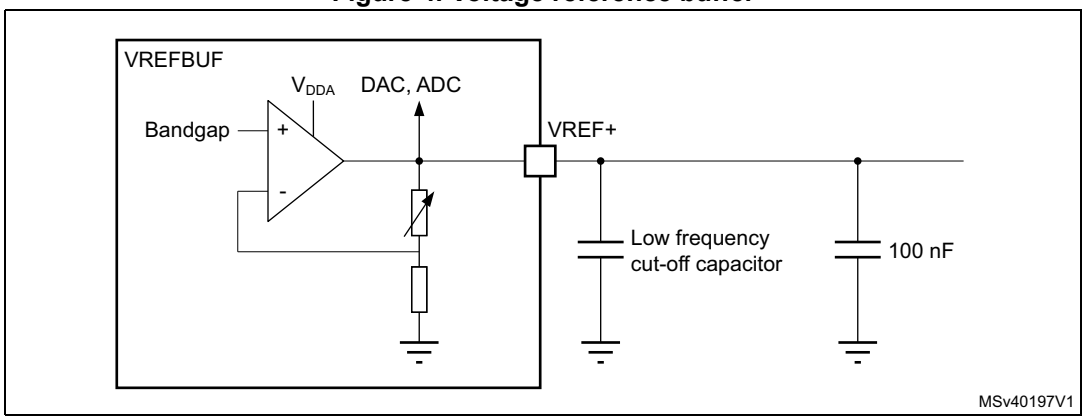
The STM32MP153C/F devices embed a voltage reference buffer which can be used as voltage reference for ADC, DACs and also as voltage reference for external components through the VREF+ pin.

The internal voltage reference buffer supports four voltages:

- 1.5 V
- 1.8 V
- 2.048 V
- 2.5 V

An external voltage reference can be provided through the VREF+ pin when the internal voltage reference buffer is off.

**Figure 4. Voltage reference buffer**




## 3.27 Digital filter for sigma delta modulators (DFSDM1)

The device embeds one DFSDM with support for 6 digital filters modules and 8 external input serial channels (transceivers) or alternately 8 internal parallel inputs.

The DFSDM peripheral is dedicated to interface external ΣΔ modulators to STM32MP153C/F and perform digital filtering of the received data streams. ΣΔ modulators are used to convert analog signals into digital serial streams that constitute the inputs of the DFSDM. The DFSDM can also interface PDM (pulse density modulation) microphones and perform the PDM to PCM conversion and filtering (hardware accelerated). The DFSDM features optional parallel data stream inputs from internal ADC peripherals or STM32MP153C/F memory (through DMA/CPU transfers into DFSDM).

The DFSDM transceivers support several serial interface formats (to support various ΣΔ modulators). DFSDM digital filter modules perform digital processing according user-defined filter parameters with up to 24-bit final ADC resolution.

The DFSDM peripheral supports:

- 8 multiplexed input digital serial channels:
  - configurable SPI interface to connect various SD modulator(s)
  - configurable Manchester coded 1-wire interface support
  - PDM (pulse density modulation) microphone input support
  - maximum input clock frequency up to 20 MHz (10 MHz for Manchester coding)
  - clock output for SD modulator(s): 0…20 MHz
- Alternative inputs from 8 internal digital parallel channels (up to 16-bit input resolution):
  - internal sources: ADC data or memory data streams (DMA)
- 6 digital filter modules with adjustable digital signal processing:
  - $Sinc^x$ filter: filter order/type (1…5), oversampling ratio (1…1024)
  - integrator: oversampling ratio (1…256)
- Up to 24-bit output data resolution, signed output data format
- Automatic data offset correction (offset stored in register by user)
- Continuous or single conversion
- Start-of-conversion triggered by:
  - software trigger
  - internal timers
  - external events
  - start-of-conversion synchronously with first digital filter module (DFSDM0)
- Analog watchdog feature:
  - low value and high value data threshold registers
  - dedicated configurable $Sinc^x$ digital filter (order = 1…3, oversampling ratio = 1…32)
  - input from final output data or from selected input digital serial channels
  - continuous monitoring independently from standard conversion
- Short circuit detector to detect saturated analog input values (bottom and top range):
  - up to 8-bit counter to detect 1…256 consecutive 0's or 1's on serial data stream
  - monitoring continuously each input serial channel
- Break signal generation on analog watchdog event or on short circuit detector event
- Extremes detector:
  - storage of minimum and maximum values of final conversion data
  - refreshed by software
- DMA capability to read the final conversion data
- Interrupts: end of conversion, overrun, analog watchdog, short circuit, input serial channel clock absence
- "Regular" or "injected" conversions:
  - "regular" conversions can be requested at any time or even in continuous mode without having any impact on the timing of "injected" conversions
  - "injected" conversions for precise timing and with high conversion priority

## 3.28 Digital camera interface (DCMI)

The devices embed a camera interface that can connect with camera modules and CMOS sensors through an 8-bit to 14-bit parallel interface, to receive video data. The camera interface can achieve a data transfer rate up to 140 Mbyte/s using a 80 MHz pixel clock and 14-bit of data. It features:

- Programmable polarity for the input pixel clock and synchronization signals
- Parallel data communication can be 8-, 10-, 12- or 14-bit
- Supports 8-bit progressive video monochrome or raw Bayer format, $YC_bC_r$ 4:2:2 progressive video, RGB 565 progressive video or compressed data (like JPEG)
- Supports continuous mode or snapshot (a single frame) mode
- Capability to automatically crop the image

## 3.29 LCD-TFT display controller (LTDC)

The LCD-TFT display controller provides a 24-bit parallel digital RGB (Red, Green, Blue) and delivers all signals to interface directly to a broad range of LCD and TFT panels up to WXGA (1366×768) @60 fps resolution with the following features:

- 2 display layers with dedicated FIFO
- Color look-up table (CLUT) up to 256 colors (256×24-bit) per layer
- Up to 8 input color formats selectable per layer
- Flexible blending between two layers using alpha value (per pixel or constant)
- Flexible programmable parameters for each layer
- Color keying (transparency color)
- Up to 4 programmable interrupt events
- AXI master interface

## 3.30 True random number generator (RNG1, RNG2)

All the devices embed two RNG that deliver 32-bit random numbers generated by an integrated analog circuit.

RNG1 can be defined (in ETZPC) as accessible by secure software only.

## 3.31 Cryptographic and hash processors (CRYP1, CRYP2 and HASH1, HASH2)

The devices embed two cryptographic processors that support the advanced cryptographic algorithms usually required to ensure confidentiality, authentication, data integrity and non-repudiation when exchanging messages with a peer:

- Encryption/decryption
  - DES/TDES (data encryption standard/triple data encryption standard): ECB (electronic codebook) and CBC (cipher block chaining) chaining algorithms, 64-, 128- or 192-bit key
  - AES (advanced encryption standard): ECB, CBC, GCM, CCM, and CTR (counter mode) chaining algorithms, 128, 192 or 256-bit key
- Universal HASH
  - SHA-1, SHA224 and SHA256 (secure HASH algorithms)
  - MD5
  - HMAC

The cryptographic accelerator supports DMA request generation.

CRYP1 and HASH1 can be defined (in ETZPC) as accessible by secure software only.

## 3.32 Boot and security and OTP control (BSEC)

The BSEC (boot and security and OTP control) is intended to control an OTP (one time programmable) fuse box, used for embedded non-volatile storage for device configuration and security parameters. Some part of BSEC should be configured as accessible by secure software only.

## 3.33 Timers and watchdogs

The devices include two advanced-control timers, ten general-purpose timers, two basic timers, five low-power timers, three watchdogs, a SysTick timer in Cortex-M4 and 4 system timers in each Cortex-A7.

All timer counters can be frozen in debug mode.

*Table 4* compares the features of the advanced-control, general-purpose, basic and low-power timers.

**Table 4. Timer feature comparison**

| Timer type | Timer | Counter resolution | Counter type | Prescaler factor | DMA request generation | Capture/ compare channels | Comple-mentary output | Max interface clock (MHz) | Max timer clock (MHz)(1) |
|---|---|---|---|---|---|---|---|---|---|
| Advanced -control | TIM1, TIM8 | 16-bit | Up, down, up/down | Any integer between 1 and 65536 | Yes | 4 | Yes | 104.5 | 209 |
| General purpose | TIM2, TIM5 | 32-bit | Up, down, up/down | Any integer between 1 and 65536 | Yes | 4 | No | 104.5 | 209 |
| | TIM3, TIM4 | 16-bit | Up, down, up/down | Any integer between 1 and 65536 | Yes | 4 | No | 104.5 | 209 |
| | TIM12 | 16-bit | Up | Any integer between 1 and 65536 | No | 2 | No | 104.5 | 209 |
| | TIM13, TIM14 | 16-bit | Up | Any integer between 1 and 65536 | No | 1 | No | 104.5 | 209 |
| | TIM15 | 16-bit | Up | Any integer between 1 and 65536 | Yes | 2 | 1 | 104.5 | 209 |
| | TIM16, TIM17 | 16-bit | Up | Any integer between 1 and 65536 | Yes | 1 | 1 | 104.5 | 209 |
| Basic | TIM6, TIM7 | 16-bit | Up | Any integer between 1 and 65536 | Yes | 0 | No | 104.5 | 209 |
| Low-power | LPTIM1, LPTIM2, LPTIM3, LPTIM4, LPTIM5 | 16-bit | Up | 1, 2, 4, 8, 16, 32, 64, 128 | No | 0 | No | 104.5 | 209 |

1. The maximum timer clock is up to 209 MHz depending on TIMGxPRE bit in the RCC.

### 3.33.1 Advanced-control timers (TIM1, TIM8)

The advanced-control timers (TIM1, TIM8) can be seen as three-phase PWM generators multiplexed on 6 channels. They have complementary PWM outputs with programmable inserted dead times. They can also be considered as complete general-purpose timers. Their 4 independent channels can be used for:

- Input capture
- Output compare
- PWM generation (edge- or center-aligned modes)
- One-pulse mode output

If configured as standard 16-bit timers, they have the same features as the general-purpose timers. If configured as 16-bit PWM generators, they have full modulation capability (0-100%).

The advanced-control timer can work together with the general-purpose timers via the timer link feature for synchronization or event chaining.

TIM1 and TIM8 support independent DMA request generation.

### 3.33.2 General-purpose timers (TIM2, TIM3, TIM4, TIM5, TIM12, TIM13, TIM14, TIM15, TIM16, TIM17)

There are ten synchronizable general-purpose timers embedded in the STM32MP153C/F devices (see *Table 4* for differences).

- **TIM2, TIM3, TIM4, TIM5**

  The devices include 4 full-featured general-purpose timers: TIM2, TIM3, TIM4 and TIM5. TIM2 and TIM5 are based on a 32-bit auto-reload up/downcounter and a 16-bit prescaler while TIM3 and TIM4 are based on a 16-bit auto-reload up/downcounter and a 16-bit prescaler. All timers feature 4 independent channels for input capture/output compare, PWM or one-pulse mode output. This gives up to 16 input capture/output compare/PWMs on the largest packages.

  TIM2, TIM3, TIM4 and TIM5 general-purpose timers can work together, or with the other general-purpose timers and the advanced-control timers TIM1 and TIM8 via the timer link feature for synchronization or event chaining.

  Any of these general-purpose timers can be used to generate PWM outputs.

  TIM2, TIM3, TIM4, TIM5 all have independent DMA request generation. They are capable of handling quadrature (incremental) encoder signals and the digital outputs from 1 to 4 hall-effect sensors.

- **TIM12, TIM13, TIM14, TIM15, TIM16, TIM17**

  These timers are based on a 16-bit auto-reload upcounter and a 16-bit prescaler. TIM13, TIM14, TIM16 and TIM17 feature one independent channel, whereas TIM12 and TIM15 have two independent channels for input capture/output compare, PWM or one-pulse mode output. They can be synchronized with the TIM2, TIM3, TIM4, TIM5 full-featured general-purpose timers or used as simple timebases.

### 3.33.3 Basic timers TIM6 and TIM7

These timers are mainly used for DAC trigger and waveform generation. They can also be used as a generic 16-bit time base.

TIM6 and TIM7 support independent DMA request generation.

### 3.33.4 Low-power timer (LPTIM1, LPTIM2, LPTIM3, LPTIM4, LPTIM5)

The low-power timer has an independent clock and is running also in Stop mode if it is clocked by LSE, LSI or an external clock. It is able to wakeup the device from Stop mode.

These low-power timer supports the following features:

- 16-bit up counter with 16-bit autoreload register
- 16-bit compare register
- Configurable output: pulse, PWM
- Continuous / one-shot mode
- Selectable software / hardware input trigger
- Selectable clock source:
- Internal clock source: LSE, LSI, HSI or APB clock
- External clock source over LPTIM input (working even with no internal clock source running, used by the pulse counter application)
- Programmable digital glitch filter
- Encoder mode

### 3.33.5 Independent watchdog (IWDG1, IWDG2)

The independent watchdog is based on a 12-bit downcounter and 8-bit prescaler. It is clocked from an independent 32 kHz internal RC(LSI) and as it operates independently from the main clock, it can operate in Stop and Standby modes. It can be used either as a watchdog to reset the device when a problem occurs, or as a free-running timer for application timeout management. It is hardware- or software-configurable through the option bytes.

IWDG1 can be defined (in ETZPC) as accessible by secure software only.

### 3.33.6 System window watchdog (WWDG1)

The window watchdog is based on a 7-bit downcounter that can be set as free-running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the APB clock. It has an early warning interrupt capability and the counter can be frozen in debug mode.

### 3.33.7 SysTick timer (Cortex-M4)

This timer is embedded inside Cortex-M4 core and dedicated to real-time operating systems, but can also be used as a standard downcounter. It features:

- A 24-bit downcounter
- Autoreload capability
- Maskable system interrupt generation when the counter reaches 0
- Programmable clock source.

### 3.33.8 Generic timers (Cortex-A7 CNT)

Cortex-A7 generic timers embedded inside Cortex-A7 are fed by value from system timing generation (STGEN).

The Cortex-A7 processor provides a set of four timers for each processor:

- Physical timer for use in secure and non-secure modes. The registers for the physical timer are banked to provide secure and non-secure copies.
- Virtual timer for use in non-secure modes.
- Physical timer for use in hypervisor mode.

Generic timers are not memory mapped peripherals, they are accessible only by specific Cortex-A7 coprocessor instructions (cp15).

## 3.34 System timer generation (STGEN)

The system timing generation (STGEN) generates a time count value that provides a consistent view of time for all Cortex-A7 generic timers.

The system timing generation has the following key features:

- 64-bit wide to avoid roll-over issues.
- Starts from zero or a programmable value.
- A control APB interface (STGENC) enables the timer to be saved and restored across powerdown events.
- Read-only APB interface (STGENR) enables the timer value to be read by non-secure software and debug tools.
- The timer value incrementing can be stopped during system debug.

STGENC can be defined (in ETZPC) as accessible by secure software only.

## 3.35 Real-time clock (RTC)

The RTC provides an automatic wakeup to manage all low-power modes.

The real-time clock (RTC) is an independent BCD timer/counter. The RTC provides a time-of-day clock/calendar with programmable alarm interrupts.

The RTC includes also a periodic programmable wakeup flag with interrupt capability.

Two 32-bit registers contain the seconds, minutes, hours (12- or 24-hour format), day (day of week), date (day of month), month, and year, expressed in binary coded decimal format (BCD). The sub-seconds value is also available in binary format.

Compensations for 28-, 29- (leap year), 30-, and 31-day months are performed automatically. Daylight saving time compensation can also be performed.

Additional 32-bit registers contain the programmable alarm subseconds, seconds, minutes, hours, day, and date.

A digital calibration feature is available to compensate for any deviation in crystal oscillator accuracy.

After backup domain reset, all RTC registers are protected against possible parasitic write accesses.

As long as the supply voltage remains in the operating range, the RTC never stops, regardless of the device status (Run mode, Low-power mode or under reset).

The RTC unit main features are the following:

- Calendar with subseconds, seconds, minutes, hours (12 or 24 format), day (day of week), date (day of month), month, and year.
- Daylight saving compensation programmable by software.
- Programmable alarm with interrupt function. The alarm can be triggered by any combination of the calendar fields.
- Automatic wakeup unit generating a periodic flag that triggers an automatic wakeup interrupt.
- Reference clock detection: a more precise second source clock (50 or 60 Hz) can be used to enhance the calendar precision.
- Accurate synchronization with an external clock using the subsecond shift feature.
- Digital calibration circuit (periodic counter correction): 0.95 ppm accuracy, obtained in a calibration window of several seconds
- Timestamp function for event saving
- Maskable interrupts/events:
  - Alarm A
  - Alarm B
  - Wakeup interrupt
  - Timestamp
- TrustZone support:
  - RTC fully securable
  - Alarm A, alarm B, wakeup timer and timestamp individual secure or non-secure configuration

## 3.36 Tamper and backup registers (TAMP)

32 x 32-bit backup registers are retained in all low-power modes and also in VBAT mode. They can be used to store sensitive data as their content is protected by an tamper detection circuit. 3 tamper pins and 5 internal tampers are available for anti-tamper detection. The external tamper pins can be configured for edge detection, edge and level, level detection with filtering, or active tamper which increases the security level by auto checking that the tamper pins are not externally opened or shorted.

TAMP main features

- 32 backup registers:
  - the backup registers (TAMP_BKPxR) are implemented in the RTC domain that remains powered-on by VBAT when the $V_{DD}$ power is switched off.
- 3 external tamper detection events.
  - Each external event can be configured to be active or passive.
  - External passive tampers with configurable filter and internal pull-up.
- 5 internal tamper events.
- Any tamper detection can generate a RTC timestamp event.
- Any tamper detection erases the backup registers.
- TrustZone support:
  - Tamper secure or non-secure configuration.
  - Backup registers configuration in 3 configurable-size areas:
    1 read/write secure area.
    1 write secure/read non-secure area.
    1 read/write non-secure area.
- Monotonic counter.

## 3.37 Inter-integrated circuit interface (I2C1, I2C2, I2C3, I2C4, I2C5, I2C6)

The STM32MP153C/F embeds six $I^2C$ interfaces.

The $I^2C$ bus interface handles communications between the STM32MP153C/F and the serial $I^2C$ bus. It controls all $I^2C$ bus-specific sequencing, protocol, arbitration and timing.

The I2C peripheral supports:

- $I^2C$-bus specification and user manual rev. 5 compatibility:
  - Slave and master modes, multimaster capability
  - Standard-mode (Sm), with a bitrate up to 100 kbit/s
  - Fast-mode (Fm), with a bitrate up to 400 kbit/s
  - Fast-mode Plus (Fm+), with a bitrate up to 1 Mbit/s and 20 mA output drive I/Os
  - 7-bit and 10-bit addressing mode, multiple 7-bit slave addresses
  - Programmable setup and hold times
  - Optional clock stretching
- System management bus (SMBus) specification rev 2.0 compatibility:
  - Hardware PEC (packet error checking) generation and verification with ACK control
  - Address resolution protocol (ARP) support
  - SMBus alert
- Power system management protocol (PMBus™) specification rev 1.1 compatibility
- Independent clock: a choice of independent clock sources allowing the I2C communication speed to be independent from the PCLK reprogramming.
- Wakeup from Stop mode on address match
- Programmable analog and digital noise filters
- 1-byte buffer with DMA capability

I2C4 and I2C6 can be defined (in ETZPC) as accessible by secure software only.

## 3.38 Universal synchronous asynchronous receiver transmitter (USART1, USART2, USART3, USART6 and UART4, UART5, UART7, UART8)

The STM32MP153C/F devices have four embedded universal synchronous receiver transmitters (USART1, USART2, USART3 and USART6) and four universal asynchronous receiver transmitters (UART4, UART5, UART7 and UART8). Refer to *Table 5* for a summary of USARTx and UARTx features.

These interfaces provide asynchronous communication, IrDA SIR ENDEC support, multiprocessor communication mode, single-wire half-duplex communication mode and have LIN master/slave capability. They provide hardware management of the CTS and RTS signals, and RS485 Driver Enable. They are able to communicate at speeds of up to 10 Mbit/s.

USART1, USART2, USART3 and USART6 also provide Smartcard mode (ISO 7816 compliant) and SPI-like communication capability.

All USART have a clock domain independent from the CPU clock, allowing the USARTx to wake up the STM32MP153C/F from Stop mode using baudrates up to 200 Kbaud.The wake up events from Stop mode are programmable and can be:

- Start bit detection
- Any received data frame
- A specific programmed data frame

All USART interfaces can be served by the DMA controller.

**Table 5. USART features**

| USART modes/features(1) | USART1/2/3/6 | UART4/5/7/8 |
|---|---|---|
| Hardware flow control for modem | X | X |
| Continuous communication using DMA | X | X |
| Multiprocessor communication | X | X |
| Synchronous mode (master/slave) | X | - |
| Smartcard mode | X | - |
| Single-wire half-duplex communication | X | X |
| IrDA SIR ENDEC block | X | X |
| LIN mode | X | X |
| Dual clock domain and wakeup from low power mode | X | X |
| Receiver timeout interrupt | X | X |
| Modbus communication | X | X |
| Auto baud rate detection | X | X |
| Driver Enable | X | X |
| USART data length | 7, 8 and 9 bits | |

1. X = supported.

USART1 can be defined (in ETZPC) as accessible by secure software only.

## 3.39 Serial peripheral interface (SPI1, SPI2, SPI3, SPI4, SPI5, SPI6)– inter- integrated sound interfaces (I2S1, I2S2, I2S3)

The devices feature up to six SPIs (SPI2S1, SPI2S2, SPI2S3, SPI4, SPI5 and SPI6) that allow communication at up to 50 Mbit/s in master and slave modes, in half-duplex, full-duplex and simplex modes. The 3-bit prescaler gives 8 master mode frequencies and the frame is configurable from 4 to 16 bits. All SPI interfaces support NSS pulse mode, TI mode, hardware CRC calculation and 8x 8-bit embedded Rx and Tx FIFOs with DMA capability.

Three standard $I^2S$ interfaces (I2S1, I2S2, I2S3, multiplexed with SPI1, SPI2 and SPI3) are available. They can be operated in master or slave mode, in full-duplex and half-duplex communication modes, and can be configured to operate with a 16-/32-bit resolution as an input or output channel. Audio sampling frequencies from 8 kHz up to 192 kHz are supported. When either or both of the $I^2S$ interfaces is/are configured in master mode, the master clock can be output to the external DAC/CODEC at 256 times the sampling

frequency. All $I^2S$ interfaces support 16x 8-bit embedded Rx and Tx FIFOs with DMA capability.

SPI6 can be defined (in ETZPC) as accessible by secure software only.

## 3.40 Serial audio interfaces (SAI1, SAI2, SAI3, SAI4)

The devices embed 4 SAIs that allow the design of many stereo or mono audio protocols such as I2S, LSB or MSB-justified, PCM/DSP, TDM or AC'97. An SPDIF output is available when the audio block is configured as a transmitter. To bring this level of flexibility and reconfigurability, the SAI contains two independent audio sub-blocks. Each block has it own clock generator and I/O line controller.
Audio sampling frequencies up to 192 kHz are supported.
In addition, up to 8 microphones can be supported thanks to an embedded PDM interface.
The SAI can work in master or slave configuration. The audio sub-blocks can be either receiver or transmitter and can work synchronously or asynchronously (with respect to the other one). The SAI can be connected with other SAIs to work synchronously.

## 3.41 SPDIF receiver interface (SPDIFRX)

The SPDIFRX peripheral is designed to receive an S/PDIF flow compliant with IEC-60958 and IEC-61937. These standards support simple stereo streams up to high sample rate, and compressed multi-channel surround sound, such as those defined by Dolby or DTS (up to 5.1).

The main SPDIFRX features are the following:

- Up to 4 inputs available
- Automatic symbol rate detection
- Maximum symbol rate: 12.288 MHz
- Stereo stream from 32 to 192 kHz supported
- Supports audio IEC-60958 and IEC-61937, consumer applications
- Parity bit management
- Communication using DMA for audio samples
- Communication using DMA for control and user channel information
- Interrupt capabilities

The SPDIFRX receiver provides all the necessary features to detect the symbol rate, and decode the incoming data stream. The user can select the wanted SPDIF input, and when a valid signal is available, the SPDIFRX re-samples the incoming signal, decode the Manchester stream, recognize frames, sub-frames and blocks elements. It delivers to the CPU decoded data, and associated status flags.

The SPDIFRX also offers a signal named spdif_frame_sync, which toggles at the S/PDIF sub-frame rate that is used to compute the exact sample rate for clock drift algorithms.

## 3.42 Management data input/output (MDIOS)

The devices embed a MDIO slave interface. It includes the following features:

- 32 MDIO register addresses, each of which is managed using separate input and output data registers:
  - 32 x 16-bit firmware read/write, MDIO read-only output data registers
  - 32 x 16-bit firmware read-only, MDIO write-only input data registers
- Configurable slave (port) address
- Independently maskable interrupts/events:
  - MDIO register write
  - MDIO register read
  - MDIO protocol error
- Able to operate in and wake up from Stop mode

## 3.43 Secure digital input/output MultiMediaCard interface (SDMMC1, SDMMC2, SDMMC3)

Three secure digital input/output MultiMediaCard interfaces (SDMMC) provide an interface between the AHB bus and SD memory cards, SDIO cards and MMC devices.

The SDMMC features include the following:

- Full compliance with *MultiMediaCard System Specification Version 4.51*.
  Card support for three different databus modes: 1-bit (default), 4-bit and 8-bit.
- Full compatibility with previous versions of MultiMediaCards (backward compatibility).
- Full compliance with *SD memory card specifications version 4.1*.
  (SDR104 SDMMC_CK speed limited to maximum allowed I/O speed, SPI mode and UHS-II mode not supported).
- Full compliance with SDIO card specification version 4.0.
  Card support for two different databus modes: 1-bit (default) and 4-bit.
  (SDR104 SDMMC_CK speed limited to maximum allowed I/O speed, SPI mode and UHS-II mode not supported).
- Data transfer up to 208 Mbyte/s for the 8-bit mode.
  (depending maximum allowed I/O speed).
- Data and command output enable signals to control external bidirectional drivers.
- The SDMMC host interface embeds a dedicated DMA controller allowing high-speed transfers between the interface and the SRAM.
- IDMA linked list support

Each SDMMC is coupled with a delay block (DLYBSD) allowing support of an external data frequency above 100 MHz.

## 3.44 Controller area network (FDCAN1, FDCAN2)

The controller area network (CAN) subsystem consists of two CAN modules, a shared message RAM memory and a clock calibration unit.

Both CAN modules (FDCAN1 and FDCAN2) are compliant with ISO 11898-1 (CAN protocol specification version 2.0 part A, B) and CAN FD protocol specification version 1.0.

FDCAN1 supports time triggered CAN (TTCAN) specified in ISO 11898-4, including event synchronized time-triggered communication, global system time, and clock drift compensation. The FDCAN1 contains additional registers, specific to the time triggered feature. The CAN FD option can be used together with event-triggered and time-triggered CAN communication.

A 10 Kbyte message RAM memory implements filters, receive FIFOs, receive buffers, transmit event FIFOs, transmit buffers (and triggers for TTCAN). This message RAM is shared between the two FDCAN1 and FDCAN2 modules.

The common clock calibration unit is optional. It can be used to generate a calibrated clock for both FDCAN1 and FDCAN2 from the HSI internal RC oscillator and the PLL, by evaluating CAN messages received by the FDCAN1.

## 3.45 Universal serial bus high-speed host (USBH)

The devices embed one USB high-speed host (up to 480 Mbit/s) with two physical ports. USBH supports both low, full-speed (OHCI) as well as high-speed (EHCI) operations independently on each port. It integrates two transceivers which can be used for either low-speed (1.2 Mbit/s), full-speed (12 Mbit/s) or high-speed operation (480 Mbit/s), the second high-speed transceiver is shared with OTG high-speed.

The USB HS is compliant with the USB 2.0 specification. The USB HS controllers require dedicated clocks that are generated by a PLL inside the USB high-speed PHY.

## 3.46 USB on-the-go high-speed (OTG)

The devices embed one USB OTG high-speed (up to 480 Mbit/s) device/host/OTG peripheral. OTG supports both full-speed and high-speed operations. It integrates the transceivers for full-speed operation (12 Mbit/s) and high-speed operation (480 Mbit/s) shared with USB Host second port.

The USB OTG HS is compliant with the USB 2.0 specification and with the OTG 2.0 specification. It has software-configurable endpoint setting and supports suspend/resume. The USB OTG controllers require a dedicated 48 MHz clock that is generated by a PLL inside RCC or inside the USB high-speed PHY.

The main features are:

- Combined Rx and Tx FIFO size of 4 Kbyte with dynamic FIFO sizing
- Supports the session request protocol (SRP) and host negotiation protocol (HNP)
- 8 bidirectional endpoints
- 16 host channels with periodic OUT support
- Software configurable to OTG1.3 and OTG2.0 modes of operation
- USB 2.0 LPM (link power management) support
- Battery charging specification revision 1.2 support
- Internal FS or HS OTG PHY support
- Internal USB DMA
- HNP/SNP/IP inside (no need for any external resistor)
- For OTG/Host modes, a power switch is needed in case bus-powered devices are connected

## 3.47 Gigabit Ethernet MAC interface (ETH1)

The devices provide an IEEE-802.3-2002-compliant gigabit media access controller (GMAC) for Ethernet LAN communications through an industry-standard medium-independent interface (MII), a reduced medium-independent interface (RMII), a gigabit medium-independent interface (GMII) or a reduced gigabit medium-independent interface (RGMII).

The STM32MP153C/F requires an external physical interface device (PHY) to connect to the physical LAN bus (twisted-pair, fiber, etc.). The PHY is connected to the device port using 17 signals for MII, 7 signals for RMII, 26 signals for GMII or 13 signals for RGMII, and can be clocked using the 25 MHz (MII, RMII, GMII, RGMII) or 125 MHz (GMII, RGMII) from the STM32MP153C/F or from the PHY.

The devices include the following features:

- Operation modes and PHY interfaces
  - 10, 100, and 1000 Mbps data transfer rates
  - Support of both full-duplex and half-duplex operations
  - MII, RMII, GMII and RGMII PHY interfaces
- Multiple queues support and audio video bridging (AVB) management
  - Separate channels or queues for AV data transfer in 100 and 1000 Mbps modes
  - Two queues on the Rx paths and two queues on the Tx path for AV traffic
  - One DMA for Rx path and two DMA for Tx path (one per transmit channels)
  - Several arbitration algorithms between queues: weighted round robin (WRR), strict priority (SP), weighted strict priority (WSP), IEEE 802.1-Qav specified credit-based shaper (CBS) algorithm for Transmit channels
- Processing control
  - Multi-layer Packet filtering: MAC filtering on source (SA) and destination (DA) address with perfect and hash filter, VLAN tag-based filtering with perfect and

hash filter, Layer 3 filtering on IP source (SA) or destination (DA) address, Layer 4 filtering on source (SP) or destination (DP) port
  - Double VLAN processing: insertion of up to two VLAN tags in transmit path, tag filtering in receive path
  - IEEE 1588-2008/PTPv2 support
  - Supports network statistics with RMON/MIB counters (RFC2819/RFC2665)
- Hardware offload processing
  - Preamble and start-of-frame data (SFD) insertion or deletion
  - Integrity Checksum offload engine for IP header and TCP/UDP/ICMP payload: transmit checksum calculation and insertion, receive checksum calculation and comparison
  - Automatic ARP request response with the device's MAC address
  - TCP Segmentation: Automatic split of large transmit TCP packet into multiple small packets
- Low-power mode
  - Energy efficient Ethernet (Standard IEEE 802.3az-2010)
  - Remote wakeup packet and AMD Magic Packet™ detection

## 3.48 High-definition multimedia interface (HDMI) – Consumer electronics control (CEC)

The device embeds a HDMI-CEC controller that provides hardware support for the consumer electronics control (CEC) protocol (supplement 1 to the HDMI standard).

This protocol provides high-level control functions between all audiovisual products in an environment. It is specified to operate at low speeds with minimum processing and memory overhead. It has a clock domain independent from the CPU clock, allowing the HDMI-CEC controller to wake up the STM32MP153C/F from Stop mode on data reception.

## 3.49 Debug infrastructure

The devices offer a comprehensive set of debug and trace features to support software development and system integration.

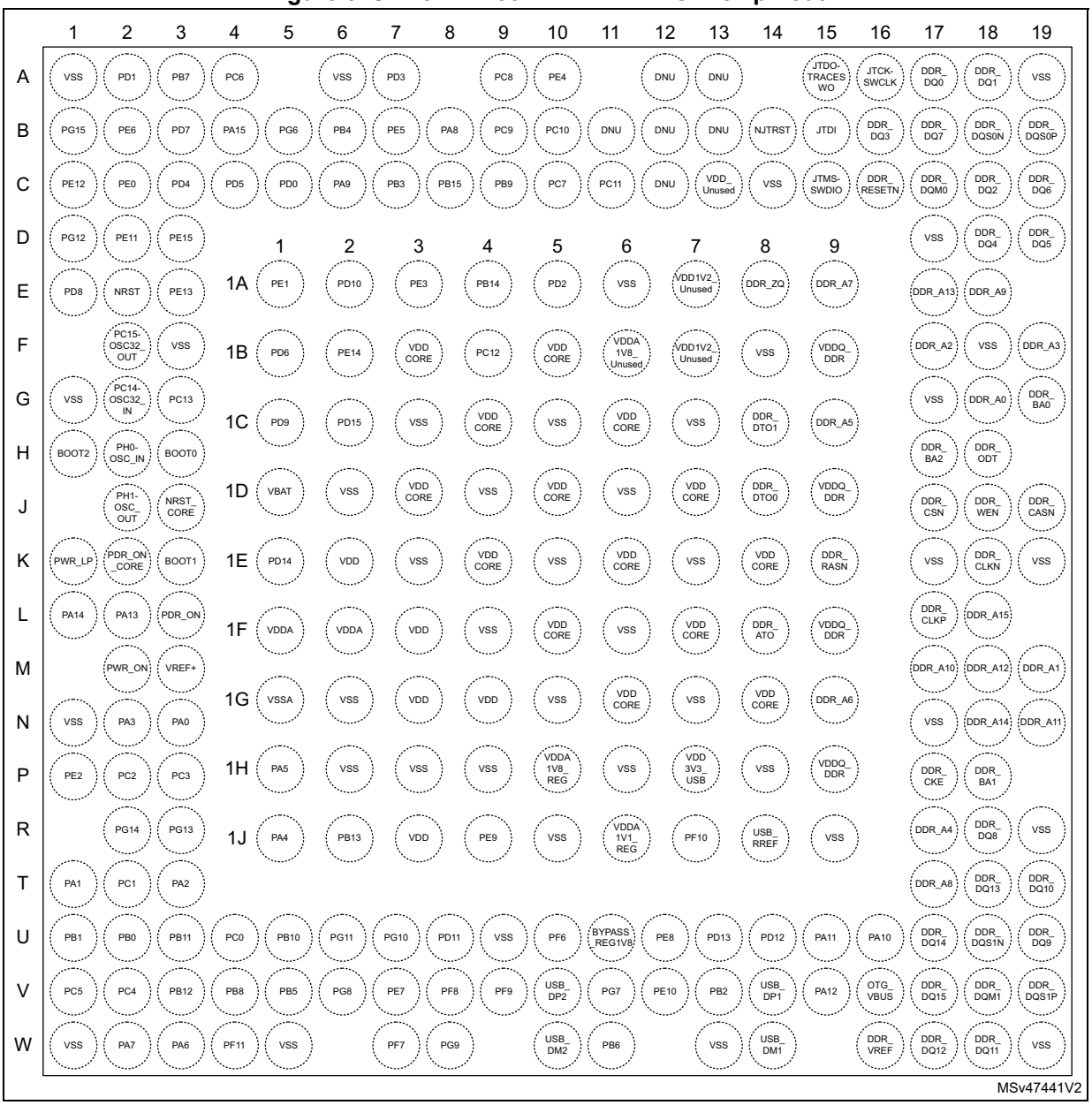
- Breakpoint debugging
- Code execution tracing
- Software instrumentation
- JTAG debug port
- Serial-wire debug port
- Trigger input and output
- Serial-wire trace port
- Trace port
- Arm® CoreSight™ debug and trace components

The debug can be controlled via a JTAG/serial-wire debug access port, using industry standard debugging tools.

A trace port allows data to be captured for logging and analysis.

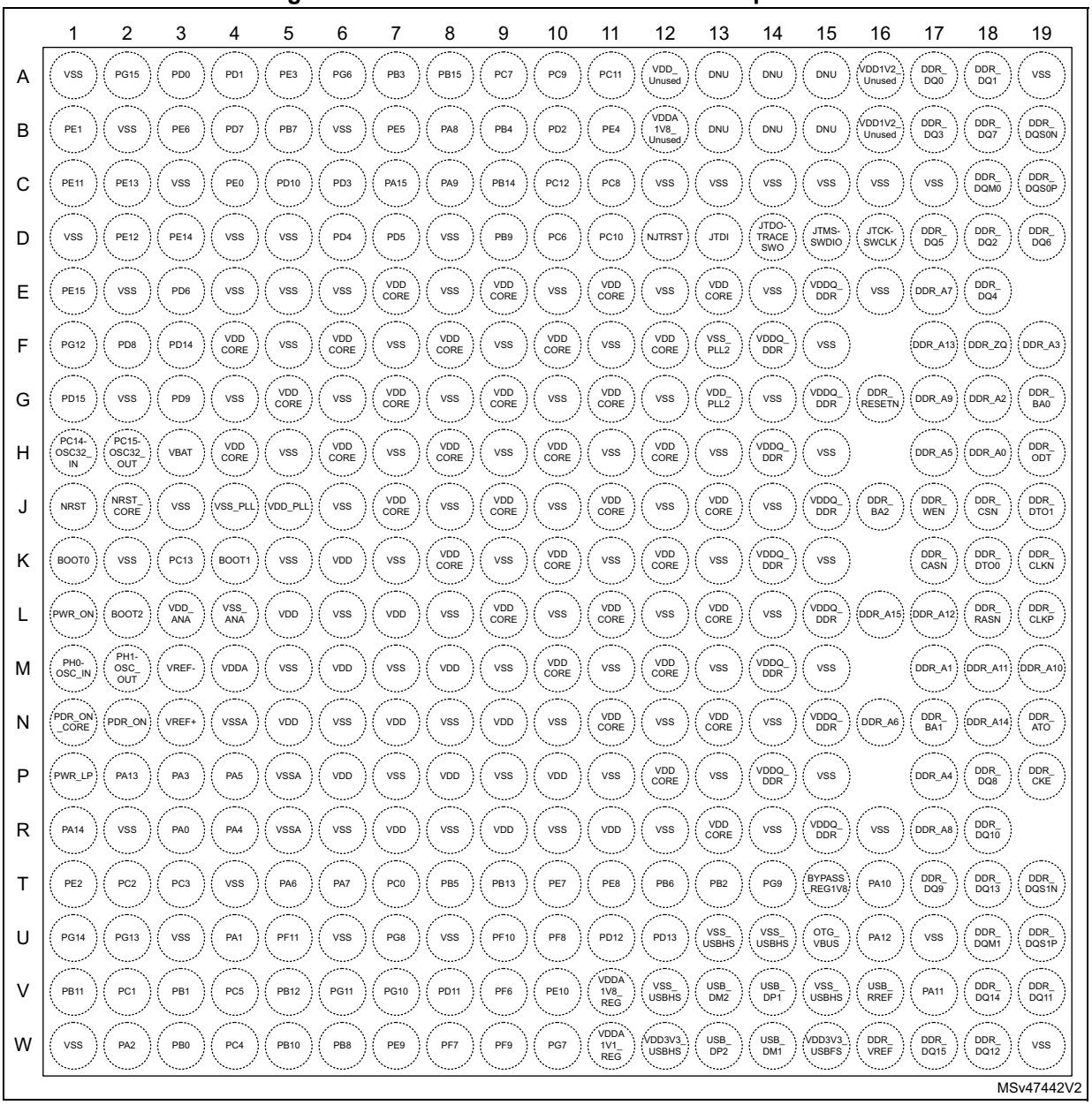
# 4 Pinouts, pin description and alternate functions

**Figure 5. STM32MP153C/FADxx TFBGA257 pinout**



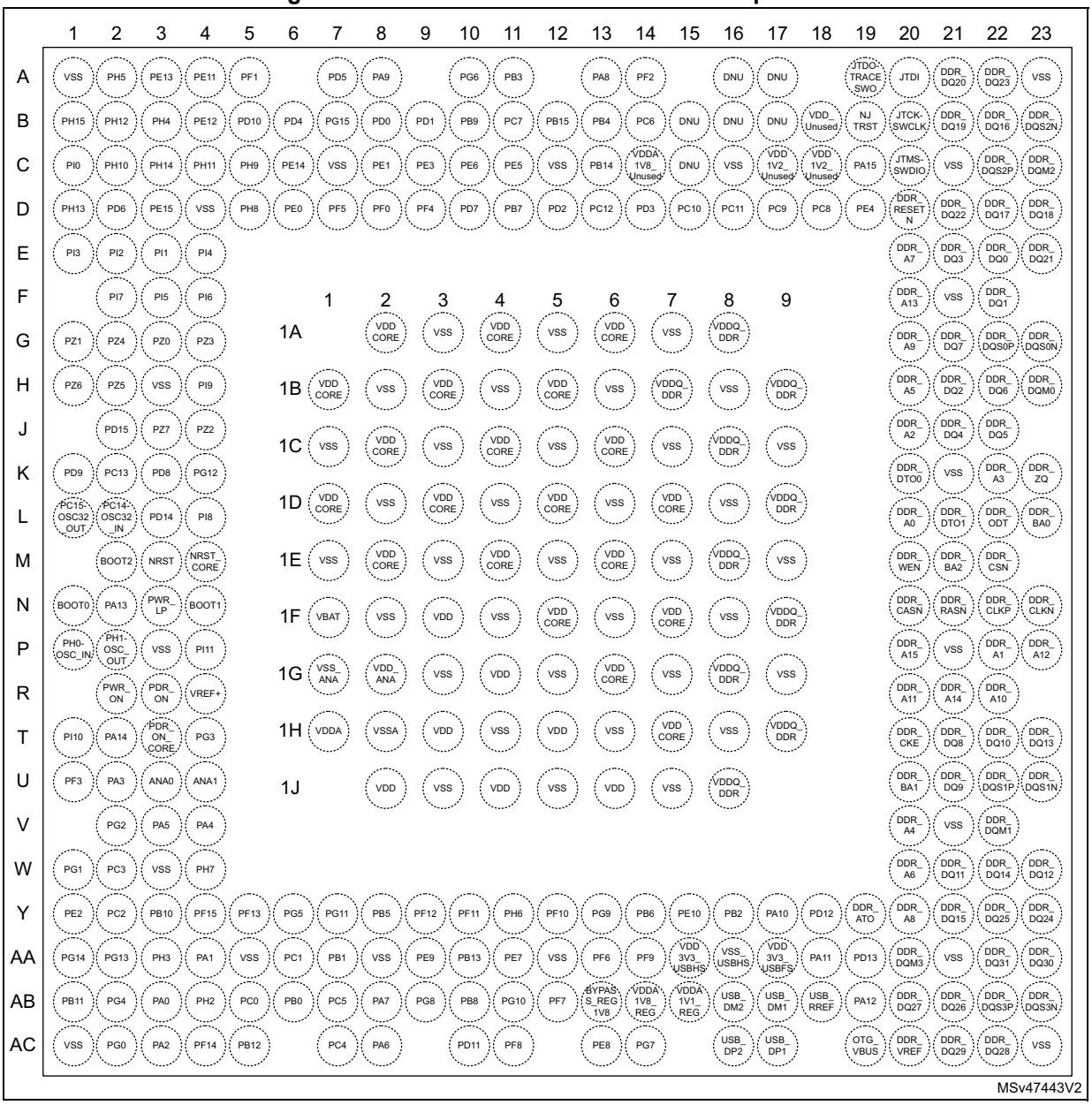

The above figure shows the package top view.

**Figure 6. STM32MP153C/FABxx LFBGA354 pinout**



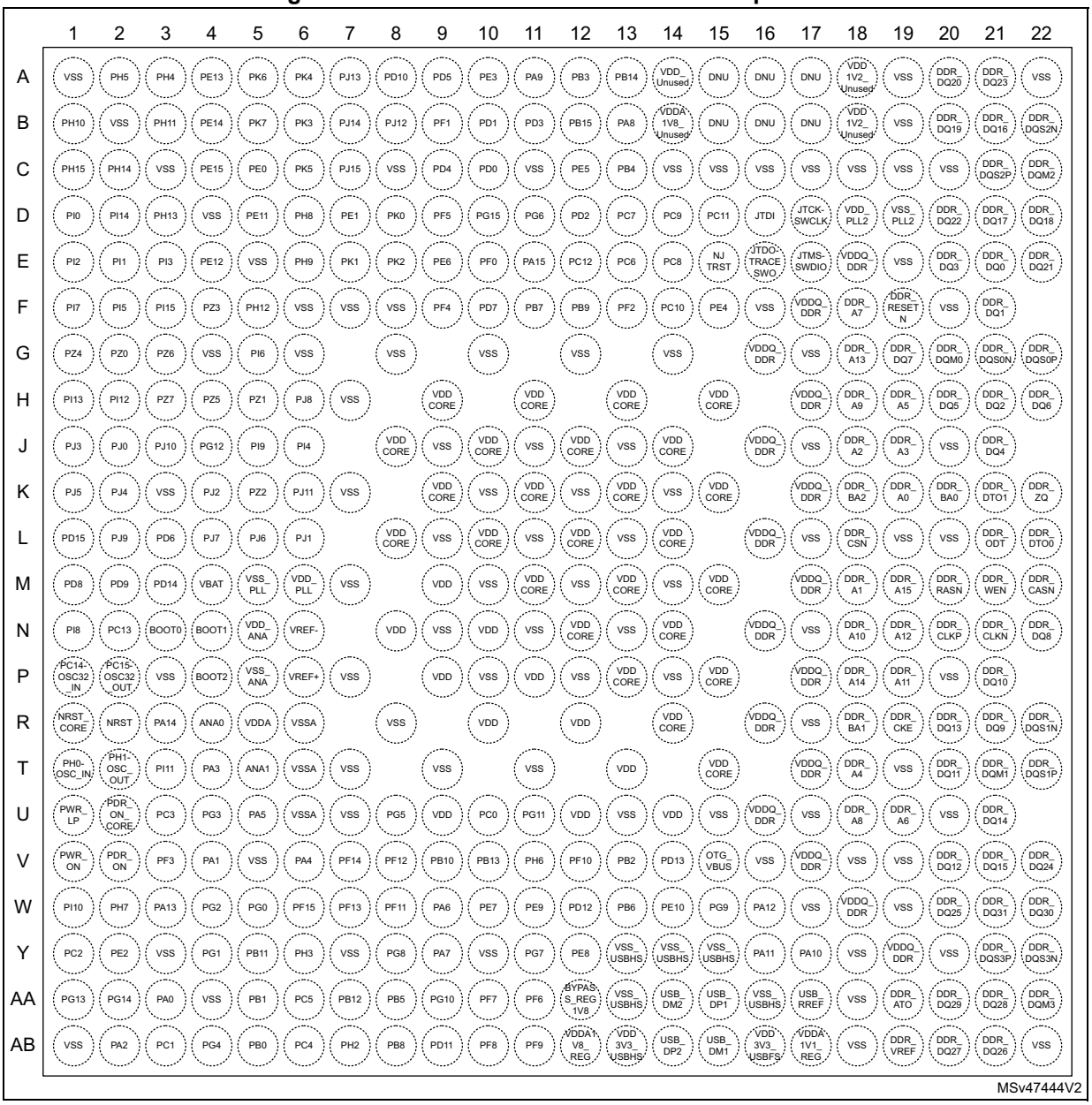

The above figure shows the package top view.

**Figure 7. STM32MP153C/FACxx TFBGA361 pinout**




The above figure shows the package top view.

**Figure 8. STM32MP153C/FAAxx LFBGA448 pinout**




MSv47444V2

The above figure shows the package top view.

**Table 6. Legend/abbreviations used in the pinout table**

| Name | Abbreviation | Definition |
|---|---|---|
| Pin name | Unless otherwise specified, the pin function during and after reset is the same as the actual pin name | |
| Pin type | S | Supply pin |
| | I | Input only pin |
| | O | Output only pin |
| | I/O | Input / output pin |
| | A | Analog or special level pin |
| I/O structure | FT(U/D/PD) | 5 V tolerant I/O (with fixed pull-up / pull-down / programmable pull-down) |
| | TT | 3.6 V tolerant I/O directly connected to DAC |
| | DDR | 1.5 V, 1.35 V or 1.2 V I/O for DDR3, DDR3L, LPDDR2/LPDDR3 interface |
| | A | Analog signal |
| | RST | Reset pin with weak pull-up resistor |
| | Option for TT or FT I/Os | |
| | _f(1) | I2C FM+ option |
| | _a(2) | Analog option (supplied by VDDA for the analog part of the I/O) |
| | _u(3) | USB option (supplied by VDD3V3_USBxx for the USB part of the I/O) |
| | _h(4) | High-speed output for 1.8V typ. VDD (for SPI, SDMMC, QUADSPI, TRACE) |
| | _e(5) | Very-high-speed option for 1.8V typ. VDD (for ETH, SPI, SDMMC, QUADSPI, TRACE) |
| Notes | Unless otherwise specified by a note, all I/Os are set as floating inputs during and after reset | |
| Alternate functions | Functions selected through GPIOx_AFR registers | |
| Additional functions | Functions directly selected/enabled through peripheral registers | |

1. The related I/O structures in *Table 7* are: FT_f, FT_fae, FT_fh, FT_fha, FT_uf
2. The related I/O structures in *Table 7* are: FT_a, TT_a, FT_ae, FT_fae, FT_fha, FT_ha, TT_ha
3. The related I/O structures in *Table 7* are: FT_u, FT_uf
4. The related I/O structures in *Table 7* are: FT_h, FT_fh, FT_fha, FT_ha, TT_ha
5. The related I/O structures in *Table 7* are: FT_e, FT_ae, FT_fae

**Table 7. STM32MP153C/F pin and ball definitions**

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| - | - | A2 | A2 | PH5 | I/O | FT_f | - | I2C2_SDA, SPI5_NSS, SAI4_SD_B, EVENTOUT | - |
| - | - | C2 | B1 | PH10 | I/O | FT | - | TIM5_CH1, I2C4_SMBA, I2C1_SMBA, DCMI_D1, LCD_R4, EVENTOUT | - |
| - | - | B2 | F5 | PH12 | I/O | FT_f | - | HDP2, TIM5_CH3, I2C4_SDA, I2C1_SDA, DCMI_D3, LCD_R6, EVENTOUT | - |
| - | - | D1 | D3 | PH13 | I/O | FT | - | TIM8_CH1N, UART4_TX, FDCAN1_TX, LCD_G2, EVENTOUT | - |
| 1E2 | K6 | 1F3 | M9 | VDD | S | - | - | - | - |
| A1 | A1 | A1 | A1 | VSS | S | - | - | - | - |
| - | - | C3 | C2 | PH14 | I/O | FT | - | TIM8_CH2N, UART4_RX, FDCAN1_RX, DCMI_D4, LCD_G3, EVENTOUT | - |
| - | - | B1 | C1 | PH15 | I/O | FT | - | TIM8_CH3N, DCMI_D11, LCD_G4, EVENTOUT | - |
| - | - | - | H6 | PJ8 | I/O | FT_h | - | TRACED14, TIM1_CH3N, TIM8_CH1, UART8_TX, LCD_G1, EVENTOUT | - |
| - | - | - | D2 | PI14 | I/O | FT_h | - | TRACECLK, LCD_CLK, EVENTOUT | - |
| - | - | - | F3 | PI15 | I/O | FT | - | LCD_G2, LCD_R0, EVENTOUT | - |
| - | - | C1 | D1 | PI0 | I/O | FT | - | TIM5_CH4, SPI2_NSS/I2S2_WS, DCMI_D13, LCD_G5, EVENTOUT | - |
| - | - | E3 | E2 | PI1 | I/O | FT_h | - | TIM8_BKIN2, SPI2_SCK/I2S2_CK, DCMI_D8, LCD_G6, EVENTOUT | - |
| - | - | E2 | E1 | PI2 | I/O | FT_h | - | TIM8_CH4, SPI2_MISO/I2S2_SDI, DCMI_D9, LCD_G7, EVENTOUT | - |
| 1B3 | E7 | 1A2 | H9 | VDDCORE | S | - | - | - | - |
| - | - | E1 | E3 | PI3 | I/O | FT_h | - | TIM8_ETR, SPI2_MOSI/I2S2_SDO, DCMI_D10, EVENTOUT | - |
| - | - | E4 | J6 | PI4 | I/O | FT | - | TIM8_BKIN, SAI2_MCLK_A, DCMI_D5, LCD_B4, EVENTOUT | - |
| - | - | F3 | F2 | PI5 | I/O | FT | - | TIM8_CH1, SAI2_SCK_A, DCMI_VSYNC, LCD_B5, EVENTOUT | - |
| - | - | F4 | G5 | PI6 | I/O | FT | - | TIM8_CH2, SAI2_SD_A, DCMI_D6, LCD_B6, EVENTOUT | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| - | - | F2 | F1 | PI7 | I/O | FT | - | TIM8_CH3, SAI2_FS_A, DCMI_D7, LCD_B7, EVENTOUT | - |
| - | A19 | A23 | A19 | VSS | S | - | - | - | - |
| - | - | G1 | H5 | PZ1 | I/O | FT_fh | - | I2C6_SDA, I2C2_SDA, I2C5_SDA, SPI1_MISO/I2S1_SDI, I2C4_SDA, USART1_RX, SPI6_MISO, EVENTOUT | - |
| - | - | G4 | F4 | PZ3 | I/O | FT_f | - | I2C6_SDA, I2C2_SDA, I2C5_SDA, SPI1_NSS/I2S1_WS, I2C4_SDA, USART1_CTS/USART1_NSS, SPI6_NSS, EVENTOUT | - |
| - | - | H4 | J5 | PI9 | I/O | FT | - | HDP1, UART4_RX, FDCAN1_RX, LCD_VSYNC, EVENTOUT | - |
| - | - | G3 | G2 | PZ0 | I/O | FT_fh | - | I2C6_SCL, I2C2_SCL, SPI1_SCK/I2S1_CK, USART1_CK, SPI6_SCK, EVENTOUT | - |
| - | - | J4 | K5 | PZ2 | I/O | FT_fh | - | I2C6_SCL, I2C2_SCL, I2C5_SMBA, SPI1_MOSI/I2S1_SDO, I2C4_SMBA, USART1_TX, SPI6_MOSI, EVENTOUT | - |
| - | - | G2 | G1 | PZ4 | I/O | FT_f | - | I2C6_SCL, I2C2_SCL, I2C5_SCL, I2C4_SCL, EVENTOUT | - |
| G1 | B2 | - | A22 | VSS | S | - | - | - | - |
| D1 | F1 | K4 | J4 | PG12 | I/O | FT_h | - | LPTIM1_IN1, SPI6_MISO, SAI4_CK2, USART6_RTS/USART6_DE, SPDIFRX_IN2, LCD_B4, SAI4_SCK_A, ETH1_PHY_INTN, FMC_NE4, LCD_B1, EVENTOUT | - |
| - | - | H2 | H4 | PZ5 | I/O | FT_f | - | I2C6_SDA, I2C2_SDA, I2C5_SDA, I2C4_SDA, USART1_RTS/USART1_DE, EVENTOUT | - |
| - | E9 | - | - | VDDCORE | S | - | - | - | - |
| - | - | H1 | G3 | PZ6 | I/O | FT_f | - | I2C6_SCL, I2C2_SCL, USART1_CK, I2S1_MCK, I2C4_SMBA, USART1_RX, EVENTOUT | - |
| - | - | J3 | H3 | PZ7 | I/O | FT_f | - | I2C6_SDA, I2C2_SDA, USART1_TX, EVENTOUT | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| - | - | - | H2 | PI12 | I/O | FT_h | - | TRACED0, HDP0, LCD_HSYNC, EVENTOUT | - |
| - | B6 | C7 | B2 | VSS | S | - | - | - | - |
| - | - | - | H1 | PI13 | I/O | FT_h | - | TRACED1, HDP1, LCD_VSYNC, EVENTOUT | - |
| - | - | 1A4 | H11 | VDDCORE | S | - | - | - | - |
| - | - | - | J3 | PJ10 | I/O | FT_h | - | TIM1_CH2N, TIM8_CH2, SPI5_MOSI, LCD_G3, EVENTOUT | - |
| - | - | - | K6 | PJ11 | I/O | FT_h | - | TIM1_CH2, TIM8_CH2N, SPI5_MISO, LCD_G4, EVENTOUT | - |
| - | - | - | J2 | PJ0 | I/O | FT_h | - | TRACED8, LCD_R7, LCD_R1, EVENTOUT | - |
| - | - | - | L6 | PJ1 | I/O | FT_h | - | TRACED9, LCD_R2, EVENTOUT | - |
| - | - | - | K4 | PJ2 | I/O | FT_h | - | TRACED10, LCD_R3, EVENTOUT | - |
| - | L5 | - | - | VDD | S | - | - | - | - |
| - | - | - | J1 | PJ3 | I/O | FT_h | - | TRACED11, LCD_R4, EVENTOUT | - |
| N1 | C3 | - | B19 | VSS | S | - | - | - | - |
| - | - | - | K2 | PJ4 | I/O | FT_h | - | TRACED12, LCD_R5, EVENTOUT | - |
| 1D3 | E11 | - | - | VDDCORE | S | - | - | - | - |
| - | - | - | K1 | PJ5 | I/O | FT_h | - | TRACED2, HDP2, LCD_R6, EVENTOUT | - |
| - | - | - | L5 | PJ6 | I/O | FT_h | - | TRACED3, HDP3, TIM8_CH2, LCD_R7, EVENTOUT | - |
| - | - | - | L4 | PJ7 | I/O | FT_h | - | TRACED13, TIM8_CH2N, LCD_G0, EVENTOUT | - |
| - | C17 | C12 | C3 | VSS | S | - | - | - | - |
| 1B1 | E3 | D2 | L3 | PD6 | I/O | FT_ha | - | TIM16_CH1N, SAI1_D1, DFSDM1_CKIN4, DFSDM1_DATIN1, SPI3_MOSI/I2S3_SDO, SAI1_SD_A, USART2_RX, FMC_NWAIT, DCMI_D10, LCD_B2, EVENTOUT | - |
| - | E13 | - | H13 | VDDCORE | S | - | - | - | - |
| - | - | - | L2 | PJ9 | I/O | FT_h | - | TRACED15, TIM1_CH3, TIM8_CH1N, UART8_RX, LCD_G2, EVENTOUT | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| - | J5 | - | M6 | VDD_PLL | S | - | - | - | - |
| - | J4 | - | M5 | VSS_PLL | S | - | - | - | - |
| 1E1 | F3 | L3 | M3 | PD14 | I/O | FT_a | - | TIM4_CH3, SAI3_MCLK_B, UART8_CTS, FMC_AD0/FMC_D0, EVENTOUT | - |
| 1C2 | G1 | J2 | L1 | PD15 | I/O | FT_a | - | TIM4_CH4, SAI3_MCLK_A, UART8_CTS, FMC_AD1/FMC_D1, LCD_R1, EVENTOUT | - |
| E1 | F2 | K3 | M1 | PD8 | I/O | FT_a | - | DFSDM1_CKIN3, SAI3_SCK_B, USART3_TX, SPDIFRX_IN2, FMC_AD13/FMC_D13, LCD_B7, EVENTOUT | - |
| 1C1 | G3 | K1 | M2 | PD9 | I/O | FT_a | - | DFSDM1_DATIN3, SAI3_SD_B, USART3_RX, FMC_AD14/FMC_D14, DCMI_HSYNC, LCD_B0, EVENTOUT | - |
| - | - | - | N8 | VDD | S | - | - | - | - |
| W1 | D1 | C21 | C8 | VSS | S | - | - | - | - |
| - | - | 1A6 | - | VDDCORE | S | - | - | - | - |
| 1D1 | H3 | 1F1 | M4 | VBAT | S | - | - | - | - |
| - | D4 | - | C11 | VSS | S | - | - | - | - |
| - | - | L4 | N1 | PI8 | I/O | FT | (1) | EVENTOUT | RTC_OUT2/ RTC_LSCO, TAMP_IN2/ TAMP_OUT3, WKUP4 |
| G3 | K3 | K2 | N2 | PC13 | I/O | FT | (1) | EVENTOUT | RTC_OUT1/ RTC_TS/ RTC_LSCO, TAMP_IN1/ TAMP_OUT2/ TAMP_OUT3, WKUP3 |
| F3 | D5 | D4 | C19 | VSS | S | - | - | - | - |
| F2 | H2 | L1 | P2 | PC15-OSC32_OUT | I/O | FT | (1) | EVENTOUT | OSC32_OUT |
| - | F4 | - | H15 | VDDCORE | S | - | - | - | - |
| 1C4 | F6 | 1B1 | - | VDDCORE | S | - | - | - | - |
| G2 | H1 | L2 | P1 | PC14-OSC32_IN | I/O | FT | (1) | EVENTOUT | OSC32_IN |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| E2 | J1 | M3 | R2 | NRST | I/O | RST | - | - | - |
| J3 | J2 | M4 | R1 | NRST_CORE | I | RST | - | - | - |
| H3 | K1 | N1 | N3 | BOOT0 | I | FTPD | - | - | - |
| K3 | K4 | N4 | N4 | BOOT1 | I | FTPD | - | - | - |
| H1 | L2 | M2 | P4 | BOOT2 | I | FTPD | - | - | - |
| H2 | M1 | P1 | T1 | PH0-OSC_IN | I/O | FT | - | EVENTOUT | OSC_IN |
| - | - | - | J8 | VDDCORE | S | - | - | - | - |
| J2 | M2 | P2 | T2 | PH1-OSC_OUT | I/O | FT | - | EVENTOUT | OSC_OUT |
| - | D8 | - | C20 | VSS | S | - | - | - | - |
| M2 | L1 | R2 | V1 | PWR_ON | O | FT | - | - | PWR_ONLP |
| K1 | P1 | N3 | U1 | PWR_LP | O | FT | - | - | - |
| K2 | N1 | T3 | U2 | PDR_ON_CORE | I | FT | - | - | - |
| L3 | N2 | R3 | V2 | PDR_ON | I | FT | - | - | - |
| - | L3 | 1G2 | N5 | VDD_ANA | S | - | - | - | - |
| - | L4 | 1G1 | P5 | VSS_ANA | S | - | - | - | - |
| L2 | P2 | N2 | W3 | PA13 | I/O | FT_a | - | DBTRGO, DBTRGI, MCO1, UART4_TX, EVENTOUT | BOOTFAILN |
| L1 | R1 | T2 | R3 | PA14 | I/O | FT_a | - | DBTRGO, DBTRGI, MCO2, EVENTOUT | - |
| - | - | P4 | T3 | PI11 | I/O | FT | - | MCO1, I2S_CKIN, LCD_G6, EVENTOUT | WKUP5 |
| - | - | T1 | W1 | PI10 | I/O | FT | - | HDP0, USART3_CTS/USART3_NSS, ETH1_GMII_RX_ER/ ETH1_MII_RX_ER, LCD_HSYNC, EVENTOUT | - |
| - | L7 | 1G4 | - | VDD | S | - | - | - | - |
| W5 | E2 | F21 | - | VSS | S | - | - | - | - |
| - | F8 | - | - | VDDCORE | S | - | - | - | - |
| 1F1 | M4 | 1H1 | R5 | VDDA | S | - | - | - | - |
| 1F2 | - | - | - | VDDA | S | - | - | - | - |
| M3 | N3 | R4 | P6 | VREF+ | S | - | - | - | - |
| 1G1 | N4 | 1H2 | R6 | VSSA | S | - | - | - | - |
| - | P5 | - | T6 | VSSA | S | - | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| - | R5 | - | U6 | VSSA | S | - | - | - | - |
| - | M3 | - | N6 | VREF- | S | - | - | - | - |
| - | - | W4 | W2 | PH7 | I/O | FT_fh | - | I2C3_SCL, SPI5_MISO, ETH1_GMII_RXD3/ ETH1_MII_RXD3/ ETH1_RGMII_RXD3, MDIOS_MDC, DCMI_D9, EVENTOUT | - |
| - | - | U1 | V3 | PF3 | I/O | FT_e | - | ETH1_GMII_TX_ER, FMC_A3, EVENTOUT | - |
| P3 | T3 | W2 | U3 | PC3 | I/O | FT_ha | - | TRACECLK, DFSDM1_DATIN1, SPI2_MOSI/I2S2_SDO, ETH1_GMII_TX_CLK/ ETH1_MII_TX_CLK, EVENTOUT | ADC1_INP13, ADC1_INN12 |
| - | - | T4 | U4 | PG3 | I/O | FT_e | - | TRACED3, TIM8_BKIN2, DFSDM1_CKIN1, ETH1_GMII_TXD7, FMC_A13, EVENTOUT | - |
| P1 | T1 | Y1 | Y2 | PE2 | I/O | FT_fae | - | TRACECLK, SAI1_CK1, I2C4_SCL, SPI4_SCK, SAI1_MCLK_A, QUADSPI_BK1_IO2, ETH1_GMII_TXD3/ ETH1_MII_TXD3/ ETH1_RGMII_TXD3, FMC_A23, EVENTOUT | - |
| - | - | - | N10 | VDD | S | - | - | - | - |
| - | E4 | H3 | D4 | VSS | S | - | - | - | - |
| N2 | P3 | U2 | T4 | PA3 | I/O | FT_a | - | TIM2_CH4, TIM5_CH4, LPTIM5_OUT, TIM15_CH2, USART2_RX, LCD_B2, ETH1_GMII_COL/ ETH1_MII_COL, LCD_B5, EVENTOUT | ADC1_INP15, PVD_IN |
| P2 | T2 | Y2 | Y1 | PC2 | I/O | FT_ae | - | DFSDM1_CKIN1, SPI2_MISO/I2S2_SDI, DFSDM1_CKOUT, ETH1_GMII_TXD2/ ETH1_MII_TXD2/ ETH1_RGMII_TXD2, DCMI_PIXCLK, EVENTOUT | ADC1_INP12, ADC1_INN11 |
| - | - | V2 | W4 | PG2 | I/O | FT_e | - | TRACED2, MCO2, TIM8_BKIN, ETH1_GMII_TXD6, FMC_A12, EVENTOUT | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| R2 | U1 | AA1 | AA2 | PG14 | I/O | FT_e | - | TRACED1, LPTIM1_ETR, SPI6_MOSI, SAI4_D1, USART6_TX, QUADSPI_BK2_IO3, SAI4_SD_A, ETH1_GMII_TXD1/ ETH1_MII_TXD1/ ETH1_RGMII_TXD1/ ETH1_RMII_TXD1, FMC_A25, LCD_B0, EVENTOUT | - |
| - | - | W1 | Y4 | PG1 | I/O | FT_e | - | TRACED1, ETH1_GMII_TXD5, FMC_A11, EVENTOUT | - |
| R3 | U2 | AA2 | AA1 | PG13 | I/O | FT_e | - | TRACED0, LPTIM1_OUT, SAI1_CK2, SAI4_CK1, SPI6_SCK, SAI1_SCK_A, USART6_CTS/USART6_NSS, SAI4_MCLK_A, ETH1_GMII_TXD0/ ETH1_MII_TXD0/ ETH1_RGMII_TXD0/ ETH1_RMII_TXD0, FMC_A24, LCD_R0, EVENTOUT | - |
| - | - | U3 | R4 | ANA0 | A | A | - | - | ADC1_INP0, ADC1_INN1, ADC2_INP0, ADC2_INN1 |
| N3 | R3 | AB3 | AA3 | PA0 | I/O | FT_ha | - | TIM2_CH1/TIM2_ETR, TIM5_CH1, TIM8_ETR, TIM15_BKIN, USART2_CTS/USART2_NSS, UART4_TX, SDMMC2_CMD, SAI2_SD_B, ETH1_GMII_CRS/ ETH1_MII_CRS, EVENTOUT | ADC1_INP16, WKUP1 |
| - | E5 | - | E5 | VSS | S | - | - | - | - |
| - | - | U4 | T5 | ANA1 | A | A | - | - | ADC1_INP1, ADC2_INP1 |
| T1 | U4 | AA4 | V4 | PA1 | I/O | FT_ha | - | ETH_CLK, TIM2_CH2, TIM5_CH2, LPTIM3_OUT, TIM15_CH1N, USART2_RTS/USART2_DE, UART4_RX, QUADSPI_BK1_IO3, SAI2_MCLK_B, ETH1_GMII_RX_CLK/ ETH1_MII_RX_CLK/ ETH1_RGMII_RX_CLK/ ETH1_RMII_REF_CLK, LCD_R2, EVENTOUT | ADC1_INP17, ADC1_INN16 |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| 1H1 | P4 | V3 | U5 | PA5 | I/O | TT_ha | - | TIM2_CH1/TIM2_ETR, TIM8_CH1N, SAI4_CK1, SPI1_SCK/I2S1_CK, SPI6_SCK, SAI4_MCLK_A, LCD_R4, EVENTOUT | ADC1_INP19, ADC1_INN18, ADC2_INP19, ADC2_INN18, DAC_OUT2 |
| 1J1 | R4 | V4 | V6 | PA4 | I/O | TT_a | - | HDP0, TIM5_ETR, SAI4_D2, SPI1_NSS/I2S1_WS, SPI3_NSS/I2S3_WS, USART2_CK, SPI6_NSS, SAI4_FS_A, DCMI_HSYNC, LCD_VSYNC, EVENTOUT | ADC1_INP18, ADC2_INP18, DAC_OUT1 |
| - | - | AC2 | W5 | PG0 | I/O | FT_e | - | TRACED0, DFSDM1_DATIN0, ETH1_GMII_TXD4, FMC_A10, EVENTOUT | - |
| U3 | V1 | AB1 | Y5 | PB11 | I/O | FT_fae | - | TIM2_CH4, LPTIM2_ETR, I2C2_SDA, DFSDM1_CKIN7, USART3_RX, ETH1_GMII_TX_EN/ ETH1_MII_TX_EN/ ETH1_RGMII_TX_CTL/ ETH1_RMII_TX_EN, LCD_G5, EVENTOUT | - |
| - | - | AB2 | AB4 | PG4 | I/O | FT_e | - | TIM1_BKIN2, ETH1_GMII_GTX_CLK/ ETH1_RGMII_GTX_CLK, FMC_A14, EVENTOUT | - |
| T3 | W2 | AC3 | AB2 | PA2 | I/O | FT_ha | - | TIM2_CH3, TIM5_CH3, LPTIM4_OUT, TIM15_CH1, USART2_TX, SAI2_SCK_B, SDMMC2_D0DIR, ETH1_MDIO, MDIOS_MDIO, LCD_R1, EVENTOUT | ADC1_INP14, WKUP2 |
| 1F3 | M6 | - | - | VDD | S | - | - | - | - |
| T2 | V2 | AA6 | AB3 | PC1 | I/O | FT_ha | - | TRACED0, SAI1_D1, DFSDM1_DATIN0, DFSDM1_CKIN4, SPI2_MOSI/I2S2_SDO, SAI1_SD_A, SDMMC2_CK, ETH1_MDC, MDIOS_MDC, EVENTOUT | ADC1_INP11, ADC1_INN10, ADC2_INP11, ADC2_INN10, TAMP_IN3, WKUP6 |
| A6 | - | K21 | E19 | VSS | S | - | - | - | - |
| - | - | Y6 | U8 | PG5 | I/O | FT | - | TIM1_ETR, ETH1_GMII_CLK125/ ETH1_RGMII_CLK125, FMC_A15, EVENTOUT | - |
| - | F10 | 1B3 | J10 | VDDCORE | S | - | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| - | - | AA3 | Y6 | PH3 | I/O | FT_h | - | DFSDM1_CKIN4, QUADSPI_BK2_IO1, SAI2_MCLK_B, ETH1_GMII_COL/ ETH1_MII_COL, LCD_R1, EVENTOUT | - |
| U2 | W3 | AB6 | AB5 | PB0 | I/O | FT_a | - | TIM1_CH2N, TIM3_CH3, TIM8_CH2N, DFSDM1_CKOUT, UART4_CTS, LCD_R3, ETH1_GMII_RXD2/ ETH1_MII_RXD2/ ETH1_RGMII_RXD2, MDIOS_MDIO, LCD_G1, EVENTOUT | ADC1_INP9, ADC1_INN5, ADC2_INP9, ADC2_INN5 |
| - | - | Y4 | W6 | PF15 | I/O | FT_fh | - | TRACED7, I2C4_SDA, I2C1_SDA, ETH1_GMII_RXD7, FMC_A9, EVENTOUT | - |
| U1 | V3 | AA7 | AA5 | PB1 | I/O | FT_a | - | TIM1_CH3N, TIM3_CH4, TIM8_CH3N, DFSDM1_DATIN1, LCD_R6, ETH1_GMII_RXD3/ ETH1_MII_RXD3/ ETH1_RGMII_RXD3, MDIOS_MDC, LCD_G0, EVENTOUT | ADC1_INP5, ADC2_INP5 |
| - | E6 | - | F6 | VSS | S | - | - | - | - |
| - | - | AC4 | V7 | PF14 | I/O | FT_fha | - | TRACED6, DFSDM1_CKIN6, I2C4_SCL, I2C1_SCL, ETH1_GMII_RXD6, FMC_A8, EVENTOUT | ADC2_INP6, ADC2_INN2 |
| - | - | Y5 | W7 | PF13 | I/O | FT_ha | - | TRACED5, DFSDM1_DATIN6, I2C4_SMBA, I2C1_SMBA, DFSDM1_DATIN3, ETH1_GMII_RXD5, FMC_A7, EVENTOUT | ADC2_INP2 |
| - | - | AB4 | AB7 | PH2 | I/O | FT_h | - | LPTIM1_IN2, QUADSPI_BK2_IO0, SAI2_SCK_B, ETH1_GMII_CRS/ ETH1_MII_CRS, LCD_R0, EVENTOUT | - |
| V1 | V4 | AB7 | AA6 | PC5 | I/O | FT_a | - | SAI1_D3, DFSDM1_DATIN2, SAI4_D4, SAI1_D4, SPDIFRX_IN4, ETH1_GMII_RXD1/ ETH1_MII_RXD1/ ETH1_RGMII_RXD1/ ETH1_RMII_RXD1, SAI4_D3, EVENTOUT | ADC1_INP8, ADC1_INN4, ADC2_INP8, ADC2_INN4 |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| V2 | W4 | AC7 | AB6 | PC4 | I/O | FT_a | - | DFSDM1_CKIN2, I2S1_MCK, SPDIFRX_IN3, ETH1_GMII_RXD0/ ETH1_MII_RXD0/ ETH1_RGMII_RXD0/ ETH1_RMII_RXD0, EVENTOUT | ADC1_INP4, ADC2_INP4 |
| - | M8 | - | P9 | VDD | S | - | - | - | - |
| 1D2 | E8 | P3 | F7 | VSS | S | - | - | - | - |
| 1J3 | R7 | 1J2 | U9 | VDD | S | - | - | - | - |
| - | - | Y9 | V8 | PF12 | I/O | FT_ha | - | TRACED4, ETH1_GMII_RXD4, FMC_A6, EVENTOUT | ADC1_INP6, ADC1_INN2 |
| 1E4 | - | - | - | VDDCORE | S | - | - | - | - |
| W4 | U5 | Y10 | W8 | PF11 | I/O | FT_ha | - | SPI5_MOSI, SAI2_SD_B, DCMI_D12, LCD_G5, EVENTOUT | ADC1_INP2 |
| - | E10 | - | F8 | VSS | S | - | - | - | - |
| W2 | T6 | AB8 | Y9 | PA7 | I/O | FT_ha | - | TIM1_CH1N, TIM3_CH2, TIM8_CH1N, SAI4_D1, SPI1_MOSI/I2S1_SDO, SPI6_MOSI, TIM14_CH1, QUADSPI_CLK, ETH1_GMII_RX_DV/ ETH1_MII_RX_DV/ ETH1_RGMII_RX_CTL/ ETH1_RMII_CRS_DV, SAI4_SD_A, EVENTOUT | ADC1_INP7, ADC1_INN3, ADC2_INP7, ADC2_INN3 |
| - | F12 | - | J12 | VDDCORE | S | - | - | - | - |
| W3 | T5 | AC8 | W9 | PA6 | I/O | FT_ha | - | TIM1_BKIN, TIM3_CH1, TIM8_BKIN, SAI4_CK2, SPI1_MISO/I2S1_SDI, SPI6_MISO, TIM13_CH1, MDIOS_MDC, SAI4_SCK_A, DCMI_PIXCLK, LCD_G2, EVENTOUT | ADC1_INP3, ADC2_INP3 |
| - | - | 1H3 | - | VDD | S | - | - | - | - |
| U4 | T7 | AB5 | U10 | PC0 | I/O | FT_ha | - | DFSDM1_CKIN0, LPTIM2_IN2, DFSDM1_DATIN4, SAI2_FS_B, QUADSPI_BK2_NCS, LCD_R5, EVENTOUT | ADC1_INP10, ADC2_INP10 |
| 1G2 | E12 | P21 | F16 | VSS | S | - | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| U5 | W5 | Y3 | V9 | PB10 | I/O | FT_fha | - | TIM2_CH3, LPTIM2_IN1, I2C2_SCL, SPI2_SCK/I2S2_CK, DFSDM1_DATIN7, USART3_TX, QUADSPI_BK1_NCS, ETH1_GMII_RX_ER/ ETH1_MII_RX_ER, LCD_G4, EVENTOUT | - |
| - | - | 1B5 | - | VDDCORE | S | - | - | - | - |
| V3 | V5 | AC5 | AA7 | PB12 | I/O | FT_ae | - | TIM1_BKIN, I2C6_SMBA, I2C2_SMBA, SPI2_NSS/I2S2_WS, DFSDM1_DATIN1, USART3_CK, USART3_RX, FDCAN2_RX, ETH1_GMII_TXD0/ ETH1_MII_TXD0/ ETH1_RGMII_TXD0/ ETH1_RMII_TXD0, UART5_RX, EVENTOUT | - |
| - | G5 | - | J14 | VDDCORE | S | - | - | - | - |
| 1J2 | T9 | AA10 | V10 | PB13 | I/O | FT_e | - | TIM1_CH1N, DFSDM1_CKOUT, LPTIM2_OUT, SPI2_SCK/I2S2_CK, DFSDM1_CKIN1, USART3_CTS/USART3_NSS, FDCAN2_TX, ETH1_GMII_TXD1/ ETH1_MII_TXD1/ ETH1_RGMII_TXD1/ ETH1_RMII_TXD1, UART5_TX, EVENTOUT | - |
| - | E14 | V21 | F20 | VSS | S | - | - | - | - |
| V5 | T8 | Y8 | AA8 | PB5 | I/O | FT_e | - | ETH_CLK, TIM17_BKIN, TIM3_CH2, SAI4_D1, I2C1_SMBA, SPI1_MOSI/I2S1_SDO, I2C4_SMBA, SPI3_MOSI/I2S3_SDO, SPI6_MOSI, FDCAN2_RX, SAI4_SD_A, ETH1_PPS_OUT, UART5_RX, DCMI_D10, LCD_G7, EVENTOUT | - |
| U6 | V6 | Y7 | U11 | PG11 | I/O | FT_e | - | TRACED11, USART1_TX, UART4_TX, SPDIFRX_IN1, ETH1_GMII_TX_EN/ ETH1_MII_TX_EN/ ETH1_RGMII_TX_CTL/ ETH1_RMII_TX_EN, DCMI_D3, LCD_B3, EVENTOUT | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| 1B5 | G7 | 1C2 | - | VDDCORE | S | - | - | - | - |
| - | - | Y11 | V11 | PH6 | I/O | FT_h | - | TIM12_CH1, I2C2_SMBA, SPI5_SCK, ETH1_GMII_RXD2/ ETH1_MII_RXD2/ ETH1_RGMII_RXD2, MDIOS_MDIO, DCMI_D8, EVENTOUT | - |
| 1H2 | E16 | - | G4 | VSS | S | - | - | - | - |
| V4 | W6 | AB10 | AB8 | PB8 | I/O | FT_fae | - | HDP6, TIM16_CH1, TIM4_CH3, DFSDM1_CKIN7, I2C1_SCL, SDMMC1_CKIN, I2C4_SCL, SDMMC2_CKIN, UART4_RX, FDCAN1_RX, SDMMC2_D4, ETH1_GMII_TXD3/ ETH1_MII_TXD3/ ETH1_RGMII_TXD3, SDMMC1_D4, DCMI_D6, LCD_B6, EVENTOUT | - |
| - | - | - | K9 | VDDCORE | S | - | - | - | - |
| V6 | U7 | AB9 | Y8 | PG8 | I/O | FT_e | - | TRACED15, TIM2_CH1/TIM2_ETR, ETH_CLK, TIM8_ETR, SPI6_NSS, SAI4_D2, USART6_RTS/USART6_DE, USART3_RTS/USART3_DE, SPDIFRX_IN3, SAI4_FS_A, ETH1_PPS_OUT, LCD_G7, EVENTOUT | - |
| - | N5 | - | P11 | VDD | S | - | - | - | - |
| U7 | V7 | AB11 | AA9 | PG10 | I/O | FT_h | - | TRACED10, UART8_CTS, LCD_G3, SAI2_SD_B, QUADSPI_BK2_IO2, FMC_NE3, DCMI_D2, LCD_B2, EVENTOUT | - |
| - | F5 | W3 | - | VSS | S | - | - | - | - |
| 1J4 | W7 | AA9 | W11 | PE9 | I/O | FT_ha | - | TIM1_CH1, DFSDM1_CKOUT, UART7_RTS/UART7_DE, QUADSPI_BK2_IO2, FMC_AD6/FMC_D6, EVENTOUT | - |
| - | G9 | - | - | VDDCORE | S | - | - | - | - |
| V7 | T10 | AA11 | W10 | PE7 | I/O | FT_h | - | TIM1_ETR, TIM3_ETR, DFSDM1_DATIN2, UART7_RX, QUADSPI_BK2_IO0, FMC_AD4/FMC_D4, EVENTOUT | - |
| 1C3 | F7 | - | G6 | VSS | S | - | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| U8 | V8 | AC10 | AB9 | PD11 | I/O | FT_h | - | LPTIM2_IN2, I2C4_SMBA, I2C1_SMBA, USART3_CTS/USART3_NSS, QUADSPI_BK1_IO0, SAI2_SD_A, FMC_A16/FMC_CLE, EVENTOUT | - |
| 1D5 | G11 | 1C4 | - | VDDCORE | S | - | - | - | - |
| W7 | W8 | AB12 | AA10 | PF7 | I/O | FT_ha | - | TIM17_CH1, SPI5_SCK, SAI1_MCLK_B, UART7_TX, QUADSPI_BK1_IO2, EVENTOUT | - |
| V8 | U10 | AC11 | AB10 | PF8 | I/O | FT_ha | - | TRACED12, TIM16_CH1N, SPI5_MISO, SAI1_SCK_B, UART7_RTS/UART7_DE, TIM13_CH1, QUADSPI_BK1_IO0, EVENTOUT | - |
| - | - | - | K11 | VDDCORE | S | - | - | - | - |
| 1J7 | U9 | Y12 | V12 | PF10 | I/O | FT_h | - | TIM16_BKIN, SAI1_D3, SAI4_D4, SAI1_D4, QUADSPI_CLK, SAI4_D3, DCMI_D11, LCD_DE, EVENTOUT | - |
| - | F9 | AA5 | G8 | VSS | S | - | - | - | - |
| U10 | V9 | AA13 | AA11 | PF6 | I/O | FT_ha | - | TIM16_CH1, SPI5_NSS, SAI1_SD_B, UART7_RX, QUADSPI_BK1_IO3, SAI4_SCK_B, EVENTOUT | - |
| - | H4 | - | - | VDDCORE | S | - | - | - | - |
| U14 | U11 | Y18 | W12 | PD12 | I/O | FT_fha | - | LPTIM1_IN1, TIM4_CH1, LPTIM2_IN1, I2C4_SCL, I2C1_SCL, USART3_RTS/USART3_DE, QUADSPI_BK1_IO1, SAI2_FS_A, FMC_A17/FMC_ALE, EVENTOUT | - |
| - | F11 | AA8 | G10 | VSS | S | - | - | - | - |
| V9 | W9 | AA14 | AB11 | PF9 | I/O | FT_ha | - | TRACED13, TIM17_CH1N, SPI5_MOSI, SAI1_FS_B, UART7_CTS, TIM14_CH1, QUADSPI_BK1_IO1, EVENTOUT | - |
| - | H6 | 1C6 | K13 | VDDCORE | S | - | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| V11 | W10 | AC14 | Y11 | PG7 | I/O | FT_h | - | TRACED5, SAI1_MCLK_A, USART6_CK, UART8_RTS/UART8_DE, QUADSPI_CLK, QUADSPI_BK2_IO3, DCMI_D13, LCD_CLK, EVENTOUT | - |
| 1E3 | F15 | - | G12 | VSS | S | - | - | - | - |
| 1F5 | - | - | - | VDDCORE | S | - | - | - | - |
| W11 | T12 | Y14 | W13 | PB6 | I/O | FT_fha | - | TIM16_CH1N, TIM4_CH1, I2C1_SCL, CEC, I2C4_SCL, USART1_TX, FDCAN2_TX, QUADSPI_BK1_NCS, DFSDM1_DATIN5, UART5_TX, DCMI_D5, EVENTOUT | - |
| U12 | T11 | AC13 | Y12 | PE8 | I/O | FT_h | - | TIM1_CH1N, DFSDM1_CKIN2, UART7_TX, QUADSPI_BK2_IO1, FMC_AD5/FMC_D5, EVENTOUT | - |
| V12 | V10 | Y15 | W14 | PE10 | I/O | FT_ha | - | TIM1_CH2N, DFSDM1_DATIN4, UART7_CTS, QUADSPI_BK2_IO3, FMC_AD7/FMC_D7, EVENTOUT | - |
| - | H8 | 1D1 | K15 | VDDCORE | S | - | - | - | - |
| V13 | T13 | Y16 | V13 | PB2 | I/O | FT_ha | - | TRACED4, RTC_OUT2, SAI1_D1, DFSDM1_CKIN1, USART1_RX, I2S_CKIN, SAI1_SD_A, SPI3_MOSI/I2S3_SDO, UART4_RX, QUADSPI_CLK, EVENTOUT | - |
| - | H10 | - | - | VDDCORE | S | - | - | - | - |
| U13 | U12 | AA19 | V14 | PD13 | I/O | FT_fha | - | LPTIM1_OUT, TIM4_CH2, I2C4_SDA, I2C1_SDA, I2S3_MCK, QUADSPI_BK1_IO3, SAI2_SCK_A, FMC_A18, EVENTOUT | - |
| - | N7 | - | - | VDD | S | - | - | - | - |
| - | G2 | AA12 | G14 | VSS | S | - | - | - | - |
| 1J8 | V16 | AB18 | AA17 | USB_RREF | A | A | - | - | - |
| - | W12 | AA15 | AB13 | VDD3V3_ USBHS | S | - | - | - | - |
| 1H7 | - | - | - | VDD3V3_ USB | S | - | - | - | - |
| V10 | W13 | AC16 | AB14 | USB_DP2 | A | FT_u | - | - | USBH_HS_DP2, OTG_HS_DP |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| W10 | V13 | AB16 | AA14 | USB_DM2 | A | FT_u | - | - | USBH_HS_DM2, OTG_HS_DM |
| - | U13 | AA16 | Y13 | VSS_USBHS | S | - | - | - | - |
| - | - | - | Y14 | VSS_USBHS | S | - | - | - | - |
| U11 | T15 | AB13 | AA12 | BYPASS_ REG1V8 | I | FT | - | - | - |
| W8 | T14 | Y13 | W15 | PG9 | I/O | FT_h | - | DBTRGO, USART6_RX, SPDIFRX_IN4, QUADSPI_BK2_IO2, SAI2_FS_B, FMC_NE2/FMC_NCE, DCMI_VSYNC, LCD_R1, EVENTOUT | - |
| 1G3 | - | 1H5 | R10 | VDD | S | - | - | - | - |
| - | N9 | - | - | VDD | S | - | - | - | - |
| 1H5 | V11 | AB14 | AB12 | VDDA1V8_ REG | S | - | - | - | - |
| 1H3 | - | - | G17 | VSS | S | - | - | - | - |
| 1J6 | W11 | AB15 | AB17 | VDDA1V1_ REG | S | - | - | - | - |
| - | G4 | AA21 | H7 | VSS | S | - | - | - | - |
| - | - | - | R12 | VDD | S | - | - | - | - |
| - | P6 | - | - | VDD | S | - | - | - | - |
| - | U14 | - | Y15 | VSS_USBHS | S | - | - | - | - |
| - | V12 | - | AA13 | VSS_USBHS | S | - | - | - | - |
| 1D4 | G6 | AC1 | J9 | VSS | S | - | - | - | - |
| - | V15 | - | AA16 | VSS_USBHS | S | - | - | - | - |
| W14 | W14 | AB17 | AB15 | USB_DM1 | A | FT_u | - | - | USBH_HS_DM1 |
| V14 | V14 | AC17 | AA15 | USB_DP1 | A | FT_u | - | - | USBH_HS_DP1 |
| V15 | U16 | AB19 | W16 | PA12 | I/O | FT_uf | - | TIM1_ETR, I2C6_SDA, I2C5_SDA, UART4_TX, USART1_RTS/USART1_DE, SAI2_FS_B, FDCAN1_TX, LCD_R5, EVENTOUT | OTG_FS_DP |
| - | G8 | - | J11 | VSS | S | - | - | - | - |
| - | - | - | L8 | VDDCORE | S | - | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| U15 | V17 | AA18 | Y16 | PA11 | I/O | FT_uf | - | TIM1_CH4, I2C6_SCL, I2C5_SCL, SPI2_NSS/I2S2_WS, UART4_RX, USART1_CTS/USART1_NSS, FDCAN1_RX, LCD_R4, EVENTOUT | OTG_FS_DM |
| 1C6 | H12 | 1D3 | - | VDDCORE | S | - | - | - | - |
| 1F4 | G10 | AC23 | - | VSS | S | - | - | - | - |
| - | W15 | AA17 | AB16 | VDD3V3_ USBFS | S | - | - | - | - |
| V16 | U15 | AC19 | V15 | OTG_VBUS | A | FT_u | - | - | OTG_FS_VBUS, OTG_HS_VBUS |
| U16 | T16 | Y17 | Y17 | PA10 | I/O | FT_u | - | TIM1_CH3, SPI3_NSS/I2S3_WS, USART1_RX, MDIOS_MDIO, SAI4_FS_B, DCMI_D1, LCD_B1, EVENTOUT | OTG_FS_ID, OTG_HS_ID |
| - | - | AB20 | AB20 | DDR_DQ27 | I/O | DDR | - | - | - |
| 1B9 | E15 | 1A8 | E18 | VDDQ_DDR | S | - | - | - | - |
| - | - | AB21 | AB21 | DDR_DQ26 | I/O | DDR | - | - | - |
| - | G12 | - | J13 | VSS | S | - | - | - | - |
| - | - | AC22 | AA21 | DDR_DQ28 | I/O | DDR | - | - | - |
| 1H4 | G14 | 1A3 | J17 | VSS | S | - | - | - | - |
| - | - | AC21 | AA20 | DDR_DQ29 | I/O | DDR | - | - | - |
| - | - | Y22 | W20 | DDR_DQ25 | I/O | DDR | - | - | - |
| - | - | AB22 | Y21 | DDR_DQS3P | I/O | DDR | - | - | - |
| - | H5 | - | J20 | VSS | S | - | - | - | - |
| - | - | AB23 | Y22 | DDR_DQS3N | I/O | DDR | - | - | - |
| - | - | - | F17 | VDDQ_DDR | S | - | - | - | - |
| - | - | AA20 | AA22 | DDR_DQM3 | O | DDR | - | - | - |
| - | F14 | 1B7 | - | VDDQ_DDR | S | - | - | - | - |
| - | - | AA22 | W21 | DDR_DQ31 | I/O | DDR | - | - | - |
| - | H7 | 1A5 | K3 | VSS | S | - | - | - | - |
| - | - | AA23 | W22 | DDR_DQ30 | I/O | DDR | - | - | - |
| U9 | H9 | 1A7 | K7 | VSS | S | - | - | - | - |
| - | - | Y23 | V22 | DDR_DQ24 | I/O | DDR | - | - | - |
| - | - | - | G16 | VDDQ_DDR | S | - | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| - | - | - | L10 | VDDCORE | S | - | - | - | - |
| W16 | W16 | AC20 | AB19 | DDR_VREF | A | A | - | - | - |
| - | H11 | - | K10 | VSS | S | - | - | - | - |
| W17 | W18 | W23 | V20 | DDR_DQ12 | I/O | DDR | - | - | - |
| 1C5 | H13 | 1B2 | K12 | VSS | S | - | - | - | - |
| V17 | W17 | Y21 | V21 | DDR_DQ15 | I/O | DDR | - | - | - |
| - | H15 | - | K14 | VSS | S | - | - | - | - |
| U17 | V18 | W22 | U21 | DDR_DQ14 | I/O | DDR | - | - | - |
| W18 | V19 | W21 | T20 | DDR_DQ11 | I/O | DDR | - | - | - |
| - | G15 | 1B9 | H17 | VDDQ_DDR | S | - | - | - | - |
| V19 | U19 | U22 | T22 | DDR_DQS1P | I/O | DDR | - | - | - |
| 1E5 | - | 1B4 | L9 | VSS | S | - | - | - | - |
| U18 | T19 | U23 | R22 | DDR_DQS1N | I/O | DDR | - | - | - |
| V18 | U18 | V22 | T21 | DDR_DQM1 | O | DDR | - | - | - |
| 1D9 | - | - | J16 | VDDQ_DDR | S | - | - | - | - |
| T18 | T18 | T23 | R20 | DDR_DQ13 | I/O | DDR | - | - | - |
| - | J3 | 1B6 | - | VSS | S | - | - | - | - |
| U19 | T17 | U21 | R21 | DDR_DQ9 | I/O | DDR | - | - | - |
| 1G5 | J6 | - | L11 | VSS | S | - | - | - | - |
| T19 | R18 | T22 | P21 | DDR_DQ10 | I/O | DDR | - | - | - |
| - | H14 | - | - | VDDQ_DDR | S | - | - | - | - |
| R18 | P18 | T21 | N22 | DDR_DQ8 | I/O | DDR | - | - | - |
| - | J8 | 1B8 | L13 | VSS | S | - | - | - | - |
| 1J5 | J10 | - | L17 | VSS | S | - | - | - | - |
| 1F8 | N19 | Y19 | AA19 | DDR_ATO | A | A | - | - | - |
| - | J7 | - | - | VDDCORE | S | - | - | - | - |
| - | - | 1C8 | - | VDDQ_DDR | S | - | - | - | - |
| 1G9 | N16 | W20 | U19 | DDR_A6 | O | DDR | - | - | - |
| - | - | - | K17 | VDDQ_DDR | S | - | - | - | - |
| T17 | R17 | Y20 | U18 | DDR_A8 | O | DDR | - | - | - |
| - | J12 | 1C1 | L19 | VSS | S | - | - | - | - |
| R17 | P17 | V20 | T18 | DDR_A4 | O | DDR | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| 1A6 | J14 | 1C3 | L20 | VSS | S | - | - | - | - |
| P17 | P19 | T20 | R19 | DDR_CKE | O | DDR | - | - | - |
| P18 | N17 | U20 | R18 | DDR_BA1 | O | DDR | - | - | - |
| - | J15 | - | L16 | VDDQ_DDR | S | - | - | - | - |
| N18 | N18 | R21 | P18 | DDR_A14 | O | DDR | - | - | - |
| - | K2 | - | M7 | VSS | S | - | - | - | - |
| N19 | M18 | R20 | P19 | DDR_A11 | O | DDR | - | - | - |
| - | K5 | 1C5 | M10 | VSS | S | - | - | - | - |
| 1D6 | K7 | - | M12 | VSS | S | - | - | - | - |
| M17 | M19 | R22 | N18 | DDR_A10 | O | DDR | - | - | - |
| - | J9 | 1D5 | L12 | VDDCORE | S | - | - | - | - |
| - | - | 1D9 | - | VDDQ_DDR | S | - | - | - | - |
| M18 | L17 | P23 | N19 | DDR_A12 | O | DDR | - | - | - |
| M19 | M17 | P22 | M18 | DDR_A1 | O | DDR | - | - | - |
| - | K9 | 1C7 | M14 | VSS | S | - | - | - | - |
| J19 | K17 | N20 | M22 | DDR_CASN | O | DDR | - | - | - |
| 1F6 | K11 | - | N9 | VSS | S | - | - | - | - |
| J18 | J17 | M20 | M21 | DDR_WEN | O | DDR | - | - | - |
| - | K14 | - | M17 | VDDQ_DDR | S | - | - | - | - |
| 1E9 | L18 | N21 | M20 | DDR_RASN | O | DDR | - | - | - |
| L17 | L19 | N22 | N20 | DDR_CLKP | O | DDR | - | - | - |
| - | K13 | 1C9 | - | VSS | S | - | - | - | - |
| K18 | K19 | N23 | N21 | DDR_CLKN | O | DDR | - | - | - |
| 1F9 | - | 1E8 | N16 | VDDQ_DDR | S | - | - | - | - |
| 1D8 | K18 | K20 | L22 | DDR_DTO0 | O | DDR | - | - | - |
| 1C8 | J19 | L21 | K21 | DDR_DTO1 | O | DDR | - | - | - |
| L18 | L16 | P20 | M19 | DDR_A15 | O | DDR | - | - | - |
| 1H6 | - | 1D2 | N11 | VSS | S | - | - | - | - |
| 1E6 | - | - | - | VDDCORE | S | - | - | - | - |
| - | K15 | - | N13 | VSS | S | - | - | - | - |
| J17 | J18 | M22 | L18 | DDR_CSN | O | DDR | - | - | - |
| H18 | H19 | L22 | L21 | DDR_ODT | O | DDR | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| H17 | J16 | M21 | K18 | DDR_BA2 | O | DDR | - | - | - |
| 1C7 | L6 | 1D4 | N17 | VSS | S | - | - | - | - |
| G18 | H18 | L20 | K19 | DDR_A0 | O | DDR | - | - | - |
| - | L15 | - | P17 | VDDQ_DDR | S | - | - | - | - |
| G19 | G19 | L23 | K20 | DDR_BA0 | O | DDR | - | - | - |
| E17 | F17 | F20 | G18 | DDR_A13 | O | DDR | - | - | - |
| - | L8 | - | P3 | VSS | S | - | - | - | - |
| F17 | G18 | J20 | J18 | DDR_A2 | O | DDR | - | - | - |
| 1E7 | L10 | 1D6 | P7 | VSS | S | - | - | - | - |
| F19 | F19 | K22 | J19 | DDR_A3 | O | DDR | - | - | - |
| - | - | 1F9 | - | VDDQ_DDR | S | - | - | - | - |
| C16 | G16 | D20 | F19 | DDR_ RESETN | O | DDR | - | - | - |
| - | M14 | - | R16 | VDDQ_DDR | S | - | - | - | - |
| 1C9 | H17 | H20 | H19 | DDR_A5 | O | DDR | - | - | - |
| - | L12 | 1D8 | P10 | VSS | S | - | - | - | - |
| 1A9 | E17 | E20 | F18 | DDR_A7 | O | DDR | - | - | - |
| - | L14 | - | P12 | VSS | S | - | - | - | - |
| 1A8 | F18 | K23 | K22 | DDR_ZQ | A | A | - | - | - |
| E18 | G17 | G20 | H18 | DDR_A9 | O | DDR | - | - | - |
| 1G7 | M5 | 1E1 | P14 | VSS | S | - | - | - | - |
| - | J11 | 1D7 | L14 | VDDCORE | S | - | - | - | - |
| D18 | E18 | J21 | J21 | DDR_DQ4 | I/O | DDR | - | - | - |
| - | M7 | - | P20 | VSS | S | - | - | - | - |
| D19 | D17 | J22 | H20 | DDR_DQ5 | I/O | DDR | - | - | - |
| W13 | M9 | 1E3 | - | VSS | S | - | - | - | - |
| C18 | D18 | H21 | H21 | DDR_DQ2 | I/O | DDR | - | - | - |
| - | - | - | T17 | VDDQ_DDR | S | - | - | - | - |
| C19 | D19 | H22 | H22 | DDR_DQ6 | I/O | DDR | - | - | - |
| - | - | 1G8 | - | VDDQ_DDR | S | - | - | - | - |
| B19 | C19 | G22 | G22 | DDR_DQS0P | I/O | DDR | - | - | - |
| - | M11 | - | R8 | VSS | S | - | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| B18 | B19 | G23 | G21 | DDR_DQS0N | I/O | DDR | - | - | - |
| - | N15 | - | - | VDDQ_DDR | S | - | - | - | - |
| C17 | C18 | H23 | G20 | DDR_DQM0 | O | DDR | - | - | - |
| 1H9 | - | - | U16 | VDDQ_DDR | S | - | - | - | - |
| B17 | B18 | G21 | G19 | DDR_DQ7 | I/O | DDR | - | - | - |
| 1B8 | M13 | 1E5 | R17 | VSS | S | - | - | - | - |
| A18 | A18 | F22 | F21 | DDR_DQ1 | I/O | DDR | - | - | - |
| - | M15 | 1E7 | T7 | VSS | S | - | - | - | - |
| A17 | A17 | E22 | E21 | DDR_DQ0 | I/O | DDR | - | - | - |
| B16 | B17 | E21 | E20 | DDR_DQ3 | I/O | DDR | - | - | - |
| - | P14 | 1H9 | V17 | VDDQ_DDR | S | - | - | - | - |
| 1H8 | - | - | T9 | VSS | S | - | - | - | - |
| - | J13 | - | - | VDDCORE | S | - | - | - | - |
| - | - | E23 | E22 | DDR_DQ21 | I/O | DDR | - | - | - |
| - | N6 | 1E9 | T11 | VSS | S | - | - | - | - |
| - | - | D21 | D20 | DDR_DQ22 | I/O | DDR | - | - | - |
| C14 | N8 | - | T19 | VSS | S | - | - | - | - |
| - | - | D22 | D21 | DDR_DQ17 | I/O | DDR | - | - | - |
| - | - | D23 | D22 | DDR_DQ18 | I/O | DDR | - | - | - |
| - | - | - | W18 | VDDQ_DDR | S | - | - | - | - |
| - | - | C22 | C21 | DDR_DQS2P | I/O | DDR | - | - | - |
| - | N10 | 1F2 | U7 | VSS | S | - | - | - | - |
| - | - | B23 | B22 | DDR_DQS2N | I/O | DDR | - | - | - |
| - | R15 | 1J8 | - | VDDQ_DDR | S | - | - | - | - |
| - | - | C23 | C22 | DDR_DQM2 | O | DDR | - | - | - |
| - | - | - | Y19 | VDDQ_DDR | S | - | - | - | - |
| - | - | B22 | B21 | DDR_DQ16 | I/O | DDR | - | - | - |
| - | N12 | 1F4 | U13 | VSS | S | - | - | - | - |
| - | - | A22 | A21 | DDR_DQ23 | I/O | DDR | - | - | - |
| 1J9 | N14 | - | U15 | VSS | S | - | - | - | - |
| - | - | B21 | B20 | DDR_DQ19 | I/O | DDR | - | - | - |
| - | - | A21 | A20 | DDR_DQ20 | I/O | DDR | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| - | - | 1J4 | - | VDD | S | - | - | - | - |
| - | P7 | 1F6 | - | VSS | S | - | - | - | - |
| - | - | - | M11 | VDDCORE | S | - | - | - | - |
| C15 | D15 | C20 | E17 | JTMS-SWDIO | I/O | FTU | - | - | - |
| A16 | D16 | B20 | D17 | JTCK-SWCLK | I | FTD | - | - | - |
| A15 | D14 | A19 | E16 | JTDO-TRACESWO | O | FTU | - | - | - |
| B15 | D13 | A20 | D16 | JTDI | I | FTU | - | - | - |
| 1G6 | K8 | 1E2 | - | VDDCORE | S | - | - | - | - |
| B14 | D12 | B19 | E15 | NJTRST | I | FTU | - | - | - |
| - | G13 | - | D18 | VDD_PLL2 | S | - | - | - | - |
| - | F13 | - | D19 | VSS_PLL2 | S | - | - | - | - |
| 1B6 | B12 | C14 | B14 | VDDA1V8_Unused | S | - | - | - | - |
| - | C12 | C16 | C14 | VSS | S | - | - | - | - |
| - | C13 | - | C15 | VSS | S | - | - | - | - |
| A13 | B15 | B17 | B17 | DNU | DNU | - | - | - | - |
| B13 | A15 | A17 | A17 | DNU | DNU | - | - | - | - |
| 1B7 | A16 | C17 | A18 | VDD1V2_Unused | S | - | - | - | - |
| B12 | A14 | A16 | A16 | DNU | DNU | - | - | - | - |
| A12 | B14 | B16 | B16 | DNU | DNU | - | - | - | - |
| - | C14 | - | C16 | VSS | S | - | - | - | - |
| - | C15 | - | C17 | VSS | S | - | - | - | - |
| - | C16 | - | C18 | VSS | S | - | - | - | - |
| B11 | B13 | C15 | B15 | DNU | DNU | - | - | - | - |
| C12 | A13 | B15 | A15 | DNU | DNU | - | - | - | - |
| - | P8 | - | T13 | VDD | S | - | - | - | - |
| C13 | A12 | B18 | A14 | VDD_Unused | S | - | - | - | - |
| 1A7 | B16 | C18 | B18 | VDD1V2_Unused | S | - | - | - | - |
| D17 | P9 | - | U17 | VSS | S | - | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| C11 | A11 | D16 | D15 | PC11 | I/O | FT_ha | - | TRACED3, DFSDM1_DATIN5, SPI3_MISO/I2S3_SDI, USART3_RX, UART4_RX, QUADSPI_BK2_NCS, SAI4_SCK_B, SDMMC1_D3, DCMI_D4, EVENTOUT | - |
| - | K10 | - | - | VDDCORE | S | - | - | - | - |
| A10 | B11 | D19 | F15 | PE4 | I/O | FT_h | - | TRACED1, SAI1_D2, DFSDM1_DATIN3, TIM15_CH1N, SPI4_NSS, SAI1_FS_A, SDMMC2_CKIN, SDMMC1_CKIN, SDMMC2_D4, SDMMC1_D4, FMC_A20, DCMI_D4, LCD_B0, EVENTOUT | - |
| - | - | - | M13 | VDDCORE | S | - | - | - | - |
| A9 | C11 | D18 | E14 | PC8 | I/O | FT_ha | - | TRACED0, TIM3_CH3, TIM8_CH3, UART4_TX, USART6_CK, UART5_RTS/UART5_DE, SDMMC1_D0, DCMI_D2, EVENTOUT | - |
| - | P11 | 1F8 | U20 | VSS | S | - | - | - | - |
| B10 | D11 | D15 | F14 | PC10 | I/O | FT_ha | - | TRACED2, DFSDM1_CKIN5, SPI3_SCK/I2S3_CK, USART3_TX, UART4_TX, QUADSPI_BK1_IO1, SAI4_MCLK_B, SDMMC1_D2, DCMI_D8, LCD_R2, EVENTOUT | - |
| 1D7 | K12 | 1E4 | - | VDDCORE | S | - | - | - | - |
| B6 | B9 | B13 | C13 | PB4 | I/O | FT_ha | - | TRACED8, TIM16_BKIN, TIM3_CH1, SAI4_CK2, SPI1_MISO/I2S1_SDI, SPI3_MISO/I2S3_SDI, SPI2_NSS/I2S2_WS, SPI6_MISO, SDMMC2_D3, SAI4_SCK_A, UART7_TX, EVENTOUT | - |
| B9 | A10 | D17 | D14 | PC9 | I/O | FT_fh | - | TRACED1, TIM3_CH4, TIM8_CH4, I2C3_SDA, I2S_CKIN, UART5_CTS, QUADSPI_BK1_IO0, SDMMC1_D1, DCMI_D3, LCD_B2, EVENTOUT | - |
| G17 | P13 | 1G3 | V5 | VSS | S | - | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| C10 | A9 | B11 | D13 | PC7 | I/O | FT_ha | - | HDP4, TIM3_CH2, TIM8_CH2, DFSDM1_DATIN3, I2S3_MCK, USART6_RX, SDMMC1_D123DIR, SDMMC2_D123DIR, SDMMC2_D7, SDMMC1_D7, DCMI_D1, LCD_G6, EVENTOUT | - |
| - | L9 | - | M15 | VDDCORE | S | - | - | - | - |
| A4 | D10 | B14 | E13 | PC6 | I/O | FT_ha | - | HDP1, TIM3_CH1, TIM8_CH1, DFSDM1_CKIN3, I2S2_MCK, USART6_TX, SDMMC1_D0DIR, SDMMC2_D0DIR, SDMMC2_D6, SDMMC1_D6, DCMI_D0, LCD_HSYNC, EVENTOUT | - |
| - | - | A14 | F13 | PF2 | I/O | FT_h | - | I2C2_SMBA, SDMMC2_D0DIR, SDMMC3_D0DIR, SDMMC1_D0DIR, FMC_A2, EVENTOUT | - |
| 1A5 | B10 | D12 | D12 | PD2 | I/O | FT_ha | - | TIM3_ETR, I2C5_SMBA, UART4_RX, UART5_RX, SDMMC1_CMD, DCMI_D11, EVENTOUT | - |
| 1G4 | P10 | - | - | VDD | S | - | - | - | - |
| - | P15 | - | V16 | VSS | S | - | - | - | - |
| - | - | 1E6 | - | VDDCORE | S | - | - | - | - |
| B8 | B8 | A13 | B13 | PA8 | I/O | FT_fh | - | MCO1, TIM1_CH1, TIM8_BKIN2, I2C3_SCL, SPI3_MOSI/I2S3_SDO, USART1_CK, SDMMC2_CKIN, SDMMC2_D4, OTG_FS_SOF/OTG_HS_SOF, SAI4_SD_B, UART7_RX, LCD_R6, EVENTOUT | - |
| 1A4 | C9 | C13 | A13 | PB14 | I/O | FT_h | - | TIM1_CH2N, TIM12_CH1, TIM8_CH2N, USART1_TX, SPI2_MISO/I2S2_SDI, DFSDM1_DATIN2, USART3_RTS/USART3_DE, SDMMC2_D0, EVENTOUT | - |
| 1B4 | C10 | D13 | E12 | PC12 | I/O | FT_h | - | TRACECLK, MCO2, SAI4_D3, SPI3_MOSI/I2S3_SDO, USART3_CK, UART5_TX, SAI4_SD_B, SDMMC1_CK, DCMI_D9, EVENTOUT | - |
| K17 | R2 | 1G5 | V18 | VSS | S | - | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| C8 | A8 | B12 | B12 | PB15 | I/O | FT_h | - | RTC_REFIN, TIM1_CH3N, TIM12_CH2, TIM8_CH3N, USART1_RX, SPI2_MOSI/I2S2_SDO, DFSDM1_CKIN2, SDMMC2_D1, EVENTOUT | - |
| - | L11 | - | N12 | VDDCORE | S | - | - | - | - |
| B7 | B7 | C11 | C12 | PE5 | I/O | FT_h | - | TRACED3, SAI1_CK2, DFSDM1_CKIN3, TIM15_CH1, SPI4_MISO, SAI1_SCK_A, SDMMC2_D0DIR, SDMMC1_D0DIR, SDMMC2_D6, SDMMC1_D6, FMC_A21, DCMI_D6, LCD_G0, EVENTOUT | - |
| - | - | - | U12 | VDD | S | - | - | - | - |
| C7 | A7 | A11 | A12 | PB3 | I/O | FT_h | - | TRACED9, TIM2_CH2, SAI4_CK1, SPI1_SCK/I2S1_CK, SPI3_SCK/I2S3_CK, SPI6_SCK, SDMMC2_D2, SAI4_MCLK_A, UART7_RX, EVENTOUT | - |
| - | R6 | - | V19 | VSS | S | - | - | - | - |
| B5 | A6 | A10 | D11 | PG6 | I/O | FT_h | - | TRACED14, TIM17_BKIN, SDMMC2_CMD, DCMI_D12, LCD_R7, EVENTOUT | - |
| 1F7 | - | - | - | VDDCORE | S | - | - | - | - |
| A7 | C6 | D14 | B11 | PD3 | I/O | FT_h | - | HDP5, DFSDM1_CKOUT, SPI2_SCK/I2S2_CK, DFSDM1_DATIN0, USART2_CTS/USART2_NSS, SDMMC1_D123DIR, SDMMC2_D7, SDMMC2_D123DIR, SDMMC1_D7, FMC_CLK, DCMI_D5, LCD_G7, EVENTOUT | - |
| C9 | D9 | B10 | F12 | PB9 | I/O | FT_fh | - | HDP7, TIM17_CH1, TIM4_CH4, DFSDM1_DATIN7, I2C1_SDA, SPI2_NSS/I2S2_WS, I2C4_SDA, SDMMC2_CDIR, UART4_TX, FDCAN1_TX, SDMMC2_D5, SDMMC1_CDIR, SDMMC1_D5, DCMI_D7, LCD_B7, EVENTOUT | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| B4 | C7 | C19 | E11 | PA15 | I/O | FT_h | - | DBTRGI, TIM2_CH1/TIM2_ETR, SAI4_D2, SDMMC1_CDIR, CEC, SPI1_NSS/I2S1_WS, SPI3_NSS/I2S3_WS, SPI6_NSS, UART4_RTS/UART4_DE, SDMMC2_D5, SDMMC2_CDIR, SDMMC1_D5, SAI4_FS_A, UART7_TX, LCD_R1, EVENTOUT | - |
| N17 | - | 1G7 | W17 | VSS | S | - | - | - | - |
| C6 | C8 | A8 | A11 | PA9 | I/O | FT_h | - | TIM1_CH2, I2C3_SMBA, SPI2_SCK/I2S2_CK, USART1_TX, SDMMC2_CDIR, SDMMC2_D5, DCMI_D0, LCD_R5, EVENTOUT | - |
| A3 | B5 | D11 | F11 | PB7 | I/O | FT_fh | - | TIM17_CH1N, TIM4_CH2, I2C1_SDA, I2C4_SDA, USART1_RX, SDMMC2_D1, DFSDM1_CKIN5, FMC_NL, DCMI_VSYNC, EVENTOUT | - |
| - | L13 | 1F5 | N14 | VDDCORE | S | - | - | - | - |
| A2 | A4 | B9 | B10 | PD1 | I/O | FT_fh | - | I2C6_SCL, DFSDM1_DATIN6, I2C5_SCL, SAI3_SD_A, UART4_TX, FDCAN1_TX, SDMMC3_D0, DFSDM1_CKIN7, FMC_AD3/FMC_D3, EVENTOUT | - |
| - | R9 | 1J6 | - | VDD | S | - | - | - | - |
| C5 | A3 | B8 | C10 | PD0 | I/O | FT_fh | - | I2C6_SDA, DFSDM1_CKIN6, I2C5_SDA, SAI3_SCK_A, UART4_RX, FDCAN1_RX, SDMMC3_CMD, DFSDM1_DATIN7, FMC_AD2/FMC_D2, EVENTOUT | - |
| - | R8 | - | W19 | VSS | S | - | - | - | - |
| 1A3 | A5 | C9 | A10 | PE3 | I/O | FT_h | - | TRACED0, TIM15_BKIN, SAI1_SD_B, SDMMC2_CK, FMC_A19, EVENTOUT | - |
| C4 | D7 | A7 | A9 | PD5 | I/O | FT_h | - | USART2_TX, SDMMC3_D2, FMC_NWE, EVENTOUT | - |
| B3 | B4 | D10 | F10 | PD7 | I/O | FT_fh | - | TRACED6, DFSDM1_DATIN4, I2C2_SCL, DFSDM1_CKIN1, USART2_CK, SPDIFRX_IN1, SDMMC3_D3, FMC_NE1, EVENTOUT | - |
| - | M10 | - | - | VDDCORE | S | - | - | - | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| B1 | A2 | B7 | D10 | PG15 | I/O | FT_fh | - | TRACED7, SAI1_D2, I2C2_SDA, SAI1_FS_A, USART6_CTS/USART6_NSS, SDMMC3_CK, DCMI_D13, EVENTOUT | - |
| B2 | B3 | C10 | E9 | PE6 | I/O | FT_h | - | TRACED2, TIM1_BKIN2, SAI1_D1, TIM15_CH2, SPI4_MOSI, SAI1_SD_A, SDMMC2_D0, SDMMC1_D2, SAI2_MCLK_B, FMC_A22, DCMI_D7, LCD_G1, EVENTOUT | - |
| - | R10 | 1G9 | Y3 | VSS | S | - | - | - | - |
| - | - | D8 | E10 | PF0 | I/O | FT_fh | - | I2C2_SDA, SDMMC3_D0, SDMMC3_CKIN, FMC_A0, EVENTOUT | - |
| - | - | - | P13 | VDDCORE | S | - | - | - | - |
| - | - | A5 | B9 | PF1 | I/O | FT_fh | - | I2C2_SCL, SDMMC3_CMD, SDMMC3_CDIR, FMC_A1, EVENTOUT | - |
| F18 | R12 | 1H4 | - | VSS | S | - | - | - | - |
| - | - | D9 | F9 | PF4 | I/O | FT_h | - | USART2_RX, SDMMC3_D1, SDMMC3_D123DIR, FMC_A4, EVENTOUT | - |
| 1E8 | M12 | 1F7 | - | VDDCORE | S | - | - | - | - |
| C3 | D6 | B6 | C9 | PD4 | I/O | FT_h | - | SAI3_FS_A, USART2_RTS/USART2_DE, SDMMC3_D1, DFSDM1_CKIN0, FMC_NOE, EVENTOUT | - |
| - | - | - | U14 | VDD | S | - | - | - | - |
| - | - | D7 | D9 | PF5 | I/O | FT_h | - | USART2_TX, SDMMC3_D2, FMC_A5, EVENTOUT | - |
| - | R14 | - | Y7 | VSS | S | - | - | - | - |
| 1A2 | C5 | B5 | A8 | PD10 | I/O | FT_h | - | RTC_REFIN, TIM16_BKIN, DFSDM1_CKOUT, I2C5_SMBA, SPI3_MISO/I2S3_SDI, SAI3_FS_B, USART3_CK, FMC_AD15/FMC_D15, LCD_B3, EVENTOUT | - |
| - | N11 | - | P15 | VDDCORE | S | - | - | - | - |
| - | - | - | B8 | PJ12 | I/O | FT | - | LCD_G3, LCD_B0, EVENTOUT | - |
| - | - | - | A7 | PJ13 | I/O | FT | - | LCD_G4, LCD_B1, EVENTOUT | - |
| - | - | - | B7 | PJ14 | I/O | FT | - | LCD_B2, EVENTOUT | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| A19 | R16 | 1H6 | Y10 | VSS | S | - | - | - | - |
| - | - | - | C7 | PJ15 | I/O | FT | - | LCD_B3, EVENTOUT | - |
| - | - | 1G6 | - | VDDCORE | S | - | - | - | - |
| - | - | - | D8 | PK0 | I/O | FT_h | - | TIM1_CH1N, TIM8_CH3, SPI5_SCK, LCD_G5, EVENTOUT | - |
| - | - | - | E7 | PK1 | I/O | FT_h | - | TRACED4, TIM1_CH1, HDP4, TIM8_CH3N, SPI5_NSS, LCD_G6, EVENTOUT | - |
| - | - | - | E8 | PK2 | I/O | FT_h | - | TRACED5, TIM1_BKIN, HDP5, TIM8_BKIN, LCD_G7, EVENTOUT | - |
| - | R11 | - | - | VDD | S | - | - | - | - |
| - | T4 | - | Y18 | VSS | S | - | - | - | - |
| - | N13 | - | R14 | VDDCORE | S | - | - | - | - |
| - | - | - | B6 | PK3 | I/O | FT | - | LCD_B4, EVENTOUT | - |
| - | - | - | A6 | PK4 | I/O | FT | - | LCD_B5, EVENTOUT | - |
| - | - | - | C6 | PK5 | I/O | FT_h | - | TRACED6, HDP6, LCD_B6, EVENTOUT | - |
| K19 | U3 | 1H8 | Y20 | VSS | S | - | - | - | - |
| - | - | - | A5 | PK6 | I/O | FT_h | - | TRACED7, HDP7, LCD_B7, EVENTOUT | - |
| 1G8 | P12 | - | - | VDDCORE | S | - | - | - | - |
| - | - | - | B5 | PK7 | I/O | FT | - | LCD_DE, EVENTOUT | - |
| C2 | C4 | D6 | C5 | PE0 | I/O | FT_h | - | LPTIM1_ETR, TIM4_ETR, LPTIM2_ETR, SPI3_SCK/I2S3_CK, SAI4_MCLK_B, UART8_RX, SAI2_MCLK_A, FMC_NBL0, DCMI_D2, EVENTOUT | - |
| 1A1 | B1 | C8 | D7 | PE1 | I/O | FT | - | LPTIM1_IN2, I2S2_MCK, SAI3_SD_B, UART8_TX, FMC_NBL1, DCMI_D3, EVENTOUT | - |
| - | U6 | 1J3 | AA4 | VSS | S | - | - | - | - |
| - | - | D5 | D6 | PH8 | I/O | FT_f | - | TIM5_ETR, I2C3_SDA, DCMI_HSYNC, LCD_R2, EVENTOUT | - |
| - | - | 1H7 | T15 | VDDCORE | S | - | - | - | - |
| - | - | C5 | E6 | PH9 | I/O | FT | - | TIM12_CH2, I2C3_SMBA, DCMI_D0, LCD_R3, EVENTOUT | - |

Table 7. STM32MP153C/F pin and ball definitions (continued)

| Pin Number | | | | Pin name (function after reset) | Pin type | I/O structure | Notes | Pin functions | |
|---|---|---|---|---|---|---|---|---|---|
| TFBGA257 | LFBGA354 | TFBGA361 | LFBGA448 | | | | | Alternate functions | Additional functions |
| D2 | C1 | A4 | D5 | PE11 | I/O | FT | - | TIM1_CH2, DFSDM1_CKIN4, SPI4_NSS, USART6_CK, SAI2_SD_B, FMC_AD8/FMC_D8, DCMI_D4, LCD_G3, EVENTOUT | - |
| C1 | D2 | B4 | E4 | PE12 | I/O | FT_h | - | TIM1_CH3N, DFSDM1_DATIN5, SPI4_SCK, SDMMC1_D0DIR, SAI2_SCK_B, FMC_AD9/FMC_D9, LCD_B4, EVENTOUT | - |
| E3 | C2 | A3 | A4 | PE13 | I/O | FT_h | - | HDP2, TIM1_CH3, DFSDM1_CKIN5, SPI4_MISO, SAI2_FS_B, FMC_AD10/FMC_D10, DCMI_D6, LCD_DE, EVENTOUT | - |
| - | R13 | - | - | VDDCORE | S | - | - | - | - |
| - | - | C4 | B3 | PH11 | I/O | FT_f | - | TIM5_CH2, I2C4_SCL, I2C1_SCL, DCMI_D2, LCD_R5, EVENTOUT | - |
| R19 | U8 | - | AA18 | VSS | S | - | - | - | - |
| - | U17 | 1J5 | AB1 | VSS | S | - | - | - | - |
| W19 | W1 | - | AB18 | VSS | S | - | - | - | - |
| - | W19 | 1J7 | AB22 | VSS | S | - | - | - | - |
| 1B2 | D3 | C6 | B4 | PE14 | I/O | FT_h | - | TIM1_CH4, SPI4_MOSI, UART8_RTS/UART8_DE, SAI2_MCLK_B, SDMMC1_D123DIR, FMC_AD11/FMC_D11, LCD_G0, LCD_CLK, EVENTOUT | - |
| D3 | E1 | D3 | C4 | PE15 | I/O | FT | - | HDP3, TIM1_BKIN, TIM15_BKIN, USART2_CTS/USART2_NSS, UART8_CTS, FMC_NCE2, FMC_AD12/FMC_D12, LCD_R7, EVENTOUT | - |
| - | - | B3 | A3 | PH4 | I/O | FT_f | - | I2C2_SCL, LCD_G5, LCD_G4, EVENTOUT | - |

1. IO supplied by VSW domain.

Table 8. Alternate function AF0 to AF7[1]

| Port | | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 |
|---|---|---|---|---|---|---|---|---|---|
| | | HDP/SYS/RTC | TIM1/2/16/17/ LPTIM1/SYS/ RTC | SAI1/4/I2C6/ TIM3/4/5/12/ HDP/SYS | SAI4/I2C2/ TIM8/ LPTIM2/3/4/5/ DFSDM1 /SDMMC1 | SAI4/ I2C1/2/3/4/5/ USART1/ TIM15/LPTIM2/ DFSDM1/CEC | SPI1/I2S1/ SPI2/I2S2/ SPI3/I2S3/ SPI4/5/6/I2C1/ SDMMC1/3/ CEC | SPI3/I2S3/ SAI1/3/4/ I2C4/UART4/ DFSDM1 | SPI2/I2S2/ SPI3/I2S3/ SPI6/ USART1/2/3/6/ UART7/ SDMMC2 |
| Port A | PA0 | - | TIM2_CH1/ TIM2_ETR | TIM5_CH1 | TIM8_ETR | TIM15_BKIN | - | - | USART2_CTS/ USART2_NSS |
| | PA1 | ETH_CLK | TIM2_CH2 | TIM5_CH2 | LPTIM3_OUT | TIM15_CH1N | - | - | USART2_RTS/ USART2_DE |
| | PA2 | - | TIM2_CH3 | TIM5_CH3 | LPTIM4_OUT | TIM15_CH1 | - | - | USART2_TX |
| | PA3 | - | TIM2_CH4 | TIM5_CH4 | LPTIM5_OUT | TIM15_CH2 | - | - | USART2_RX |
| | PA4 | HDP0 | - | TIM5_ETR | - | SAI4_D2 | SPI1_NSS/ I2S1_WS | SPI3_NSS/ I2S3_WS | USART2_CK |
| | PA5 | - | TIM2_CH1/ TIM2_ETR | - | TIM8_CH1N | SAI4_CK1 | SPI1_SCK/I2S1 _CK | - | - |
| | PA6 | - | TIM1_BKIN | TIM3_CH1 | TIM8_BKIN | SAI4_CK2 | SPI1_MISO/ I2S1_SDI | - | - |
| | PA7 | - | TIM1_CH1N | TIM3_CH2 | TIM8_CH1N | SAI4_D1 | SPI1_MOSI/ I2S1_SDO | - | - |
| | PA8 | MCO1 | TIM1_CH1 | - | TIM8_BKIN2 | I2C3_SCL | SPI3_MOSI/ I2S3_SDO | - | USART1_CK |
| | PA9 | - | TIM1_CH2 | - | - | I2C3_SMBA | SPI2_SCK/ I2S2_CK | - | USART1_TX |
| | PA10 | - | TIM1_CH3 | - | - | - | SPI3_NSS/ I2S3_WS | - | USART1_RX |
| | PA11 | - | TIM1_CH4 | I2C6_SCL | - | I2C5_SCL | SPI2_NSS/ I2S2_WS | UART4_RX | USART1_CTS/ USART1_NSS |
| | PA12 | - | TIM1_ETR | I2C6_SDA | - | I2C5_SDA | - | UART4_TX | USART1_RTS/ USART1_DE |

**Table 8. Alternate function AF0 to AF7(1) (continued)**

| Port | | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 |
|---|---|---|---|---|---|---|---|---|---|
| | | HDP/SYS/RTC | TIM1/2/16/17/ LPTIM1/SYS/ RTC | SAI1/4/I2C6/ TIM3/4/5/12/ HDP/SYS | SAI4/I2C2/ TIM8/ LPTIM2/3/4/5/ DFSDM1 /SDMMC1 | SAI4/ I2C1/2/3/4/5/ USART1/ TIM15/LPTIM2/ DFSDM1/CEC | SPI1/I2S1/ SPI2/I2S2/ SPI3/I2S3/ SPI4/5/6/I2C1/ SDMMC1/3/ CEC | SPI3/I2S3/ SAI1/3/4/ I2C4/UART4/ DFSDM1 | SPI2/I2S2/ SPI3/I2S3/ SPI6/ USART1/2/3/6/ UART7/ SDMMC2 |
| Port A | PA13 | DBTRGO | DBTRGI | MCO1 | - | - | - | - | - |
| | PA14 | DBTRGO | DBTRGI | MCO2 | - | - | - | - | - |
| | PA15 | DBTRGI | TIM2_CH1/ TIM2_ETR | SAI4_D2 | SDMMC1_ CDIR | CEC | SPI1_NSS/ I2S1_WS | SPI3_NSS/ I2S3_WS | SPI6_NSS |
| Port B | PB0 | - | TIM1_CH2N | TIM3_CH3 | TIM8_CH2N | - | - | DFSDM1_ CKOUT | - |
| | PB1 | - | TIM1_CH3N | TIM3_CH4 | TIM8_CH3N | - | - | DFSDM1_ DATIN1 | - |
| | PB2 | TRACED4 | RTC_OUT2 | SAI1_D1 | DFSDM1_ CKIN1 | USART1_RX | I2S_CKIN | SAI1_SD_A | SPI3_MOSI/ I2S3_SDO |
| | PB3 | TRACED9 | TIM2_CH2 | - | - | SAI4_CK1 | SPI1_SCK/ I2S1_CK | SPI3_SCK/ I2S3_CK | - |
| | PB4 | TRACED8 | TIM16_BKIN | TIM3_CH1 | - | SAI4_CK2 | SPI1_MISO/ I2S1_SDI | SPI3_MISO/ I2S3_SDI | SPI2_NSS/ I2S2_WS |
| | PB5 | ETH_CLK | TIM17_BKIN | TIM3_CH2 | SAI4_D1 | I2C1_SMBA | SPI1_MOSI/ I2S1_SDO | I2C4_SMBA | SPI3_MOSI/ I2S3_SDO |
| | PB6 | - | TIM16_CH1N | TIM4_CH1 | - | I2C1_SCL | CEC | I2C4_SCL | USART1_TX |
| | PB7 | - | TIM17_CH1N | TIM4_CH2 | - | I2C1_SDA | - | I2C4_SDA | USART1_RX |
| | PB8 | HDP6 | TIM16_CH1 | TIM4_CH3 | DFSDM1_ CKIN7 | I2C1_SCL | SDMMC1_ CKIN | I2C4_SCL | SDMMC2_ CKIN |
| | PB9 | HDP7 | TIM17_CH1 | TIM4_CH4 | DFSDM1_ DATIN7 | I2C1_SDA | SPI2_NSS/ I2S2_WS | I2C4_SDA | SDMMC2_ CDIR |
| | PB10 | - | TIM2_CH3 | - | LPTIM2_IN1 | I2C2_SCL | SPI2_SCK/ I2S2_CK | DFSDM1_ DATIN7 | USART3_TX |

Table 8. Alternate function AF0 to AF7[1] (continued)

| Port | | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 |
|---|---|---|---|---|---|---|---|---|---|
| | | HDP/SYS/RTC | TIM1/2/16/17/ LPTIM1/SYS/ RTC | SAI1/4/I2C6/ TIM3/4/5/12/ HDP/SYS | SAI4/I2C2/ TIM8/ LPTIM2/3/4/5/ DFSDM1 /SDMMC1 | SAI4/ I2C1/2/3/4/5/ USART1/ TIM15/LPTIM2/ DFSDM1/CEC | SPI1/I2S1/ SPI2/I2S2/ SPI3/I2S3/ SPI4/5/6/I2C1/ SDMMC1/3/ CEC | SPI3/I2S3/ SAI1/3/4/ I2C4/UART4/ DFSDM1 | SPI2/I2S2/ SPI3/I2S3/ SPI6/ USART1/2/3/6/ UART7/ SDMMC2 |
| Port B | PB11 | - | TIM2_CH4 | - | LPTIM2_ETR | I2C2_SDA | - | DFSDM1_ CKIN7 | USART3_RX |
| | PB12 | - | TIM1_BKIN | I2C6_SMBA | - | I2C2_SMBA | SPI2_NSS/ I2S2_WS | DFSDM1_ DATIN1 | USART3_CK |
| | PB13 | - | TIM1_CH1N | - | DFSDM1_ CKOUT | LPTIM2_OUT | SPI2_SCK/ I2S2_CK | DFSDM1_ CKIN1 | USART3_CTS/ USART3_NSS |
| | PB14 | - | TIM1_CH2N | TIM12_CH1 | TIM8_CH2N | USART1_TX | SPI2_MISO/ I2S2_SDI | DFSDM1_ DATIN2 | USART3_RTS/ USART3_DE |
| | PB15 | RTC_REFIN | TIM1_CH3N | TIM12_CH2 | TIM8_CH3N | USART1_RX | SPI2_MOSI/ I2S2_SDO | DFSDM1_ CKIN2 | - |
| Port C | PC0 | - | - | - | DFSDM1_ CKIN0 | LPTIM2_IN2 | - | DFSDM1_ DATIN4 | - |
| | PC1 | TRACED0 | - | SAI1_D1 | DFSDM1_ DATIN0 | DFSDM1_ CKIN4 | SPI2_MOSI/ I2S2_SDO | SAI1_SD_A | - |
| | PC2 | - | - | - | DFSDM1_ CKIN1 | - | SPI2_MISO/ I2S2_SDI | DFSDM1_ CKOUT | - |
| | PC3 | TRACECLK | - | - | DFSDM1_ DATIN1 | - | SPI2_MOSI/ I2S2_SDO | - | - |
| | PC4 | - | - | - | DFSDM1_ CKIN2 | - | I2S1_MCK | - | - |
| | PC5 | - | - | SAI1_D3 | DFSDM1_ DATIN2 | SAI4_D4 | - | SAI1_D4 | - |
| | PC6 | HDP1 | - | TIM3_CH1 | TIM8_CH1 | DFSDM1_ CKIN3 | I2S2_MCK | - | USART6_TX |

Table 8. Alternate function AF0 to AF7[1] (continued)

| Port | | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 |
|---|---|---|---|---|---|---|---|---|---|
| | | HDP/SYS/RTC | TIM1/2/16/17/ LPTIM1/SYS/ RTC | SAI1/4/I2C6/ TIM3/4/5/12/ HDP/SYS | SAI4/I2C2/ TIM8/ LPTIM2/3/4/5/ DFSDM1 /SDMMC1 | SAI4/ I2C1/2/3/4/5/ USART1/ TIM15/LPTIM2/ DFSDM1/CEC | SPI1/I2S1/ SPI2/I2S2/ SPI3/I2S3/ SPI4/5/6/I2C1/ SDMMC1/3/ CEC | SPI3/I2S3/ SAI1/3/4/ I2C4/UART4/ DFSDM1 | SPI2/I2S2/ SPI3/I2S3/ SPI6/ USART1/2/3/6/ UART7/ SDMMC2 |
| Port C | PC7 | HDP4 | - | TIM3_CH2 | TIM8_CH2 | DFSDM1_ DATIN3 | - | I2S3_MCK | USART6_RX |
| | PC8 | TRACED0 | - | TIM3_CH3 | TIM8_CH3 | - | - | UART4_TX | USART6_CK |
| | PC9 | TRACED1 | - | TIM3_CH4 | TIM8_CH4 | I2C3_SDA | I2S_CKIN | - | - |
| | PC10 | TRACED2 | - | - | DFSDM1_ CKIN5 | - | - | SPI3_SCK/ I2S3_CK | USART3_TX |
| | PC11 | TRACED3 | - | - | DFSDM1_ DATIN5 | - | - | SPI3_MISO/ I2S3_SDI | USART3_RX |
| | PC12 | TRACECLK | MCO2 | SAI4_D3 | - | - | - | SPI3_MOSI/ I2S3_SDO | USART3_CK |
| | PC13 | - | - | - | - | - | - | - | - |
| | PC14 | - | - | - | - | - | - | - | - |
| | PC15 | - | - | - | - | - | - | - | - |
| Port D | PD0 | - | - | I2C6_SDA | DFSDM1_ CKIN6 | I2C5_SDA | - | SAI3_SCK_A | - |
| | PD1 | - | - | I2C6_SCL | DFSDM1_ DATIN6 | I2C5_SCL | - | SAI3_SD_A | - |
| | PD2 | - | - | TIM3_ETR | - | I2C5_SMBA | - | UART4_RX | - |
| | PD3 | HDP5 | - | - | DFSDM1_ CKOUT | - | SPI2_SCK/ I2S2_CK | DFSDM1_ DATIN0 | USART2_CTS/ USART2_NSS |
| | PD4 | - | - | - | - | - | - | SAI3_FS_A | USART2_RTS/ USART2_DE |
| | PD5 | - | - | - | - | - | - | - | USART2_TX |

Table 8. Alternate function AF0 to AF7[1] (continued)

| Port | | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 |
|---|---|---|---|---|---|---|---|---|---|
| | | HDP/SYS/RTC | TIM1/2/16/17/ LPTIM1/SYS/ RTC | SAI1/4/I2C6/ TIM3/4/5/12/ HDP/SYS | SAI4/I2C2/ TIM8/ LPTIM2/3/4/5/ DFSDM1 /SDMMC1 | SAI4/ I2C1/2/3/4/5/ USART1/ TIM15/LPTIM2/ DFSDM1/CEC | SPI1/I2S1/ SPI2/I2S2/ SPI3/I2S3/ SPI4/5/6/I2C1/ SDMMC1/3/ CEC | SPI3/I2S3/ SAI1/3/4/ I2C4/UART4/ DFSDM1 | SPI2/I2S2/ SPI3/I2S3/ SPI6/ USART1/2/3/6/ UART7/ SDMMC2 |
| Port D | PD6 | - | TIM16_CH1N | SAI1_D1 | DFSDM1_ CKIN4 | DFSDM1_ DATIN1 | SPI3_MOSI/ I2S3_SDO | SAI1_SD_A | USART2_RX |
| | PD7 | TRACED6 | - | - | DFSDM1_ DATIN4 | I2C2_SCL | - | DFSDM1_ CKIN1 | USART2_CK |
| | PD8 | - | - | - | DFSDM1_ CKIN3 | - | - | SAI3_SCK_B | USART3_TX |
| | PD9 | - | - | - | DFSDM1_ DATIN3 | - | - | SAI3_SD_B | USART3_RX |
| | PD10 | RTC_REFIN | TIM16_BKIN | - | DFSDM1_ CKOUT | I2C5_SMBA | SPI3_MISO/ I2S3_SDI | SAI3_FS_B | USART3_CK |
| | PD11 | - | - | - | LPTIM2_IN2 | I2C4_SMBA | I2C1_SMBA | - | USART3_CTS/ USART3_NSS |
| | PD12 | - | LPTIM1_IN1 | TIM4_CH1 | LPTIM2_IN1 | I2C4_SCL | I2C1_SCL | - | USART3_RTS/ USART3_DE |
| | PD13 | - | LPTIM1_OUT | TIM4_CH2 | - | I2C4_SDA | I2C1_SDA | I2S3_MCK | - |
| | PD14 | - | - | TIM4_CH3 | - | - | - | SAI3_MCLK_B | - |
| | PD15 | - | - | TIM4_CH4 | - | - | - | SAI3_MCLK_A | - |
| Port E | PE0 | - | LPTIM1_ETR | TIM4_ETR | - | LPTIM2_ETR | SPI3_SCK/ I2S3_CK | SAI4_MCLK_B | - |
| | PE1 | - | LPTIM1_IN2 | - | - | - | I2S2_MCK | SAI3_SD_B | - |
| | PE2 | TRACECLK | - | SAI1_CK1 | - | I2C4_SCL | SPI4_SCK | SAI1_MCLK_A | - |
| | PE3 | TRACED0 | - | - | - | TIM15_BKIN | - | SAI1_SD_B | - |

Table 8. Alternate function AF0 to AF7[1] (continued)

| Port | | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 |
|---|---|---|---|---|---|---|---|---|---|
| | | HDP/SYS/RTC | TIM1/2/16/17/ LPTIM1/SYS/ RTC | SAI1/4/I2C6/ TIM3/4/5/12/ HDP/SYS | SAI4/I2C2/ TIM8/ LPTIM2/3/4/5/ DFSDM1 /SDMMC1 | SAI4/ I2C1/2/3/4/5/ USART1/ TIM15/LPTIM2/ DFSDM1/CEC | SPI1/I2S1/ SPI2/I2S2/ SPI3/I2S3/ SPI4/5/6/I2C1/ SDMMC1/3/ CEC | SPI3/I2S3/ SAI1/3/4/ I2C4/UART4/ DFSDM1 | SPI2/I2S2/ SPI3/I2S3/ SPI6/ USART1/2/3/6/ UART7/ SDMMC2 |
| Port E | PE4 | TRACED1 | - | SAI1_D2 | DFSDM1_ DATIN3 | TIM15_CH1N | SPI4_NSS | SAI1_FS_A | SDMMC2_ CKIN |
| | PE5 | TRACED3 | - | SAI1_CK2 | DFSDM1_ CKIN3 | TIM15_CH1 | SPI4_MISO | SAI1_SCK_A | SDMMC2_ D0DIR |
| | PE6 | TRACED2 | TIM1_BKIN2 | SAI1_D1 | - | TIM15_CH2 | SPI4_MOSI | SAI1_SD_A | SDMMC2_D0 |
| | PE7 | - | TIM1_ETR | TIM3_ETR | DFSDM1_ DATIN2 | - | - | - | UART7_RX |
| | PE8 | - | TIM1_CH1N | - | DFSDM1_ CKIN2 | - | - | - | UART7_TX |
| | PE9 | - | TIM1_CH1 | - | DFSDM1_ CKOUT | - | - | - | UART7_RTS/ UART7_DE |
| | PE10 | - | TIM1_CH2N | - | DFSDM1_ DATIN4 | - | - | - | UART7_CTS |
| | PE11 | - | TIM1_CH2 | - | DFSDM1_ CKIN4 | - | SPI4_NSS | - | USART6_CK |
| | PE12 | - | TIM1_CH3N | - | DFSDM1_ DATIN5 | - | SPI4_SCK | - | - |
| | PE13 | HDP2 | TIM1_CH3 | - | DFSDM1_ CKIN5 | - | SPI4_MISO | - | - |
| | PE14 | - | TIM1_CH4 | - | - | - | SPI4_MOSI | - | - |
| | PE15 | HDP3 | TIM1_BKIN | - | - | TIM15_BKIN | - | - | USART2_CTS/ USART2_NSS |
| Port F | PF0 | - | - | - | - | I2C2_SDA | - | - | - |
| | PF1 | - | - | - | - | I2C2_SCL | - | - | - |

Table 8. Alternate function AF0 to AF7[1] (continued)

| Port | | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 |
|---|---|---|---|---|---|---|---|---|---|
| | | HDP/SYS/RTC | TIM1/2/16/17/ LPTIM1/SYS/ RTC | SAI1/4/I2C6/ TIM3/4/5/12/ HDP/SYS | SAI4/I2C2/ TIM8/ LPTIM2/3/4/5/ DFSDM1 /SDMMC1 | SAI4/ I2C1/2/3/4/5/ USART1/ TIM15/LPTIM2/ DFSDM1/CEC | SPI1/I2S1/ SPI2/I2S2/ SPI3/I2S3/ SPI4/5/6/I2C1/ SDMMC1/3/ CEC | SPI3/I2S3/ SAI1/3/4/ I2C4/UART4/ DFSDM1 | SPI2/I2S2/ SPI3/I2S3/ SPI6/ USART1/2/3/6/ UART7/ SDMMC2 |
| Port F | PF2 | - | - | - | - | I2C2_SMBA | - | - | - |
| | PF3 | - | - | - | - | - | - | - | - |
| | PF4 | - | - | - | - | - | - | - | USART2_RX |
| | PF5 | - | - | - | - | - | - | - | USART2_TX |
| | PF6 | - | TIM16_CH1 | - | - | - | SPI5_NSS | SAI1_SD_B | UART7_RX |
| | PF7 | - | TIM17_CH1 | - | - | - | SPI5_SCK | SAI1_MCLK_B | UART7_TX |
| | PF8 | TRACED12 | TIM16_CH1N | - | - | - | SPI5_MISO | SAI1_SCK_B | UART7_RTS/ UART7_DE |
| | PF9 | TRACED13 | TIM17_CH1N | - | - | - | SPI5_MOSI | SAI1_FS_B | UART7_CTS |
| | PF10 | - | TIM16_BKIN | SAI1_D3 | SAI4_D4 | - | - | SAI1_D4 | - |
| | PF11 | - | - | - | - | - | SPI5_MOSI | - | - |
| | PF12 | TRACED4 | - | - | - | - | - | - | - |
| | PF13 | TRACED5 | - | - | DFSDM1_ DATIN6 | I2C4_SMBA | I2C1_SMBA | DFSDM1_ DATIN3 | - |
| | PF14 | TRACED6 | - | - | DFSDM1_ CKIN6 | I2C4_SCL | I2C1_SCL | - | - |
| | PF15 | TRACED7 | - | - | - | I2C4_SDA | I2C1_SDA | - | - |
| Port G | PG0 | TRACED0 | - | - | DFSDM1_ DATIN0 | - | - | - | - |
| | PG1 | TRACED1 | - | - | - | - | - | - | - |
| | PG2 | TRACED2 | MCO2 | - | TIM8_BKIN | - | - | - | - |

Table 8. Alternate function AF0 to AF7[1] (continued)

| Port | | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 |
|---|---|---|---|---|---|---|---|---|---|
| | | HDP/SYS/RTC | TIM1/2/16/17/ LPTIM1/SYS/ RTC | SAI1/4/I2C6/ TIM3/4/5/12/ HDP/SYS | SAI4/I2C2/ TIM8/ LPTIM2/3/4/5/ DFSDM1 /SDMMC1 | SAI4/ I2C1/2/3/4/5/ USART1/ TIM15/LPTIM2/ DFSDM1/CEC | SPI1/I2S1/ SPI2/I2S2/ SPI3/I2S3/ SPI4/5/6/I2C1/ SDMMC1/3/ CEC | SPI3/I2S3/ SAI1/3/4/ I2C4/UART4/ DFSDM1 | SPI2/I2S2/ SPI3/I2S3/ SPI6/ USART1/2/3/6/ UART7/ SDMMC2 |
| Port G | PG3 | TRACED3 | - | - | TIM8_BKIN2 | DFSDM1_ CKIN1 | - | - | - |
| | PG4 | - | TIM1_BKIN2 | - | - | - | - | - | - |
| | PG5 | - | TIM1_ETR | - | - | - | - | - | - |
| | PG6 | TRACED14 | TIM17_BKIN | - | - | - | - | - | - |
| | PG7 | TRACED5 | - | - | - | - | - | SAI1_MCLK_A | USART6_CK |
| | PG8 | TRACED15 | TIM2_CH1/ TIM2_ETR | ETH_CLK | TIM8_ETR | - | SPI6_NSS | SAI4_D2 | USART6_RTS/ USART6_DE |
| | PG9 | DBTRGO | - | - | - | - | - | - | USART6_RX |
| | PG10 | TRACED10 | - | - | - | - | - | - | - |
| | PG11 | TRACED11 | - | - | - | USART1_TX | - | UART4_TX | - |
| | PG12 | - | LPTIM1_IN1 | - | - | - | SPI6_MISO | SAI4_CK2 | USART6_RTS/ USART6_DE |
| | PG13 | TRACED0 | LPTIM1_OUT | SAI1_CK2 | - | SAI4_CK1 | SPI6_SCK | SAI1_SCK_A | USART6_CTS/ USART6_NSS |
| | PG14 | TRACED1 | LPTIM1_ETR | - | - | - | SPI6_MOSI | SAI4_D1 | USART6_TX |
| | PG15 | TRACED7 | - | SAI1_D2 | - | I2C2_SDA | - | SAI1_FS_A | USART6_CTS/ USART6_NSS |
| Port H | PH0 | - | - | - | - | - | - | - | - |
| | PH1 | - | - | - | - | - | - | - | - |
| | PH2 | - | LPTIM1_IN2 | - | - | - | - | - | - |

Table 8. Alternate function AF0 to AF7[1] (continued)

| Port | | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 |
|---|---|---|---|---|---|---|---|---|---|
| | | HDP/SYS/RTC | TIM1/2/16/17/ LPTIM1/SYS/ RTC | SAI1/4/I2C6/ TIM3/4/5/12/ HDP/SYS | SAI4/I2C2/ TIM8/ LPTIM2/3/4/5/ DFSDM1 /SDMMC1 | SAI4/ I2C1/2/3/4/5/ USART1/ TIM15/LPTIM2/ DFSDM1/CEC | SPI1/I2S1/ SPI2/I2S2/ SPI3/I2S3/ SPI4/5/6/I2C1/ SDMMC1/3/ CEC | SPI3/I2S3/ SAI1/3/4/ I2C4/UART4/ DFSDM1 | SPI2/I2S2/ SPI3/I2S3/ SPI6/ USART1/2/3/6/ UART7/ SDMMC2 |
| Port H | PH3 | - | - | - | DFSDM1_ CKIN4 | - | - | - | - |
| | PH4 | - | - | - | - | I2C2_SCL | - | - | - |
| | PH5 | - | - | - | - | I2C2_SDA | SPI5_NSS | - | - |
| | PH6 | - | - | TIM12_CH1 | - | I2C2_SMBA | SPI5_SCK | - | - |
| | PH7 | - | - | - | - | I2C3_SCL | SPI5_MISO | - | - |
| | PH8 | - | - | TIM5_ETR | - | I2C3_SDA | - | - | - |
| | PH9 | - | - | TIM12_CH2 | - | I2C3_SMBA | - | - | - |
| | PH10 | - | - | TIM5_CH1 | - | I2C4_SMBA | I2C1_SMBA | - | - |
| | PH11 | - | - | TIM5_CH2 | - | I2C4_SCL | I2C1_SCL | - | - |
| | PH12 | HDP2 | - | TIM5_CH3 | - | I2C4_SDA | I2C1_SDA | - | - |
| | PH13 | - | - | - | TIM8_CH1N | - | - | - | - |
| | PH14 | - | - | - | TIM8_CH2N | - | - | - | - |
| | PH15 | - | - | - | TIM8_CH3N | - | - | - | - |
| Port I | PI0 | - | - | TIM5_CH4 | - | - | SPI2_NSS/ I2S2_WS | - | - |
| | PI1 | - | - | - | TIM8_BKIN2 | - | SPI2_SCK/ I2S2_CK | - | - |
| | PI2 | - | - | - | TIM8_CH4 | - | SPI2_MISO/ I2S2_SDI | - | - |
| | PI3 | - | - | - | TIM8_ETR | - | SPI2_MOSI/ I2S2_SDO | - | - |

Table 8. Alternate function AF0 to AF7[1] (continued)

| Port | | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 |
|---|---|---|---|---|---|---|---|---|---|
| | | HDP/SYS/RTC | TIM1/2/16/17/ LPTIM1/SYS/ RTC | SAI1/4/I2C6/ TIM3/4/5/12/ HDP/SYS | SAI4/I2C2/ TIM8/ LPTIM2/3/4/5/ DFSDM1 /SDMMC1 | SAI4/ I2C1/2/3/4/5/ USART1/ TIM15/LPTIM2/ DFSDM1/CEC | SPI1/I2S1/ SPI2/I2S2/ SPI3/I2S3/ SPI4/5/6/I2C1/ SDMMC1/3/ CEC | SPI3/I2S3/ SAI1/3/4/ I2C4/UART4/ DFSDM1 | SPI2/I2S2/ SPI3/I2S3/ SPI6/ USART1/2/3/6/ UART7/ SDMMC2 |
| Port I | PI4 | - | - | - | TIM8_BKIN | - | - | - | - |
| | PI5 | - | - | - | TIM8_CH1 | - | - | - | - |
| | PI6 | - | - | - | TIM8_CH2 | - | - | - | - |
| | PI7 | - | - | - | TIM8_CH3 | - | - | - | - |
| | PI8 | - | - | - | - | - | - | - | - |
| | PI9 | HDP1 | - | - | - | - | - | - | - |
| | PI10 | HDP0 | - | - | - | - | - | - | - |
| | PI11 | MCO1 | - | - | - | - | I2S_CKIN | - | - |
| | PI12 | TRACED0 | - | HDP0 | - | - | - | - | - |
| | PI13 | TRACED1 | - | HDP1 | - | - | - | - | - |
| | PI14 | TRACECLK | - | - | - | - | - | - | - |
| | PI15 | - | - | - | - | - | - | - | - |
| Port J | PJ0 | TRACED8 | - | - | - | - | - | - | - |
| | PJ1 | TRACED9 | - | - | - | - | - | - | - |
| | PJ2 | TRACED10 | - | - | - | - | - | - | - |
| | PJ3 | TRACED11 | - | - | - | - | - | - | - |
| | PJ4 | TRACED12 | - | - | - | - | - | - | - |
| | PJ5 | TRACED2 | - | HDP2 | - | - | - | - | - |
| | PJ6 | TRACED3 | - | HDP3 | TIM8_CH2 | - | - | - | - |
| | PJ7 | TRACED13 | - | - | TIM8_CH2N | - | - | - | - |

Table 8. Alternate function AF0 to AF7[1] (continued)

| Port | | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 |
|---|---|---|---|---|---|---|---|---|---|
| | | HDP/SYS/RTC | TIM1/2/16/17/ LPTIM1/SYS/ RTC | SAI1/4/I2C6/ TIM3/4/5/12/ HDP/SYS | SAI4/I2C2/ TIM8/ LPTIM2/3/4/5/ DFSDM1 /SDMMC1 | SAI4/ I2C1/2/3/4/5/ USART1/ TIM15/LPTIM2/ DFSDM1/CEC | SPI1/I2S1/ SPI2/I2S2/ SPI3/I2S3/ SPI4/5/6/I2C1/ SDMMC1/3/ CEC | SPI3/I2S3/ SAI1/3/4/ I2C4/UART4/ DFSDM1 | SPI2/I2S2/ SPI3/I2S3/ SPI6/ USART1/2/3/6/ UART7/ SDMMC2 |
| Port J | PJ8 | TRACED14 | TIM1_CH3N | - | TIM8_CH1 | - | - | - | - |
| | PJ9 | TRACED15 | TIM1_CH3 | - | TIM8_CH1N | - | - | - | - |
| | PJ10 | - | TIM1_CH2N | - | TIM8_CH2 | - | SPI5_MOSI | - | - |
| | PJ11 | - | TIM1_CH2 | - | TIM8_CH2N | - | SPI5_MISO | - | - |
| | PJ12 | - | - | - | - | - | - | - | - |
| | PJ13 | - | - | - | - | - | - | - | - |
| | PJ14 | - | - | - | - | - | - | - | - |
| | PJ15 | - | - | - | - | - | - | - | - |
| Port K | PK0 | - | TIM1_CH1N | - | TIM8_CH3 | - | SPI5_SCK | - | - |
| | PK1 | TRACED4 | TIM1_CH1 | HDP4 | TIM8_CH3N | - | SPI5_NSS | - | - |
| | PK2 | TRACED5 | TIM1_BKIN | HDP5 | TIM8_BKIN | - | - | - | - |
| | PK3 | - | - | - | - | - | - | - | - |
| | PK4 | - | - | - | - | - | - | - | - |
| | PK5 | TRACED6 | - | HDP6 | - | - | - | - | - |
| | PK6 | TRACED7 | - | HDP7 | - | - | - | - | - |
| | PK7 | - | - | - | - | - | - | - | - |
| Port Z | PZ0 | - | - | I2C6_SCL | I2C2_SCL | - | SPI1_SCK/ I2S1_CK | - | USART1_CK |
| | PZ1 | - | - | I2C6_SDA | I2C2_SDA | I2C5_SDA | SPI1_MISO/ I2S1_SDI | I2C4_SDA | USART1_RX |

Table 8. Alternate function AF0 to AF7[1] (continued)

| Port | | AF0 | AF1 | AF2 | AF3 | AF4 | AF5 | AF6 | AF7 |
|---|---|---|---|---|---|---|---|---|---|
| | | HDP/SYS/RTC | TIM1/2/16/17/ LPTIM1/SYS/ RTC | SAI1/4/I2C6/ TIM3/4/5/12/ HDP/SYS | SAI4/I2C2/ TIM8/ LPTIM2/3/4/5/ DFSDM1 /SDMMC1 | SAI4/ I2C1/2/3/4/5/ USART1/ TIM15/LPTIM2/ DFSDM1/CEC | SPI1/I2S1/ SPI2/I2S2/ SPI3/I2S3/ SPI4/5/6/I2C1/ SDMMC1/3/ CEC | SPI3/I2S3/ SAI1/3/4/ I2C4/UART4/ DFSDM1 | SPI2/I2S2/ SPI3/I2S3/ SPI6/ USART1/2/3/6/ UART7/ SDMMC2 |
| Port Z | PZ2 | - | - | I2C6_SCL | I2C2_SCL | I2C5_SMBA | SPI1_MOSI/ I2S1_SDO | I2C4_SMBA | USART1_TX |
| | PZ3 | - | - | I2C6_SDA | I2C2_SDA | I2C5_SDA | SPI1_NSS/ I2S1_WS | I2C4_SDA | USART1_CTS/ USART1_NSS |
| | PZ4 | - | - | I2C6_SCL | I2C2_SCL | I2C5_SCL | - | I2C4_SCL | - |
| | PZ5 | - | - | I2C6_SDA | I2C2_SDA | I2C5_SDA | - | I2C4_SDA | USART1_RTS/ USART1_DE |
| | PZ6 | - | - | I2C6_SCL | I2C2_SCL | USART1_CK | I2S1_MCK | I2C4_SMBA | USART1_RX |
| | PZ7 | - | - | I2C6_SDA | I2C2_SDA | - | - | - | USART1_TX |

1. Refer to *Table 9* for AF8 to AF15.

Table 9. Alternate function AF8 to AF15[1]

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port A | PA0 | UART4_TX | SDMMC2_CMD | SAI2_SD_B | ETH1_GMII_ CRS/ ETH1_MII_CRS | - | - | - | EVENTOUT |
| | PA1 | UART4_RX | QUADSPI_ BK1_IO3 | SAI2_MCLK_B | ETH1_GMII_RX _CLK/ ETH1_MII_RX_ CLK/ ETH1_RGMII_ RX_CLK/ ETH1_RMII_ REF_CLK | - | - | LCD_R2 | EVENTOUT |
| | PA2 | SAI2_SCK_B | - | SDMMC2_ D0DIR | ETH1_MDIO | MDIOS_MDIO | - | LCD_R1 | EVENTOUT |
| | PA3 | - | LCD_B2 | - | ETH1_GMII_ COL/ ETH1_MII_COL | - | - | LCD_B5 | EVENTOUT |
| | PA4 | SPI6_NSS | - | - | - | SAI4_FS_A | DCMI_HSYNC | LCD_VSYNC | EVENTOUT |
| | PA5 | SPI6_SCK | - | - | - | SAI4_MCLK_A | - | LCD_R4 | EVENTOUT |
| | PA6 | SPI6_MISO | TIM13_CH1 | - | MDIOS_MDC | SAI4_SCK_A | DCMI_PIXCLK | LCD_G2 | EVENTOUT |
| | PA7 | SPI6_MOSI | TIM14_CH1 | QUADSPI_CLK | ETH1_GMII_RX _DV/ ETH1_MII_RX_ DV/ ETH1_RGMII_ RX_CTL/ ETH1_RMII_ CRS_DV | SAI4_SD_A | - | - | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port A | PA8 | SDMMC2_ CKIN | SDMMC2_D4 | OTG_FS_SOF/ OTG_HS_SOF | - | SAI4_SD_B | UART7_RX | LCD_R6 | EVENTOUT |
| | PA9 | SDMMC2_ CDIR | - | SDMMC2_D5 | - | - | DCMI_D0 | LCD_R5 | EVENTOUT |
| | PA10 | - | - | - | MDIOS_MDIO | SAI4_FS_B | DCMI_D1 | LCD_B1 | EVENTOUT |
| | PA11 | - | FDCAN1_RX | - | - | - | - | LCD_R4 | EVENTOUT |
| | PA12 | SAI2_FS_B | FDCAN1_TX | - | - | - | - | LCD_R5 | EVENTOUT |
| | PA13 | UART4_TX | - | - | - | - | - | - | EVENTOUT |
| | PA14 | - | - | - | - | - | - | - | EVENTOUT |
| | PA15 | UART4_RTS/ UART4_DE | SDMMC2_D5 | SDMMC2_ CDIR | SDMMC1_D5 | SAI4_FS_A | UART7_TX | LCD_R1 | EVENTOUT |
| Port B | PB0 | UART4_CTS | LCD_R3 | - | ETH1_GMII_ RXD2/ ETH1_MII_ RXD2/ ETH1_RGMII_ RXD2 | MDIOS_MDIO | - | LCD_G1 | EVENTOUT |
| | PB1 | - | LCD_R6 | - | ETH1_GMII_ RXD3/ ETH1_MII_ RXD3/ ETH1_RGMII_ RXD3 | MDIOS_MDC | - | LCD_G0 | EVENTOUT |
| | PB2 | UART4_RX | QUADSPI_CLK | - | - | - | - | - | EVENTOUT |
| | PB3 | SPI6_SCK | SDMMC2_D2 | - | - | SAI4_MCLK_A | UART7_RX | - | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port B | PB4 | SPI6_MISO | SDMMC2_D3 | - | - | SAI4_SCK_A | UART7_TX | - | EVENTOUT |
| | PB5 | SPI6_MOSI | FDCAN2_RX | SAI4_SD_A | ETH1_PPS_ OUT | UART5_RX | DCMI_D10 | LCD_G7 | EVENTOUT |
| | PB6 | - | FDCAN2_TX | QUADSPI_BK1 _NCS | DFSDM1_ DATIN5 | UART5_TX | DCMI_D5 | - | EVENTOUT |
| | PB7 | - | - | SDMMC2_D1 | DFSDM1_ CKIN5 | FMC_NL | DCMI_VSYNC | - | EVENTOUT |
| | PB8 | UART4_RX | FDCAN1_RX | SDMMC2_D4 | ETH1_GMII_ TXD3/ ETH1_MII_ TXD3/ ETH1_RGMII_ TXD3 | SDMMC1_D4 | DCMI_D6 | LCD_B6 | EVENTOUT |
| | PB9 | UART4_TX | FDCAN1_TX | SDMMC2_D5 | SDMMC1_CDI R | SDMMC1_D5 | DCMI_D7 | LCD_B7 | EVENTOUT |
| | PB10 | - | QUADSPI_ BK1_NCS | - | ETH1_GMII_ RX_ER/ ETH1_MII_ RX_ER | - | - | LCD_G4 | EVENTOUT |
| | PB11 | - | - | - | ETH1_GMII_ TX_EN/ ETH1_MII_ TX_EN/ ETH1_RGMII_ TX_CTL/ ETH1_RMII_ TX_EN | - | - | LCD_G5 | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port B | PB12 | USART3_RX | FDCAN2_RX | - | ETH1_GMII_ TXD0/ ETH1_MII_ TXD0/ ETH1_RGMII_ TXD0/ ETH1_RMII_ TXD0 | - | - | UART5_RX | EVENTOUT |
| | PB13 | - | FDCAN2_TX | - | ETH1_GMII_ TXD1/ ETH1_MII_ TXD1/ ETH1_RGMII_ TXD1/ ETH1_RMII_ TXD1 | - | - | UART5_TX | EVENTOUT |
| | PB14 | - | SDMMC2_D0 | - | - | - | - | - | EVENTOUT |
| | PB15 | - | SDMMC2_D1 | - | - | - | - | - | EVENTOUT |
| Port C | PC0 | SAI2_FS_B | - | QUADSPI_BK2 _NCS | - | - | - | LCD_R5 | EVENTOUT |
| | PC1 | - | SDMMC2_CK | - | ETH1_MDC | MDIOS_MDC | - | - | EVENTOUT |
| | PC2 | - | - | - | ETH1_GMII_ TXD2/ ETH1_MII_ TXD2/ ETH1_RGMII_ TXD2 | - | DCMI_PIXCLK | - | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port C | PC3 | - | - | - | ETH1_GMII_ TX_CLK/ ETH1_MII_ TX_CLK | - | - | - | EVENTOUT |
| | PC4 | - | SPDIFRX_IN3 | - | ETH1_GMII_ RXD0/ ETH1_MII_ RXD0/ ETH1_RGMII_ RXD0/ ETH1_RMII_ RXD0 | - | - | - | EVENTOUT |
| | PC5 | - | SPDIFRX_IN4 | - | ETH1_GMII_ RXD1/ ETH1_MII_ RXD1/ ETH1_RGMII_ RXD1/ ETH1_RMII_ RXD1 | SAI4_D3 | - | - | EVENTOUT |
| | PC6 | SDMMC1_ D0DIR | SDMMC2_ D0DIR | SDMMC2_D6 | - | SDMMC1_D6 | DCMI_D0 | LCD_HSYNC | EVENTOUT |
| | PC7 | SDMMC1_ D123DIR | SDMMC2_ D123DIR | SDMMC2_D7 | - | SDMMC1_D7 | DCMI_D1 | LCD_G6 | EVENTOUT |
| | PC8 | UART5_RTS/ UART5_DE | - | - | - | SDMMC1_D0 | DCMI_D2 | - | EVENTOUT |
| | PC9 | UART5_CTS | QUADSPI_BK1 _IO0 | - | - | SDMMC1_D1 | DCMI_D3 | LCD_B2 | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port C | PC10 | UART4_TX | QUADSPI_ BK1_IO1 | SAI4_MCLK_B | - | SDMMC1_D2 | DCMI_D8 | LCD_R2 | EVENTOUT |
| | PC11 | UART4_RX | QUADSPI_ BK2_NCS | SAI4_SCK_B | - | SDMMC1_D3 | DCMI_D4 | - | EVENTOUT |
| | PC12 | UART5_TX | - | SAI4_SD_B | - | SDMMC1_CK | DCMI_D9 | - | EVENTOUT |
| | PC13 | - | - | - | - | - | - | - | EVENTOUT |
| | PC14 | - | - | - | - | - | - | - | EVENTOUT |
| | PC15 | - | - | - | - | - | - | - | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port D | PD0 | UART4_RX | FDCAN1_RX | SDMMC3_CMD | DFSDM1_ DATIN7 | FMC_AD2/ FMC_D2 | - | - | EVENTOUT |
| | PD1 | UART4_TX | FDCAN1_TX | SDMMC3_D0 | DFSDM1_ CKIN7 | FMC_AD3/ FMC_D3 | - | - | EVENTOUT |
| | PD2 | UART5_RX | - | - | - | SDMMC1_CMD | DCMI_D11 | - | EVENTOUT |
| | PD3 | SDMMC1_ D123DIR | SDMMC2_D7 | SDMMC2_ D123DIR | SDMMC1_D7 | FMC_CLK | DCMI_D5 | LCD_G7 | EVENTOUT |
| | PD4 | - | - | SDMMC3_D1 | DFSDM1_ CKIN0 | FMC_NOE | - | - | EVENTOUT |
| | PD5 | - | - | SDMMC3_D2 | - | FMC_NWE | - | - | EVENTOUT |
| | PD6 | - | - | - | - | FMC_NWAIT | DCMI_D10 | LCD_B2 | EVENTOUT |
| | PD7 | - | SPDIFRX_IN1 | SDMMC3_D3 | - | FMC_NE1 | - | - | EVENTOUT |
| | PD8 | - | SPDIFRX_IN2 | - | - | FMC_AD13/ FMC_D13 | - | LCD_B7 | EVENTOUT |
| | PD9 | - | - | - | - | FMC_AD14/ FMC_D14 | DCMI_HSYNC | LCD_B0 | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port D | PD10 | - | - | - | - | FMC_AD15/ FMC_D15 | - | LCD_B3 | EVENTOUT |
| | PD11 | - | QUADSPI_ BK1_IO0 | SAI2_SD_A | - | FMC_A16/ FMC_CLE | - | - | EVENTOUT |
| | PD12 | - | QUADSPI_ BK1_IO1 | SAI2_FS_A | - | FMC_A17/FMC _ALE | - | - | EVENTOUT |
| | PD13 | - | QUADSPI_ BK1_IO3 | SAI2_SCK_A | - | FMC_A18 | - | - | EVENTOUT |
| | PD14 | UART8_CTS | - | - | - | FMC_AD0/ FMC_D0 | - | - | EVENTOUT |
| | PD15 | UART8_CTS | - | - | - | FMC_AD1/ FMC_D1 | - | LCD_R1 | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port E | PE0 | UART8_RX | - | SAI2_MCLK_A | - | FMC_NBL0 | DCMI_D2 | - | EVENTOUT |
| | PE1 | UART8_TX | - | - | - | FMC_NBL1 | DCMI_D3 | - | EVENTOUT |
| | PE2 | - | QUADSPI_ BK1_IO2 | - | ETH1_GMII_ TXD3/ ETH1_MII_ TXD3/ ETH1_RGMII_ TXD3 | FMC_A23 | - | - | EVENTOUT |
| | PE3 | - | SDMMC2_CK | - | - | FMC_A19 | - | - | EVENTOUT |
| | PE4 | SDMMC1_ CKIN | SDMMC2_D4 | - | SDMMC1_D4 | FMC_A20 | DCMI_D4 | LCD_B0 | EVENTOUT |
| | PE5 | SDMMC1_ D0DIR | SDMMC2_D6 | - | SDMMC1_D6 | FMC_A21 | DCMI_D6 | LCD_G0 | EVENTOUT |
| | PE6 | SDMMC1_D2 | - | SAI2_MCLK_B | - | FMC_A22 | DCMI_D7 | LCD_G1 | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port E | PE7 | - | - | QUADSPI_ BK2_IO0 | - | FMC_AD4/ FMC_D4 | - | - | EVENTOUT |
| | PE8 | - | - | QUADSPI_ BK2_IO1 | - | FMC_AD5/ FMC_D5 | - | - | EVENTOUT |
| | PE9 | - | - | QUADSPI_ BK2_IO2 | - | FMC_AD6/ FMC_D6 | - | - | EVENTOUT |
| | PE10 | - | - | QUADSPI_ BK2_IO3 | - | FMC_AD7/ FMC_D7 | - | - | EVENTOUT |
| | PE11 | - | - | SAI2_SD_B | - | FMC_AD8/ FMC_D8 | DCMI_D4 | LCD_G3 | EVENTOUT |
| | PE12 | SDMMC1_ D0DIR | - | SAI2_SCK_B | - | FMC_AD9/ FMC_D9 | - | LCD_B4 | EVENTOUT |
| | PE13 | - | - | SAI2_FS_B | - | FMC_AD10/ FMC_D10 | DCMI_D6 | LCD_DE | EVENTOUT |
| | PE14 | UART8_RTS/ UART8_DE | - | SAI2_MCLK_B | SDMMC1_ D123DIR | FMC_AD11/ FMC_D11 | LCD_G0 | LCD_CLK | EVENTOUT |
| | PE15 | UART8_CTS | - | FMC_NCE2 | - | FMC_AD12/ FMC_D12 | - | LCD_R7 | EVENTOUT |
| Port F | PF0 | - | SDMMC3_D0 | SDMMC3_ CKIN | - | FMC_A0 | - | - | EVENTOUT |
| | PF1 | - | SDMMC3_CMD | SDMMC3_ CDIR | - | FMC_A1 | - | - | EVENTOUT |
| | PF2 | - | SDMMC2_ D0DIR | SDMMC3_ D0DIR | SDMMC1_ D0DIR | FMC_A2 | - | - | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port F | PF3 | - | - | - | ETH1_GMII_ TX_ER | FMC_A3 | - | - | EVENTOUT |
| | PF4 | - | SDMMC3_D1 | SDMMC3_ D123DIR | - | FMC_A4 | - | - | EVENTOUT |
| | PF5 | - | SDMMC3_D2 | - | - | FMC_A5 | - | - | EVENTOUT |
| | PF6 | - | QUADSPI_ BK1_IO3 | - | - | SAI4_SCK_B | - | - | EVENTOUT |
| | PF7 | - | QUADSPI_ BK1_IO2 | - | - | - | - | - | EVENTOUT |
| | PF8 | - | TIM13_CH1 | QUADSPI_ BK1_IO0 | - | - | - | - | EVENTOUT |
| | PF9 | - | TIM14_CH1 | QUADSPI_ BK1_IO1 | - | - | - | - | EVENTOUT |
| | PF10 | - | QUADSPI_CLK | - | - | SAI4_D3 | DCMI_D11 | LCD_DE | EVENTOUT |
| | PF11 | - | - | SAI2_SD_B | - | - | DCMI_D12 | LCD_G5 | EVENTOUT |
| | PF12 | - | - | - | ETH1_GMII_ RXD4 | FMC_A6 | - | - | EVENTOUT |
| | PF13 | - | - | - | ETH1_GMII_ RXD5 | FMC_A7 | - | - | EVENTOUT |
| | PF14 | - | - | - | ETH1_GMII_ RXD6 | FMC_A8 | - | - | EVENTOUT |
| Port F | PF15 | - | - | - | ETH1_GMII_ RXD7 | FMC_A9 | - | - | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port G | PG0 | - | - | - | ETH1_GMII_ TXD4 | FMC_A10 | - | - | EVENTOUT |
| | PG1 | - | - | - | ETH1_GMII_ TXD5 | FMC_A11 | - | - | EVENTOUT |
| | PG2 | - | - | - | ETH1_GMII_ TXD6 | FMC_A12 | - | - | EVENTOUT |
| | PG3 | - | - | - | ETH1_GMII_ TXD7 | FMC_A13 | - | - | EVENTOUT |
| | PG4 | - | - | - | ETH1_GMII_ GTX_CLK/ ETH1_RGMII_ GTX_CLK | FMC_A14 | - | - | EVENTOUT |
| | PG5 | - | - | - | ETH1_GMII_ CLK125/ ETH1_RGMII_ CLK125 | FMC_A15 | - | - | EVENTOUT |
| | PG6 | - | - | SDMMC2_CMD | - | - | DCMI_D12 | LCD_R7 | EVENTOUT |
| | PG7 | UART8_RTS/ UART8_DE | QUADSPI_CLK | - | QUADSPI_ BK2_IO3 | - | DCMI_D13 | LCD_CLK | EVENTOUT |
| | PG8 | USART3_RTS/ USART3_DE | SPDIFRX_IN3 | SAI4_FS_A | ETH1_PPS_ OUT | - | - | LCD_G7 | EVENTOUT |
| | PG9 | SPDIFRX_IN4 | QUADSPI_ BK2_IO2 | SAI2_FS_B | - | FMC_NE2/FMC _NCE | DCMI_VSYNC | LCD_R1 | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port G | PG10 | UART8_CTS | LCD_G3 | SAI2_SD_B | QUADSPI_ BK2_IO2 | FMC_NE3 | DCMI_D2 | LCD_B2 | EVENTOUT |
| | PG11 | SPDIFRX_IN1 | - | - | ETH1_GMII_ TX_EN/ ETH1_MII_ TX_EN/ ETH1_RGMII_ TX_CTL/ ETH1_RMII_ TX_EN | - | DCMI_D3 | LCD_B3 | EVENTOUT |
| | PG12 | SPDIFRX_IN2 | LCD_B4 | SAI4_SCK_A | ETH1_PHY_ INTN | FMC_NE4 | - | LCD_B1 | EVENTOUT |
| | PG13 | - | - | SAI4_MCLK_A | ETH1_GMII_ TXD0/ ETH1_MII_ TXD0/ ETH1_RGMII_ TXD0/ ETH1_RMII_ TXD0 | FMC_A24 | - | LCD_R0 | EVENTOUT |
| | PG14 | - | QUADSPI_ BK2_IO3 | SAI4_SD_A | ETH1_GMII_ TXD1/ ETH1_MII_ TXD1/ ETH1_RGMII_ TXD1/ ETH1_RMII_ TXD1 | FMC_A25 | - | LCD_B0 | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port G | PG15 | - | - | SDMMC3_CK | - | - | DCMI_D13 | - | EVENTOUT |
| Port H | PH0 | - | - | - | - | - | - | - | EVENTOUT |
| | PH1 | - | - | - | - | - | - | - | EVENTOUT |
| | PH2 | - | QUADSPI_ BK2_IO0 | SAI2_SCK_B | ETH1_GMII_ CRS/ ETH1_MII_CRS | - | - | LCD_R0 | EVENTOUT |
| | PH3 | - | QUADSPI_ BK2_IO1 | SAI2_MCLK_B | ETH1_GMII_ COL/ ETH1_MII_COL | - | - | LCD_R1 | EVENTOUT |
| | PH4 | - | LCD_G5 | - | - | - | - | LCD_G4 | EVENTOUT |
| | PH5 | - | - | - | - | SAI4_SD_B | - | - | EVENTOUT |
| | PH6 | - | - | - | ETH1_GMII_ RXD2/ ETH1_MII_ RXD2/ ETH1_RGMII_ RXD2 | MDIOS_MDIO | DCMI_D8 | - | EVENTOUT |
| | PH7 | - | - | - | ETH1_GMII_ RXD3/ ETH1_MII_ RXD3/ ETH1_RGMII_ RXD3 | MDIOS_MDC | DCMI_D9 | - | EVENTOUT |
| | PH8 | - | - | - | - | - | DCMI_HSYNC | LCD_R2 | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port H | PH9 | - | - | - | - | - | DCMI_D0 | LCD_R3 | EVENTOUT |
| | PH10 | - | - | - | - | - | DCMI_D1 | LCD_R4 | EVENTOUT |
| | PH11 | - | - | - | - | - | DCMI_D2 | LCD_R5 | EVENTOUT |
| | PH12 | - | - | - | - | - | DCMI_D3 | LCD_R6 | EVENTOUT |
| | PH13 | UART4_TX | FDCAN1_TX | - | - | - | - | LCD_G2 | EVENTOUT |
| | PH14 | UART4_RX | FDCAN1_RX | - | - | - | DCMI_D4 | LCD_G3 | EVENTOUT |
| | PH15 | - | - | - | - | - | DCMI_D11 | LCD_G4 | EVENTOUT |
| Port I | PI0 | - | - | - | - | - | DCMI_D13 | LCD_G5 | EVENTOUT |
| | PI1 | - | - | - | - | - | DCMI_D8 | LCD_G6 | EVENTOUT |
| | PI2 | - | - | - | - | - | DCMI_D9 | LCD_G7 | EVENTOUT |
| | PI3 | - | - | - | - | - | DCMI_D10 | - | EVENTOUT |
| | PI4 | - | - | SAI2_MCLK_A | - | - | DCMI_D5 | LCD_B4 | EVENTOUT |
| | PI5 | - | - | SAI2_SCK_A | - | - | DCMI_VSYNC | LCD_B5 | EVENTOUT |
| | PI6 | - | - | SAI2_SD_A | - | - | DCMI_D6 | LCD_B6 | EVENTOUT |
| | PI7 | - | - | SAI2_FS_A | - | - | DCMI_D7 | LCD_B7 | EVENTOUT |
| | PI8 | - | - | - | - | - | - | - | EVENTOUT |
| | PI9 | UART4_RX | FDCAN1_RX | - | - | - | - | LCD_VSYNC | EVENTOUT |
| | PI10 | USART3_CTS/ USART3_NSS | - | - | ETH1_GMII_ RX_ER/ ETH1_MII_ RX_ER | - | - | LCD_HSYNC | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port I | PI11 | - | LCD_G6 | - | - | - | - | - | EVENTOUT |
| | PI12 | - | - | - | - | - | - | LCD_HSYNC | EVENTOUT |
| | PI13 | - | - | - | - | - | - | LCD_VSYNC | EVENTOUT |
| | PI14 | - | - | - | - | - | - | LCD_CLK | EVENTOUT |
| | PI15 | - | LCD_G2 | - | - | - | - | LCD_R0 | EVENTOUT |
| Port J | PJ0 | - | LCD_R7 | - | - | - | - | LCD_R1 | EVENTOUT |
| | PJ1 | - | - | - | - | - | - | LCD_R2 | EVENTOUT |
| | PJ2 | - | - | - | - | - | - | LCD_R3 | EVENTOUT |
| | PJ3 | - | - | - | - | - | - | LCD_R4 | EVENTOUT |
| | PJ4 | - | - | - | - | - | - | LCD_R5 | EVENTOUT |
| | PJ5 | - | - | - | - | - | - | LCD_R6 | EVENTOUT |
| | PJ6 | - | - | - | - | - | - | LCD_R7 | EVENTOUT |
| | PJ7 | - | - | - | - | - | - | LCD_G0 | EVENTOUT |
| | PJ8 | UART8_TX | - | - | - | - | - | LCD_G1 | EVENTOUT |
| | PJ9 | UART8_RX | - | - | - | - | - | LCD_G2 | EVENTOUT |
| | PJ10 | - | - | - | - | - | - | LCD_G3 | EVENTOUT |
| | PJ11 | - | - | - | - | - | - | LCD_G4 | EVENTOUT |
| | PJ12 | - | LCD_G3 | - | - | - | - | LCD_B0 | EVENTOUT |
| | PJ13 | - | LCD_G4 | - | - | - | - | LCD_B1 | EVENTOUT |
| | PJ14 | - | - | - | - | - | - | LCD_B2 | EVENTOUT |

Table 9. Alternate function AF8 to AF15[1] (continued)

| Port | | AF8 | AF9 | AF10 | AF11 | AF12 | AF13 | AF14 | AF15 |
|---|---|---|---|---|---|---|---|---|---|
| | | SPI6/SAI2/ USART3/ UART4/5/8/ SDMMC1/2/ SPDIFRX | FDCAN1/2/ TIM13/14/ QUADSPI/ SDMMC2/3/ LCD/SPDIFRX | SAI2/4/ QUADSPI/ FMC/ SDMMC2/3/ OTG_FS/ OTG_HS | DFSDM1/ QUADSPI/ SDMMC1/ MDIOS/ETH1 | SAI4/UART5/ FMC/SDMMC1/ MDIOS | UART7/DCMI/ LCD/RNG | UART5/LCD | SYS |
| Port J | PJ15 | - | - | - | - | - | - | LCD_B3 | EVENTOUT |
| Port K | PK0 | - | - | - | - | - | - | LCD_G5 | EVENTOUT |
| | PK1 | - | - | - | - | - | - | LCD_G6 | EVENTOUT |
| | PK2 | - | - | - | - | - | - | LCD_G7 | EVENTOUT |
| | PK3 | - | - | - | - | - | - | LCD_B4 | EVENTOUT |
| | PK4 | - | - | - | - | - | - | LCD_B5 | EVENTOUT |
| | PK5 | - | - | - | - | - | - | LCD_B6 | EVENTOUT |
| | PK6 | - | - | - | - | - | - | LCD_B7 | EVENTOUT |
| | PK7 | - | - | - | - | - | - | LCD_DE | EVENTOUT |
| Port Z | PZ0 | SPI6_SCK | - | - | - | - | - | - | EVENTOUT |
| | PZ1 | SPI6_MISO | - | - | - | - | - | - | EVENTOUT |
| | PZ2 | SPI6_MOSI | - | - | - | - | - | - | EVENTOUT |
| | PZ3 | SPI6_NSS | - | - | - | - | - | - | EVENTOUT |
| | PZ4 | - | - | - | - | - | - | - | EVENTOUT |
| | PZ5 | - | - | - | - | - | - | - | EVENTOUT |
| | PZ6 | - | - | - | - | - | - | - | EVENTOUT |
| | PZ7 | - | - | - | - | - | - | - | EVENTOUT |

1. Refer to *Table 8* for AF0 to AF7.

# 5 Memory mapping

Refer to the product line reference manual for details on the memory mapping as well as the boundary addresses for all peripherals.

# 6 Electrical characteristics

## 6.1 Parameter conditions

Unless otherwise specified, all voltages are referenced to $V_{SS}$.

### 6.1.1 Minimum and maximum values

Unless otherwise specified the minimum and maximum values are guaranteed in the worst conditions of junction temperature, supply voltage and frequencies by tests in production on 100% of the devices with an junction temperature at $T_J$ = 25 °C and $T_J$ = $T_{Jmax}$ (given by the selected temperature range).

Data based on characterization results, design simulation and/or technology characteristics are indicated in the table footnotes and are not tested in production. Based on characterization, the minimum and maximum values refer to sample tests and represent the mean value plus or minus three times the standard deviation (mean±3σ).

### 6.1.2 Typical values

Unless otherwise specified, typical data are based on $T_J$ = 25 °C, $V_{DD}$ = 3.3 V, $V_{DDCORE}$ = 1.2 V. They are given only as design guidelines and are not tested.

Typical ADC accuracy values are determined by characterization of a batch of samples from a standard diffusion lot over the full temperature range, where 95% of the devices have an error less than or equal to the value indicated (mean±2σ).

### 6.1.3 Typical curves

Unless otherwise specified, all typical curves are given only as design guidelines and are not tested.

### 6.1.4 Loading capacitor

The loading conditions used for pin parameter measurement are shown in *Figure 9*.

### 6.1.5 Pin input voltage

The input voltage measurement on a pin of the device is described in *Figure 10*.

**Figure 9. Pin loading conditions**

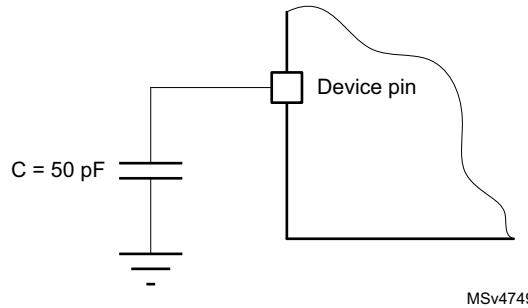
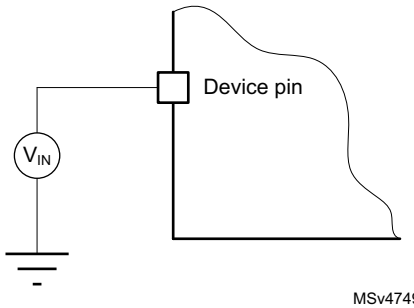
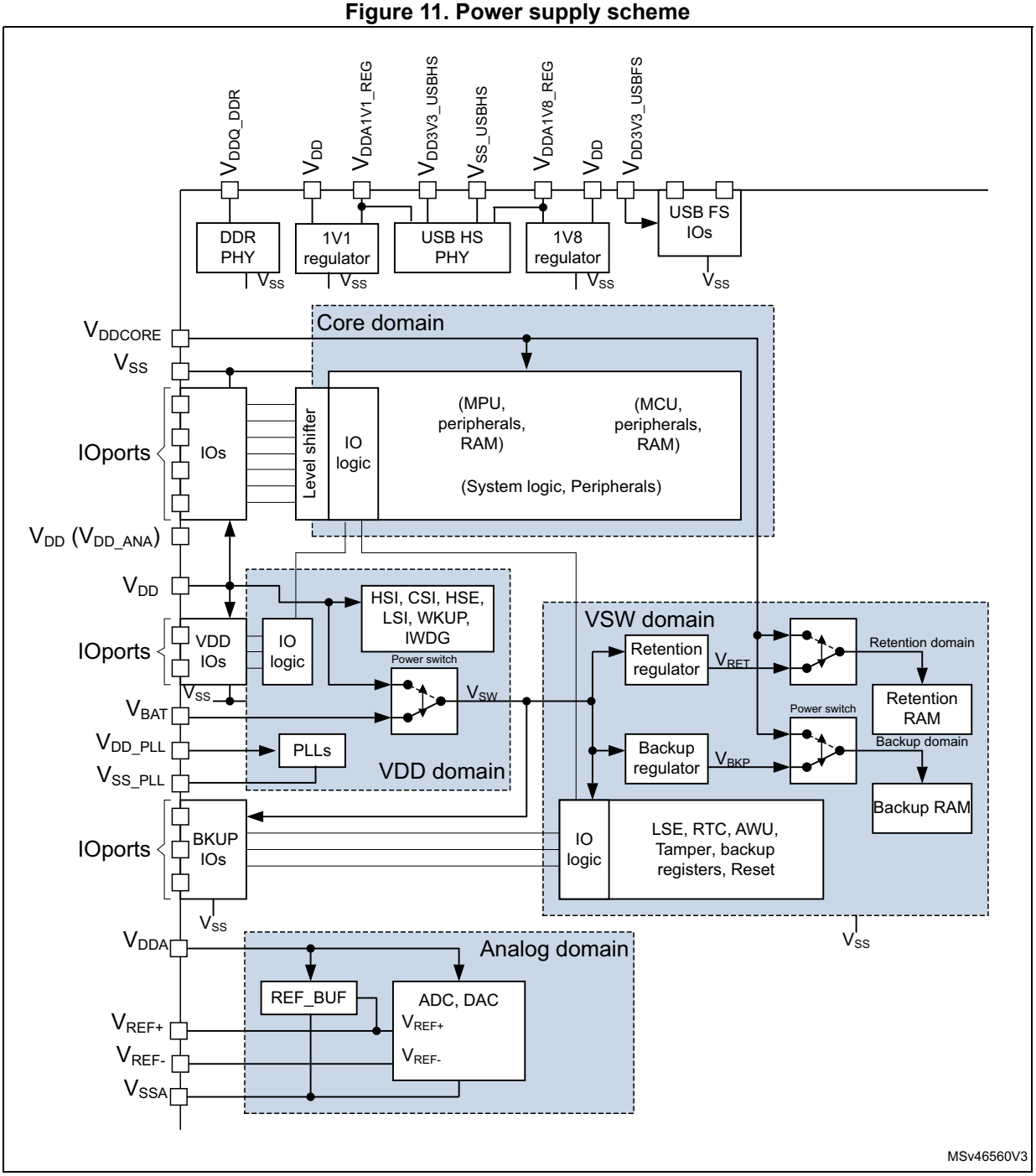



**Figure 10. Pin input voltage**



### 6.1.6 Power supply scheme

**Figure 11. Power supply scheme**

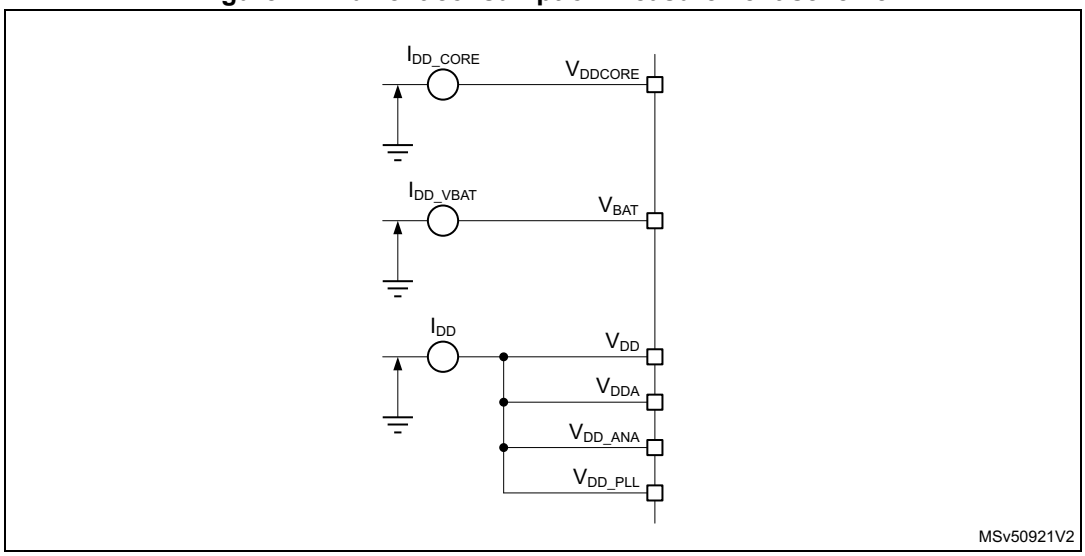



**Caution:** Each power supply pair ($V_{DD}/V_{SS}$, $V_{DDCORE}/V_{SS}$, $V_{DDA}/V_{SSA}$ ...) must be decoupled with filtering ceramic capacitors. These capacitors must be placed as close as possible to, or below, the appropriate pins on the underside of the PCB to ensure good operation of the device. It is not recommended to remove filtering capacitors to reduce PCB size or cost. This might cause incorrect operation of the device.

The number of needed capacitances and their values are provided in AN5031 “Getting started with STM32MP1 Series hardware development” available from the ST website *www.st.com*.

### 6.1.7 Current consumption measurement

**Figure 12. Current consumption measurement scheme**




## 6.2 Absolute maximum ratings

Stresses above the absolute maximum ratings listed in *Table 10: Voltage characteristics*, *Table 11: Current characteristics*, and *Table 12: Thermal characteristics* may cause permanent damage to the device. These are stress ratings only and the functional operation of the device at these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability. Device mission profile (application conditions) is compliant with JEDEC JESD47 qualification standard, extended mission profiles are available on demand.

**Table 10. Voltage characteristics (1)**

| Symbols | Ratings | Min | Max | Unit |
|---|---|---|---|---|
| $V_{DDX}$ - $V_{SSX}$ | External main supply voltage (including $V_{DD}$, $V_{DD_ANA}$, $V_{DD_PLL}$, $V_{DDA}$, $V_{DD3V3_USB}$, $V_{BAT}$, $V_{REF+}$) | -0.3 | 3.9 | V |
| $V_{DDCORE}$ - $V_{SS}$ | External core supply voltage | -0.3 | 1.5 | V |
| $V_{DDA_DDR}$ - $V_{SS}$ | DDR IO supply voltage | -0.3 | 1.98 | V |
| $V_{DDA1V8}$ - $V_{SS}$ | 1.8 V supply ($V_{DDA1V8_REG}$) | -0.3 | 3.9 | V |

**Table 10. Voltage characteristics (continued)(1)**

| Symbols | Ratings | Min | Max | Unit |
|---|---|---|---|---|
| $V_{IN}$(2) | Input voltage on FT_xxx pins | $V_{SS}$ - 0.3 | Min($V_{DD}$, $V_{DDA}$, $V_{DD3V3_USB}$, $V_{BAT}$) +3.9(3)(4) | V |
| | Input voltage on TT_xx pins | | 3.9 | V |
| | Input voltage on OTG_VBUS pin | | 6.0 | V |
| | Input voltage on USB/OTG_HS_DP/DM pins | | 5.25 | V |
| | Input voltage on OTG_FS_DP/DM pins | | 5.5 | V |
| | Input voltage on any other pins | | 3.9 | V |
| $\lvert\Delta V_{DDX}\rvert$ | Variations between different $V_{DDX}$ power pins of the same domain | - | 50 | mV |
| $\lvert V_{SSx}-V_{SS}\rvert$ | Variations between all the different ground pins | - | 50 | mV |
| $V_{REF+}$ - $V_{DDA}$ | Allowed voltage difference for $V_{REF+}$ > $V_{DDA}$ | - | 0.4 | V |

1. All power ($V_{DD}$, $V_{DDA}$, $V_{DD3V3_USB}$, $V_{DDCORE}$, $V_{BAT}$) and ground ($V_{SS}$, $V_{SSA}$, $V_{SSX}$) pins must always be connected to the external/internal power supply, in the permitted range.
2. $V_{IN}$ maximum must always be respected. Refer to *Table 49* for the maximum allowed injected current values.
3. This formula has to be applied on power supplies related to the IO structure described by the pin definition table.
4. To sustain a voltage higher than 3.9 V the internal pull-up/pull-down resistors must be disabled.

**Table 11. Current characteristics**

| Symbols | Ratings | Max | Unit |
|---|---|---|---|
| $\Sigma IV_{DD}$ | Total current into sum of all $V_{DD}$ power lines (source)(1) | 440 | mA |
| $\Sigma IV_{SS}$ | Total current out of sum of all $V_{SS}$ ground lines (sink)(1) | 440 | |
| $IV_{DD}$ | Maximum current into each $V_{DD}$ power pin (source)(1) | 100 | |
| $IV_{SS}$ | Maximum current out of each $V_{SS}$ ground pin (sink)(1) | 100 | |
| $I_{IO}$ | Output current sunk by any I/O and control pin | 20 | |
| $\Sigma I_{(PIN)}$ | Total output current sunk by sum of all I/Os and control pins(2) | 140 | |
| | Total output current sourced by sum of all I/Os and control pins(2) | 140 | |
| $I_{INJ(PIN)}$(3)(4) | Injected current on FT_xxx, TT_xx, NRST pins except PA4, PA5 | -5/+0 | |
| | Injected current on PA4, PA5 | -0/0 | |
| $\Sigma I_{INJ(PIN)}$ | Total injected current (sum of all I/Os and control pins)(5) | ±25 | |

1. All power ($V_{DD}$, $V_{DDA}$, $V_{DD3V3_USB}$, $V_{DDCORE}$) and ground ($V_{SS}$, $V_{SSA}$, $V_{SSX}$) pins must always be connected to the external/internal power supply, in the permitted range.
2. This current consumption must be correctly distributed over all I/Os and control pins. The total output current must not be sunk/sourced between two consecutive power supply pins.
3. Positive injection is not possible on these I/Os and does not occur for input voltages lower than the specified maximum value.
4. A positive injection is induced by $V_{IN}$>$V_{DD}$ while a negative injection is induced by $V_{IN}$<$V_{SS}$. $I_{INJ(PIN)}$ must never be exceeded. Refer also to *Table 10: Voltage characteristics* for the maximum allowed input voltage values.

5. When several inputs are submitted to a current injection, the maximum $\sum I_{INJ(PIN)}$ is the absolute sum of the positive and negative injected currents (instantaneous values).

**Table 12. Thermal characteristics**

| Symbol | Ratings | Value | Unit |
|---|---|---|---|
| $T_{STG}$ | Storage temperature range | -65 to +150 | °C |
| $T_J$ | Maximum junction temperature (suffix 1) | 105 | |
| | Maximum junction temperature (suffix 3) | 125 | |

## 6.3 Operating conditions

**Table 13. General operating conditions**

| Symbol | Parameter | Operating conditions | Min. | Typ | Max. | Unit |
|---|---|---|---|---|---|---|
| $F_{mpuss_ck}$ | Cortex-A7 subsystem | STM32MP153C | 0 | - | 650 | MHz |
| | | STM32MP153F | 0 | - | 800 | |
| $F_{axiss_ck}$, $F_{hclk5}$, $F_{hclk6}$ | Internal AXI, AHB5, AHB6 clock frequency | - | 0 | - | 266 | |
| $F_{mcu_ck}$ | Internal MCU AHB clock frequency | - | 0 | - | 209 | |
| $F_{pclk1}$ | Internal APB1 clock frequency | - | 0 | - | 104.5 | |
| $F_{pclk2}$ | Internal APB2 clock frequency | - | 0 | - | 104.5 | |
| $F_{pclk3}$ | Internal APB3 clock frequency | - | 0 | - | 104.5 | |
| $F_{pclk4}$ | Internal APB4 clock frequency | - | 0 | - | 133 | |
| $F_{pclk5}$ | Internal APB5 clock frequency | - | 0 | - | 133 | |
| $V_{DD}$ | I/Os and embedded regulators (REG1V1, REG1V8) supply voltage | SYSCFG_IOCTRLSETR = 0 | 1.71(1)(2) | - | 3.6 | V |
| | | SYSCFG_IOCTRLSETR ≠ 0 | 1.71 | - | 2.7 | |
| $V_{DD_ANA}$(3) | System analog supply voltage | - | 1.71 | - | 3.6 | V |
| $V_{DD_PLL}$, $V_{DD_PLL2}$(4) | PLL supply voltage | - | 1.71 | - | 3.6 | V |

**Table 13. General operating conditions (continued)**

| Symbol | Parameter | Operating conditions | Min. | Typ | Max. | Unit |
|---|---|---|---|---|---|---|
| $V_{DDCORE}$ | Digital core domain supply voltage | Run mode ($F_{mpuss_ck}$ above 650 MHz)(5) | 1.30 | 1.34 | 1.38 | V |
| | | Run mode ($F_{mpuss_ck}$ up to 650 MHz) | 1.18 | 1.20 | 1.25 | |
| | | Stop, LP-Stop mode | 1.10 | 1.20 | 1.25 | |
| | | LPLV-Stop mode | 0.85 | 0.90 | 1.25(6) | |
| | | Standby mode | 0 | 0 | 0.75 | |
| $V_{DDA}$ | Analog operating voltage | ADC used with $V_{REF}$ < 2 V | 1.62 | - | 2 | V |
| | | ADC used with $V_{REF}$ > 2 V | 2 | - | 3.6 | |
| | | DAC used | 1.8 | - | 3.6 | |
| | | VREFBUF with $V_{REF}$ = 1.5 V(7) | 1.8 | - | 3.6 | |
| | | VREFBUF with $V_{REF}$ = 1.5 V and ADC used | | - | 2 | |
| | | VREFBUF with $V_{REF}$ = 1.8 V(8) | 2.1 | - | 3.6 | |
| | | VREFBUF with $V_{REF}$ = 2.048 V | 2.35 | - | 3.6 | |
| | | VREFBUF with $V_{REF}$ = 2.5 V | 2.8 | - | 3.6 | |
| | | ADC, DAC, $V_{REF}$ not used | 0 | - | 3.6 | |
| $V_{BAT}$ | Backup operating voltage | 64 KB retention SRAM not used | 1.2 | - | 3.6 | V |
| | | 64 KB retention SRAM used | 1.4 | | | |
| $V_{DD3V3_USBFS}$(9) | USB FS I/O supply voltage | USB OTG FS used | 3 | 3.3 | 3.6 | V |
| | | USB OTG FS not used | 0 | - | 3.6 | |
| $V_{DD3V3_USBHS}$(9)(10) | USB HS I/O supply voltage | USBH or USB OTG HS used | 3.07 | 3.3 | 3.6 | V |
| | | USBH and USB OTG HS not used | 0 | - | 3.6 | |
| $V_{DD3V3_USB}$(9) | USB I/O supply voltage | USB used | 3.07 | 3.3 | 3.6 | V |
| | | USB not used | 0 | - | 3.6 | |
| $V_{DDQ_DDR}$(11) | DDR PHY supply voltage | DDR3 memory | 1.425 | 1.5 | 1.575 | V |
| | | DDR3L memory | 1.283 | 1.35 | 1.45 | |
| | | LPDDR2 or LPDDR3 | 1.14 | 1.2 | 1.3 | |
| $V_{DDA1V8_REG}$ | USB HS PHY voltage supply with 1.8 V regulator in bypass mode | BYPASS_REG1V8 = $V_{DD}$ | 1.65 | 1.8 | 1.95 | V |

**Table 13. General operating conditions (continued)**

| Symbol | Parameter | Operating conditions | Min. | Typ | Max. | Unit |
|---|---|---|---|---|---|---|
| VIN | I/O Input voltage | TTxa I/O | -0.3 | - | $V_{DD}$+0.3 | V |
| | | OTG_VBUS I/O | -0.3 | - | 6 | |
| | | DDR I/O | -0.3 | - | $V_{DDQ_DDR}$ | |
| | | USB HS I/O | -1 | - | 5.25 | |
| | | All I/O except TTxa | -0.3 | - | See(12) | |
| $T_J$ | Junction temperature range | Suffix 1 version | -20 | - | 105 | °C |
| | | Suffix 3 version | -40 | - | 125 | |

1. Once nRST is released functionality is guaranteed down to $V_{BOR}$ falling edge max.
2. Min $V_{DD}$ is 2.25 V when REG1V8 is used BYPASS_REG1V8 = 0.
3. Should be connected to same power supply voltage as $V_{DD}$.
4. It is recommended to connect $V_{DD_PLL}$ and $V_{DD_PLL2}$ to same power supply as $V_{DD}$.
5. Only for STM32MP153Fxx1 devices
6. 1.25 V is the max allowed voltage, however LPLV-Stop mode is only relevant for $V_{DDCORE}$ up to 0.95 V. In LPLV-Stop mode, if VDDQ_DDR is not shutdown, to avoid overconsumption on VDDQ_DDR, the DDR memory must be put in SelfRefresh and DDR PHY must be set in retention mode (setting bit DDRRETEN: DDR retention enable of PWR control register 3 (PWR_CR3)).
7. DAC cannot be used with $V_{REF}$ below 1.8 V.
8. ADC cannot be used with $V_{REF}$ below 2 V and $V_{DDA}$ above 2 V.
9. Depending on package selected, either $V_{DD3V3_USBFS}$ and $V_{DD3V3_USBHS}$ or only $V_{DD3V3_USB}$ are available.
10. For operation with voltage higher than Min ($V_{DD}$, $V_{DDA}$, $V_{DD3V3_USBFS}$) +0.3 V, the internal Pull-up and Pull-Down resistors must be disabled.
11. Independent from any other supply.
12. Min($V_{DD}$, $V_{DDA}$, $V_{DD3V3_USBFS}$) +3.6 V < 5.5 V. This formula has to be applied on power supplies related to the IO structure described by the pin definition table.

### 6.3.1 General operating conditions

### 6.3.2 Operating conditions at power-up / power-down

Subject to general operating conditions.

**Table 14. Operating conditions at power-up / power-down**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{VDD}$(1) | $V_{DD}$ rise time rate | 0 | ∞ | µs/V |
| | $V_{DD}$ fall time rate | 10 | ∞ | |
| $t_{VDDA}$ | $V_{DDA}$ rise time rate | 0 | ∞ | |
| | $V_{DDA}$ fall time rate | 10 | ∞ | |
| $t_{VDD3V3_USB}$(2) $t_{VDD3V3_USBHS}$ $t_{VDD3V3_USBFS}$ | $V_{DD3V3_USBxx}$ rise time rate | 0 | ∞ | |
| | $V_{DD3V3_USBxx}$ fall time rate | 10 | ∞ | |
| $t_{VDDCORE}$ | $V_{DDCORE}$ rise time rate (from reset to RUN mode) | - | 2000(3) | |
| | $V_{DDCORE}$ rise time rate (from LPLV-Stop to RUN mode) | - | 1000(4) | |
| | $V_{DDCORE}$ fall time rate | 7.33 | ∞ | |

1. $V_{DD}$ must be present before $V_{DDCORE}$ .
2. $V_{DDA1V8_REG}$ must be present before $V_{DD3V3_USBHS}$.
3. In case $V_{DDCORE}$ rise time is larger than 2 ms/V, user should control the NRST_CORE signal with a Power Good (PG) control signal from the external regulator to avoid dysfunction of the device due to $V_{DDCORE}$ potentially not yet established when internal reset signal is de-activated after $t_{VDDCORETEMPO}$ (cf. *Table 14* and *Figure 13*).
4. In case $V_{DDCORE}$ rise time at exit of LPLV-Stop is larger than 1 ms/V, there is a risk of unwanted reset due to $V_{DDCORE}$ potentially not yet established after $t_{SEL_VDDCORETEMPO}$ (cf. *Table 14* and *Figure 14*). In such a case, the $V_{DDCORE}$ supply should not be decreased during LPLV-Stop mode.

**Figure 13. $V_{DDCORE}$ rise time from reset**

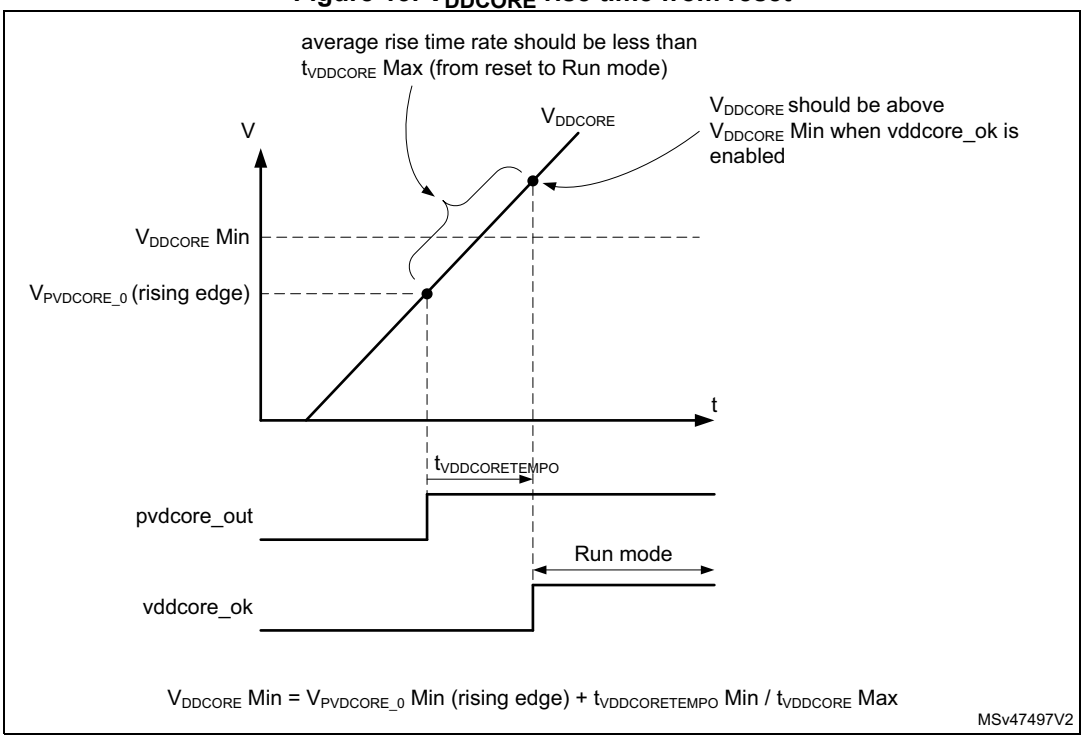
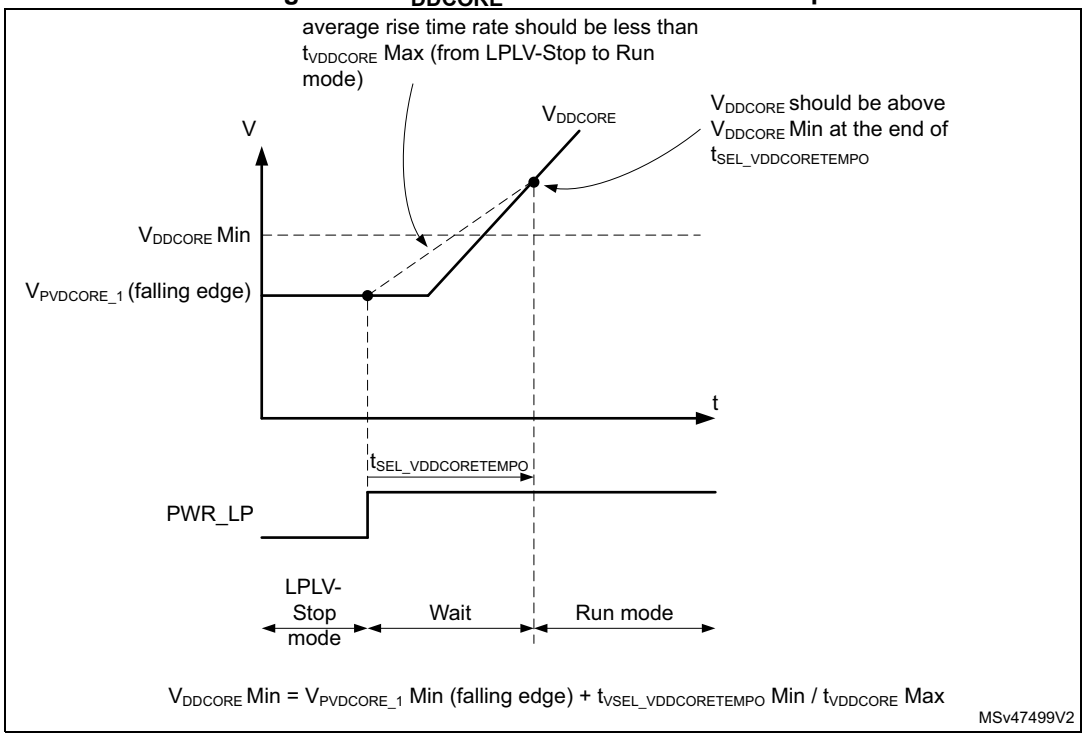


**Figure 14. $V_{DDCORE}$ rise time from LPLV-Stop**




## 6.3.3 Embedded reset and power control block characteristics

The parameters given in *Table 15* are derived from tests performed under ambient temperature and $V_{DD}$ supply voltage conditions summarized in *Table 13: General operating conditions*.

**Table 15. Embedded reset and power control block characteristics**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $t_{RSTTEMPO}$(1) | Reset temporization. after BOR0 released | - | - | 377 | 550 | µs |
| $V_{BOR0}$(1) | Brown-out reset threshold 0 | Rising edge | 1.62 | 1.67 | 1.71 | V |
| | | Falling edge | 1.58 | 1.63 | 1.67 | |
| $V_{BOR1}$ | Brown-out reset threshold 1 | Rising edge | 2.055 | 2.1 | 2.145 | V |
| | | Falling edge | 1.955 | 2 | 2.045 | |
| $V_{BOR2}$ | Brown-out reset threshold 2 | Rising edge | 2.355 | 2.4 | 2.445 | V |
| | | Falling edge | 2.255 | 2.3 | 2.345 | |
| $V_{BOR3}$ | Brown-out reset threshold 3 | Rising edge | 2.655 | 2.7 | 2.745 | V |
| | | Falling edge | 2.555 | 2.6 | 2.645 | |
| $V_{PVD0}$ | Programmable Voltage Detector threshold 0 | Rising edge | 1.905 | 1.95 | 1.995 | V |
| | | Falling edge | 1.805 | 1.85 | 1.895 | |

**Table 15. Embedded reset and power control block characteristics (continued)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $V_{PVD1}$ | Programmable Voltage Detector threshold 1 | Rising edge | 2.055 | 2.1 | 2.145 | V |
| | | Falling edge | 1.955 | 2 | 2.045 | |
| $V_{PVD2}$ | Programmable Voltage Detector threshold 2 | Rising edge | 2.205 | 2.25 | 2.295 | V |
| | | Falling edge | 2.105 | 2.15 | 2.195 | |
| $V_{PVD3}$ | Programmable Voltage Detector threshold 3 | Rising edge | 2.355 | 2.4 | 2.445 | V |
| | | Falling edge | 2.255 | 2.3 | 2.345 | |
| $V_{PVD4}$ | Programmable Voltage Detector threshold 4 | Rising edge | 2.505 | 2.55 | 2.595 | V |
| | | Falling edge | 2.405 | 2.45 | 2.495 | |
| $V_{PVD5}$ | Programmable Voltage Detector threshold 5 | Rising edge | 2.655 | 2.7 | 2.745 | V |
| | | Falling edge | 2.555 | 2.6 | 2.645 | |
| $V_{PVD6}$ | Programmable Voltage Detector threshold 6 | Rising edge | 2.805 | 2.85 | 2.895 | V |
| | | Falling edge in RUN mode | 2.705 | 2.75 | 2.795 | |
| $V_{hyst_BOR0}$ | Hysteresis voltage of BOR0 | Hysteresis in RUN mode | - | 40 | - | mV |
| $V_{hyst_BOR}$ | Hysteresis voltage of BOR | Unless BOR0 | - | 100 | - | mV |
| $V_{hyst_BOR_PVD}$ | Hysteresis voltage of BOR (unless BOR0) and PVD(2) | Hysteresis in RUN mode | - | 100 | - | mV |
| $I_{DD_BOR_PVD}$(1)(3) | BOR (unless BOR0) and PVD consumption from $V_{DD}$ | - | 0.246 | - | 0.626 | µA |
| $V_{AVM_0}$ | Analog voltage ($V_{DDA}$) detector threshold 0 | Rising edge | 1.655 | 1.7 | 1.745 | V |
| | | Falling edge | 1.555 | 1.6 | 1.645 | |
| $V_{AVM_1}$ | Analog voltage ($V_{DDA}$) detector threshold 1 | Rising edge | 2.055 | 2.1 | 2.145 | V |
| | | Falling edge | 1.955 | 2 | 2.045 | |
| $V_{AVM_2}$ | Analog voltage ($V_{DDA}$) detector threshold 2 | Rising edge | 2.455 | 2.5 | 2.545 | V |
| | | Falling edge | 2.355 | 2.4 | 2.445 | |
| $V_{AVM_3}$ | Analog voltage ($V_{DDA}$) detector threshold 3 | Rising edge | 2.755 | 2.8 | 2.845 | V |
| | | Falling edge | 2.655 | 2.7 | 2.745 | |
| $V_{hyst_VDDA}$ | Hysteresis of analog voltage ($V_{DDA}$) detector | - | - | 100 | - | mV |
| $I_{VDD_AVM}$(1) | Analog Voltage Monitoring ($V_{DDA}$) consumption on $V_{DD}$ | - | - | - | 0.248 | µA |
| $I_{VDDA_AVM}$(1) | Analog Voltage Monitoring ($V_{DDA}$) consumption on $V_{DDA}$ | Resistor bridge | - | 2.12 | - | µA |
| $V_{PVDCORE_0}$(4) | Digital core domain supply voltage ($V_{DDCORE}$) detector threshold 0 (Run) | Rising edge | 0.95 | 0.995 | 1.04 | V |
| | | Falling edge | 0.91 | 0.955 | 1 | |

**Table 15. Embedded reset and power control block characteristics (continued)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $V_{PVDCORE_1}$(5) | Digital core domain supply voltage ($V_{DDCORE}$) detector threshold 1 (LPLV_Stop) | Falling edge | 0.71 | 0.755 | 0.8 | V |
| $V_{hyst_VDDCORE}$ | Hysteresis of Digital core domain supply voltage ($V_{DDCORE}$) detector | - | - | 40 | - | mV |
| $t_{VDDCORETEMPO}$ | Tempo on VPVDCORE_0 at rising edge of $V_{DDCORE}$ to ensure that $V_{DDCORE}$ is fully established | - | 200 | 340 | 550 | µs |
| $t_{SEL_VDDCORETEMPO}$ | Tempo on $V_{PVDCORE_1}$ at rising edge of $V_{DDCORE}$ to ensure that $V_{DDCORE}$ is fully established on exit of LPLV-Stop mode | - | 234 | 380 | 606 | µs |
| $I_{VDD_VDDCOREVM}$(1) | $V_{DDCORE}$ Voltage Monitoring consumption on $V_{DD}$ | - | 1.7 | 2.6 | 4.2 | µA |
| USB_VTH | USB Threshold voltage | - | - | 1.21 | - | V |

1. Guaranteed by design.
2. No hysteresis when using PVD_IN pin.
3. BOR0 is enabled in all modes and its consumption is therefore included in the supply current characteristics tables.
4. During the first rising edge of $V_{DDCORE}$, the slope should be less than 2 ms/V to ensure $V_{DDCORE}$ is fully established before the end of the $t_{VDDCORETEMPO}$.
5. When exiting from LPLV-Stop mode to RUN mode the rising slope for $V_{DDCORE}$ should be less than 1 ms/V to ensure $V_{DDCORE}$ is fully established before the end of the $t_{VDDCORETEMPO}$.

### 6.3.4 Embedded reference voltage

The parameters given in *Table 16*, *Table 17* are derived from tests performed under ambient temperature and $V_{DD}$ supply voltage conditions summarized in *Table 13: General operating conditions*.

**Table 16. Embedded reference voltage**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $V_{REFINT}$ | Internal reference voltages | -40 °C < TJ < 125 °C | 1.175 | 1.210 | 1.241 | V |
| $t_{S_vrefint}$(1)(2) | ADC sampling time when reading the internal reference voltage | - | 4.3 | - | - | µs |
| $t_{S_vbat}$(1) | $V_{BAT}$ sampling time when reading the internal $V_{BAT}$ reference voltage | - | 9.8 | - | - | |
| $t_{start_vrefint}$ | Start time of reference voltage buffer when ADC is enable | - | 0.8 | - | 4.6 | |
| $I_{refbuf}$(2) | Reference Buffer consumption for ADC | $V_{DDA}$ = 3.3 V | 9.1 | 13.6 | 27.7 | µA |

**Table 16. Embedded reference voltage (continued)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $\Delta V_{REFINT}$(2) | Internal reference voltage spread over the temperature range | -40 °C < $T_J$ < 125 °C | - | 4.3 | 15 | mV |
| $T_{coeff_VREFINT}$ | Average temperature coefficient | Average temperature coefficient | - | 19 | 67 | ppm/°C |
| $V_{DDcoeff}$ | Average Voltage coefficient | 3.0 V < $V_{DD}$ < 3.6 V | - | 10 | 1370 | ppm/V |

1. The shortest sampling time for the application can be determined by multiple iterations.
2. Guaranteed by design.

**Table 17. Embedded reference voltage calibration value**

| Symbol | Parameter | Memory address |
|---|---|---|
| $V_{REFIN_CAL}$ | Raw data acquired at temperature of 30 °C, $V_{DDA}$ = $V_{REF+}$ = 3.3 V | 0x5C00 5250[31:16](1)(2) |

1. Mandatory to read in 32-bits word and do relevant mask and shift to isolate required bits.
2. These address is inside BSEC which should be enabled in RCC to allow access.

## 6.3.5 Embedded regulators characteristics

The parameters given in *Table 18*, *Table 19* are derived from tests performed under ambient temperature and $V_{DD}$ supply voltage conditions summarized in *Table 13: General operating conditions*.

### REG1V1 embedded regulator (USB_PHY)

**Table 18. REG1V1 embedded regulator (USB_PHY) characteristics(1)**

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $V_{DDA1V1_REG}$ | Regulated output voltage | - | 1.045 | 1.1 | 1.155 | V |
| $C_L$ | Load Capacitor | - | 1.1 | 2.2(2) | 3.3 | µF |
| esr | Equivalent Serial Resistor of Cload | - | 0.1 | 25 | 600 | mΩ |
| $I_{load}$ | Static load current(3) | - | 0 | - | 30 | mA |
| $t_{START}$ | Start-up time. from PWR_CR3.REG11EN = 1 to PWR_CR3.REG11RDY = 1 | $C_L$=2.2uF | - | 93 | - | µs |
| | | $C_L$=3.3uF | - | - | 180 | |
| $I_{INRUSH}$ | $V_{DD}$ Inrush Current to load external capacitor at start | - | - | 50 | 60 | mA |
| $I_{VDD}$ | Regulator Current consumption on $V_{DD}$ | Regulator Enabled and $I_{load}$ = 0 mA | - | 150 | 205 | µA |
| | | Regulator Enabled and $I_{load}$ = 30 mA | - | 176 | 242 | |

1. Guaranteed by design.
2. For better dynamic performances a 2.2 µF typical value external capacitor is recommended.
3. Load is for internal STM32MP153C/F analog blocks, no additional external load is accepted unless mentioned.

### REG1V8 embedded regulator (USB)

**Table 19. REG1V8 embedded regulator (USB) characteristics(1)**

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $V_{DD}$ | Regulator input voltage | - | 2.25 | 3.3 | 3.6 | V |
| $V_{DDA1V8_REG}$ | Regulated output voltage | after trimming | 1.7 | 1.8 | 1.9 | V |
| $C_L$ | Load Capacitor | - | 0.5 | 2.2(2) | 3.3 | µF |
| esr | Equivalent Serial Resistor of Cload | - | 0.1 | 25 | 600 | mΩ |
| $I_{load}$ | Static load current(3) | - | - | - | 70 | mA |
| $t_{START}$ | Start-up time. from PWR_CR3.REG11EN = 1 to PWR_CR3.REG11RDY = 1 | $C_L$=2.2uF | - | 81 | - | µs |
| | | $C_L$=3.3uF | - | - | 150 | |
| $I_{INRUSH}$ | $V_{DD}$ Inrush Current to load external capacitor at start | - | - | 80 | 100 | mA |
| $I_{VDD}$ | Regulator Current consumption on $V_{DD}$ | Regulator Enabled and $I_{load}$ = 0 mA | - | 130 | 181 | µA |
| | | Regulator Enabled and $I_{load}$ = 70 mA | - | 170 | 231 | |

1. Guaranteed by design.
2. For better dynamic performances a 2.2 µF typical value external capacitor is recommended.
3. Load is for internal STM32MP153C/F analog blocks, no additional external load is accepted unless mentioned.

## 6.3.6 Supply current characteristics

The current consumption is a function of several parameters and factors such as the operating voltage, ambient temperature, I/O pin loading, device software configuration, operating frequencies, I/O pin switching rate, program location in memory and executed binary code.

The current consumption is measured as described in *Figure 12: Current consumption measurement scheme*.

All the Run mode current consumption measurements given in this section are performed with a CoreMark code unless otherwise specified.

### Typical and maximum current consumption

The device is placed under the following conditions:

- All I/O pins are in analog input mode except when explicitly mentioned.
- All peripherals are disabled except when explicitly mentioned.
- The maximum values are obtained for $V_{DD}/V_{BAT}$ = 3.6 V and $V_{DDCORE}$ = 1.25 V, and the typical values for $V_{DD}/V_{BAT}$ = 3.3 V and $V_{DDCORE}$ = 1.2 V unless otherwise specified.

The parameters given in *Table 21* to *Table 25* are derived from tests performed under supply voltage conditions summarized in *Table 13: General operating conditions*.

**Table 20. Current consumption ($I_{DDCORE}$) in Run mode(1)**

| Symbol | Parameter | Conditions | | | | | | Typ | Max | | | | Unit |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | - | MPU SS mode | MCU SS mode | Oscillator | MPU clk (MHz) | MCU clk (MHz) | Tj = 25 °C | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | |
| $I_{DDCORE}$ | Supply current in Run mode | All peripherals enabled(2) | CRun (P0Run, P1Run) | CRun | HSE+HSI+LSI+PLL | 800(3) | 209 | 575 | 620 | 865 | 1050 | | mA |
| | | | | | | 744(3) | | 560 | 605 | 850 | 1035 | | |
| | | | | | | 648 | | 400 | 485 | 675 | 815 | 1000 | |
| | | | | | | 600 | | 385 | 475 | 660 | 805 | 1000 | |
| | | | | | | 400 | | 340 | 420 | 610 | 750 | 945 | |
| $I_{DDCORE}$ | Supply current in Run mode | All peripherals enabled(2) | CRun (P0Run, P1Run) | CStop | HSE+HSI+LSI+PLL | 800(3) | 209 | 560 | 610 | 850 | 1040 | | mA |
| | | | | | | 744(3) | | 545 | 590 | 835 | 1025 | | |
| | | | | | | 648 | | 385 | 475 | 660 | 805 | 1000 | |
| | | | | | | 600 | | 375 | 460 | 650 | 795 | 990 | |
| | | | | | | 400 | | 325 | 405 | 595 | 740 | 935 | |
| $I_{DDCORE}$ | Supply current in Run mode | All peripherals disabled | CRun (P0Run, P1Run) | CStop | HSE+HSI+LSI+PLL | 800(3) | 209 | 415 | 460 | 710 | 895 | | mA |
| | | | | | | 744(3) | | 400 | 445 | 695 | 880 | | |
| | | | | | | 648 | | 275 | 345 | 535 | 680 | 880 | |
| | | | | | | 600 | | 270 | 335 | 525 | 665 | 865 | |
| | | | | | | 400 | | 235 | 295 | 470 | 615 | 810 | |

Table 20. Current consumption ($I_{DDCORE}$) in Run mode[1] (continued)

| Symbol | Parameter | Conditions | | | | | | Typ | Max | | | | Unit |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | - | MPU SS mode | MCU SS mode | Oscillator | MPU clk (MHz) | MCU clk (MHz) | Tj = 25 °C | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | |
| $I_{DDCORE}$ | Supply current in Run mode | All peripherals disabled | CRun (P0Run, P1Stop) | CStop | HSE+HSI+PLL | 800[3] | - | 275 | 320 | 575 | 760 | - | mA |
| | | | | | HSE+HSI+PLL | 744[3] | - | 265 | 310 | 565 | 750 | - | |
| | | | | | HSE+HSI+PLL | 648 | - | 180 | 240 | 425 | 570 | 770 | |
| | | | | | HSE+HSI+PLL | 600 | - | 175 | 230 | 420 | 565 | 765 | |
| | | | | | HSE+HSI+PLL | 300 | - | 135 | 190 | 380 | 520 | 725 | |
| | | | | | HSE+HSI+PLL | 150 | - | 92 | 135 | 330 | 470 | 675 | |
| | | | | | HSE+HSI+PLL | 64 | - | 65 | 105 | 295 | 440 | 645 | |
| | | | | | HSE+HSI+PLL | 24 | - | 51 | 90 | 280 | 425 | 630 | |
| | | | | | HSE+HSI | 24 | - | 35.5 | 70 | 265 | 410 | 615 | |
| | | | | | HSI+PLL | 64 | - | 65 | 85 | 275 | 420 | 625 | |
| | | | | | HSI+PLL | 24 | - | 51 | 75 | 270 | 415 | 620 | |
| | | | | | HSI | 64 | - | 49 | 75 | 270 | 410 | 615 | |

Table 20. Current consumption ($I_{DDCORE}$) in Run mode[1] (continued)

| Symbol | Parameter | Conditions | | | | | | Typ | Max | | | | Unit |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | - | MPU SS mode | MCU SS mode | Oscillator | MPU clk (MHz) | MCU clk (MHz) | Tj = 25 °C | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | |
| $I_{DDCORE}$ | Supply current in Run mode | MPU in CSleep with WFI (CLK OFF). All peripherals disabled | CSleep (P0Stop, P1Stop) | CStop | HSE+HSI+PLL | 800[3] | - | 165 | 210 | 465 | 650 | - | mA |
| | | | | | HSE+HSI+PLL | 744[3] | - | 160 | 205 | 465 | 650 | - | |
| | | | | | HSE+HSI+PLL | 648 | - | 110 | 160 | 350 | 495 | 695 | |
| | | | | | HSE+HSI+PLL | 600 | - | 110 | 155 | 350 | 490 | 695 | |
| | | | | | HSE+HSI+PLL | 300 | - | 100 | 150 | 340 | 485 | 685 | |
| | | | | | HSE+HSI+PLL | 150 | - | 74 | 115 | 310 | 450 | 655 | |
| | | | | | HSE+HSI+PLL | 64 | - | 57 | 95 | 290 | 430 | 635 | |
| | | | | | HSE+HSI+PLL | 24 | - | 48.5 | 85 | 280 | 420 | 625 | |
| | | | | | HSE+HSI | 24 | - | 32.5 | 70 | 265 | 405 | 610 | |
| | | | | | HSI+PLL | 64 | - | 57 | 80 | 275 | 415 | 620 | |
| | | | | | HSI+PLL | 24 | - | 48 | 75 | 270 | 410 | 615 | |
| | | | | | HSI | 64 | - | 41 | 70 | 265 | 405 | 610 | |

Table 20. Current consumption ($I_{DDCORE}$) in Run mode[1] (continued)

| Symbol | Parameter | Conditions | | | | | | Typ | Max | | | | Unit |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | - | MPU SS mode | MCU SS mode | Oscillator | MPU clk (MHz) | MCU clk (MHz) | Tj = 25 °C | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | |
| $I_{DDCORE}$ | Supply current in Run mode | All peripherals disabled | CStop (P0Stop, P1Stop) | CRun | HSE+HSI+PLL | - | 209 | 71 | 115 | 305 | 450 | 650 | mA |
| | | | | | HSE+HSI+PLL | - | 100 | 53 | 95 | 285 | 430 | 635 | |
| | | | | | HSE+HSI+PLL | - | 64 | 59.5 | 100 | 295 | 435 | 640 | |
| | | | | | HSE+HSI+PLL | - | 24 | 53 | 95 | 285 | 430 | 635 | |
| | | | | | HSE+HSI+PLL | - | 10 | 38.5 | 75 | 270 | 410 | 615 | |
| | | | | | HSE+HSI+PLL | - | 4 | 37.5 | 75 | 270 | 410 | 615 | |
| | | | | | HSE+HSI | - | 24 | 27.5 | 65 | 260 | 400 | 605 | |
| | | | | | HSI+PLL | - | 64 | 59 | 85 | 280 | 420 | 625 | |
| | | | | | HSI+PLL | - | 24 | 53 | 80 | 275 | 415 | 620 | |
| | | | | | HSI | - | 64 | 33.5 | 65 | 260 | 400 | 605 | |
| | | | | | CSI+HSI+PLL | - | 64 | 59.5 | 85 | 280 | 420 | 625 | |
| | | | | | CSI+HSI+PLL | - | 24 | 53 | 80 | 275 | 415 | 620 | |
| | | | | | CSI+HSI+PLL | - | 4 | 37 | 70 | 265 | 405 | 610 | |
| | | | | | CSI+HSI | - | 4 | 24 | 60 | 255 | 395 | 600 | |

**Table 20. Current consumption ($I_{DDCORE}$) in Run mode(1) (continued)**

| Symbol | Parameter | Conditions | | | | | | Typ | Max | | | | Unit |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | - | MPU SS mode | MCU SS mode | Oscillator | MPU clk (MHz) | MCU clk (MHz) | Tj = 25 °C | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | |
| $I_{DDCORE}$ | Supply current in Run mode | MCU in CSleep with WFI (CLK OFF). All peripherals disabled | CStop (P0Stop, P1Stop) | CSleep | HSE+HSI+PLL | - | 209 | 59.5 | 100 | 295 | 435 | 640 | mA |
| | | | | | HSE+HSI+PLL | - | 100 | 47.5 | 90 | 280 | 420 | 625 | |
| | | | | | HSE+HSI+PLL | - | 64 | 56 | 95 | 290 | 430 | 635 | |
| | | | | | HSE+HSI+PLL | - | 24 | 52 | 90 | 285 | 425 | 630 | |
| | | | | | HSE+HSI+PLL | - | 10 | 38 | 75 | 270 | 410 | 615 | |
| | | | | | HSE+HSI+PLL | - | 4 | 37 | 75 | 270 | 410 | 615 | |
| | | | | | HSE+HSI | - | 24 | 26 | 65 | 260 | 400 | 605 | |
| | | | | | HSI+PLL | - | 64 | 55.5 | 80 | 275 | 415 | 620 | |
| | | | | | HSI+PLL | - | 24 | 51.5 | 80 | 275 | 410 | 620 | |
| | | | | | HSI | - | 64 | 30 | 65 | 260 | 400 | 605 | |
| | | | | | CSI+HSI+PLL | - | 64 | 56 | 85 | 275 | 420 | 625 | |
| | | | | | CSI+HSI+PLL | - | 24 | 51.5 | 80 | 275 | 415 | 620 | |
| | | | | | CSI+HSI+PLL | - | 4 | 37 | 70 | 265 | 405 | 610 | |
| | | | | | CSI+HSI | - | 4 | 23.5 | 60 | 255 | 395 | 600 | |

1. HSE = 24 MHz, AXI clk ($F_{axiss_ck}$) = Max($F_{mpuss_ck}$, 264).
2. Activity on peripherals and bus masters other than processors, could lead to additional power consumption above these values, largely dependent on the amount of initialized peripherals and their activity.
3. Typical value given with $V_{DDCORE}$ = 1.34 V, maximum values given with $V_{DDCORE}$ = 1.38 V.

**Table 21. Current consumption ($I_{DD}$) in Run mode(1)**

| Symbol | Parameter | Conditions | | | Typ | Max | | | | Unit |
|---|---|---|---|---|---|---|---|---|---|---|
| | | MPU SS mode | MCU SS mode | Oscillator | Tj = 25 °C | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | |
| $I_{DD}$ | Supply current in Run mode | CRun (P0Run, P1Run) | CRun | HSE+HSI+LSI+PLL1,2,3,4 | 3.95 | 6.14 | 6.40 | 6.50 | 6.60 | mA |
| $I_{DD}$ | Supply current in Run mode | CRun (P0Run, P1Stop) | CStop | HSI+PLL1,2 | 3.00 | 4.67 | 4.90 | 5.00 | 5.10 | mA |
| | | | | HSE+HSI | 1.75 | 3.45 | 3.48 | 3.49 | 3.50 | |
| | | | | HSI | 1.25 | 2.46 | 2.48 | 2.49 | 2.50 | |

1. HSE = 24 MHz.

**Table 22. Current consumption in Stop mode(1)**

| Symbol | Parameter | Conditions | | | Typ | | | | Max | | | | Unit |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | - | MPU SS mode | MCU SS mode | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | |
| $I_{DD}$ | Supply current in Stop mode | All peripherals disabled | CStop (P0Stop, P1Stop) | CStop | 980 | 985 | 985 | 995 | 1500 | 1560 | 1580 | 1600 | µA |
| | | All peripherals disabled | CStandby (P0Stop, P1Stop) | CStop | 980 | 985 | 985 | 995 | 1500 | 1560 | 1580 | 1600 | |
| $I_{DDCORE}$ | | All peripherals disabled | CStop (P0Stop, P1Stop) | CStop | 19000 | 90500 | 150000 | 230000 | 55000 | 261000 | 425000 | 585000 | |
| | | All peripherals disabled | CStandby (P0Stop, P1Stop) | CStop | 19000 | 90000 | 150000 | 225000 | 54500 | 261000 | 425000 | 585000 | |

1. HSE = 24 MHz.

**Table 23. Current consumption in LPLV-Stop mode(1)**

| Symbol | Parameter | Conditions | | | Typ(2) | | | | Max(3) | | | | Unit |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | - | MPU SS mode | MCU SS mode | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | |
| $I_{DD}$ | Supply current in LPLV-Stop mode | All Peripheral disabled | CStop (P0Stop, P1Stop) | CStop | 980 | 985 | 985 | 995 | 1500 | 1560 | 1580 | 1600 | µA |
| | | All Peripheral disabled | CStandby (P0Stop, P1Stop) | CStop | 980 | 985 | 985 | 995 | 1500 | 1560 | 1580 | 1600 | |
| $I_{DDCORE}$ | | All Peripheral disabled | CStop (P0Stop, P1Stop) | CStop | 7150 | 39000 | 67500 | 105000 | 25000 | 122000 | 190000 | 290000 | |
| | | All Peripheral disabled | CStandby (P0Stop, P1Stop) | CStop | 7150 | 39000 | 67500 | 105000 | 25000 | 122000 | 190000 | 290000 | |

1. HSE = 24 MHz.
2. $V_{DDCORE}$ = 0.9 V.
3. $V_{DDCORE}$ = 0.95 V.

**Table 24. Current consumption in Standby mode(1)**

| Symbol | Parameter | Conditions | | | | Typ | | | | Max | | | | Unit |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | - | | MPU SS mode | MCU SS mode | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj= 125 °C | |
| $I_{DD}$ | Supply current in Standby mode | Backup SRAM OFF, RTC OFF, LSE OFF | Retention RAM OFF | CStandby (P0Stop, P1Stop) | CStop | 1.95 | 4.00 | 7.60 | 13.5 | 4 | 12 | 18 | 32 | µA |
| | | Backup SRAM ON, RTC ON, LSE ON, medium_high drive | | CStandby (P0Stop, P1Stop) | CStop | 9.6 | 38.5 | 64.5 | 105 | 17.5 | 70 | 110 | 180 | |
| | | | Retention RAM ON | CStandby (P0Stop, P1Stop) | CStop | 74 | 460 | 800 | 1300 | 130 | 850 | 1500 | 2300 | |

1. IWDG OFF, LSI OFF, $V_{DDCORE}$ = 0 V.

**Table 25. Current consumption in $V_{BAT}$ mode**

| Symbol | Parameter | Conditions | | | Typ | | | | Max | | | | Unit |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | - | | $V_{BAT}$ (V) | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | |
| $I_{DDVBAT}$ | Supply current in $V_{BAT}$ mode | Backup SRAM OFF, RTC OFF, LSE OFF | Retention RAM OFF | 1.6 | 0.007 | 0.13 | 0.39 | 1.1 | - | - | - | - | µA |
| | | | | 2.4 | 0.008 | 0.14 | 0.415 | 1.15 | - | - | - | - | |
| | | | | 3 | 0.012 | 0.175 | 0.495 | 1.35 | - | - | - | - | |
| | | | | 3.3 | 0.041 | 0.52 | 1.45 | 3.9 | - | - | - | - | |
| | | | | 3.6 | 0.073 | 0.62 | 1.65 | 4.25 | 0.11 | 1 | 2.2 | 6 | |
| | | Backup SRAM OFF, RTC ON, LSE ON, medium_high drive | | 1.6 | 0.84 | 1.05 | 1.35 | 2.1 | - | - | - | - | |
| | | | | 2.4 | 1.05 | 1.3 | 1.6 | 2.45 | - | - | - | - | |
| | | | | 3 | 1.25 | 1.5 | 1.9 | 2.8 | - | - | - | - | |
| | | | | 3.3 | 1.4 | 2 | 3.05 | 5.7 | - | - | - | - | |
| | | | | 3.6 | 1.55 | 2.25 | 3.35 | 6.25 | 2 | 3.5 | 5.5 | 9 | |
| | | Backup SRAM ON, RTC ON,. LSE ON, medium_high drive | | 1.6 | 7.75 | 31 | 54 | 87.5 | - | - | - | - | |
| | | | | 2.4 | 8.25 | 31.5 | 55 | 88.5 | - | - | - | - | |
| | | | | 3 | 8.45 | 33 | 57 | 91.5 | - | - | - | - | |
| | | | | 3.3 | 9.5 | 34 | 59 | 95.5 | - | - | - | - | |
| | | | | 3.6 | 9.55 | 35 | 60.5 | 98 | 15 | 62 | 93 | 151 | |
| | | Backup SRAM ON, RTC ON,. LSE ON, high drive | | 1.6 | 7.9 | 31.5 | 55 | 89 | - | - | - | - | |
| | | | | 2.4 | 8.4 | 32.5 | 56 | 90 | - | - | - | - | |
| | | | | 3 | 8.6 | 33.5 | 58 | 93 | - | - | - | - | |
| | | | | 3.3 | 9.2 | 35 | 60.5 | 97.5 | - | - | - | - | |
| | | | | 3.6 | 9.85 | 36 | 62.5 | 100 | 15 | 63 | 93 | 151 | |

**Table 25. Current consumption in $V_{BAT}$ mode (continued)**

| Symbol | Parameter | Conditions | | | Typ | | | | Max | | | | Unit |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | - | | $V_{BAT}$ (V) | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | Tj = 25 °C | Tj = 85 °C | Tj = 105 °C | Tj = 125 °C | |
| $I_{DDVBAT}$ | Supply current in $V_{BAT}$ mode | Backup SRAM ON, RTC ON,. LSE ON, medium_high drive | Retention RAM ON | 1.6 | 74 | 405 | 760 | 1250 | - | - | - | - | µA |
| | | | | 2.4 | 76 | 410 | 765 | 1250 | - | - | - | - | |
| | | | | 3 | 81 | 420 | 785 | 1300 | - | - | - | - | |
| | | | | 3.3 | 79 | 430 | 795 | 1300 | - | - | - | - | |
| | | | | 3.6 | 84.5 | 435 | 815 | 1350 | 180 | 850 | 1350 | 2000 | |
| | | Backup SRAM ON, RTC ON, LSE ON, high drive | | 1.6 | 75.5 | 405 | 770 | 1250 | - | - | - | - | |
| | | | | 2.4 | 75.5 | 410 | 770 | 1250 | - | - | - | - | |
| | | | | 3 | 76 | 425 | 790 | 1300 | - | - | - | - | |
| | | | | 3.3 | 78 | 435 | 805 | 1300 | - | - | - | - | |
| | | | | 3.6 | 84.5 | 440 | 820 | 1350 | 180 | 870 | 1350 | 2000 | |

### I/O system current consumption

The current consumption of the I/O system has two components: static and dynamic.

### I/O static current consumption

All the I/Os used as inputs with pull-up generate a current consumption when the pin is externally held low. The value of this current consumption can be simply computed by using the pull-up/pull-down resistors values given in *Table 50: I/O static characteristics*.

For the output pins, any external pull-down or external load must also be considered to estimate the current consumption.

An additional I/O current consumption is due to I/Os configured as inputs if an intermediate voltage level is externally applied. This current consumption is caused by the input Schmitt trigger circuits used to discriminate the input value. Unless this specific configuration is required by the application, this supply current consumption can be avoided by configuring these I/Os in analog mode. This is notably the case of ADC input pins which should be configured as analog inputs.

**Caution:** Any floating input pin can also settle to an intermediate voltage level or switch inadvertently, as a result of external electromagnetic noise. To avoid a current consumption related to floating pins, they must either be configured in analog mode, or forced internally to a definite digital value. This can be done either by using pull-up/down resistors or by configuring the pins in output mode.

### I/O dynamic current consumption

The I/Os used by an application contribute to the current consumption. When an I/O pin switches, it uses the current from the MCU supply voltage to supply the I/O pin circuitry and to charge/discharge the capacitive load (internal or external) connected to the pin.

The theoretical formula is provided below:

$$I_{SW} = V_{DDx} \times f_{SW} \times C_L$$

where

$I_{SW}$ is the current sunk by a switching I/O to charge/discharge the capacitive load

$V_{DDx}$ is the MCU supply voltage

$f_{SW}$ is the I/O switching frequency

$C_L$ is the total capacitance seen by the I/O pin: C = CINT+ CEXT

## 6.3.7 Wakeup time from low-power modes

The wakeup times given in *Table 26* are measured starting from the wakeup event trigger up to the first instruction executed by the MPU or MCU:

- For CSleep modes:
  - the MPU or MCU goes in low-power mode after WFE (Wait For Event) instruction.
- For CStop modes:
  - MCU goes in low-power mode after WFE (Wait For Event) instruction.
  - MPU goes in low-power mode after WFI (Wait For Interrupt) instruction.
- WKUPx pin is used to wakeup from low-power modes.

All timings are derived from tests performed under ambient temperature and $V_{DD}$ = 3.3 V.

**Table 26. Low-power mode wakeup timings**

| Symbol | Parameter | System mode | Conditions (after wakeup) | Typ(1) | Max(1) | Unit |
|---|---|---|---|---|---|---|
| **MPU wakeup** | | | | | | |
| $t_{WUCSLEEP_MPU}$ | MPU wakeup from CSleep, MCU in CSleep | Run | HSE 24 MHz, SYSRAM | 31 | 32 | mpuss_ck clock cycles |
| $t_{WUCSTOP_MPU}$ | MPU wakeup from CStop, MCU in CStop | Stop | HSI 64 MHz, SYSRAM | 5.7 | 9 | µs |
| | | | HSE + PLL 648 MHz, SYSRAM | 112 | 220 | |
| | MPU wakeup from CStop, MCU in CRun | Run | HSI 64 MHz, SYSRAM | 0.54 | 1 | |
| | | | HSE + PLL 648 MHz, SYSRAM | 0.083 | 0.17 | |
| $t_{WULPLV-Stop_MPU}$ | MPU wakeup from CStop with system in LPLV-Stop (LVDS=1), MCU in CStop | LPLV-Stop | HSI 64 MHz, SYSRAM | 410 | 640 | |
| **MCU wakeup** | | | | | | |
| $t_{WUCSLEEP_MCU}$ | MCU wakeup from CSleep, MPU in CSleep | Run | HSE 24 MHz, SRAM | 6 | 7 | mcu_ck clock cycles |
| $t_{WULPLV-Stop_MCU}$ | MCU wakeup from CStop with system in LPLV-Stop (LVDS=1), MPU in CStop | LPLV-Stop | HSI 64 MHz, SRAM, MCTMPSKP = 1 | 5.3 | 8 | µs |
| | | | HSI 64 MHz, SRAM, MCTMPSKP = 0, PWR_LP delay = 1 ms | 1.4 | 2.2 | ms |
| $t_{WUCSTOP_MCU}$ | MCU wakeup from CStop, MPU in CStop | Stop | HSI 64 MHz, SRAM | 5.3 | 8 | µs |
| $t_{WUCSTOP_MCU2}$ | MCU wakeup from CStop, HSI active (HSIKERON=1), MPU in CStop | Stop (HSI active) | HSI 64 MHz, SRAM | 0.33 | 0.5 | |
| $t_{WUCSTOP_MCU3}$ | MCU wakeup from CStop, MPU in CRun | Run | HSI 64 MHz, SRAM | 0.12 | 0.18 | |
| $t_{WUSTANDBY_MCU}$ | MCU wakeup from STANDBY | Standby | HSI 64 MHz, RETRAM | 2550 | 3000 | |

1. Guaranteed by characterization results unless otherwise specified.

**Table 27. Wakeup time using USART/LPUART(1)**

| Symbol | Parameter | Conditions | Typ | Max | Unit |
|---|---|---|---|---|---|
| tWUUSART tWULPUART | Wakeup time needed to calculate the maximum USART/LPUART baud rate allowing the wakeup from stop mode when USART/LPUART clock source is HSI. | Stop | - | 6.7 | µs |
| | | LPLV-Stop | - | 240.7(2) | µs |

1. Guaranteed by design.

2. Including the $t_{SEL_VDDCORETEMPO}$ = 234 µs.

## 6.3.8 External clock source characteristics

### High-speed external user clock generated from an external source

In bypass mode the HSE oscillator is switched off and the input pin is a standard I/O.

Digital and analog bypass modes are available.

The external clock signal has to respect the *Table 50: I/O static characteristics*. However, the recommended clock input waveform is shown in *Figure 15* for digital bypass mode and in *Figure 16* for analog bypass mode. In analog bypass mode the clock can be a sinusoidal waveform.

**Table 28. High-speed external user clock characteristics (digital bypass)(1)**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $f_{HSE_ext}$ | User external clock source frequency | 8 | 24 | 48 | MHz |
| $V_{SW}$ ($V_{HSEH}$ -$V_{HSEL}$) | OSC_IN amplitude | 0.7×$V_{DD}$ | - | $V_{DD}$ | V |
| $V_{DC}$ | OSC_IN input voltage | $V_{SS}$ | - | 0.3×$V_{SS}$ | |
| $t_{W(HSE)}$ | OSC_IN high or low time | 7 | - | - | ns |

1. Guaranteed by design.

**Figure 15. High-speed external clock source AC timing diagram (digital bypass)**

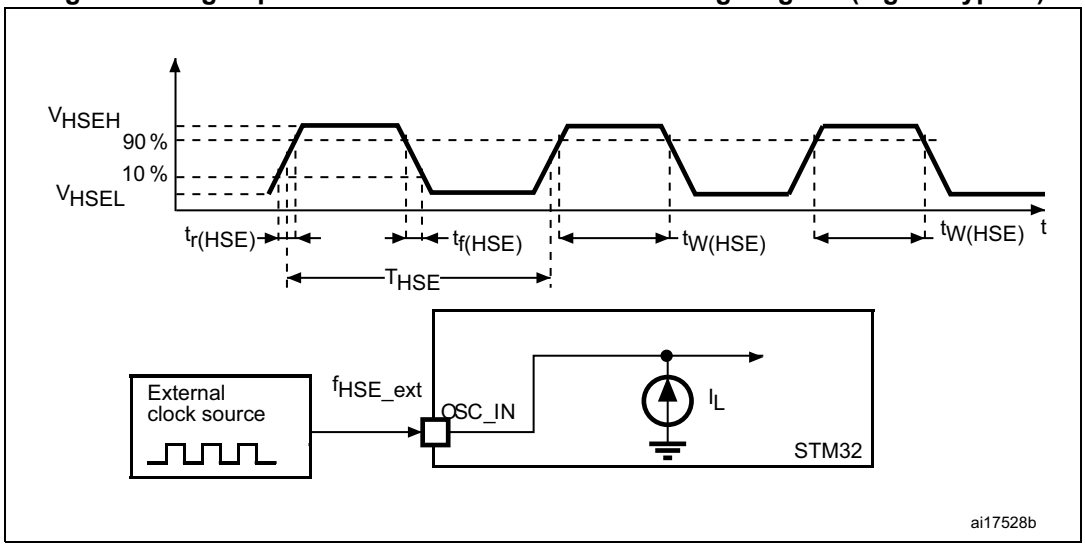


**Table 29. High-speed external user clock characteristics (analog bypass)(1)**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $f_{HSE_ext}$ | User external clock source frequency | 8 | 24 | 48 | MHz |
| | duty cycle (Square wave) | 45 | 50 | 55 | % |
| | duty cycle deterioration | 0 | ±10(2) | ±20(3) | % |
| $V_{HSE}$ | Absolute input range | 0 | - | $V_{DD}$ | - |
| $V_{PP}$ | OSC_IN peak-to-peak amplitude | 0.2(4) | - | 0.67×$V_{DD}$ | V |
| $t_{SU}$(5) | Time to start | - | 1 | 10(6) | µs |
| $tr/tf_{(HSE)}$ | Rise and Fall time (10% to 90% threshold levels of the input peak-to-peak amplitude) | 0.05 ×$T_{HSE}$ | - | 0.3 ×$T_{HSE}$ | ns |
| $I_{(HSE)}$ | Power consumption | - | 150(7) | 500(8) | µA |

1. Guaranteed by design.
2. Guaranteed by design with a square wave signal (@25 °C, $V_{DD}$=3.3 V /$V_{PP}$ = 400 mV / $V_{DC}$=1 V) where $V_{DC}$ is the DC component of the input signal.
3. Guaranteed by design with a square wave signal (@25 °C, $V_{DD}$=1.71 V /$V_{PP}$ = 200 mV / $V_{DC}$=0.8 V) where $V_{DC}$ is the DC component of the input signal.
4. minimum peak-to-peak amplitude (@25 °C, 0.1<$V_{DC}$<$V_{DD}$-0.1 V) where $V_{DC}$ is the DC component of the input signal.
5. $t_{SU(HSE)}$ is the startup time measured from the moment it is enabled (by software) to a stabilized analog bypass clock interface is reached. This value is measured with 200 mV peak-to-peak amplitude.
6. Maximum start-up time is obtained with 200 mV peak-to-peak amplitude.
7. with a sine wave signal ($V_{PP}$ = 400 mV / $V_{DC}$=0.4 V) where $V_{DC}$ is the DC component of the input signal.
8. with a sine wave signal ($V_{DD}$ = 3.6 V / $V_{PP}$ = 800 mV / $V_{DC}$ = 1.8 V) where $V_{DC}$ is the DC component of the input signal.

**Figure 16. High-speed external clock source AC timing diagram (analog bypass)**

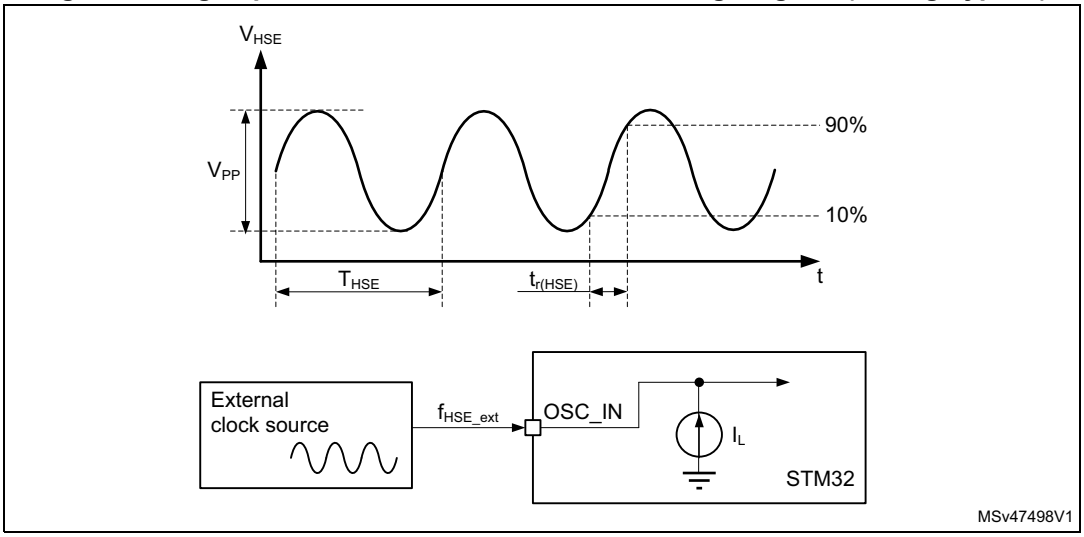
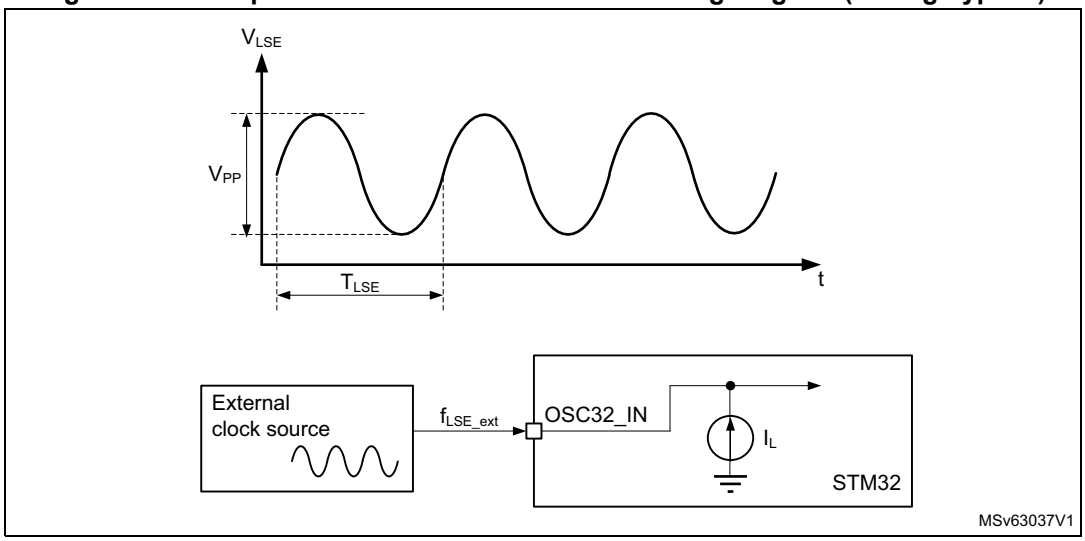


**Table 30. Low-speed external user clock characteristics (analog bypass)(1)**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $f_{LSE_ext}$ | User external clock source frequency | - | 32.768 | - | kHz |
| $V_{LSE}$ | Absolute input range | 0 | - | $V_{SW}$(2) | - |
| $V_{PP}$ | OSC32_IN peak-to-peak amplitude | 0.2(3) | 1 | - | V |
| $I_{(LSE)}$ | Power consumption | - | 120 | - | nA |

1. Guaranteed by design.
2. $V_{SW}$ is equal to $V_{DD}$ when present or $V_{BAT}$ otherwise
3. Minimum peak-to-peak amplitude (@25 °C, 0.1 < $V_{DC}$ < $V_{SW}$ - 0.1 V) where $V_{DC}$ is the DC component of the input signal.

**Figure 17. Low-speed external clock source AC timing diagram (analog bypass)**




## Low-speed external user clock generated from an external source

In bypass mode the LSE oscillator is switched off and the input pin is a standard I/O. The external clock signal has to respect the *Table 50: I/O static characteristics*. However, the recommended clock input waveform is shown in *Figure 18* for digital bypass and *Figure 17* for analog bypass.

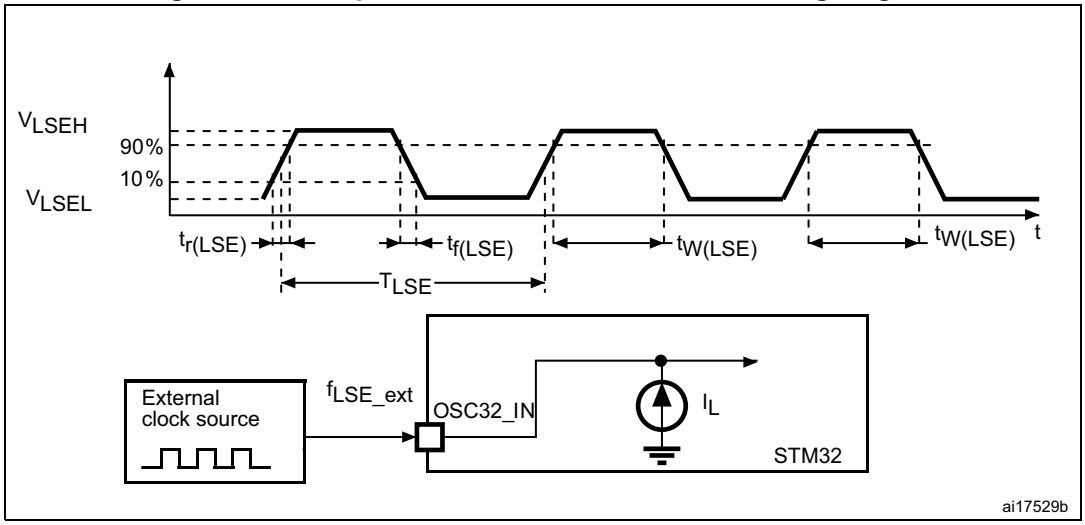
**Table 31. Low-speed external user clock characteristics (digital bypass)(1)**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $f_{LSE_ext}$ | User external clock source frequency | - | 32.768 | 1000 | kHz |
| $V_{LSEH}$ | OSC32_IN input pin high level voltage | 0.7 × $V_{DD}$ | - | $V_{DD}$ | V |
| $V_{LSEL}$ | OSC32_IN input pin low level voltage | $V_{SS}$ | - | 0.3 $V_{DD}$ | |
| $t_{w(LSEH)}$ $t_{w(LSEL)}$ | OSC32_IN high or low time | 250 | - | - | ns |

1. Guaranteed by design.

*Note: For information on selecting the crystal, refer to the application note AN2867 "Oscillator design guide for ST microcontrollers" available from the ST website www.st.com.*

**Figure 18. Low-speed external clock source AC timing diagram**




### High-speed external clock generated from a crystal/ceramic resonator

The high-speed external (HSE) clock can be supplied with a 8 to 48 MHz crystal/ceramic resonator oscillator. All the information given in this paragraph are based on characterization results obtained with typical external components specified in *Table 32*. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time. Refer to the crystal resonator manufacturer for more details on the resonator characteristics (frequency, package, accuracy).

**Table 32. 8-48 MHz HSE oscillator characteristics(1)**

| Symbol | Parameter | Operating conditions(2) | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| F | Oscillator frequency | - | 8 | 24 | 48 | MHz |
| $R_F$ | Feedback resistor | - | - | 200 | - | kΩ |
| $I_{DD(HSE)}$ | HSE current consumption | During startup(3) | - | - | 4 | mA |
| | | $V_{DD}$ = 3 V, Rm = 150 Ω<br>$C_L$ = 12 pF at 4 MHz | - | 0.35 | - | |
| | | $V_{DD}$ = 3 V, Rm = 120 Ω<br>$C_L$ = 12 pF at 16 MHz | - | 0.40 | - | |
| | | $V_{DD}$ = 3 V, Rm = 100 Ω<br>$C_L$ = 10 pF at 24 MHz | - | 0.45 | - | |
| | | $V_{DD}$ = 3 V, Rm = 80 Ω<br>$C_L$ = 8 pF at 32 MHz | - | 0.65 | - | |
| | | $V_{DD}$ = 3 V, Rm = 80 Ω<br>$C_L$ = 8 pF at 48 MHz | - | 0.95 | - | |

**Table 32. 8-48 MHz HSE oscillator characteristics(1) (continued)**

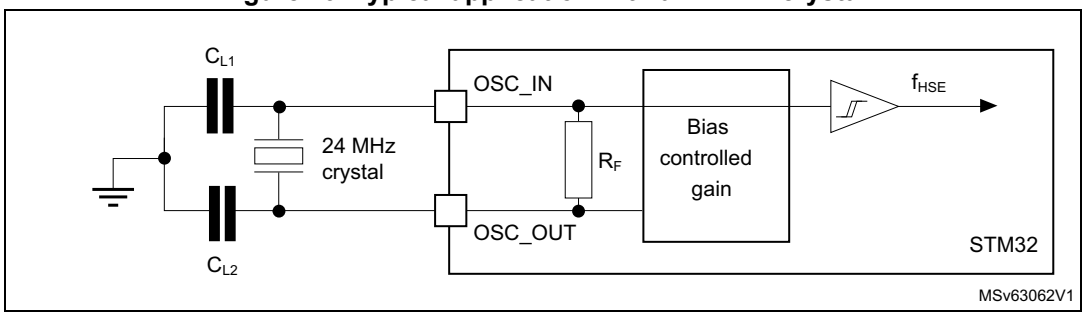
| Symbol | Parameter | Operating conditions(2) | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $Gm_{critmax}$ | Maximum critical crystal gm | Startup | - | - | 1.5 | mA/V |
| $t_{SU}$(4) | Start-up time | $V_{DD}$ is stabilized | - | 2 | - | ms |

1. Guaranteed by design.
2. Resonator characteristics given by the crystal/ceramic resonator manufacturer.
3. This consumption level occurs during the first 2/3 of the $t_{SU(HSE)}$ startup time.
4. $t_{SU(HSE)}$ is the startup time measured from the moment it is enabled (by software) to a stabilized 8 MHz oscillation is reached. This value is measured for a standard crystal resonator and it can vary significantly with the crystal manufacturer.

For $C_{L1}$ and $C_{L2}$, it is recommended to use high-quality external ceramic capacitors in the 5 pF to 25 pF range (typical), designed for high-frequency applications, and selected to match the requirements of the crystal or resonator (see *Figure 19*). $C_{L1}$ and $C_{L2}$ are usually the same size. The crystal manufacturer typically specifies a load capacitance which is the series combination of $C_{L1}$ and $C_{L2}$. The PCB and MCU pin capacitance must be included (10 pF can be used as a rough estimate of the combined pin and board capacitance) when sizing $C_{L1}$ and $C_{L2}$.

*Note: For information on selecting the crystal, refer to the application note AN2867 "Oscillator design guide for ST microcontrollers" available from the ST website www.st.com.*

**Figure 19. Typical application with a 24 MHz crystal**




## Low-speed external clock generated from a crystal/ceramic resonator

The low-speed external (LSE) clock can be supplied with a 32.768 kHz crystal/ceramic resonator oscillator. All the information given in this paragraph are based on characterization results obtained with typical external components specified in *Table 33*. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time. Refer to the crystal resonator manufacturer for more details on the resonator characteristics (frequency, package, accuracy).

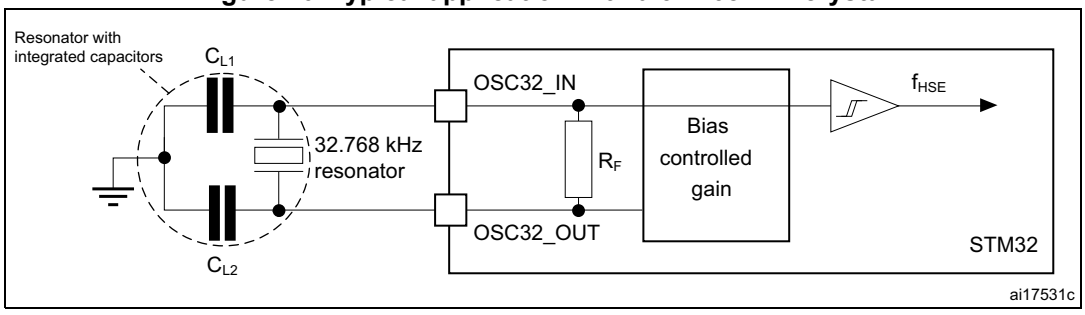
**Table 33. Low-speed external user clock characteristics(1)**

| Symbol | Parameter | Operating conditions(2) | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| F | Oscillator frequency | - | - | 32.768 | - | kHz |
| $I_{DD}$ | LSE current consumption | LSEDRV[1:0] = 00, Low drive capability | - | 290 | - | nA |
| | | LSEDRV[1:0] = 01, Medium Low drive capability | - | 390 | - | |
| | | LSEDRV[1:0] = 10, Medium high drive capability | - | 550 | - | |
| | | LSEDRV[1:0] = 11, High drive capability | - | 900 | - | |
| $Gm_{critmax}$ | Maximum critical crystal gm | LSEDRV[1:0] = 00, Low drive capability | - | - | 0.5 | µA/V |
| | | LSEDRV[1:0] = 01, Medium Low drive capability | - | - | 0.75 | |
| | | LSEDRV[1:0] = 10, Medium high drive capability | - | - | 1.7 | |
| | | LSEDRV[1:0] = 11, High drive capability | - | - | 2.7 | |
| $t_{SU}$(3) | Startup time | $V_{DD}$ is stabilized | - | 2 | - | s |

1. Guaranteed by design.
2. Refer to the note and caution paragraphs below the table, and to the application note AN2867 “Oscillator design guide for ST microcontrollers.
3. $t_{SU}$ is the startup time measured from the moment it is enabled (by software) to a stabilized 32.768 k Hz oscillation is reached. This value is measured for a standard crystal resonator and it can vary significantly with the crystal manufacturer.

*Note: For information on selecting the crystal, refer to the application note AN2867 “Oscillator design guide for ST microcontrollers” available from the ST website www.st.com.*

**Figure 20. Typical application with a 32.768 kHz crystal**




1. Adding an external resistor between OSC32_IN and OSC32_OUT is forbidden.

### 6.3.9 External clock source security characteristics

**Table 34. High-speed external user clock security system (HSE CSS)(1)**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $t_{DCM(HSE_CSS)}$ | Time to detect clock missing | - | 2 | - | µs |
| $t_{DCP(HSE_CSS)}$ | Time to detect clock presence | - | - | 250 | ns |
| $I_{VDD(HSE_CSS)}$ | Power consumption ($f_{HSE}$ = 48 MHz) | - | - | 50 | µA |

1. Guaranteed by design.

### 6.3.10 Internal clock source characteristics

The parameters given in *Table 35*, *Table 36* and *Table 37* are derived from tests performed under ambient temperature and $V_{DD}$ supply voltage conditions summarized in *Table 13: General operating conditions*.

#### 64 MHz high-speed internal RC oscillator (HSI)

**Table 35. HSI oscillator characteristics(1)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $f_{HSI}$(2) | HSI frequency | $V_{DD}$ = 3.3 V, $T_J$ = 30 °C | 63.7 | 64 | 64.3 | MHz |
| TRIM | HSI user trimming step | Trimming is not a multiple of 32 | - | 0.24 | 0.33 | % |
| | | Trimming is 128, 256 and 384 | - | -2.43 | - | |
| | | Trimming is 64, 192, 320 and 448 | - | -0.70 | - | |
| | | Other trimming are a multiple of 32 (not including multiple of 64 and 128) | - | -0.30 | - | |
| DuCy(HSI) | Duty Cycle | - | 45 | - | 55 | % |
| $\Delta_{VDD\ (HSI)}$ | HSI oscillator frequency drift over $V_{DD}$ (reference is 3.3 V) | $V_{DD}$ = 1.71 to 3.6 V | -0.12 | - | 0.03 | % |
| $\Delta_{TEMP\ (HSI)}$(3) | HSI oscillator frequency drift over temperature after factory calibration | $T_J$ = -20 to 110 °C | -1.25 | - | 0.75 | % |
| | | $T_J$ = -40 to 125 °C | -1.75 | - | 0.95 | |
| $t_{su}$(HSI) | HSI oscillator start-up time (Time between Enable rising and First output clock edge.) | - | - | 1.47 | 2 | µs |
| $t_{stab}$(HSI) | HSI oscillator stabilization time | at 1% of target frequency | - | 3 | - | µs |
| $I_{DD}$(HSI) | HSI oscillator power consumption | - | - | 300 | 400 | µA |

1. Guaranteed by design unless otherwise specified.
2. Guaranteed by test in production.
3. Guaranteed by characterization results.

### 4 MHz low-power internal RC oscillator (CSI)

**Table 36. CSI oscillator characteristics(1)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $f_{CSI}$(2) | CSI frequency | $V_{DD}$ = 3.3 V, $T_J$ = 30 °C | 3.98 | 4 | 4.02 | MHz |
| TRIM | Trimming step | Trimming code is not a multiple of 16 | - | 0.85 | 1 | % |
| | | Trimming code is a multiple of 16 | - | -1.65 | - | - |
| DuCy(CSI) | Duty Cycle | - | 45 | - | 55 | % |
| $\Delta_{VDD}$ (CSI) + $\Delta_{TEMP}$ (CSI)(3) | CSI oscillator frequency drift over $V_{DD}$ & drift over temperature | $V_{DD}$ = 1.71 to 3.6 V<br>$T_J$ = 0 to 85 °C | - | ±1.43 | - | % |
| $t_{su(CSI)}$ | CSI oscillator startup time | - | - | 1.5 | 2.4 | µs |
| $t_{stab(CSI)}$ | CSI oscillator stabilization time (to reach ±5% of $f_{CSI}$) | $T_J$ = 0 to 85 °C | - | 5 | - | cycle |
| $I_{DD(CSI)}$ | CSI oscillator power consumption | - | - | 30 | - | µA |

1. Guaranteed by design.
2. Guaranteed by test in production.
3. Guaranteed by characterization results.

### 32 kHz low-speed internal (LSI) RC oscillator

**Table 37. LSI oscillator characteristics(1)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $f_{LSI}$ | LSI frequency | $T_J$ = 30 °C,(2)<br>$V_{DD}$ = 3.3 V | 31.4 | 32 | 32.6 | kHz |
| | | $T_J$ = -40 to 125 °C,<br>$V_{DD}$ = 1.71 to 3.6 V | 29 | 32 | 33.6 | |
| $t_{su(LSI)}$ | LSI oscillator startup time (Time between Enable rising and First output clock edge.) | - | - | 64 | 125 | µs |
| $t_{stab(LSI)}$ | LSI oscillator stabilization time (5% of final value) | - | - | 110 | 170 | |
| $I_{DD(LSI)}$ | LSI oscillator power consumption | - | - | 120 | 230 | nA |

1. Guaranteed by design.
2. Guaranteed by test in production.

## 6.3.11 PLL characteristics

The parameters given in *Table 38*, *Table 39*, *Table 40* are derived from tests performed under temperature and $V_{DD}$ supply voltage conditions summarized in *Table 13: General operating conditions*.

### PLL1_1600, PLL2_1600 characteristics

**Table 38. PLL1_1600, PLL2_1600 characteristics(1)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $f_{PLL_IN}$ | PLL input clock | Normal mode and Sigma delta mode | 8 | - | 16 | MHz |
| | PLL input clock duty cycle | - | 10 | - | 90 | % |
| $f_{PLL_P_Q_R_OUT}$ | PLL P,Q,R multiplier output clock | - | 3.125 | - | 800(2) | MHz |
| | PLL P,Q,R clock duty cycle | Division by 1 | 45 | 50 | 55 | % |
| | | Even divisions (N multiple of 2) | 45 | 50 | 55 | |
| | | Odd divisions (N not multiple of 2) | [100, (N+1)/2N] - 5 | [100, (N+1)/2N] | [100, (N+1)/2N] + 5 | |
| $f_{VCO_OUT}$ | PLL VCO output | - | 800 | - | 1600 | MHz |
| $t_{LOCK}$ | PLL lock time | Normal mode | - | 50 | 150 | µs |
| | | Sigma-delta mode (CKIN ≥ 8 MHz) | - | 65 | 170 | |
| $A_{LOCK}$ | Lock Accuracy (Ratio VCO frequency versus target frequency at lock) | - | - | - | ±2 | % |

**Table 38. PLL1_1600, PLL2_1600 characteristics(1) (continued)**

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| Jitter | RMS cycle-to-cycle jitter | $f_{PLL_P_Q_R_OUT}$ division = 1 to 16 Without Fractional mode | VCO = 800 MHz | - | 18(3) | - | ±ps |
| | | | VCO = 1066 MHz | - | 14(3) | - | |
| | | | VCO = 1600 MHz | - | 12(3) | - | |
| | | $f_{PLL_P_Q_R_OUT}$ division = 1 to 16 With Fractional mode | VCO = 1066 MHz | - | 20(3) | - | |
| | | | VCO = 1600 MHz | - | 18(3) | - | |
| | RMS period jitter | $f_{PLL_P_Q_R_OUT}$ division = 1 to 16 Without Fractional mode | VCO = 800 MHz | - | 16(3) | - | ±ps |
| | | | VCO = 1066 MHz | - | 12(3) | - | |
| | | | VCO = 1600 MHz | - | 10(3) | - | |
| | | $f_{PLL_P_Q_R_OUT}$ division = 1 to 16 With Fractional mode | VCO = 1066 MHz | - | 16(3) | - | |
| | | | VCO = 1600 MHz | - | 15(3) | - | |
| | Long term jitter | $f_{PLL_P_Q_R_OUT}$ division = 1 to 16 $f_{PLL_IN}$ = 8 MHz Without Fractional mode | VCO = 800 MHz | - | 225(4) | - | ps |
| | | | VCO = 1066 MHz | - | 200(4) | - | |
| | | | VCO = 1600 MHz | - | 100(4) | - | |
| | | $f_{PLL_P_Q_R_OUT}$ division = 1 to 16 $f_{PLL_IN}$ = 8 MHz With Fractional mode | VCO = 800 MHz | - | 350(4) | - | |
| | | | VCO = 1066 MHz | - | 250(4) | - | |
| | | | VCO = 1600 MHz | - | 150(4) | - | |
| $I_{VDD_PLL}$(2) | PLL power consumption on $V_{DD_PLL\ (Analog)}$ | VCO freq = 1600 MHz | | - | 930 | - | µA |
| | | VCO freq = 800 MHz | | - | 560 | - | |
| $I_{VDDCORE}$(2) | PLL power consumption on $V_{DDCORE\ (Digital)}$ | VCO freq = 1600 MHz | | - | 4200 | - | µA |
| | | VCO freq = 800 MHz | | - | 2100 | - | |

1. Guaranteed by design unless otherwise specified.
2. Guaranteed by characterization results.
3. Measured on DDR high speed IO.
4. Measured on DDR high speed IO for 10000 output clock cycles.

### PLL3_800, PLL4_800 characteristics

**Table 39. PLL3_800, PLL4_800 characteristics(1)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $f_{PLL_IN}$ | PLL input clock | Normal mode | 4 | - | 16 | MHz |
| | - | Sigma delta mode | 8 | - | 16 | |
| | PLL input clock duty cycle | - | 10 | - | 90 | % |

**Table 39. PLL3_800, PLL4_800 characteristics(1) (continued)**

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| $f_{PLL_P_Q_R_OUT}$ | PLL P,Q,R multiplier output clock | - | | 3.125 | - | 800(2) | MHz |
| | PLL P,Q,R clock duty cycle | Even divisions (N multiple of 2) | | 45 | 50 | 55 | % |
| | | Odd divisions (N not multiple of 2) | | [100, (N+1)/2N] - 5 | [100, (N+1)/2N] | [100, (N+1)/2N] + 5 | |
| $f_{VCO_OUT}$ | PLL VCO output | - | | 400 | - | 800 | MHz |
| $t_{LOCK}$ | PLL lock time | Normal mode | | 15 | 50 | 150 | µs |
| | | Sigma-delta mode (CKIN ≥ 8 MHz) | | 25 | 65 | 170 | |
| $A_{LOCK}$ | Lock accuracy (Ratio VCO frequency versus target frequency at lock) | - | | - | - | ±2 | % |
| Jitter | RMS cycle-to-cycle jitter | $f_{PLL_P_Q_R_OUT}$ division = 25 to 100 Without Fractional mode | VCO = 400 MHz | - | 80(3) | - | ±ps |
| | | | VCO = 600 MHz | - | 50(3) | - | |
| | | | VCO = 800 MHz | - | 45(3) | - | |
| | | $f_{PLL_P_Q_R_OUT}$ division = 25 to 100 With Fractional mode | VCO = 600 MHz | - | 65(3) | - | |
| | | | VCO = 800 MHz | - | 60(3) | - | |
| | RMS period jitter | $f_{PLL_P_Q_R_OUT}$ division = 25 to 100 Without Fractional mode | VCO = 400 MHz | - | 75(3) | - | ±ps |
| | | | VCO = 600 MHz | - | 38(3) | - | |
| | | | VCO = 800 MHz | - | 30(3) | - | |
| | | $f_{PLL_P_Q_R_OUT}$ division = 25 to 100 With Fractional mode | VCO = 600 MHz | - | 55(3) | - | |
| | | | VCO = 800 MHz | - | 50(3) | - | |
| | Long term jitter | $f_{PLL_P_Q_R_OUT}$ division = 25 to 100 $f_{PLL_IN}$ = 8 MHz Without Fractional mode | VCO = 400 MHz | - | 225(4) | - | ps |
| | | | VCO = 600 MHz | - | 150(4) | - | |
| | | | VCO = 800 MHz | - | 125(4) | - | |
| | | $f_{PLL_P_Q_R_OUT}$ division = 25 to 100 $f_{PLL_IN}$ = 8 MHz With Fractional mode | VCO = 400 MHz | - | 300(4) | - | |
| | | | VCO = 600 MHz | - | 200(4) | - | |
| | | | VCO = 800 MHz | - | 150(4) | - | |
| $I_{VDD_PLL}$ | PLL power consumption on $V_{DD_PLL\ (Analog)}$ | VCO freq = 800 MHz | | - | 600 | 610 | µA |
| | | VCO freq = 400 MHz | | - | 320 | 350 | |

**Table 39. PLL3_800, PLL4_800 characteristics(1) (continued)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $I_{VDDCORE}$ | PLL power consumption on $V_{DDCORE}$ (Digital) | VCO freq = 800 MHz | - | 2200 | 5250 | µA |
| | | VCO freq = 400 MHz | - | 1130 | 4550 | |

1. Guaranteed by design unless otherwise specified.
2. Guaranteed by characterization results.
3. Measured on GPIO.
4. Measured on GPIO for 10000 output clock cycles.

### PLL_USB (2880 MHz) characteristics

**Table 40. USB_PLL characteristics(1)**

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $f_{PLL_IN}$ | PLL input clock | | 19.2 | 24 | 38.4 | MHz |
| $f_{PLL_INFIN}$ | PFD input clock | | 19.2 | 24 | 38.4 | MHz |
| $f_{PLL_OUT}$ | PLL multiplier output clock | | - | 480 | - | MHz |
| $f_{VCO_OUT}$ | PLL VCO output | | - | 2880 | - | MHz |
| $t_{LOCK}$ | PLL lock time | | - | - | 100 | µs |
| $t_{PDN}$ | PLL power down time | | 10 | - | - | µs |
| $I_{DDA1V1_REG(PLL)}$ | PLL power consumption on $V_{DDA1V1_REG}$ (internal connection) | PLL in power down | - | 5 | 425 | µA |
| | | $f_{VCO_OUT}$ = 2880 MHz | - | 4.4 | 5.6 | mA |
| $I_{DDA1V8_REG(PLL)}$ | PLL power consumption on $V_{DDA1V8_REG}$ (internal connection) | PLL in power down | - | - | 2 | µA |
| | | $f_{VCO_OUT}$ = 2880 MHz | - | 2 | 2.5 | mA |

1. Guaranteed by design unless otherwise specified.

## 6.3.12 PLL spread spectrum clock generation (SSCG) characteristics

The spread spectrum clock generation (SSCG) feature allows the reduction of electromagnetic interferences (see *Table 46: EMI characteristics*). It is available only on the PLL1_1600 and PLL2_1600.

**Table 41. SSCG parameters constraint**

| Symbol | Parameter | Min | Typ | Max(1) | Unit |
|---|---|---|---|---|---|
| $f_{Mod}$ | Modulation frequency | 20 | - | 60 | kHz |
| md | Peak modulation depth | 0.25 | - | 2 | % |
| MODEPER * INCSTEP | - | - | - | $2^{15}$-1 | - |

1. Guaranteed by design.

Equation 1

The frequency modulation period (MODEPER) is given by the equation below:

$$MODEPER = round[f_{PLL_IN}/(4 \times f_{Mod})]$$

$f_{PLL_IN}$ and fMod must be expressed in Hz.

As an example:

If $f_{PLL_IN}$ = 1 MHz, and $f_{MOD}$ = 1 kHz, the modulation depth (MODEPER) is given by equation 1:

$$MODEPER = round[10^6/(4 \times 10^3)] = 250$$

Equation 2

Equation 2 allows the increment step (INCSTEP) calculation:

$$INCSTEP = round[((2^{15} - 1) \times md \times PLLN)/(100 \times 5 \times MODEPER)]$$

$f_{VCO_OUT}$ must be expressed in MHz.

With a modulation depth (md) = ±2% (4% peak-to-peak), and PLLN = 240 (in MHz):

$$INCSTEP = round[((2^{15} - 1) \times 2 \times 240)/(100 \times 5 \times 250)] = 126 md(quantitazed)\%$$

An amplitude quantization error may be generated because the linear modulation profile is obtained by taking the quantized values (rounded to the nearest integer) of MODPER and INCSTEP. As a result, the achieved modulation depth is quantized. The percentage quantized modulation depth is given by the following formula:

$$md_{quantized}\% = (MODEPER \times INCSTEP \times 100 \times 5)/((2^{15} - 1) \times PLLN)$$

As a result:

$$md_{quantized}\% = (250 \times 126 \times 100 \times 5)/((2^{15} - 1) \times 240) = 2.002\%(peak)$$

*Figure 21* and *Figure 22* show the main PLL output clock waveforms in center spread and down spread modes, where:

F0 is $f_{PLL_OUT}$ nominal.

$T_{mode}$ is the modulation period.

md is the modulation depth.

**Figure 21. PLL output clock waveforms in center spread mode**

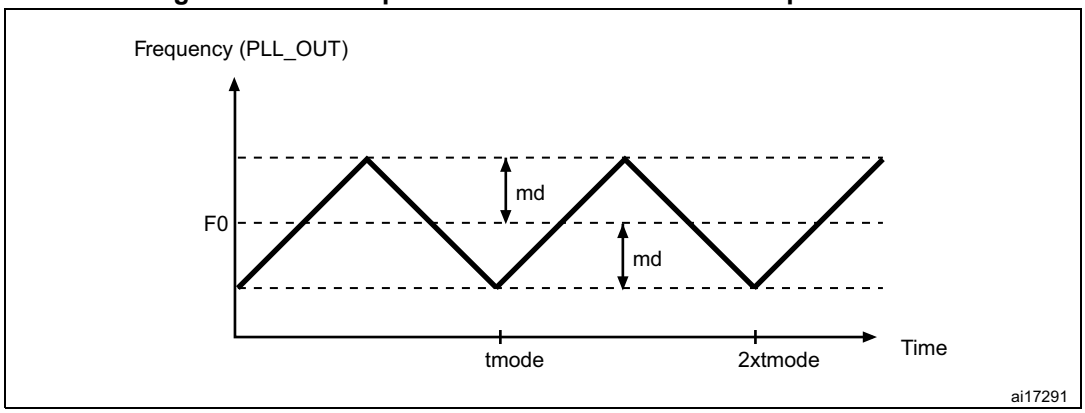
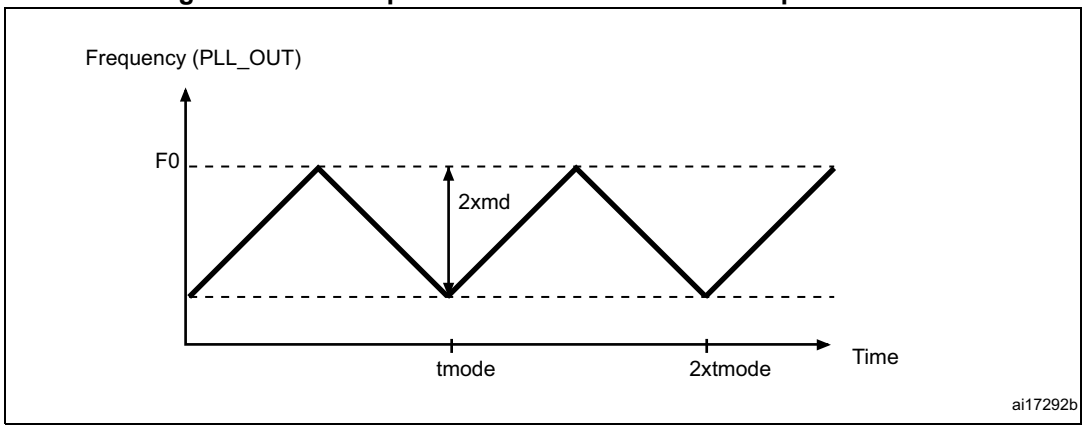



**Figure 22. PLL output clock waveforms in down spread mode**




## 6.3.13 Memory characteristics

### OTP characteristics

The characteristics are given at $T_J$ = -40 to 125 °C unless otherwise specified.

**Table 42. OTP characteristics**

| Symbol | Parameter | Conditions | Min | Max | Unit |
|---|---|---|---|---|---|
| $I_{VDDCORE}$ | OTP consumption on $V_{DDCORE}$ | Programming | - | 450 | µA |
| | | Reading | - | 490 | µA |
| | | PowerDown | - | 4.2 | µA |
| $I_{VDD}$ | OTP consumption on $V_{DD}$ | Programming | - | 10000 | µA |
| | | Reading | - | 2200 | µA |
| | | PowerDown | - | 1 | µA |
| $F_{OTP}$ (1) | OTP operating Frequency | - | - | 67 | MHz |
| NB_CYCLE (2) | Maximum number of reading cycles | - | - | 500 | Million |

1. Guaranteed by design.
2. Guaranteed by characterization results.

### DDR characteristics

DDR3, DDR3L I/O DC specifications

The following table provides input and output DC threshold values and on-die-termination (ODT) recommended values. The conditions for the output threshold values are un-terminated outputs loaded with 1 pF capacitor load. The ODT values are measured after impedance calibration.

**Table 43. DC specifications – DDR3 or DDR3L mode(1)**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $V_{IH(DC)}$ | DC input voltage high | $V_{REF}$ + 0.09 | - | $V_{DDQ}$ | V |
| $V_{IL(DC)}$ | DC input voltage low | $V_{SSQ}$ - 0.3 | - | $V_{REF}$ - 0.09 | V |
| $V_{OH}$ | DC output logic high | 0.8 × $V_{DDQ}$ | - | - | V |
| $V_{OL}$ | DC output logic low | - | - | 0.2 × $V_{DDQ}$ | V |
| $R_{TT}$ | Input termination resistance (ODT) to $V_{DDQ}/2$ | 100<br>54<br>36 | 120<br>60<br>40 | 140<br>66<br>44 | Ω |
| $I_{LS}$ | Input leakage current, SSTL mode, unterminated | - | 0.01 | 4.8 | µA |

1. Guaranteed by design.

LPDDR2, LPDDR3 I/O DC specifications

The following table provides input and output DC threshold values. The conditions for the output threshold values are un-terminated outputs loaded with 1 pF capacitor load.

**Table 44. DC specifications – LPDDR2 or LPDDR3 mode(1)**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $V_{IH(DC)}$ | DC input voltage high | $V_{REF}$ + 0.13 | - | $V_{DDQ}$ | V |
| $V_{IL(DC)}$ | DC input voltage low | $V_{SSQ}$ | - | $V_{REF}$ - 0.13 | V |
| $V_{OH}$ | DC output logic high | 0.9 × $V_{DDQ}$ | - | - | V |
| $V_{OL}$ | DC output logic low | - | - | 0.1 × $V_{DDQ}$ | V |
| ILEAK | Input leakage current | - | 0.01 | 4.51 | µA |

1. Guaranteed by design.

## 6.3.14 EMC characteristics

Susceptibility tests are performed on a sample basis during device characterization.

### Functional EMS (electromagnetic susceptibility)

While a simple application is executed on the device (toggling 2 LEDs through I/O ports). the device is stressed by two electromagnetic events until a failure occurs. The failure is indicated by the LEDs:

- **Electrostatic discharge (ESD)** (positive and negative) is applied to all device pins until a functional disturbance occurs. This test is compliant with the IEC 61000-4-2 standard.
- **FTB**: a burst of fast transient voltage (positive and negative) is applied to $V_{DD}$ and $V_{SS}$ through a 100 pF capacitor, until a functional disturbance occurs. This test is compliant with the IEC 61000-4-4 standard.

A device reset allows normal operations to be resumed.

The test results are given in *Table 45*. They are based on the EMS levels and classes defined in application note AN1709 available from the ST website *www.st.com*.

**Table 45. EMS characteristics**

| Symbol | Parameter | Conditions | Level/ Class |
|---|---|---|---|
| $V_{FESD}$ | Voltage limits to be applied on any I/O pin to induce a functional disturbance | $V_{DD}$ = 3.3 V, $T_A$ = +25 °C, LFBGA448, $F_{mpuss_ck}$ = 650 or 800 MHz, $F_{mcu_ck}$ = 209 MHz, M4 core not running, conforms to IEC 61000-4-2 | 2B |
| $V_{FTB}$ | Fast transient voltage burst limits to be applied through 100 pF on $V_{DD}$ and $V_{SS}$ pins to induce a functional disturbance | | 5A |

As a consequence, it is recommended to add a serial resistor (1 kΩ) located as close as possible to the MCU to the pins exposed to noise (connected to tracks longer than 50 mm on PCB).

### Designing hardened software to avoid noise problems

EMC characterization and optimization are performed at component level with a typical application environment and simplified MCU software. It should be noted that good EMC performance is highly dependent on the user application and the software in particular.

Therefore it is recommended that the user applies EMC software optimization and prequalification tests in relation with the EMC level requested for his application.

### Software recommendations

The software flowchart must include the management of runaway conditions such as:

- Corrupted program counter
- Unexpected reset
- Critical Data corruption (control registers...)

### Prequalification trials

Most of the common failures (unexpected reset and program counter corruption) can be reproduced by manually forcing a low state on the NRST pin or the Oscillator pins for 1 second.

To complete these trials, ESD stress can be applied directly on the device, over the range of specification values. When unexpected behavior is detected, the software can be hardened

to prevent unrecoverable errors occurring (see application note AN1015 available from the ST website *www.st.com*.).

### Electromagnetic Interference (EMI)

The electromagnetic field emitted by the device are monitored while a simple application, executing EEMBC code, is running. This emission test is compliant with SAE IEC61967-2 standard which specifies the test board and the pin loading.

**Table 46. EMI characteristics**

| Symbol | Parameter | Conditions | Monitored frequency band | Max vs. [$f_{HSE}/F_{mpuss_ck}$] | | Unit |
|---|---|---|---|---|---|---|
| | | | | 24/650 MHz | 24/800 MHz | |
| $S_{EMI}$ | Peak level | $V_{DD}$ = 3.6 V, $T_A$ = 25 °C, LFBGA448 package, $F_{mcu_ck}$ = 209 MHz, M4 core not running, conforming to IEC61967-2 | 0.1 to 30 MHz | 5 | 5 | dBµV |
| | | | 30 to 130 MHz | -2 | -1 | |
| | | | 130 MHz to 1 GHz | 19 | 22 | |
| | | | 1 GHz to 2 GHz | 9 | 10 | |
| | | | EMI Level | 3.5 | 3.5 | - |

## 6.3.15 Absolute maximum ratings (electrical sensitivity)

Based on three different tests (ESD, LU) using specific measurement methods, the device is stressed in order to determine its performance in terms of electrical sensitivity.

### Electrostatic discharge (ESD)

Electrostatic discharges (a positive then a negative pulse) are applied to the pins of each sample according to each pin combination. This test conforms to the ANSI/ESDA/JEDEC JS-001 and ANSI/ESDA/JEDEC JS-002 standards.

**Table 47. ESD absolute maximum ratings**

| Symbol | Ratings | Conditions | Packages | Class | Maximum value(1) | Unit |
|---|---|---|---|---|---|---|
| $V_{ESD(HBM)}$ | Electrostatic discharge voltage (human body model) | $T_A$ = +25 °C conforming to ANSI/ESDA/JEDEC JS-001 | All | 2 | 2000 | V |
| $V_{ESD(CDM)}$ | Electrostatic discharge voltage (charge device model) | $T_A$ = +25 °C conforming to ANSI/ESDA/JEDEC JS-002 | All | C1 | 250 | |

1. Guaranteed by characterization results.

### Static latchup

Two complementary static tests are required on three parts to assess the latchup performance:

- A supply overvoltage is applied to each power supply pin
- A current injection is applied to each input, output and configurable I/O pin

These tests are compliant with JESD78 IC latchup standard.

**Table 48. Electrical sensitivities**

| Symbol | Parameter | Conditions | Class |
|---|---|---|---|
| LU | Static latchup class | $T_A$ = +25 °C conforming to JESD78 | II level A |

## 6.3.16 I/O current injection characteristics

As a general rule, a current injection to the I/O pins, due to external voltage below $V_{SS}$ or above $V_{DD}$ (for standard, 3.3 V-capable I/O pins) should be avoided during the normal product operation. However, in order to give an indication of the robustness of the device in cases when an abnormal injection accidentally happens, susceptibility tests are performed on a sample basis during the device characterization.

### Functional susceptibility to I/O current injection

While a simple application is executed on the device, the device is stressed by injecting current into the I/O pins programmed in floating input mode. While current is injected into the I/O pin, one at a time, the device is checked for functional failures.

The failure is indicated by an out of range parameter: ADC error above a certain limit (higher than 5 LSB TUE), out of conventional limits of induced leakage current on adjacent pins (out of –5 µA/+0 µA range), or other functional failure (for example reset, oscillator frequency deviation).

The following tables are the compilation of the SIC1/SIC2 and functional ESD results.

Negative induced A negative induced leakage current is caused by negative injection and positive induced leakage current by positive injection.

**Table 49. I/O current injection susceptibility(1)**

| Symbol | Description | Negative injection | Positive injection | Unit |
|---|---|---|---|---|
| $I_{INJ}$ | ANA0, ANA1, PA4, PA5 | 0 | 0 | mA |
| | PG2, PG3, PG4, PH2 | 0 | N/A | |
| | All other FTxx I/Os | 5 | N/A | |

1. Guaranteed by characterization.

## 6.3.17 I/O port characteristics

General input/output characteristics

Unless otherwise specified, the parameters given in *Table 50: I/O static characteristics* are derived from tests performed under the conditions summarized in *Table 13: General operating conditions*. All I/Os are CMOS and TTL compliant.

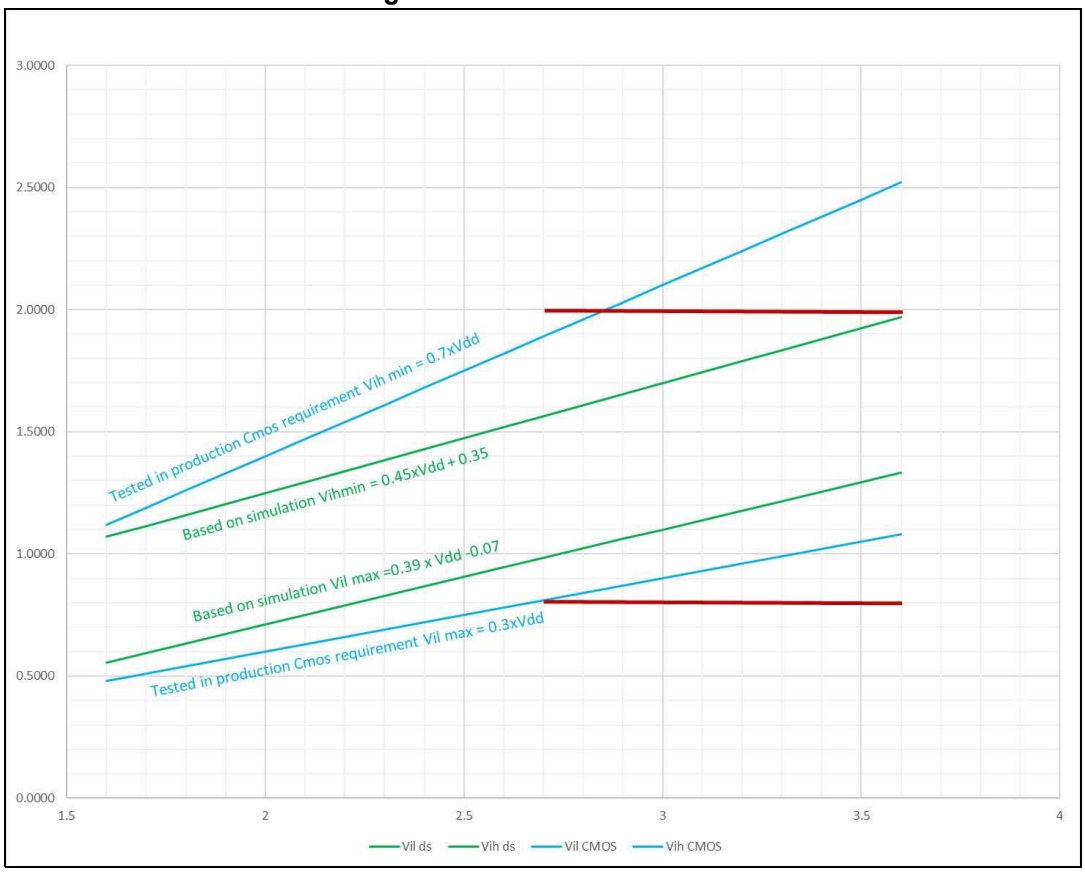
**Table 50. I/O static characteristics**

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $V_{IL}$(1) | I/O input low level voltage | 1.71 V < $V_{DD}$ < 2.7 V | - | - | 0.35 × $V_{DD}$ | V |
| | | 2.7 V < $V_{DD}$ < 3.6 V | - | - | 0.3 × $V_{DD}$ | |
| | | 1.71 V < $V_{DD}$ < 3.6 V | - | - | 0.45 × $V_{DD}$ + 0.35 | |
| $V_{IH}$(1) | I/O input high level voltage | 1.71 V < $V_{DD}$ < 3.6 V | 0.7 × $V_{DD}$ | - | - | V |
| $V_{HYS}$(1) | TT_xx, FT_xxx and NRST I/O input hysteresis | 1.71 V < $V_{DD}$ < 3.6 V | - | 0.1 × $V_{DD}$ | - | mV |
| $I_{leak}$ | FT_xx input leakage current(1) | 0 < $V_{IN}$ ≤ Max($V_{DD}$)(6) | - | - | 250 | nA |
| | | Max($V_{DD}$) < $V_{IN}$ ≤ 5.5 V (6)(2)(3) | - | - | 3500 | |
| | FT_u, IO | 0 < $V_{IN}$ ≤ Max($V_{DD}$)(6) | - | - | 500 | |
| | | Max($V_{DD}$) < $V_{IN}$ ≤ 5.5 V (6)(3) | - | - | 5000(4) | |
| | TT_xx input leakage current | 0 < $V_{IN}$ ≤ Max($V_{DD}$) (6) | - | - | 100 | |
| $R_{PU}$ | Weak pull-up equivalent resistor(5) | $V_{IN}$=$V_{SS}$ | 25 | 40 | 55 | kΩ |
| $R_{PD}$ | Weak pull-down equivalent resistor(5) | $V_{IN}$=$V_{DD}$(6) | 25 | 40 | 55 | |
| $C_{IO}$ | I/O pin capacitance | - | - | 5 | - | pF |

1. Guaranteed by design.
2. All FT_xx IO except FT_uf, FT_u.
3. $V_{IN}$ must be less than Max($V_{DD}$) + 3.6 V.
4. To sustain a voltage higher than MIN($V_{DD}$, $V_{DDA}$, $V_{DD3V3_USBxxx}$) +0.3 V, the internal pull-up and pull-down resistors must be disabled.
5. The pull-up and pull-down resistors are designed with a true resistance in series with a switchable PMOS/NMOS. This PMOS/NMOS contribution to the series resistance is minimal (~10% order).
6. Max($V_{DD}$) is the maximum value of all the I/O supplies.

All I/Os are CMOS and TTL compliant (no software configuration required). Their characteristics cover more than the strict CMOS-technology or TTL parameters. The coverage of these requirements for FT I/Os is shown in *Figure 23*.

**Figure 23. VIL/VIH for FT I/Os**




## Output driving current

The GPIOs (general purpose input/outputs) can sink or source up to ±8 mA, and sink or source up to ±20 mA (with a relaxed $V_{OL}/V_{OH}$).

In the user application, the number of I/O pins which can drive current must be limited to respect the absolute maximum rating specified in *Section 6.2*. In particular:

- The sum of the currents sourced by all the I/Os on $V_{DD}$, plus the maximum Run mode consumption of the MCU sourced on $V_{DD}$, cannot exceed the absolute maximum rating $\sum I_{VDD}$ (see *Table 11*).
- The sum of the currents sunk by all the I/Os on $V_{SS}$ plus the maximum Run mode consumption of the MCU sunk on $V_{SS}$ cannot exceed the absolute maximum rating $\sum I_{VSS}$ (see *Table 11*).

## Output voltage levels

Unless otherwise specified, the parameters given in *Table 51* are derived from tests performed under ambient temperature and $V_{DD}$ supply voltage conditions summarized in *Table 13: General operating conditions*. All I/Os are CMOS and TTL compliant.

**Table 51. Output voltage characteristics for all I/Os except PC13, PC14, PC15 and PI8(1)**

| Symbol | Parameter | Conditions(3) | Min | Max | Unit |
|---|---|---|---|---|---|
| $V_{OL}$ | Output low level voltage | CMOS port(2)<br>$I_{IO}$ = 8 mA<br>2.0 V ≤ $V_{DD}$ ≤ 3.6 V | - | 0.4 | V |
| $V_{OH}$ | Output high level voltage | CMOS port(2)<br>$I_{IO}$ = -8 mA<br>2.0 V ≤ $V_{DD}$ ≤ 3.6 V | $V_{DD}$-0.4 | - | |
| $V_{OL}$(3) | Output low level voltage | TTL port(2)<br>$I_{IO}$ = 8 mA<br>2.0 V ≤ $V_{DD}$ ≤ 3.6 V | - | 0.4 | |
| $V_{OH}$(3) | Output high level voltage | TTL port(2)<br>$I_{IO}$ = -8 mA<br>2.0 V ≤ $V_{DD}$ ≤ 3.6 V | 2.4 | - | |
| $V_{OL}$(3) | Output low level voltage | $I_{IO}$ = 20 mA<br>2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 1.3 | |
| $V_{OH}$(3) | Output high level voltage | $I_{IO}$ = -20 mA<br>2.7 V ≤ $V_{DD}$ ≤ 3.6 V | $V_{DD}$-1.3 | - | |
| $V_{OL}$(3) | Output low level voltage | $I_{IO}$ = 4 mA<br>1.71 V ≤ $V_{DD}$ ≤ 3.6 V | - | 0.45 | |
| $V_{OH}$ (3) | Output high level voltage | $I_{IO}$ = -4 mA<br>1.71 V ≤ $V_{DD}$ ≤ 3.6 V | $V_{DD}$-0.45 | - | |
| $V_{OLFM+}$(3) | Output low level voltage for an FT_f IO pin in FM+ mode | $I_{IO}$ = 20 mA<br>2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 0.4 | |
| | | $I_{IO}$ = 10 mA<br>1.71 V ≤ $V_{DD}$ ≤ 3.6 V | - | 0.4 | |

1. The IIO current sourced or sunk by the device must always respect the absolute maximum rating specified in *Table 10: Voltage characteristics*, and the sum of the currents sourced or sunk by all the I/Os (I/O ports and control pins) must always respect the absolute maximum ratings ∑IIO.
2. TTL and CMOS outputs are compatible with JEDEC standards JESD36 and JESD52.
3. Guaranteed by design.

**Table 52. Output voltage characteristics for PC13, PC14, PC15 and PI8(1)**

| Symbol | Parameter | Conditions(3) | Min | Max | Unit |
|---|---|---|---|---|---|
| $V_{OL}$ | Output low level voltage | CMOS port(2)<br>$I_{IO}$ = 3 mA<br>2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 0.4 | V |
| $V_{OH}$ | Output high level voltage | CMOS port(2)<br>$I_{IO}$ = -3 mA<br>2.7 V ≤ $V_{DD}$ ≤ 3.6 V | $V_{DD}$ − 0.4 | - | |
| $V_{OL}$(3) | Output low level voltage | TTL port(2)<br>$I_{IO}$ = 3 mA<br>2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 0.4 | |
| $V_{OH}$(2) | Output high level voltage | TTL port(2)<br>$I_{IO}$ = -3 mA<br>2.7 V ≤ $V_{DD}$ ≤ 3.6 V | 2.4 | - | |
| $V_{OL}$(2) | Output low level voltage | $I_{IO}$ = 1.5 mA<br>1.62 V ≤ $V_{DD}$ ≤ 3.6 V | - | 0.4 | |
| $V_{OH}$(2) | Output high level voltage | $I_{IO}$ = -1.5 mA<br>1.62 V ≤ $V_{DD}$ ≤ 3.6 V | $V_{DD}$ − 0.4 | - | |

1. The $I_{IO}$ current sourced or sunk by the device must always respect the absolute maximum rating specified in *Table 10: Voltage characteristics*, and the sum of the currents sourced or sunk by all the I/Os (I/O ports and control pins) must always respect the absolute maximum ratings ΣIIO.
2. TTL and CMOS outputs are compatible with JEDEC standards JESD36 and JESD52.
3. Guaranteed by design.

## Output buffer timing characteristics (HSLV option disabled)

**Table 53. Output timing characteristics (HSLV OFF)(1)(2)**

| Speed | Symbol | Parameter | conditions | Min | Max | Unit |
|---|---|---|---|---|---|---|
| 00 | $F_{max}$(3) | Maximum frequency | C = 50 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 20 | MHz |
| | | | C = 30 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 24 | |
| | | | C = 20 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 26 | |
| | | | C = 10 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 30 | |
| | | | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 10 | |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 11 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 12 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 13 | |
| | $t_r/t_f$(4) | Output high to low level fall time and output low to high level rise time | C = 50 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 13.3 | ns |
| | | | C = 30 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 11.4 | |
| | | | C = 20 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 10.2 | |
| | | | C = 10 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 8.8 | |
| | | | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 23 | |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 20 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 18.3 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 16 | |
| 01 | $F_{max}$(3) | Maximum frequency | C = 50 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 68 | MHz |
| | | | C = 30 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 83 | |
| | | | C = 20 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 88 | |
| | | | C = 10 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 103 | |
| | | | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 25 | |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 28 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 30 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 36 | |
| | $t_r/t_f$(4) | Output high to low level fall time and output low to high level rise time | C = 50 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 4.9 | ns |
| | | | C = 30 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 3.9 | |
| | | | C = 20 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 3.3 | |
| | | | C = 10 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 2.7 | |
| | | | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 8.1 | |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 6.5 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 5.7 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 4.6 | |

**Table 53. Output timing characteristics (HSLV OFF)(1)(2) (continued)**

| Speed | Symbol | Parameter | conditions | Min | Max | Unit |
|---|---|---|---|---|---|---|
| 10 | $F_{max}$(3) | Maximum frequency | C = 50 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 94 | MHz |
| | | | C = 30 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 124 | |
| | | | C = 20 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 144 | |
| | | | C = 10 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 166 | |
| | | | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 53 | |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 66 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 72 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 81 | |
| | $t_r/t_f$(4) | Output high to low level fall time and output low to high level rise time | C = 50 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 3.5 | ns |
| | | | C = 30 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 2.7 | |
| | | | C = 20 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 2.2 | |
| | | | C = 10 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 1.7 | |
| | | | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 6.3 | |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 4.8 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 4 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 3.2 | |
| 11 | $F_{max}$(3) | Maximum frequency | C = 50 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 110 | MHz |
| | | | C = 30 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 150 | |
| | | | C = 20 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 185 | |
| | | | C = 10 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 210 | |
| | | | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 62 | |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 70 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 79 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 94 | |
| | $t_r/t_f$(4) | Output high to low level fall time and output low to high level rise time | C = 50 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 3 | ns |
| | | | C = 30 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 2.2 | |
| | | | C = 20 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 1.8 | |
| | | | C = 10 pF, 2.7 V ≤ $V_{DD}$ ≤ 3.6 V(5) | - | 1.3 | |
| | | | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 5.3 | |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 4 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 3.3 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(5) | - | 2.5 | |

1. Guaranteed by design.
2. GPIO under VSW domain (PC13, PC14, PC15, PI8) are frequency limited. The maximum frequency is 2 MHz with a maximum load of 30 pF. Only one I/O at a time can be used as GPIO output and these I/Os must not be used as a current source (e.g to drive a LED). For theses IOs, the speed value must be kept to (default) 00.

3. The maximum frequency is defined with the following conditions: ($t_r$+$t_f$) ≤ 2/3, skew ≤ 1/20 T and 45% < duty cycle < 55%.
4. The fall and rise times are defined between 90% and 10% and between 10% and 90% of the output waveform, respectively.
5. Compensation system enabled.

### Output buffer timing characteristics (IO structure with _h, HSLV option enabled)

The HSLVEN_xx bits of SYSCFG_IOCTRLSETR register (together with OTP bit PRODUCT_BELOW_2V5) can be used to optimize the I/O speed when the product voltage is below 2.5 V typ. (2.7 V max.).

**Table 54. Output timing characteristics (HSLV ON, _h IO structure)(1)**

| Speed | Symbol | Parameter | conditions | Min | Max | Unit |
|---|---|---|---|---|---|---|
| 00 | $F_{max}$(2) | Maximum frequency | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 20 | MHz |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 22 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 24 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 28 | |
| | $t_r/t_f$(3) | Output high to low level fall time and output low to high level rise time | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 9.9 | ns |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 8.1 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 7.1 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 5.8 | |
| 01 | $F_{max}$(2) | Maximum frequency | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 58 | MHz |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 79 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 90 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 100 | |
| | $t_r/t_f$(3) | Output high to low level fall time and output low to high level rise time | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 5.7 | ns |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 4.2 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 3.5 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 2.7 | |
| 10 | $F_{max}$(2) | Maximum frequency | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 71 | MHz |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 101 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 126 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 162 | |
| | $t_r/t_f$(3) | Output high to low level fall time and output low to high level rise time | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 4.7 | ns |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 3.3 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 2.7 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 1.9 | |

**Table 54. Output timing characteristics (HSLV ON, _h IO structure)(1) (continued)**

| Speed | Symbol | Parameter | conditions | Min | Max | Unit |
|---|---|---|---|---|---|---|
| 11 | $F_{max}$(2) | Maximum frequency | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 77 | MHz |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 111 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 145 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 172 | |
| | $t_r/t_f$(3) | Output high to low level fall time and output low to high level rise time | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 4.3 | ns |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 3 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 2.3 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 1.6 | |

1. Guaranteed by design.
2. The maximum frequency is defined with the following conditions: ($t_r$+$t_f$) ≤ 2/3, skew ≤ 1/20 T and 45% < duty cycle < 55%.
3. The fall and rise times are defined between 90% and 10% and between 10% and 90% of the output waveform, respectively.
4. Compensation system enabled.

### Output buffer timing characteristics (IO structure with _e, HSLV option enabled)

The HSLVEN_xx bits of SYSCFG_IOCTRLSETR register (together with OTP bit PRODUCT_BELOW_2V5) can be used to optimize the I/O speed when the product voltage is below 2.5 V typ. (2.7 V max.).

**Table 55. Output timing characteristics (HSLV ON, _e IO structure)(1)**

| Speed | Symbol | Parameter | conditions | Min | Max | Unit |
|---|---|---|---|---|---|---|
| 00 | $F_{max}$(2) | Maximum frequency | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 36 | MHz |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 41 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 46 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 55 | |
| | $t_r/t_f$(3) | Output high to low level fall time and output low to high level rise time | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 9.2 | ns |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 7.4 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 6.5 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 5.2 | |

**Table 55. Output timing characteristics (HSLV ON, _e IO structure)(1) (continued)**

| Speed | Symbol | Parameter | conditions | Min | Max | Unit |
|---|---|---|---|---|---|---|
| 01 | $F_{max}$(2) | Maximum frequency | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 55 | MHz |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 71 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 85 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 100 | |
| | $t_r/t_f$(3) | Output high to low level fall time and output low to high level rise time | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 6.1 | ns |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 4.7 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 3.9 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | 3 | |
| 10 | $F_{max}$(2) | Maximum frequency | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 68 | MHz |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 95 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 118 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 162 | |
| | $t_r/t_f$(3) | Output high to low level fall time and output low to high level rise time | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 4.9 | ns |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 3.5 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 2.8 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 2.1 | |
| 11 | $F_{max}$(2) | Maximum frequency | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 80 | MHz |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 121 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 162 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 245 | |
| | $t_r/t_f$(3) | Output high to low level fall time and output low to high level rise time | C = 50 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 4.2 | ns |
| | | | C = 30 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 2.8 | |
| | | | C = 20 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 2.1 | |
| | | | C = 10 pF, 1.71 V ≤ $V_{DD}$ ≤ 2.7 V(4) | - | 1.4 | |

1. Guaranteed by design.
2. The maximum frequency is defined with the following conditions: (tr+tf) ≤ 2/3, skew ≤ 1/20 T and 45% < Duty cycle < 55%.
3. The fall and rise times are defined between 90% and 10% and between 10% and 90% of the output waveform, respectively.
4. Compensation system enabled.

## 6.3.18 NRST and NRST_CORE pin characteristics

The NRST and NRST_CORE pins input driver uses CMOS technology. It is connected to a permanent pull-up resistor, $R_{PU}$ (see *Table 50: I/O static characteristics*).

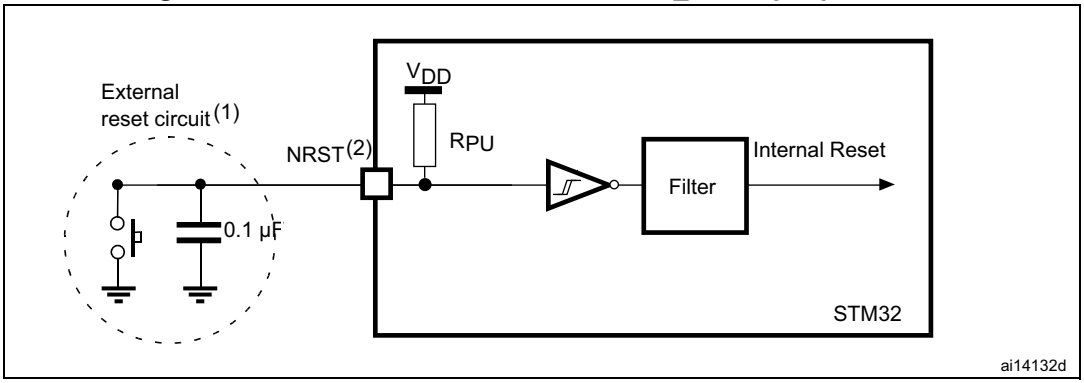
Unless otherwise specified, the parameters given in *Table 56* are derived from tests performed under the ambient temperature and $V_{DD}$ supply voltage conditions summarized in *Table 13: General operating conditions*.

**Table 56. NRST and NRST_CORE pin characteristics**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $R_{PU}$(2) | Weak pull-up equivalent resistor(1) | $V_{IN}$ = $V_{SS}$ | 30 | 40 | 50 | kΩ |
| $V_{F(NRST)}$(2) | NRST/NRST_CORE Input filtered pulse | 1.71 V < $V_{DD}$ < 3.6 V | - | - | 50 | ns |
| $V_{NF(NRST)}$(2) | NRST/NRST_CORE Input not filtered pulse | 1.71 V < $V_{DD}$ < 3.6 V | 350 | - | - | |

1. The pull-up is designed with a true resistance in series with a switchable PMOS. This PMOS contribution to the series resistance must be minimum (~10% order).
2. Guaranteed by design.

**Figure 24. Recommended NRST and NRST_CORE pin protection**




1. The reset network protects the device against parasitic resets.
2. The user must ensure that the level on the NRST/NRST_CORE pin can go below the $V_{IL(NRST)}$ max level specified in *Table 56*. Otherwise the reset is not taken into account by the device.

## 6.3.19 FMC characteristics

Unless otherwise specified, the parameters given in *Table 57* to *Table 70* for the FMC interface are derived from tests performed under the ambient temperature, $F_{mc_hclk}$ ($F_{hclk6}$) frequency and $V_{DD}$ supply voltage conditions summarized in *Table 13: General operating conditions*, with the following configuration:

- Output speed is set to OSPEEDRy[1:0] = 11
- Measurement points are done at CMOS levels: 0.5×$V_{DD}$

Refer to *Section 6.3.17: I/O port characteristics* for more details on the input/output characteristics.

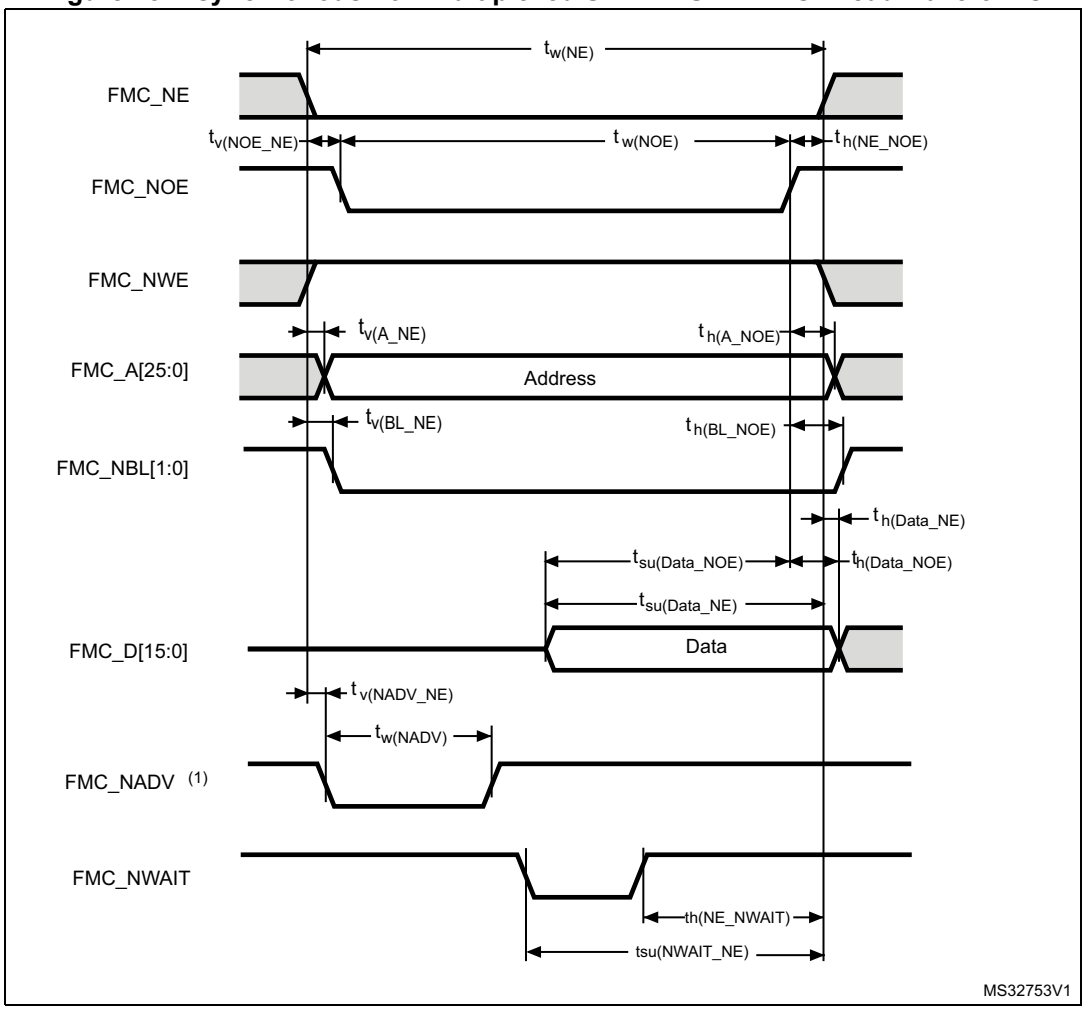
### Asynchronous waveforms and timings

*Figure 25* through *Figure 28* represent asynchronous waveforms and *Table 57* through *Table 64* provide the corresponding timings. The results shown in these tables are obtained with the following FMC configuration:

- AddressSetupTime = 0x1
- AddressHoldTime = 0x1
- DataSetupTime = 0x1 (except for asynchronous NWAIT mode, DataSetupTime = 0x5)
- DataHoldTime = 0x1 ($1\times T_{fmc_ker_ck}$ for read operations and $2\times T_{fmc_ker_ck}$ for write operations)
- ByteLaneSetup = 0x1
- BusTurnAroundDuration = 0x0
- Capacitive load $C_L$ = 30 pF

In all the timing tables, the $T_{fmc_ker_ck}$ is the fmc_ker_ck clock period.

**Figure 25. Asynchronous non-multiplexed SRAM/PSRAM/NOR read waveforms**




1. Mode 2/B, C and D only. In Mode 1, FMC_NADV is not used.

**Table 57. Asynchronous non-multiplexed SRAM/PSRAM/NOR read timings(1)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{w(NE)}$ | FMC_NE low time | $3T_{fmc_ker_ck}$-1 | $3T_{fmc_ker_ck}$+0.5 | ns |
| $t_{v(NOE_NE)}$ | FMC_NEx low to FMC_NOE low | 0 | 1 | |
| $t_{w(NOE)}$ | FMC_NOE low time | $2T_{fmc_ker_ck}$-1 | $2T_{fmc_ker_ck}$+1 | |
| $t_{h(NE_NOE)}$ | FMC_NOE high to FMC_NE high hold time | $T_{fmc_ker_ck}$-1 | - | |
| $t_{v(A_NE)}$ | FMC_NEx low to FMC_A valid | - | 1 | |
| $t_{h(A_NOE)}$ | Address hold time after FMC_NOE high | $2T_{fmc_ker_ck}$-1 | - | |
| $t_{su(Data_NE)}$ | Data to FMC_NEx high setup time | $T_{fmc_ker_ck}$+15 | - | |
| $t_{su(Data_NOE)}$ | Data to FMC_NOEx high setup time | 16 | - | |
| $t_{h(Data_NOE)}$ | Data hold time after FMC_NOE high | 0 | - | |
| $t_{h(Data_NE)}$ | Data hold time after FMC_NEx high | 0 | - | |
| $t_{v(NADV_NE)}$ | FMC_NEx low to FMC_NADV low | - | 0 | |
| $t_{w(NADV)}$ | FMC_NADV low time | - | $T_{fmc_ker_ck}$+1 | |

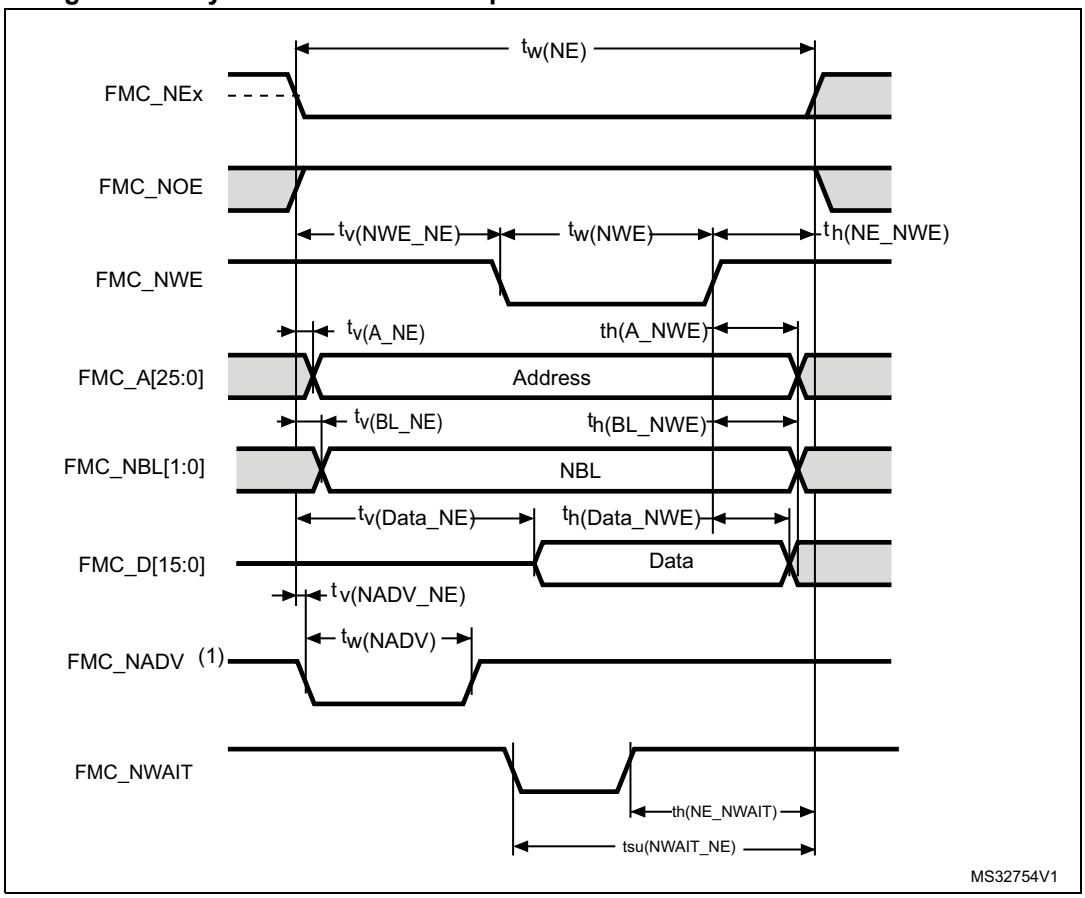
1. Guaranteed by characterization results.

**Table 58. Asynchronous non-multiplexed SRAM/PSRAM/NOR read - NWAIT timings(1)(2)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{w(NE)}$ | FMC_NE low time | $7T_{fmc_ker_ck}$-0.5 | $7T_{fmc_ker_ck}$+1 | ns |
| $t_{w(NOE)}$ | FMC_NWE low time | $6T_{fmc_ker_ck}$-0.5 | $6T_{fmc_ker_ck}$+1 | |
| $t_{w(NWAIT)}$ | FMC_NWAIT low time | $T_{fmc_ker_ck}$ | - | |
| $t_{su(NWAIT_NE)}$ | FMC_NWAIT valid before FMC_NEx high | $7T_{fmc_ker_ck}$+2 | - | |
| $t_{h(NE_NWAIT)}$ | FMC_NEx hold time after FMC_NWAIT invalid | $5T_{fmc_ker_ck}$ | - | |

1. Guaranteed by characterization results.
2. $N_{WAIT}$ pulse width is equal to 1 AHB cycle.

**Figure 26. Asynchronous non-multiplexed SRAM/PSRAM/NOR write waveforms**




1. Mode 2/B, C and D only. In Mode 1, FMC_NADV is not used.

**Table 59. Asynchronous non-multiplexed SRAM/PSRAM/NOR write timings(1)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{w(NE)}$ | FMC_NE low time | $4T_{fmc_ker_ck}$-0.5 | $4T_{fmc_ker_ck}$+1 | ns |
| $t_{v(NWE_NE)}$ | FMC_NEx low to FMC_NWE low | $T_{fmc_ker_ck}$-0.5 | $T_{fmc_ker_ck}$+1 | |
| $t_{w(NWE)}$ | FMC_NWE low time | $T_{fmc_ker_ck}$-0.5 | $T_{fmc_ker_ck}$+0.5 | |
| $t_{h(NE_NWE)}$ | FMC_NWE high to FMC_NE high hold time | $2T_{fmc_ker_ck}$-0.5 | - | |
| $t_{v(A_NE)}$ | FMC_NEx low to FMC_A valid | - | 0 | |
| $t_{h(A_NWE)}$ | Address hold time after FMC_NWE high | $3T_{fmc_ker_ck}$-1 | - | |
| $t_{v(BL_NE)}$ | FMC_NEx low to FMC_BL valid | - | 0.5 | |
| $t_{h(BL_NWE)}$ | FMC_BL hold time after FMC_NWE high | $3T_{fmc_ker_ck}$-0.5 | - | |
| $t_{v(Data_NE)}$ | Data to FMC_NEx low to Data valid | - | 2.5 | |
| $t_{h(Data_NWE)}$ | Data hold time after FMC_NWE high | $3T_{fmc_ker_ck}$-1 | - | |
| $t_{v(NADV_NE)}$ | FMC_NEx low to FMC_NADV low | - | 0.5 | |
| $t_{w(NADV)}$ | FMC_NADV low time | - | $T_{fmc_ker_ck}$+0.5 | |

1. Guaranteed by characterization results.

**Table 60. Asynchronous non-multiplexed SRAM/PSRAM/NOR write - NWAIT timings(1)(2)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{w(NE)}$ | FMC_NE low time | $8T_{fmc_ker_ck}$-0.5 | $8T_{fmc_ker_ck}$+0.5 | ns |
| $t_{w(NWE)}$ | FMC_NWE low time | $5T_{fmc_ker_ck}$-0.5 | $5T_{fmc_ker_ck}$+1 | |
| $t_{su(NWAIT_NE)}$ | FMC_NWAIT valid before FMC_NEx high | $8T_{fmc_ker_ck}$+4 | - | |
| $t_{h(NE_NWAIT)}$ | FMC_NEx hold time after FMC_NWAIT invalid | $6T_{fmc_ker_ck}$ | - | |

1. Guaranteed by characterization results.
2. $N_{WAIT}$ pulse width is equal to 1 AHB cycle.

**Figure 27. Asynchronous multiplexed PSRAM/NOR read waveforms**

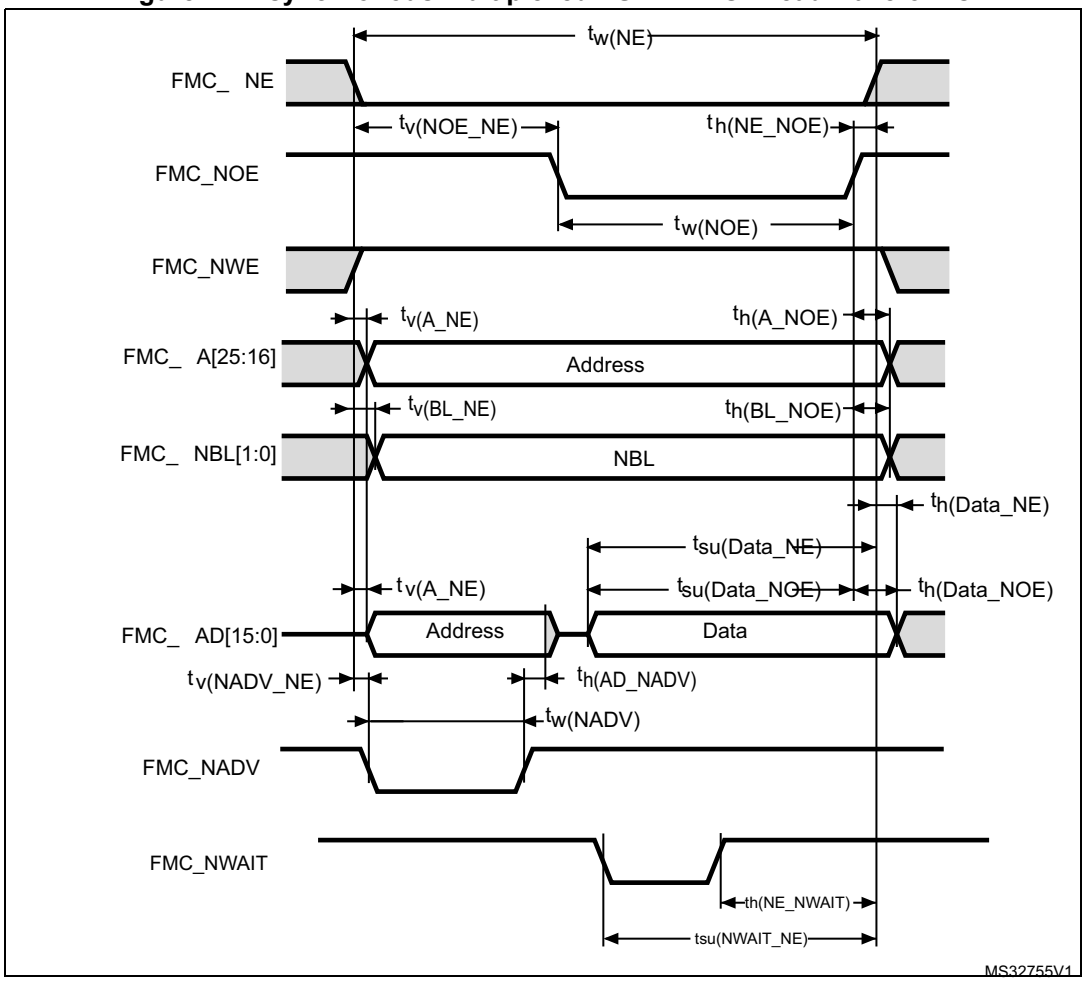


**Table 61. Asynchronous multiplexed PSRAM/NOR read timings(1)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{w(NE)}$ | FMC_NE low time | $4T_{fmc_ker_ck}$-0.5 | $4T_{fmc_ker_ck}$+1 | ns |
| $t_{v(NOE_NE)}$ | FMC_NEx low to FMC_NOE low | $2T_{fmc_ker_ck}$-0.5 | $2T_{fmc_ker_ck}$+1 | |
| $t_{tw(NOE)}$ | FMC_NOE low time | $T_{fmc_ker_ck}$-0.5 | $T_{fmc_ker_ck}$+0.5 | |
| $t_{h(NE_NOE)}$ | FMC_NOE high to FMC_NE high hold time | $T_{fmc_ker_ck}$-1 | - | |
| $t_{v(A_NE)}$ | FMC_NEx low to FMC_A valid | - | 3 | |
| $t_{v(NADV_NE)}$ | FMC_NEx low to FMC_NADV low | 0.5 | 1.5 | |
| $t_{w(NADV)}$ | FMC_NADV low time | $T_{fmc_ker_ck}$ | $T_{fmc_ker_ck}$+1 | |
| $t_{h(AD_NADV)}$ | FMC_AD(address) valid hold time after FMC_NADV high | $T_{fmc_ker_ck}$-3 | - | |
| $t_{h(A_NOE)}$ | Address hold time after FMC_NOE high | Address held until next read operation | - | |
| $t_{su(Data_NE)}$ | Data to FMC_NEx high setup time | $T_{fmc_ker_ck}$+15 | - | |
| $t_{su(Data_NOE)}$ | Data to FMC_NOE high setup time | 16 | - | |
| $t_{h(Data_NE)}$ | Data hold time after FMC_NEx high | 0 | - | |
| $t_{h(Data_NOE)}$ | Data hold time after FMC_NOE high | 0 | - | |

1. Guaranteed by characterization results.

**Table 62. Asynchronous multiplexed PSRAM/NOR read-NWAIT timings(1)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{w(NE)}$ | FMC_NE low time | $7T_{fmc_ker_ck}$-0.5 | $8T_{fmc_ker_ck}$+1 | ns |
| $t_{w(NOE)}$ | FMC_NWE low time | $5T_{fmc_ker_ck}$-0.5 | $6T_{fmc_ker_ck}$+1 | |
| $t_{su(NWAIT_NE)}$ | FMC_NWAIT valid before FMC_NEx high | $7T_{fmc_ker_ck}$+2 | - | |
| $t_{h(NE_NWAIT)}$ | FMC_NEx hold time after FMC_NWAIT invalid | $5T_{fmc_ker_ck}$ | - | |

1. Guaranteed by characterization results.

**Figure 28. Asynchronous multiplexed PSRAM/NOR write waveforms**

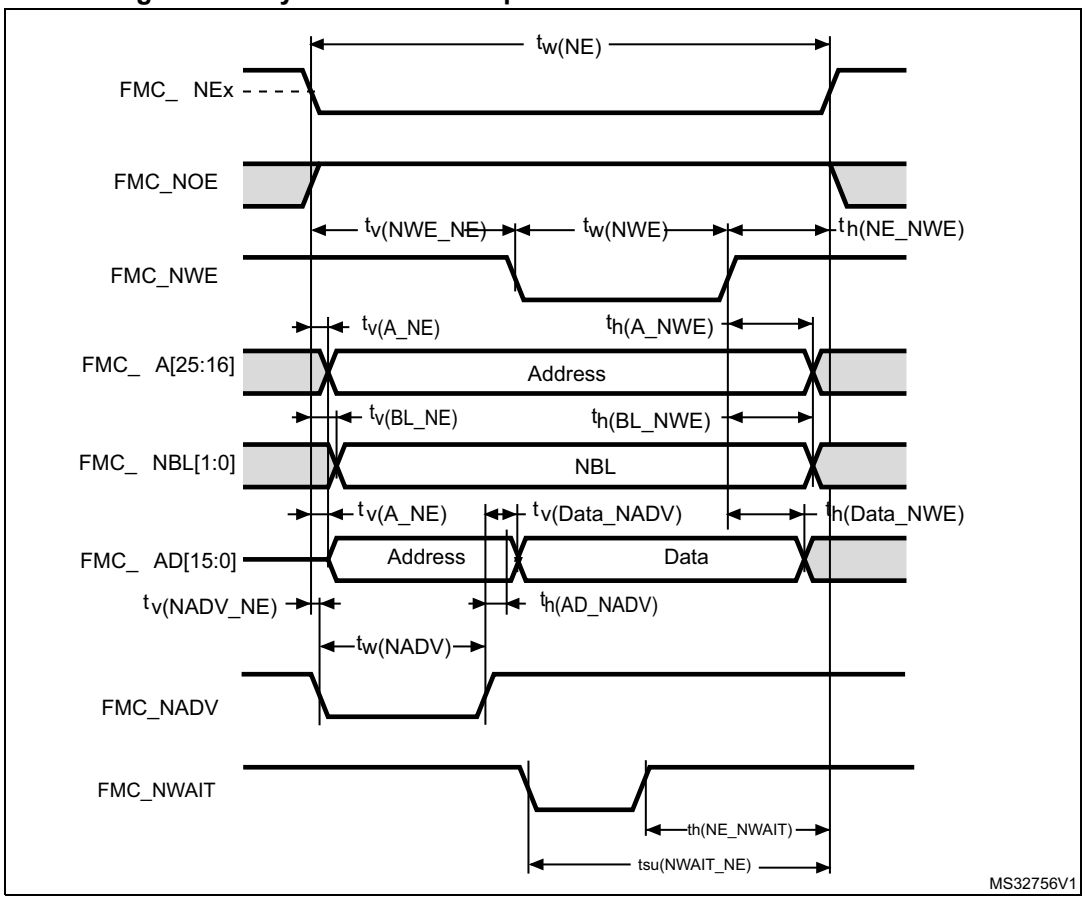


**Table 63. Asynchronous multiplexed PSRAM/NOR write timings(1)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{w(NE)}$ | FMC_NE low time | $5T_{fmc_ker_ck}$-0.5 | $5T_{fmc_ker_ck}$+1 | ns |
| $t_{v(NWE_NE)}$ | FMC_NEx low to FMC_NWE low | $T_{fmc_ker_ck}$-0.5 | $T_{fmc_ker_ck}$+1 | |
| $t_{w(NWE)}$ | FMC_NWE low time | $2T_{fmc_ker_ck}$-1 | $2T_{fmc_ker_ck}$+0.5 | |
| $t_{h(NE_NWE)}$ | FMC_NWE high to FMC_NE high hold time | $2T_{fmc_ker_ck}$-0.5 | - | |
| $t_{v(A_NE)}$ | FMC_NEx low to FMC_A valid | - | 0.5 | |
| $t_{v(NADV_NE)}$ | FMC_NEx low to FMC_NADV low | 0 | 1 | |
| $t_{w(NADV)}$ | FMC_NADV low time | $T_{fmc_ker_ck}$+0.5 | $T_{fmc_ker_ck}$+1 | |
| $t_{h(AD_NADV)}$ | FMC_AD(address) valid hold time after FMC_NADV high | $T_{fmc_ker_ck}$+0.5 | - | |
| $t_{h(A_NWE)}$ | Address hold time after FMC_NWE high | Address held until next write operation | - | |
| $t_{h(BL_NWE)}$ | FMC_BL hold time after FMC_NWE high | $3T_{fmc_ker_ck}$+0.5 | - | |
| $t_{v(BL_NE)}$ | FMC_NEx low to FMC_BL valid | - | 0.5 | |
| $t_{v(Data_NADV)}$ | FMC_NADV high to Data valid | - | $T_{fmc_ker_ck}$+4 | |
| $t_{h(Data_NWE)}$ | Data hold time after FMC_NWE high | $3T_{fmc_ker_ck}$+0.5 | - | |

1. Guaranteed by characterization results.

**Table 64. Asynchronous multiplexed PSRAM/NOR write-NWAIT timings(1)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{w(NE)}$ | FMC_NE low time | $9T_{fmc_ker_ck}$-0.5 | $9T_{fmc_ker_ck}$+0.5 | ns |
| $t_{w(NWE)}$ | FMC_NWE low time | $6T_{fmc_ker_ck}$-0.5 | $6T_{fmc_ker_ck}$+1 | |
| $t_{su(NWAIT_NE)}$ | FMC_NWAIT valid before FMC_NEx high | $8T_{fmc_ker_ck}$+4 | - | |
| $t_{h(NE_NWAIT)}$ | FMC_NEx hold time after FMC_NWAIT invalid | $6T_{fmc_ker_ck}$ | - | |

1. Guaranteed by characterization results.

### Synchronous waveforms and timings

*Figure 29* through *Figure 32* represent synchronous waveforms and *Table 65* through *Table 68* provide the corresponding timings. The results shown in these tables are obtained with the following FMC configuration:

- BurstAccessMode = FMC_BurstAccessMode_Enable
- MemoryType = FMC_MemoryType_CRAM
- WriteBurst = FMC_WriteBurst_Enable
- CLKDivision = 1
- DataLatency = 1 for NOR Flash; DataLatency = 0 for PSRAM

In all the timing tables, the $T_{fmc_ker_ck}$ is the fmc_ker_ck clock period, with the following FMC_CLK maximum values:

- For 2.7 V < $V_{DD}$ < 3.6 V, FMC_CLK = 130 MHz at 20 pF
- For 1.71 V < $V_{DD}$ < 1.9 V, FMC_CLK = 95 MHz at 20 pF

**Figure 29. Synchronous multiplexed NOR/PSRAM read timings**

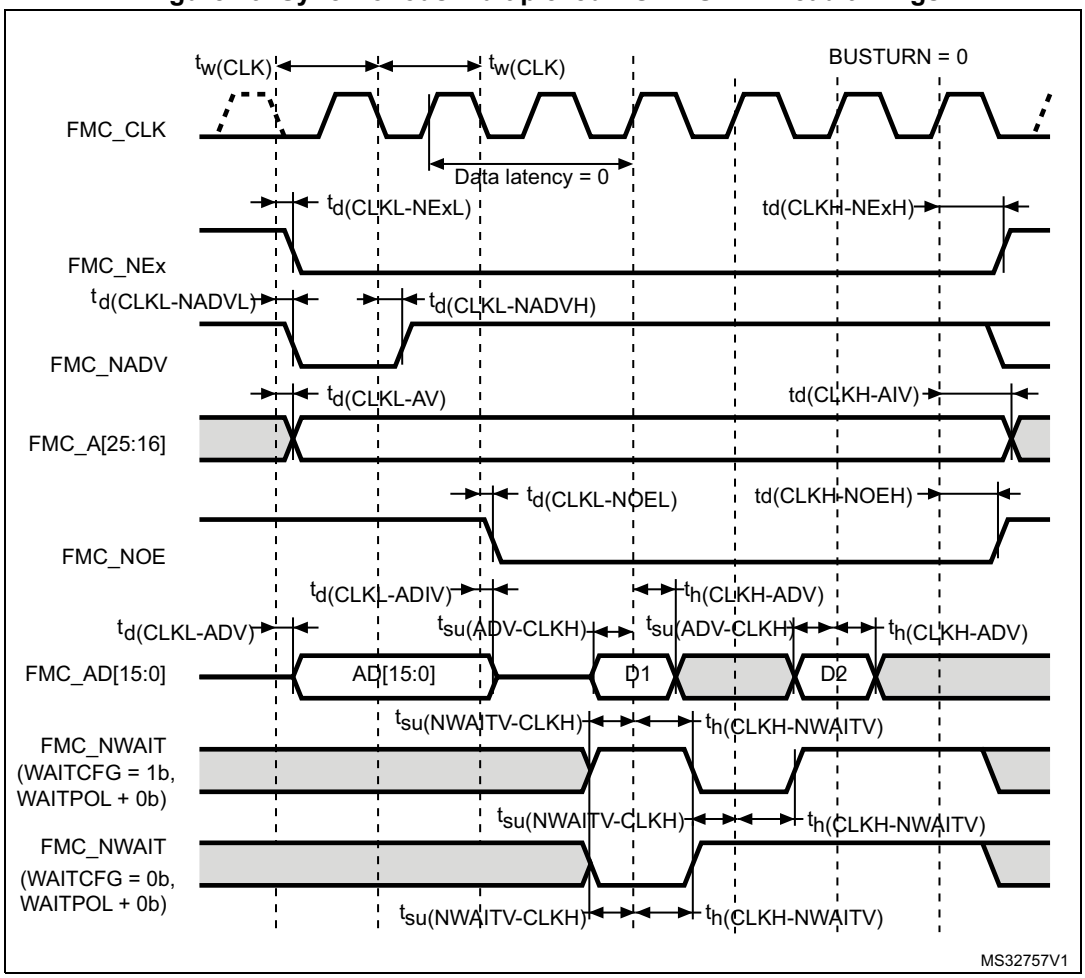


**Table 65. Synchronous multiplexed NOR/PSRAM read timings(1)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{w(CLK)}$ | FMC_CLK period | $R \times T_{fmc_ker_ck} - 1$(2) | - | ns |
| $t_{d(CLKL-NExL)}$ | FMC_CLK low to FMC_NEx low (x=0..2) | - | 1 | |
| $t_{d(CLKH_NExH)}$ | FMC_CLK high to FMC_NEx high (x= 0…2) | $R \times T_{fmc_ker_ck}/2+0.5$(2) | - | |
| $t_{d(CLKL-NADVL)}$ | FMC_CLK low to FMC_NADV low | - | 1.5 | |
| $t_{d(CLKL-NADVH)}$ | FMC_CLK low to FMC_NADV high | 1 | - | |
| $t_{d(CLKL-AV)}$ | FMC_CLK low to FMC_Ax valid (x=16…25) | - | 1 | |
| $t_{d(CLKH-AIV)}$ | FMC_CLK high to FMC_Ax invalid (x=16…25) | $R \times T_{fmc_ker_ck}/2+1.5$(2) | - | |
| $t_{d(CLKL-NOEL)}$ | FMC_CLK low to FMC_NOE low | - | 2 | |
| $t_{d(CLKH-NOEH)}$ | FMC_CLK high to FMC_NOE high | $R \times T_{fmc_ker_ck}/2+0.5$(2) | - | |
| $t_{d(CLKL-ADV)}$ | FMC_CLK low to FMC_AD[15:0] valid | - | 1.5 | |
| $t_{d(CLKL-ADIV)}$ | FMC_CLK low to FMC_AD[15:0] invalid | 1 | - | |
| $t_{su(ADV-CLKH)}$ | FMC_A/D[15:0] valid data before FMC_CLK high | 3 | - | |
| $t_{h(CLKH-ADV)}$ | FMC_A/D[15:0] valid data after FMC_CLK high | 1 | - | |
| $t_{su(NWAIT-CLKH)}$ | FMC_NWAIT valid before FMC_CLK high | 3 | - | |
| $t_{h(CLKH-NWAIT)}$ | FMC_NWAIT valid after FMC_CLK high | 1.5 | - | |

1. Guaranteed by characterization results.
2. Clock ratio R = (FMC_CLK period / fmc_ker_ck period).

**Figure 30. Synchronous multiplexed PSRAM write timings**

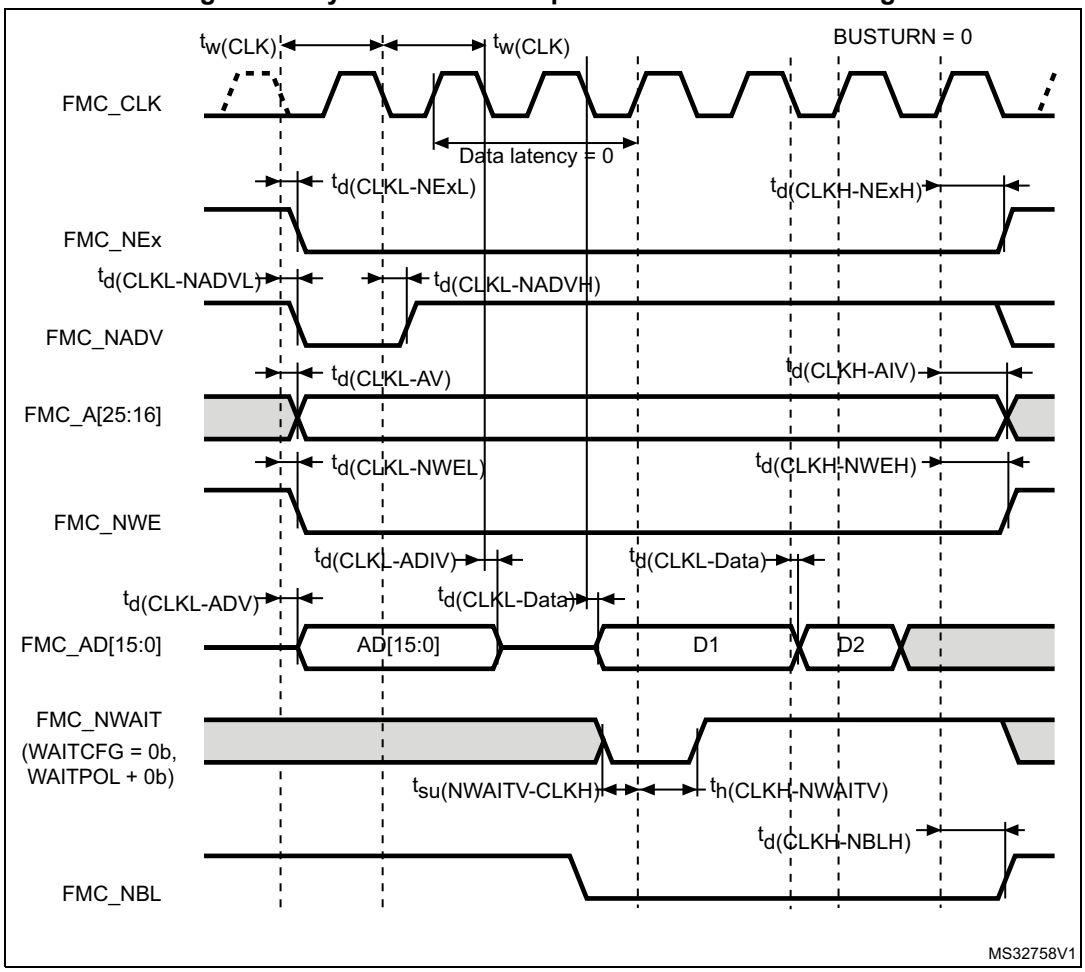


**Table 66. Synchronous multiplexed PSRAM write timings(1)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{w(CLK)}$ | FMC_CLK period, $V_{DD}$ range = 2.7 to 3.6 V | $R \times T_{fmc_ker_ck} - 1$(2) | - | ns |
| $t_{d(CLKL-NExL)}$ | FMC_CLK low to FMC_NEx low (x=0..2) | - | 1 | |
| $t_{d(CLKH-NExH)}$ | FMC_CLK high to FMC_NEx high (x= 0…2) | $R \times T_{fmc_ker_ck}/2+0.5$(2) | - | |
| $t_{d(CLKL-NADVL)}$ | FMC_CLK low to FMC_NADV low | - | 1.5 | |
| $t_{d(CLKL-NADVH)}$ | FMC_CLK low to FMC_NADV high | 1 | - | |
| $t_{d(CLKL-AV)}$ | FMC_CLK low to FMC_Ax valid (x=16…25) | - | 1 | |
| $t_{d(CLKH-AIV)}$ | FMC_CLK high to FMC_Ax invalid (x=16…25) | $R \times T_{fmc_ker_ck}/2+1.5$(2) | - | |
| $t_{d(CLKL-NWEL)}$ | FMC_CLK low to FMC_NWE low | - | 1 | |
| $t_{(CLKH-NWEH)}$ | FMC_CLK high to FMC_NWE high | $R \times T_{fmc_ker_ck}/2+0.5$(2) | - | |
| $t_{d(CLKL-ADV)}$ | FMC_CLK low to FMC_AD[15:0] valid | - | 1.5 | |
| $t_{d(CLKL-ADIV)}$ | FMC_CLK low to FMC_AD[15:0] invalid | 1 | - | |
| $t_{d(CLKL-DATA)}$ | FMC_A/D[15:0] valid data after FMC_CLK low | - | 3 | |
| $t_{d(CLKL-NBLL)}$ | FMC_CLK low to FMC_NBL low | 1 | - | |
| $t_{d(CLKH-NBLH)}$ | FMC_CLK high to FMC_NBL high | $R \times T_{fmc_ker_ck}/2+0.5$(2) | - | |
| $t_{su(NWAIT-CLKH)}$ | FMC_NWAIT valid before FMC_CLK high | 3 | - | |
| $t_{h(CLKH-NWAIT)}$ | FMC_NWAIT valid after FMC_CLK high | 1.5 | - | |

1. Guaranteed by characterization results.
2. Clock ratio R = (FMC_CLK period / fmc_ker_ck period).

**Figure 31. Synchronous non-multiplexed NOR/PSRAM read timings**

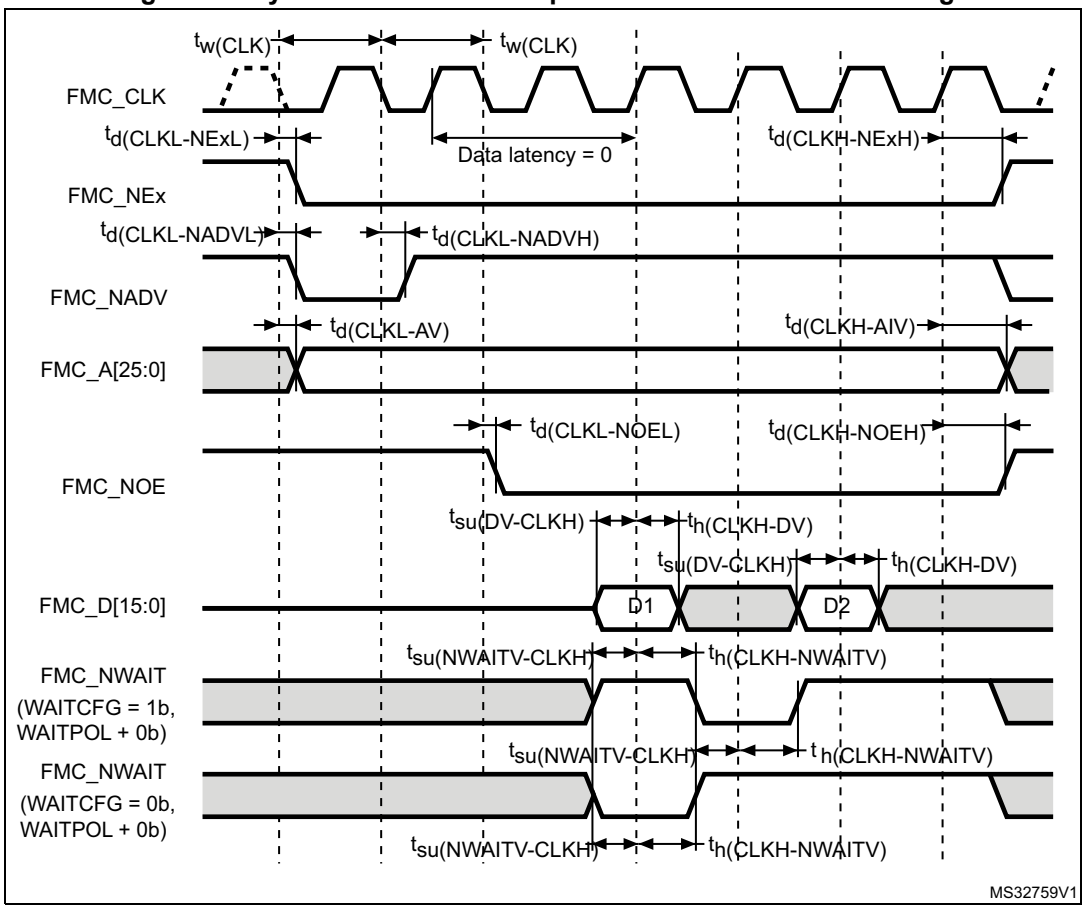



**Table 67. Synchronous non-multiplexed NOR/PSRAM read timings(1)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{w(CLK)}$ | FMC_CLK period | $R \times T_{fmc_ker_ck} - 1$(2) | - | ns |
| $t_{(CLKL-NExL)}$ | FMC_CLK low to FMC_NEx low (x=0..2) | - | 1 | |
| $t_{d(CLKH-NExH)}$ | FMC_CLK high to FMC_NEx high (x= 0…2) | $R \times T_{fmc_ker_ck}/2 + 0.5$(2) | - | |
| $t_{d(CLKL-NADVL)}$ | FMC_CLK low to FMC_NADV low | - | 1.5 | |
| $t_{d(CLKL-NADVH)}$ | FMC_CLK low to FMC_NADV high | 1 | - | |
| $t_{d(CLKL-AV)}$ | FMC_CLK low to FMC_Ax valid (x=16…25) | - | 1 | |
| $t_{d(CLKH-AIV)}$ | FMC_CLK high to FMC_Ax invalid (x=16…25) | $R \times T_{fmc_ker_ck}/2 + 1.5$(2) | - | |
| $t_{d(CLKL-NOEL)}$ | FMC_CLK low to FMC_NOE low | - | 2 | |
| $t_{d(CLKH-NOEH)}$ | FMC_CLK high to FMC_NOE high | $R \times T_{fmc_ker_ck}/2 + 1.5$(2) | - | |
| $t_{su(DV-CLKH)}$ | FMC_D[15:0] valid data before FMC_CLK high | 3 | - | |
| $t_{h(CLKH-DV)}$ | FMC_D[15:0] valid data after FMC_CLK high | 1 | - | |
| $t_{(NWAIT-CLKH)}$ | FMC_NWAIT valid before FMC_CLK high | 3 | - | |
| $t_{h(CLKH-NWAIT)}$ | FMC_NWAIT valid after FMC_CLK high | 1.5 | - | |

1. Guaranteed by characterization results.

2. Clock ratio R = (FMC_CLK period / fmc_ker_ck period).

**Figure 32. Synchronous non-multiplexed PSRAM write timings**

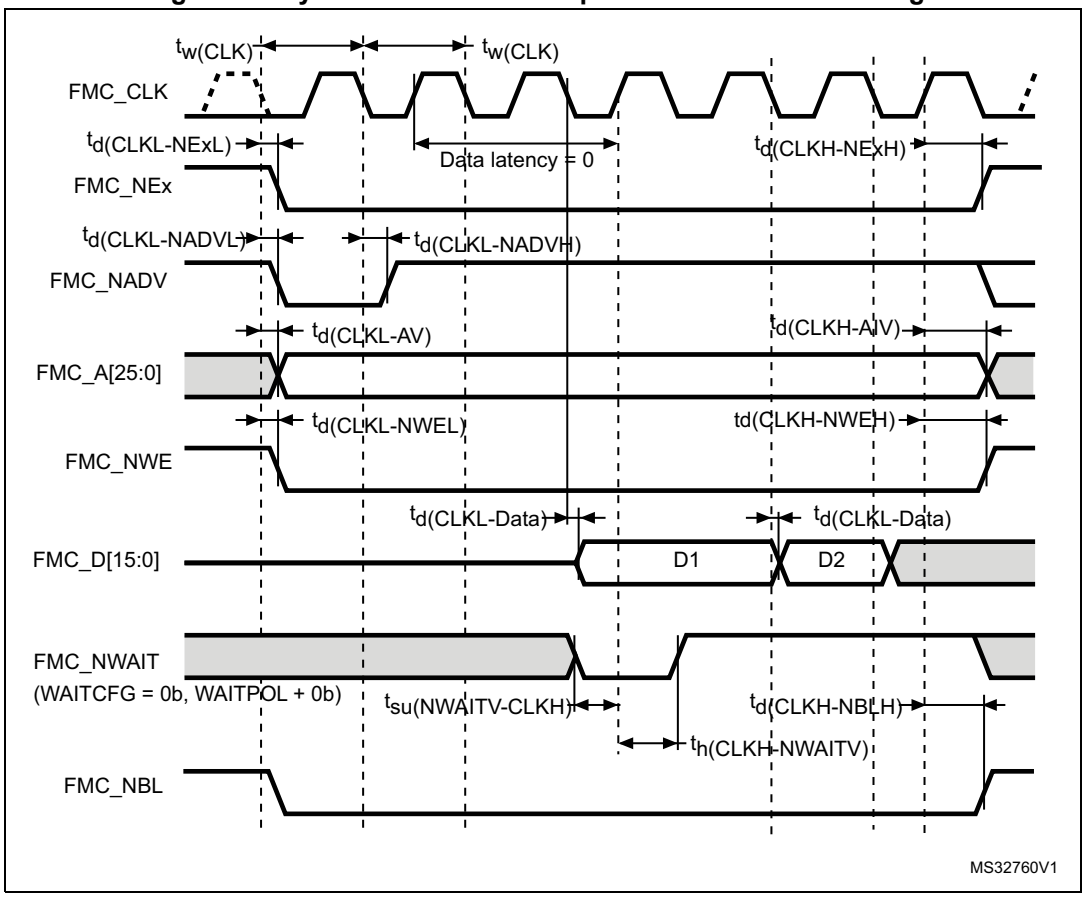


**Table 68. Synchronous non-multiplexed PSRAM write timings(1)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{(CLK)}$ | FMC_CLK period | $R \times T_{fmc_ker_ck}$ -1(2) | - | ns |
| $t_{d(CLKL-NExL)}$ | FMC_CLK low to FMC_NEx low (x=0..2) | - | 1 | |
| $t_{(CLKH-NExH)}$ | FMC_CLK high to FMC_NEx high (x= 0…2) | $R \times T_{fmc_ker_ck}/2+0.5$(2) | - | |
| $t_{d(CLKL-NADVL)}$ | FMC_CLK low to FMC_NADV low | - | 1.5 | |
| $t_{d(CLKL-NADVH)}$ | FMC_CLK low to FMC_NADV high | 1 | - | |
| $t_{d(CLKL-AV)}$ | FMC_CLK low to FMC_Ax valid (x=16…25) | - | 1 | |
| $t_{d(CLKH-AIV)}$ | FMC_CLK high to FMC_Ax invalid (x=16…25) | $R \times T_{fmc_ker_ck}/2+1.5$(2) | - | |
| $t_{d(CLKL-NWEL)}$ | FMC_CLK low to FMC_NWE low | - | 1 | |
| $t_{d(CLKH-NWEH)}$ | FMC_CLK high to FMC_NWE high | $R \times T_{fmc_ker_ck}/2+0.5$(2) | - | |
| $t_{d(CLKL-Data)}$ | FMC_D[15:0] valid data after FMC_CLK low | - | 3 | |
| $t_{d(CLKL-NBLL)}$ | FMC_CLK low to FMC_NBL low | 1 | - | |
| $t_{d(CLKH-NBLH)}$ | FMC_CLK high to FMC_NBL high | $R \times T_{fmc_ker_ck}/2+0.5$(2) | - | |
| $t_{su(NWAIT-CLKH)}$ | FMC_NWAIT valid before FMC_CLK high | 3 | - | |
| $t_{h(CLKH-NWAIT)}$ | FMC_NWAIT valid after FMC_CLK high | 1.5 | - | |

1. Guaranteed by characterization results.
2. Clock ratio R = (FMC_CLK period / fmc_ker_ck period).

### NAND controller waveforms and timings

*Figure 33* through *Figure 36* represent synchronous waveforms, and *Table 69* and *Table 70* provide the corresponding timings. The results shown in this table are obtained with the following FMC configuration:

- FMC_SetupTime = 0x01
- FMC_WaitSetupTime = 0x03
- FMC_HoldSetupTime = 0x02
- FMC_HiZSetupTime = 0x01
- Bank = FMC_Bank_NAND
- MemoryDataWidth = FMC_MemoryDataWidth_16b
- ECC = FMC_ECC_Enable
- ECCPageSize = FMC_ECCPageSize_512Bytes
- TCLRSetupTime = 0
- TARSetupTime = 0
- $C_L$ = 30 pF

In all timing tables, the $T_{fmc_ker_ck}$ is the fmc_ker_ck clock period.

**Figure 33. NAND controller waveforms for read access**

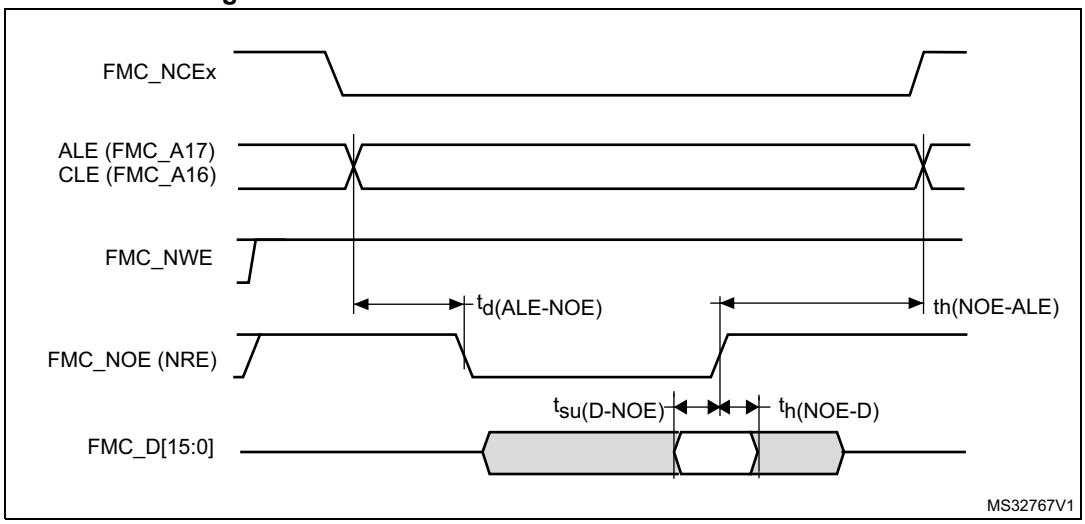



**Figure 34. NAND controller waveforms for write access**

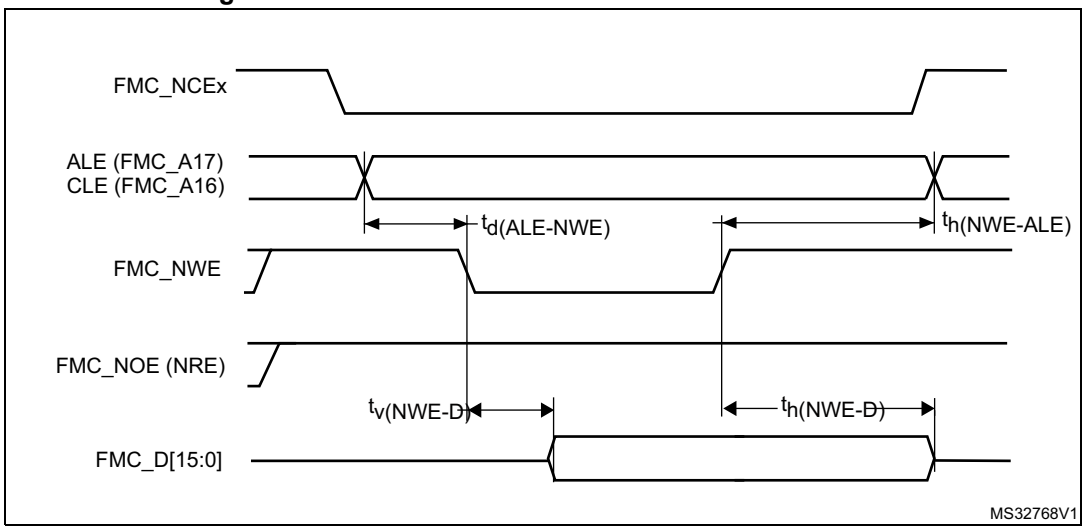


**Figure 35. NAND controller waveforms for common memory read access**

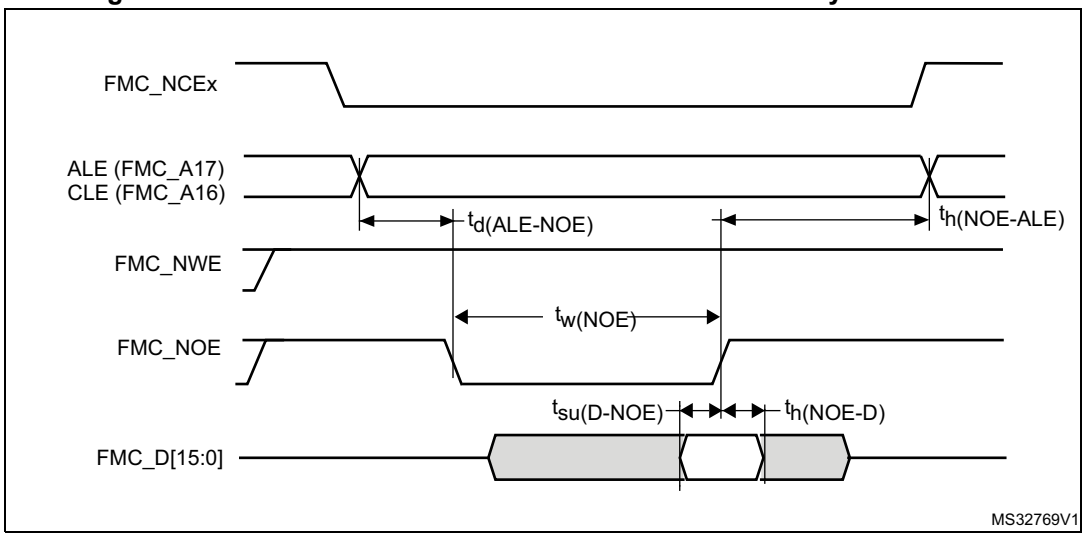



**Figure 36. NAND controller waveforms for common memory write access**

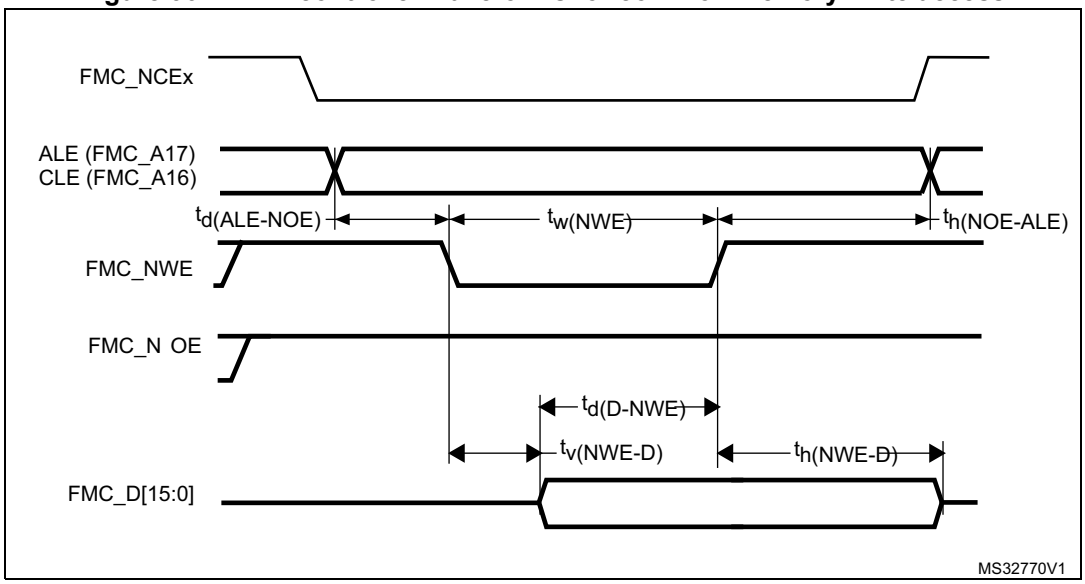



**Table 69. Switching characteristics for NAND Flash read cycles(1)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{w(N0E)}$ | FMC_NOE low width | $4T_{fmc_ker_ck}$-1 | $4T_{fmc_ker_ck}$+1 | ns |
| $t_{su(D-NOE)}$ | FMC_D[15-0] valid data before FMC_NOE high | 11 | - | |
| $t_{h(NOE-D)}$ | FMC_D[15-0] valid data after FMC_NOE high | 0 | - | |
| $t_{d(ALE-NOE)}$ | FMC_ALE valid before FMC_NOE low | - | $2T_{fmc_ker_ck}$+1 | |
| $t_{h(NOE-ALE)}$ | FMC_NWE high to FMC_ALE invalid | $3T_{fmc_ker_ck}$+0.5 | - | |

1. Guaranteed by characterization results.

**Table 70. Switching characteristics for NAND Flash write cycles(1)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{w(NWE)}$ | FMC_NWE low width | $4T_{fmc_ker_ck}$-1 | $4T_{fmc_ker_ck}$+1 | ns |
| $t_{v(NWE-D)}$ | FMC_NWE low to FMC_D[15-0] valid | 0 | - | |
| $t_{h(NWE-D)}$ | FMC_NWE high to FMC_D[15-0] invalid | $3T_{fmc_ker_ck}$ | - | |
| $t_{d(D-NWE)}$ | FMC_D[15-0] valid before FMC_NWE high | $4T_{fmc_ker_ck}$-3 | - | |
| $t_{d(ALE-NWE)}$ | FMC_ALE valid before FMC_NWE low | - | $2T_{fmc_ker_ck}$+1 | |
| $t_{h(NWE-ALE)}$ | FMC_NWE high to FMC_ALE invalid | $3T_{fmc_ker_ck}$+0.5 | - | |

1. Guaranteed by characterization results.

## 6.3.20 QUADSPI interface characteristics

Unless otherwise specified, the parameters given in *Table 71* and *Table 72* for QUADSPI are derived from tests performed under the ambient temperature, $F_{axiss_ck}$ frequency and $V_{DD}$ supply voltage conditions summarized in *Table 13: General operating conditions*, with the following configuration:

- Output speed is set to OSPEEDRy[1:0] = 11
- Measurement points are done at CMOS levels: $0.5 \times V_{DD}$
- I/O compensation cell enabled
- HSLV activated when $V_{DD} \leq 2.7$ V

Refer to *Section 6.3.17: I/O port characteristics* for more details on the input/output alternate function characteristics.

**Table 71. QUADSPI characteristics in SDR mode**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $F_{ck1/t(CLK)}$ | QUADSPI clock frequency | 2.7 V ≤ $V_{DD}$ < 3.6 V<br>$C_L$ = 20 pF | - | - | 166 | MHz |
| | | 1.71 V < $V_{DD}$ <3.6 V<br>$C_L$ = 15 pF | - | - | 90 | |
| $t_{w(CLKH)}$ | QUADSPI clock high and low time | - | $t_{(CLK)}/2$ - 0.5 | - | $t_{(CLK)}/2$ + 0.5 | ns |
| $t_{w(CLKL)}$ | | | $t_{(CLK)}/2$ - 0.5 | - | $t_{(CLK)}/2$ + 0.5 | |
| $t_{s(IN)}$ | Data input setup time | - | 1.25 | - | - | |
| $t_{h(IN)}$ | Data input hold time | - | 2.75 | - | - | |
| $t_{v(OUT)}$ | Data output valid time | - | - | 1 | 1.5 | |
| $t_{h(OUT)}$ | Data output hold time | - | 0 | - | - | |

**Table 72. QUADSPI characteristics in DDR mode**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $F_{ck1/t(CLK)}$ | QUADSPI clock frequency | 2.7 V < $V_{DD}$ < 3.6 V CL=20 pF | - | - | 90 | MHz |
| | | 1.71 V < $V_{DD}$ < 3.6 V CL=15 pF | - | - | 90 | |
| $t_{w(CLKH)}$ | QUADSPI clock high and low time | - | $t_{(CLK)}/2$ - 0.5 | - | $t_{(CLK)}/2$ + 0.5 | ns |
| $t_{w(CLKL)}$ | | - | $t_{(CLK)}/2$ - 0.5 | - | $t_{(CLK)}/2$ + 0.5 | |
| $t_{sr(IN)}$, $t_{sf(IN)}$ | Data input setup time | - | 0.5 | - | - | |
| $t_{hr(IN)}$, $t_{hf(IN)}$ | Data input hold time | - | 2.75 | - | - | |
| $t_{vr(OUT)}$, $t_{vf(OUT)}$ | Data output valid time | DHHC = 0 | - | 1 | 1.5 | |
| | | DHHC = 1 Pres = 1, 2... | - | $t_{(CLK)}/4+1$ | $t_{(CLK)}/4+1.5$ | |
| $t_{hr(OUT)}$, $t_{hf(OUT)}$ | Data output hold time | DHHC = 0 | 0 | - | - | |
| | | DHHC = 1 Pres = 1, 2... | $t_{(CLK)}/4$ | - | - | |

**Figure 37. QUADSPI timing diagram - SDR mode**

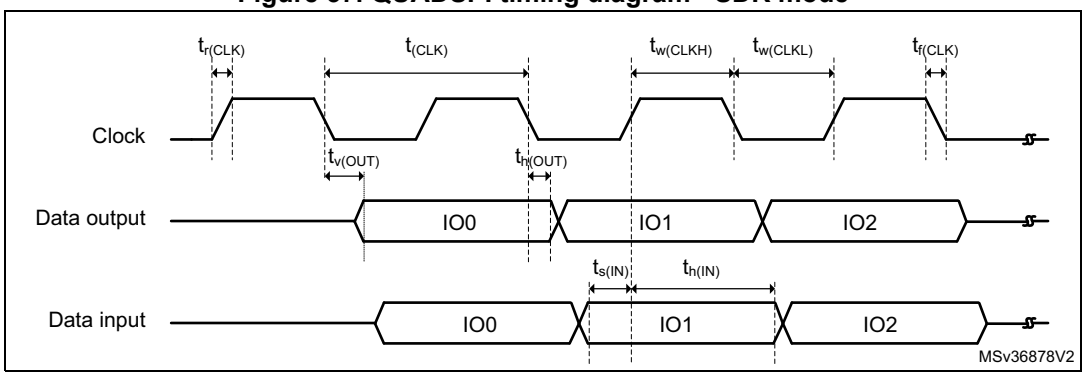
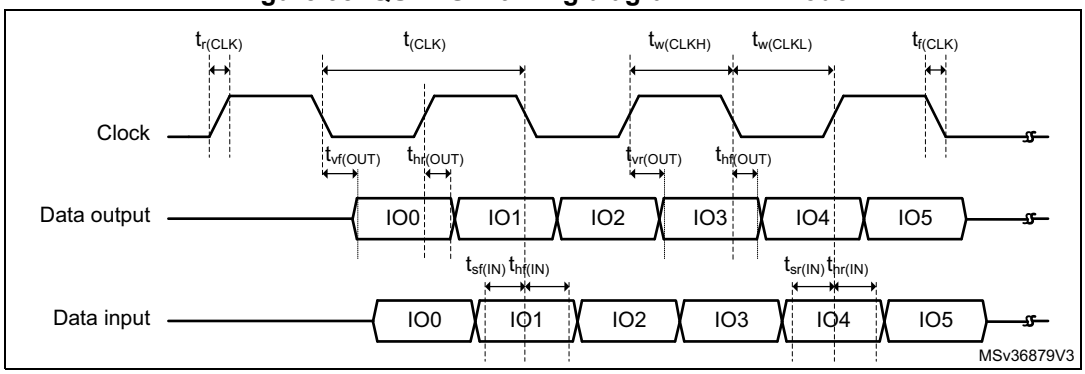



**Figure 38. QUADSPI timing diagram - DDR mode**



### 6.3.21 Delay block (DLYB) characteristics

Unless otherwise specified, the parameters given in *Table 73* for the delay block are derived from tests performed under the ambient temperature, $f_{rcc_c_ck}$ frequency and $V_{DD}$ supply voltage summarized in *Table 13: General operating conditions*.

**Table 73. Dynamics characteristics: Delay block characteristics**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $t_{init}$ | Initial delay | - | 900 | 1200 | 1500 | ps |
| $t_{\Delta}$ | Unit Delay | - | 42 | 46 | 50 | |

### 6.3.22 16-bit ADC characteristics

Unless otherwise specified, the parameters given in *Table 74* are derived from tests performed under the ambient temperature, $f_{pclk2}$ frequency and $V_{DDA}$ supply voltage conditions summarized in *Table 13: General operating conditions*.

**Table 74. ADC characteristics(1)(2)**

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| $V_{DDA}$ | Analog power supply | - | | 1.62 | - | 3.6 | V |
| $V_{REF+}$ | Positive reference voltage | $V_{DDA} \geq 2$ V | | 2 | - | $V_{DDA}$ | |
| | | $V_{DDA} < 2$ V | | $V_{DDA}$ | | | |
| $V_{REF-}$ | Negative reference voltage | - | | $V_{SSA}$ | | | |
| $f_{ADC}$ | ADC clock frequency | 2 V ≤ $V_{DDA}$ ≤3.3 V | BOOST = 1 | 0.12 | - | 36 | MHz |
| | | | BOOST = 0 | 0.12 | - | 20 | |

Table 74. ADC characteristics(1)(2) (continued)

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $f_S$ | Sampling rate for Fast channels, BOOST = 1, $f_{ADC}$ = 36 MHz, sampling time = 1.5 cycles | 16-bit resolution | - | - | 3.60 | MSPS |
| | | 14-bit resolution | - | - | 4.00 | |
| | | 12-bit resolution | - | - | 4.50 | |
| | | 10-bit resolution | - | - | 5.00 | |
| | | 8-bit resolution | - | - | 6.00 | |
| | Sampling rate for Fast channels, BOOST = 0, $f_{ADC}$ = 20 MHz, sampling time = 1.5 cycles | 16-bit resolution | - | - | 2.00 | |
| | | 14-bit resolution | - | - | 2.20 | |
| | | 12-bit resolution | - | - | 2.50 | |
| | | 10-bit resolution | - | - | 2.80 | |
| | | 8-bit resolution | - | - | 3.30 | |
| | Sampling rate for Slow channels, BOOST = 1, $f_{ADC}$ = 28 MHz, sampling time = 2.5 cycles | 16-bit resolution | - | - | 2.55 | |
| | | 14-bit resolution | - | - | 2.80 | |
| | | 12-bit resolution | - | - | 3.11 | |
| | | 10-bit resolution | - | - | 3.50 | |
| | | 8-bit resolution | - | - | 4.00 | |
| | Sampling rate for Slow channels, BOOST = 0, $f_{ADC}$ = 20 MHz, sampling time = 2.5 cycles | 16-bit resolution | - | - | 1.82 | |
| | | 14-bit resolution | - | - | 2.00 | |
| | | 12-bit resolution | - | - | 2.22 | |
| | | 10-bit resolution | - | - | 2.50 | |
| | | 8-bit resolution | - | - | 2.86 | |
| $f_{TRIG}$ | External trigger frequency | $f_{ADC}$ = 36 MHz | - | - | 3.6 | MHz |
| | | 16-bit resolution | - | - | 10 | $1/f_{ADC}$ |
| $V_{AIN}$(3) | Conversion voltage range | - | 0 | - | $V_{REF+}$ | V |
| $V_{CMIV}$ | Common mode input voltage | - | $V_{REF}$/2-10% | $V_{REF}$/2 | $V_{REF}$/2+10% | |
| $C_{ADC}$ | Internal sample and hold capacitor | - | - | 4 | - | pF |
| $t_{ADCREG_STUP}$ | ADC LDO startup time | - | - | 5 | 10 | µs |
| $t_{STAB}$ | ADC power-up time | LDO already started | 1 | | | $1/f_{ADC}$ |

**Table 74. ADC characteristics(1)(2) (continued)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $t_{CAL}$ | Offset and linearity calibration time | - | 16384 | | | $1/f_{ADC}$ |
| $t_{OFF_CAL}$ | Offset calibration time | - | 1280 | | | |
| $t_{LATR}$ | Trigger conversion latency for regular and injected channels without aborting the conversion | CKMODE = 00 | 1.5 | 2 | 2.5 | |
| | | CKMODE = 01 | - | - | 2.5 | |
| | | CKMODE = 10 | - | - | 2.5 | |
| | | CKMODE = 11 | - | - | 2.25 | |
| $t_{LATRINJ}$ | Trigger conversion latency for regular and injected channels when a regular conversion is aborted | CKMODE = 00 | 2.5 | 3 | 3.5 | |
| | | CKMODE = 01 | - | - | 3.5 | |
| | | CKMODE = 10 | - | - | 3.5 | |
| | | CKMODE = 11 | - | - | 3.25 | |
| $t_S$ | Sampling time | - | 1.5 | - | 810.5 | |
| $t_{CONV}$ | Total conversion time (including sampling time) | N-bit resolution | $t_s$ + N/2(4) | | | |
| $I_{DDA(ADC)}$ | ADC consumption from $V_{DDA}$ supply (differential) | $F_S$ = 3.6 Msps, BOOST = 1 | - | 1900 | - | µA |
| | | $F_S$ = 1 Msps, BOOST = 0 | - | 460 | - | |
| $I_{DDA(REF)}$ | ADC consumption from $V_{REF+}$ (differential) | $F_S$ = 3.6 Msps, BOOST = 1 | - | 260 | - | |
| | | $F_S$ = 1 Msps, BOOST = 0 | - | 140 | - | |
| $I_{DDA(ADC)}$ | ADC consumption from $V_{DDA}$ supply (single-ended) | $F_S$ = 3.6 Msps, BOOST = 1 | - | 1700 | - | |
| | | $F_S$ = 1 Msps, BOOST = 0 | - | 445 | - | |
| $I_{DDA(REF)}$ | ADC consumption from $V_{REF+}$ supply (single-ended) | $F_S$ = 3.6 Msps, BOOST = 1 | - | 160 | - | |
| | | $F_S$ = 1 Msps, BOOST = 0 | - | 75 | - | |

1. Guaranteed by design.
2. Voltage BOOSTER on ADC switches must be used for $V_{DDA}$ < 2.4 V (switches inside IO).
3. Depending on the package, $V_{REF-}$ can be internally connected to $V_{SSA}$.
4. 9 to 818 cycles @ 14-bit mode.

**Table 75. Minimum sampling time versus RAIN with 47 pF PCB capacitor up to 125 °C and $V_{DDA}$ = 1.6 V(1)**

| Resolution(2) | RAIN (Ω) | Fast channels(3) (ns) | Slow channels(4) (ns) |
|---|---|---|---|
| 16 bits | 47(5) | 107 | 166 |
| 14 bits | 47 | 90.8 | 144 |
| | 68 | 967 | 151 |
| | 100 | 108 | 157 |
| | 150 | 128 | 171 |
| | 220(5) | 161 | 192 |
| 12 bits | 47 | 76.7 | 125 |
| | 68 | 81.5 | 127 |
| | 100 | 89.8 | 134 |
| | 150 | 107 | 146 |
| | 220 | 132 | 169 |
| | 330 | 177 | 205 |
| | 470 | 2.36 | 264 |
| | 680 | 329 | 345 |
| | 1000(5) | 462 | 488 |
| 10 bits | 47 | 62.5 | 103 |
| | 68 | 66.2 | 106 |
| | 100 | 72.7 | 112 |
| | 150 | 85.4 | 121 |
| | 220 | 106 | 137 |
| | 330 | 140 | 168 |
| | 470 | 187 | 209 |
| | 680 | 258 | 279 |
| | 1000 | 367 | 381 |
| | 1500 | 537 | 552 |
| | 2200 | 776 | 786 |
| | 3300 | 1130 | 1140 |
| | 4700(5) | 1600 | 1600 |

**Table 75. Minimum sampling time versus RAIN with 47 pF PCB capacitor up to 125 °C and $V_{DDA}$ = 1.6 V(1) (continued)**

| Resolution(2) | RAIN (Ω) | Fast channels(3) (ns) | Slow channels(4) (ns) |
|---|---|---|---|
| 8 bits | 47 | 48.7 | 82.4 |
| | 68 | 51.4 | 84.6 |
| | 100 | 56.4 | 88.7 |
| | 150 | 65.8 | 95.7 |
| | 220 | 80.4 | 108 |
| | 330 | 106 | 130 |
| | 470 | 139 | 160 |
| | 680 | 189 | 208 |
| | 1000 | 269 | 284 |
| | 1500 | 390 | 405 |
| | 2200 | 562 | 572 |
| | 3300 | 827 | 840 |
| | 4700 | 1170 | 1170 |
| | 6800 | 1670 | 1670 |
| | 10000 | 2440 | 2430 |
| | 15000 | 3660 | 3630 |
| | 2200(5) | 5360 | 5310 |

1. Guaranteed by design.
2. The tolerance is 8 LSB for 16-bit, 4 LSB for 14-bit, 2 LSB for 12-bit, 10-bit and 8-bit conversions.
3. On ADC1, fast channels are PA6, PA7, PB0, PB1, PC4, PC5, PF11, PF12.
   On ADC2, fast channels are PA6, PA7, PB0, PB1, PC4, PC5, PF13, PF14.
4. Slow channels are all ADC inputs except the fast channels.
5. Maximum external input impedance value authorized for the given resolution.

**Table 76. ADC accuracy(1)(2)(3)(4)(5)(6)(7)**

| Symbol | Parameter | Conditions(8) | | Min | Typ(9) | Max | Unit |
|---|---|---|---|---|---|---|---|
| ET(10) | Total unadjusted error | Single ended | BOOST = 1 | - | ±5 | - | ±LSB |
| | | | BOOST = 0 | - | ±7 | - | |
| | | Differential | BOOST = 1 | - | ±6 | - | |
| | | | BOOST = 0 | - | ±5 | - | |
| ED | Differential linearity error | Single ended | BOOST = 1 | - | 3 | - | |
| | | | BOOST = 0 | - | 1 | - | |
| | | Differential | BOOST = 1 | - | 8 | - | |
| | | | BOOST = 0 | - | 2 | - | |
| EL | Integral linearity error | Single ended | BOOST = 1 | - | ±6 | - | |
| | | | BOOST = 0 | - | ±4 | - | |
| | | Differential | BOOST = 1 | - | ±6 | - | |
| | | | BOOST = 0 | - | ±4 | - | |
| ENOB(11) | Effective number of bits (2 MSPS) | Single ended | BOOST = 1 | - | 12.5 | - | bits |
| | | | BOOST = 0 | - | 12.75 | - | |
| | | Differential | BOOST = 1 | - | 13.3 | - | |
| | | | BOOST = 0 | - | 13.7 | - | |
| SINAD(11) | Signal-to-noise and distortion ratio (2 MSPS) | Single ended | BOOST = 1 | - | 77.5 | - | dB |
| | | | BOOST = 0 | - | 78.75 | - | |
| | | Differential | BOOST = 1 | - | 82 | - | |
| | | | BOOST = 0 | - | 84.2 | - | |
| SNR(11) | Signal-to-noise ratio (2 MSPS) | Single ended | BOOST = 1 | - | 77.6 | - | |
| | | | BOOST = 0 | - | 79 | - | |
| | | Differential | BOOST = 1 | - | 82.4 | - | |
| | | | BOOST = 0 | - | 84.3 | - | |
| THD(11) | Total harmonic distortion | Single ended | BOOST = 1 | - | -85 | - | |
| | | | BOOST = 0 | - | -88 | - | |
| | | Differential | BOOST = 1 | - | -90 | - | |
| | | | BOOST = 0 | - | -93 | - | |

1. Guaranteed by characterization.
2. ADC DC accuracy values are measured after internal calibration.
3. ADC accuracy versus negative injection current: injecting negative current on any analog input pins should be avoided as this significantly reduces the accuracy of the conversion being performed on another analog input. It is recommended to add a Schottky diode (pin to ground) to analog pins which may potentially inject negative current.
4. The above table gives the ADC performance in 16-bit mode.
5. Dual Simultaneous mode is limited to 12-bit.
6. Dual mode consisting in an injected conversion (reset) occurring during another (regular) conversion is forbidden.
7. Dual Interleaved 16-bit/14-bit/12-bit modes can work if the delay between the 2 ADCs is as specified in *Table 77*.

8. ADC clock frequency ≤36 MHz, 2 V ≤ $V_{DDA}$ ≤ 3.3 V, 1.6 V ≤ $V_{REF+}$ ≤ $V_{DDA}$, BOOSTEN (for I/O) = 1.
9. $V_{DDA}$ = $V_{REF+}$ = 3.3 V, 25 °C.
10. ET, ED, EL are specified for [2 V ≤ $V_{DDA}$ ≤ 3.3 V with 2 V ≤ $V_{REF+}$ ≤ $V_{DDA}$] and [1.6V ≤ $V_{DDA}$ ≤ 2 V with 1.6V ≤ $V_{REF+}$ ≤ $V_{DDA}$].
11. ENOB, SINAD, SNR and THD are specified for $V_{DDA}$ = $V_{REF+}$ = 3.3 V.

**Table 77. Minimum delay for interleaved conversion versus resolution**

| | | 16-bit Mode | | 14-bit mode | | 12-bit Mode | |
|---|---|---|---|---|---|---|---|
| **Boost** | **Fclk (MHz)** | **Delay ADC1/ADC2 (clock cycles)** | **Data rate (MSPS)** | **Delay ADC1/ADC2 (clock cycles)** | **Data rate (MSPS)** | **Delay ADC1/ADC2 (clock cycles)** | **Data rate (MSPS)** |
| 0 | 1 | 1.5 | 1.0 | 1.5 | 1.0 | 1.5 | 1.0 |
| 0 | 2 | 1.5 | 2.0 | 1.5 | 2.0 | 1.5 | 2.0 |
| 0 | 3 | 1.5 | 1.5 | 1.5 | 1.5 | 1.5 | 1.5 |
| 0 | 4 | 1.5 | 2.0 | 1.5 | 2.0 | 1.5 | 2.0 |
| 0 | 5 | 1.5 | 1.7 | 1.5 | 1.7 | 1.5 | 2.5 |
| 0 | 6 | 1.5 | 2.0 | 1.5 | 2.0 | 1.5 | 2.0 |
| 0 | 7 | 2.5 | 1.8 | 1.5 | 2.3 | 1.5 | 2.3 |
| 0 | 8 | 2.5 | 2.0 | 2.5 | 2.0 | 1.5 | 2.7 |
| 0 | 9 | 3.5 | 1.8 | 2.5 | 2.3 | 2.5 | 2.3 |
| 0 | 10 | 3.5 | 2.0 | 3.5 | 2.0 | 2.5 | 2.5 |
| 0 | 11 | 4.5 | 1.8 | 3.5 | 2.2 | 2.5 | 2.8 |
| 0 | 12 | 4.5 | 2.0 | 4.5 | 2.0 | 3.5 | 2.4 |
| 0 | 13 | 4.5 | 2.2 | 4.5 | 2.2 | 3.5 | 2.6 |
| 0 | 14 | 4.5 | 2.3 | 4.5 | 2.3 | 3.5 | 2.8 |
| 0 | 15 | 5.5 | 2.1 | 4.5 | 2.5 | 3.5 | 3.0 |
| 0 | 16 | 5.5 | 2.3 | 4.5 | 2.7 | 3.5 | 3.2 |
| 0 | 17 | 5.5 | 2.4 | 4.5 | 2.8 | 3.5 | 3.4 |
| 0 | 18 | 5.5 | 2.6 | 4.5 | 3.0 | 3.5 | 3.6 |
| 0 | 19 | 5.5 | 2.7 | 4.5 | 3.2 | 3.5 | 3.8 |
| 0 | 20 | 5.5 | 2.9 | 4.5 | 3.3 | 3.5 | 4.0 |
| 1 | 21 | 4.5 | 3.5 | 3.5 | 4.2 | 3.5 | 4.2 |
| 1 | 22 | 4.5 | 3.7 | 3.5 | 4.4 | 3.5 | 4.4 |
| 1 | 23 | 4.5 | 3.8 | 3.5 | 4.6 | 3.5 | 4.6 |
| 1 | 24 | 4.5 | 4.0 | 4.5 | 4.0 | 3.5 | 4.8 |
| 1 | 25 | 4.5 | 4.2 | 4.5 | 4.2 | 3.5 | 5.0 |
| 1 | 26 | 4.5 | 4.3 | 4.5 | 4.3 | 3.5 | 5.2 |
| 1 | 27 | 5.5 | 3.9 | 4.5 | 4.5 | 3.5 | 5.4 |

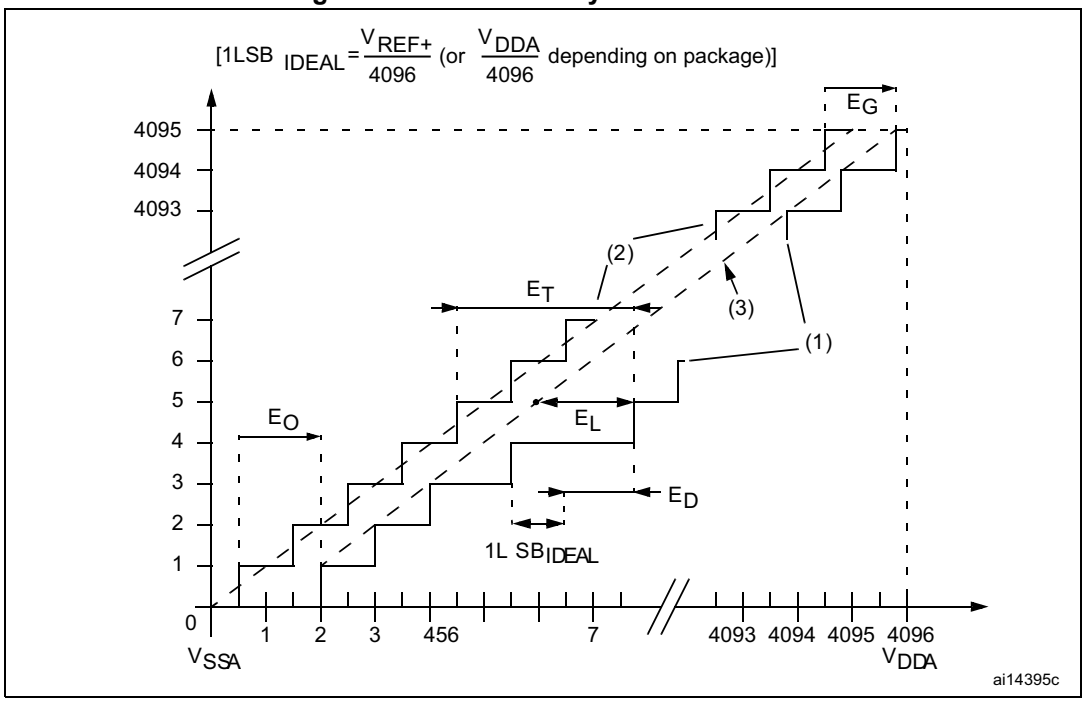
**Table 77. Minimum delay for interleaved conversion versus resolution (continued)**

| | | 16-bit Mode | | 14-bit mode | | 12-bit Mode | |
|---|---|---|---|---|---|---|---|
| **Boost** | **Fclk (MHz)** | **Delay ADC1/ADC2 (clock cycles)** | **Data rate (MSPS)** | **Delay ADC1/ADC2 (clock cycles)** | **Data rate (MSPS)** | **Delay ADC1/ADC2 (clock cycles)** | **Data rate (MSPS)** |
| 1 | 28 | 5.5 | 4.0 | 4.5 | 4.7 | 3.5 | 5.6 |
| 1 | 29 | 5.5 | 4.1 | 4.5 | 4.8 | 3.5 | 5.8 |
| 1 | 30 | 5.5 | 4.3 | 4.5 | 5.0 | 3.5 | 6.0 |
| 1 | 31 | 5.5 | 4.4 | 4.5 | 5.2 | 3.5 | 6.2 |
| 1 | 32 | 5.5 | 4.6 | 4.5 | 5.3 | 3.5 | 6.4 |
| 1 | 33 | 5.5 | 4.7 | 4.5 | 5.5 | 3.5 | 6.6 |
| 1 | 34 | 5.5 | 4.9 | 4.5 | 5.7 | 3.5 | 6.8 |
| 1 | 35 | 5.5 | 5.0 | 4.5 | 5.8 | 3.5 | 7.0 |
| 1 | 36 | 5.5 | 5.1 | 4.5 | 6.0 | 3.5 | 7.2 |

*Note: ADC accuracy vs. negative injection current: injecting a negative current on any analog input pins should be avoided as this significantly reduces the accuracy of the conversion being performed on another analog input. It is recommended to add a Schottky diode (pin to ground) to analog pins which may potentially inject negative currents.*

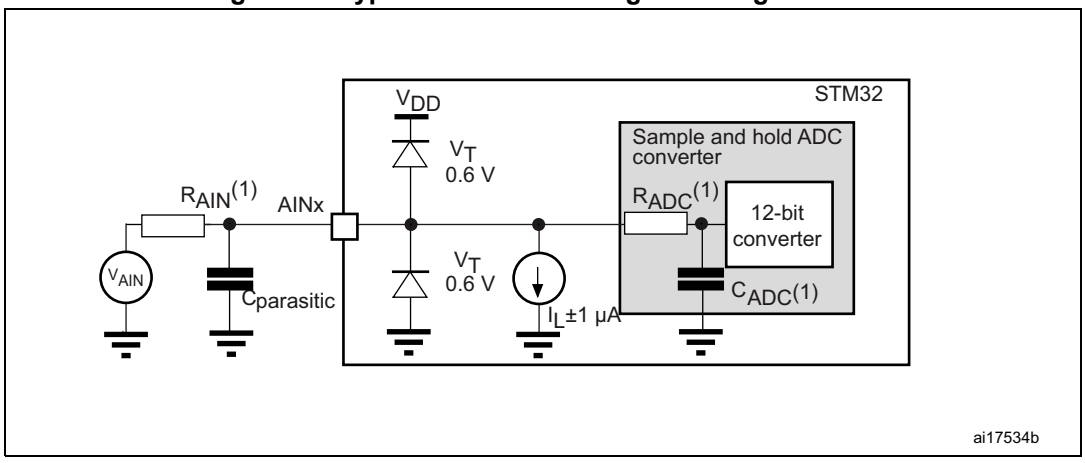
Any positive injection current within the limits specified for $I_{INJ(PIN)}$ and $\sum I_{INJ(PIN)}$ in *Section 6.2* does not affect the ADC accuracy.

**Figure 39. ADC accuracy characteristics**




1. Example of an actual transfer curve.
2. Ideal transfer curve.
3. End point correlation line.
4. ET = Total Unadjusted Error: maximum deviation between the actual and the ideal transfer curves.
   EO = Offset Error: deviation between the first actual transition and the first ideal one.
   EG = Gain Error: deviation between the last ideal transition and the last actual one.
   ED = Differential Linearity Error: maximum deviation between actual steps and the ideal one.
   EL = Integral Linearity Error: maximum deviation between any actual transition and the end point correlation line.

**Figure 40. Typical connection diagram using the ADC**




1. Refer to *Table 74* for the values of RAIN, RADC and CADC.
2. $C_{parasitic}$ represents the capacitance of the PCB (dependent on soldering and PCB layout quality) plus the pad capacitance (roughly 5 pF). A high $C_{parasitic}$ value downgrades conversion accuracy. To remedy this, $f_{ADC}$ should be reduced.

### General PCB design guidelines

PCB design guidelines are provided in AN5031 “Getting started with STM32MP1 Series hardware development.” available from the ST website *www.st.com*.

## 6.3.23 DAC electrical characteristics

**Table 78. DAC characteristics(1)(2)**

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| $V_{DDA}$ | Analog supply voltage | - | | 1.8 | 3.3 | 3.6 | V |
| $V_{REF+}$ | Positive reference voltage | - | | 1.80 | - | $V_{DDA}$ | V |
| $V_{REF-}$ | Negative reference voltage | - | | - | $V_{SSA}$ | - | V |
| $R_L$ | Resistive Load | DAC output buffer ON, Not valid in Sample & Hold mode | connected to $V_{SSA}$ | 5 | - | - | kΩ |
| | | | connected to $V_{DDA}$ | 25 | - | - | kΩ |
| $R_O$ | Output Impedance | DAC output buffer OFF | | 10.3 | 13 | 16 | kΩ |
| $R_{BON}$ | Output impedance sample and hold mode, output buffer ON | DAC output buffer ON | $V_{DD}$ = 2.7 V | - | - | 1.6 | kΩ |
| | | | $V_{DD}$ = 2.0 V | - | - | 2.6 | kΩ |
| $R_{BOFF}$ | Output impedance sample and hold mode, output buffer OFF | DAC output buffer OFF | $V_{DD}$ = 2.7 V | - | - | 17.8 | kΩ |
| | | | $V_{DD}$ = 2.0 V | - | - | 18.7 | kΩ |
| $C_L$ | Capacitive Load | DAC output buffer OFF | | - | - | 50 | pF |
| $C_{SH}$ | | Sample and Hold mode | | - | 0.1 | 1 | µF |
| $V_{DAC_OUT}$ | Voltage on DAC_OUT output | DAC output buffer ON | | 0.2 | - | $V_{DDA}$ - 0.2(3) | V |
| | | DAC output buffer OFF | | 0 | - | $V_{REF+}$ | V |
| $t_{SETTLING}$ | Settling time (full scale: for a 12-bit code transition between the lowest and the highest input codes when DAC_OUT reaches the final value of ±1LSB) | Normal mode, DAC output buffer ON | ±1 LSB | - | 2 | - | µs |
| | | Normal mode, DAC output buffer OFF, +/-1LSB, Cload ≤ 10 pF | | - | - | 2 | µs |
| $t_{WAKEUP}$(4) | Wakeup time from off state (setting the Enx bit in the DAC Control register) until the ±1LSB final value | Normal mode, DAC output buffer ON | | - | 5 | 7.5 | µs |
| | | Normal mode, DAC output buffer OFF | | - | 2 | 5 | µs |
| PSRR | $V_{DDA}$ supply rejection ratio | Normal mode DAC output buffer ON | | - | -80 | -28 | dB |

**Table 78. DAC characteristics(1)(2) (continued)**

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| $t_{SAMP}$ | Sampling time in Sample and Hold mode $C_{SH}$=100nF (Code transition between the lowest input code and the highest input code when DAC_OUT reaches final value ± 1LSB) | DACMCR.MODEx[2:0] = 100/101 (BUFFER ON) | | - | 0.7 | - | ms |
| | | DACMCR.MODEx[2:0] = 110 (BUFFER OFF) | | - | 11.5 | - | |
| | | DACMCR.MODEx[2:0] = 111 (INTERNAL BUFFER OFF) | | - | 0.3 | - | |
| $CI_{int}$ | Internal sample and hold capacitor | - | | - | 2.2 | - | pF |
| $V_{offset}$ | Middle code offset for 1 trim code step | $V_{REF+}$ = 3.6 V | | - | 450 | - | µV |
| | | $V_{REF+}$ = 1.8 V | | - | 213 | - | |
| $I_{DDA(DAC)}$ | DAC quiescent consumption from $V_{DDA}$ | DAC output buffer ON | No load, middle code (0x800) | - | 360 | - | µA |
| | | | No load, worst code (0xF1C) | - | 490 | - | |
| | | DAC output buffer OFF | No load, middle/worst code (0x800) | - | 20 | - | |
| | | Sample and Hold mode, $C_{SH}$ = 100 nF | | - | 360×TON/ (TON+TOFF) (5) | - | |
| $I_{DDV(DAC)}$ | DAC consumption from $V_{REF+}$ | DAC output buffer ON | No load, middle code (0x800) | - | 170 | - | |
| | | | No load, worst code (0xF1C) | - | 170 | - | |
| | | DAC output buffer OFF | No load, middle/worst code (0x800) | - | 160 | - | |
| | | Sample and Hold mode, Buffer ON, $C_{SH}$ = 100 nF (worst code) | | - | 170×TON/ (TON+TOFF) (5) | - | |
| | | Sample and Hold mode, Buffer OFF, $C_{SH}$ = 100 nF (worst code) | | - | 170×TON/ (TON+TOFF) (5) | - | |

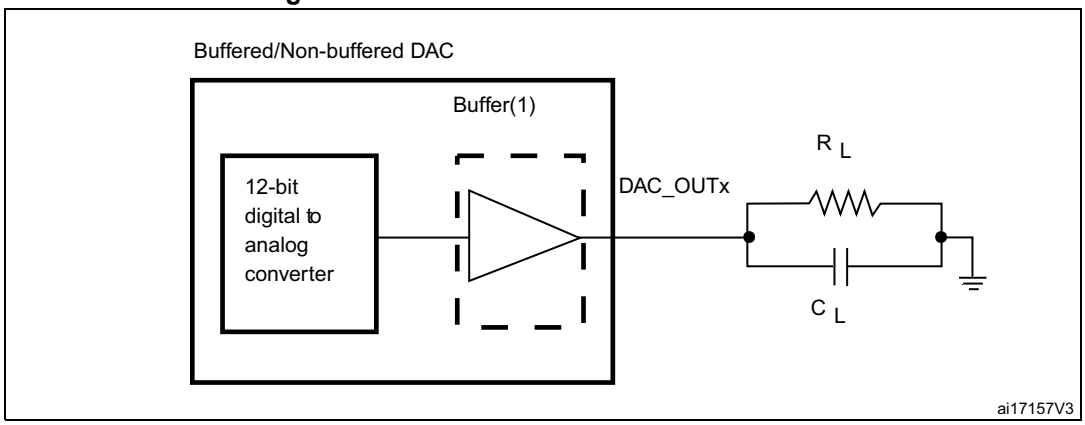
1. Guaranteed by design.
2. Unless otherwise noted, $C_L$ ≤ 50 pF with $R_L$ ≥ 5 kΩ when DAC output buffer is ON, or $C_L$ ≤ 10 pF with no $R_L$ when DAC output buffer is OFF.
3. Since $V_{REF+}$ must always be ≤ VDDA, maximum $V_{DAC_OUT}$ = minimum value between Max($V_{REF+}$) and Max($V_{DDA}$-0.2)
4. In buffered mode, the output can overshoot above the final value for low input code (starting from the minimum value).
5. TON is the refresh phase duration, while TOFF is the hold phase duration. Refer to the product reference manual for more details.

**Table 79. DAC accuracy(1)**

| Symbol | Parameter | Conditions | | Min | Typ(2) | Max | Unit |
|---|---|---|---|---|---|---|---|
| DNL | Differential non linearity(3) | - | | - | ±2 | - | LSB |
| INL | Integral non linearity(4) | - | | - | ±4 | - | LSB |
| Offset | Offset error at code 0x800 (4) | DAC output buffer ON | $V_{REF+}$ = 3.6 V | - | ±5 | - | LSB |
| | | | $V_{REF+}$ = 1.8 V | - | ±7 | - | |
| | | DAC output buffer OFF | | - | ±8 | - | |
| Offset1 | Offset error at code 0x001(5) | DAC output buffer OFF | | - | ±5 | - | LSB |
| Gain | Gain error(6) | - | | - | ±1 | - | % |
| TUECal | Total unadjusted error | DAC output buffer ON | $V_{REF+}$=3.6 V | - | ±10 | - | LSB |
| | | | $V_{REF+}$=1.8 V | - | ±8 | - | |
| SNR | Signal-to-noise ratio(7) | 1 kHz, BW = 500 kHz | | - | 67.8 | - | dB |
| THD | Total harmonic distorsion(7) | 1kHz | | - | -78.6 | - | dB |
| SINAD | Signal-to-noise and distortion ratio(7) | 1 kHz | | - | 67.5 | - | dB |
| ENOB | Effective number of bits | 1 kHz | | - | 10.9 | - | bits |

1. Unless otherwise noted, $C_L \leq 50$ pF with $R_L \geq 5$ kΩ when DAC output buffer is ON, or $C_L \leq 10$ pF with no $R_L$ when DAC output buffer is OFF.
2. Guaranteed by characterization.
3. Difference between two consecutive codes minus 1 LSB.
4. Difference between measured the value at Code i and the value measured at Code i on a line drawn between Code 0 and last Code 4095.
5. Difference between the value measured at Code (0x001) and the ideal value.
6. Difference between the ideal slope of the transfer function and the measured slope computed from code 0x000 and 0xFFF when the buffer is OFF, and from code giving 0.2 V and ($V_{REF+}$ - 0.2 V) when the buffer is ON.
7. Signal is -0.5dBFS with $F_{sampling}$=1 MHz.

**Figure 41. 12-bit buffered /non-buffered DAC**




1. The DAC integrates an output buffer that can be used to reduce the output impedance and to drive external loads directly without the use of an external operational amplifier. The buffer can be bypassed by configuring the BOFFx bit in the DAC_CR register.

## 6.3.24 Voltage reference buffer characteristics

**Table 80. VREFBUF characteristics(1)**

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| $V_{DDA}$ | Analog supply voltage | Normal mode | VSCALE = 000 | 2.8 | 3.3 | 3.6 | V |
| | | | VSCALE = 001 | 2.4 | - | 3.6 | |
| | | | VSCALE = 010 | 2.1 | - | 3.6 | |
| | | | VSCALE = 011 | 1.8 | - | 3.6 | |
| | | Degraded mode(2) | VSCALE = 000 | 1.62 | - | 2.80 | |
| | | | VSCALE = 001 | 1.62 | - | 2.40 | |
| | | | VSCALE = 010 | 1.62 | - | 2.10 | |
| | | | VSCALE = 011 | 1.62 | - | 1.80 | |
| $V_{REFBUF_OUT}$ | Voltage Reference Buffer Output | Normal mode @30 °C @$I_{load}$ = 10 uA $V_{DDA}$ = 3.3 V | VSCALE = 000 | 2.498 | 2.500 | 2.502 | |
| | | | VSCALE = 001 | 2.047 | 2.049 | 2.051 | |
| | | | VSCALE = 010 | 1.800 | 1.804 | 1.807 | |
| | | | VSCALE = 011 | 1.500 | 1.504 | 1.507 | |
| | | Degraded mode(2) | VSCALE = 000 | $V_{DDA}$- 220 mV | - | $V_{DDA}$ | |
| | | | VSCALE = 001 | $V_{DDA}$- 220 mV | - | $V_{DDA}$ | |
| | | | VSCALE = 010 | $V_{DDA}$- 220 mV | - | $V_{DDA}$ | |
| | | | VSCALE = 011 | $V_{DDA}$- 220 mV | - | $V_{DDA}$ | |
| TRIM | Trim step resolution | - | - | - | ±0.05 | - | % |
| $C_L$ | Load capacitor | - | - | 0.5 | 1 | 1.50 | uF |

**Table 80. VREFBUF characteristics(1) (continued)**

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| esr | Equivalent Serial Resistor of $C_L$ | - | - | - | - | 2 | Ω |
| $I_{load}$ | Static load current | - | - | - | - | 4 | mA |
| $I_{line_reg}$ | Line regulation | 2.8 V ≤ $V_{DDA}$ ≤ 3.6 V | $I_{load}$ = 500 µA | - | 200 | - | ppm/V |
| | | | $I_{load}$ = 4 mA | - | 100 | - | |
| $I_{load_reg}$ | Load regulation | 500 µA ≤ $I_{LOAD}$ ≤ 4 mA | Normal Mode | - | 50 | - | ppm/ mA |
| $T_{coeff}$ | Temperature coefficient | -40 °C < $T_J$ < +125 °C | - | - | $T_{coeff_VREFINT}$ +75 | - | ppm/ °C |
| PSRR | Power supply rejection | DC | - | - | 60 | - | dB |
| | | 100 kHz | - | - | 40 | - | |
| $t_{START}$ | Start-up time(3) | $C_L$ = 0.5 µF | - | - | 300 | 350 | µs |
| | | $C_L$ = 1 µF | - | - | 500 | 650 | |
| | | $C_L$ = 1.5 µF | - | - | 650 | 800 | |
| $I_{INRUSH}$ | Control of maximum DC current drive on $V_{REFBUF_OUT}$ during startup phase(4) | - | | - | 8 | 13.5 | mA |
| $I_{DDA(VREFBUF)}$ | VREFBUF consumption from $V_{DDA}$ | $I_{LOAD}$ = 0 µA | - | - | 15 | 16 | µA |
| | | $I_{LOAD}$ = 500 µA | - | - | 16 | 21 | |
| | | $I_{LOAD}$ = 4 mA | - | - | 32 | 41 | |
| $R_{VREFBUF_PullDown}$ | Pull-down resistor when ENVR = HIZ = 0 | - | | - | 100 | - | Ω |

1. Guaranteed by design.
2. In degraded mode, the voltage reference buffer cannot accurately maintain the output voltage ($V_{DDA}$-drop voltage).
3. if VREF+ pin has residual voltage when VREFBUF is enabled (VREFBUF_CSR.ENVR=1), this might create an overshoot on VREFBUF output longer than $t_{START}$.
   To avoid this, it is necessary that VREF+ pin is correctly discharged before being enabled (below VREFBUF_OUT minus 1 V, for example below 1.5 V for VSCALE = 000)
   This could be achieved by ensuring VREFBUF is in OFF mode (VREFBUF_CSR.ENVR=0 and VREFBUF_CSR.HIZ=0) for sufficient time to discharge $C_L$ through VREFBUF pull-down.
4. To properly control VREFBUF $I_{INRUSH}$ current during the startup phase and the change of scaling, $V_{DDA}$ voltage should be in the range of 1.8 V-3.6 V, 2.1 V-3.6 V, 2.4 V-3.6 V and 2.8 V-3.6 V for VSCALE = 011, 010, 001 and 000, respectively.

### 6.3.25 Temperature sensor characteristics

**Table 81. Temperature sensor characteristics**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $T_L$(1) | VSENSE linearity with temperature (from Vsensor voltage) | - | - | 3 | °C |
| | VSENSE linearity with temperature (from ADC counter) | - | - | 3 | |
| Avg_Slope(2) | Average slope (from Vsensor voltage) | - | 2 | - | mV/°C |
| | Average slope (from ADC counter) | - | 2 | - | |
| $V_{30}$(3) | Voltage at 30 °C ± 5 °C | - | 0.62 | - | V |
| $t_{start_run}$(1) | Startup time in Run mode (buffer startup) | 5.3 | - | 40.5 | µs |
| $t_{S_temp}$(1) | ADC sampling time when reading the temperature | 9.8 | - | - | |
| $I_{sens}$(1) | Sensor consumption | 0.11 | 0.18 | 0.31 | µA |
| $I_{sensbuf}$(1) | Sensor buffer consumption | 2.3 | 3.8 | 6.1 | |

1. Guaranteed by design.
2. Guaranteed by characterization.
3. Measured at $V_{DDA}$ = 3.3 V ± 10 mV. The $V_{30}$ ADC conversion result is stored in the TS_CAL1 byte.

**Table 82. Temperature sensor calibration values**

| Symbol | Parameter | Memory address |
|---|---|---|
| TS_CAL1 | TS ADC raw data acquired at temperature of 30 °C ±5 °C<br>$V_{DDA}$ = $V_{REF+}$ = 3.3 V ±10 mV | 0x5C00 525C[15:0](1)(2) |
| TS_CAL2 | TS ADC raw data acquired at temperature of 130 °C ±2 °C<br>$V_{DDA}$ = $V_{REF+}$ = 3.3 V ±10 mV | 0x5C00 525C[31:16](1)(2) |

1. It is mandatory to read a 32-bit word and to do relevant masking and shifting to isolate the required bits.
2. This address is located inside the BSEC and the access is allowed after being enabled in the RCC.

### 6.3.26 DTS characteristics

**Table 83. DTS characteristics(1)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $f_{DTS}$ | Output Clock frequency (PTAT clock) | - | - | 500 | - | kHz |
| $T_{SLOPE}$ | Average slope | - | - | 1600 | - | Hz/°C |
| $T_L$ | Linearity with temperature (from Output clock frequency). | $V_{DDCORE}$ = 1.2 V | - | - | 3.8 | °C |
| $T_{TOTAL_ERROR}$ | Temperature measurement error | $V_{DDCORE}$ = 1.2 V<br>Temperature:<br>-40 to 125 °C | -5 | - | +5 | °C |

**Table 83. DTS characteristics(1) (continued)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $T_{VDD\ CORE}$ | Additional error due to $V_{DDCORE}$ variation | - | - | 10 | - | °C/V |
| $t_{TRIM}$ | Calibration time | - | 2 | - | - | ms |
| $t_{WAKE_UP}$ | Wake-up time from off state until DTS ready signal = 1 | - | - | 50 | - | µs |
| $I_{DDCORE_DTS}$ | DTS consumption on $V_{DDCORE}$ | - | - | 20 | - | µA |

1. Guaranteed by design.

## 6.3.27 $V_{BAT}$ ADC monitoring characteristics and charging characteristics

**Table 84. $V_{BAT}$ ADC monitoring characteristics**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| R | Resistor bridge for $V_{BAT}$ | - | 26 | - | kΩ |
| Q | Ratio on $V_{BAT}$ measurement | - | 4 | - | - |
| Er(1) | Error on Q | –10 | - | +10 | % |
| $t_{S_vbat}$(1) | ADC sampling time when reading $V_{BAT}$ input | 9.8 | - | - | µs |

1. Guaranteed by design.

**Table 85. $V_{BAT}$ charging characteristics**

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $R_{BC}$ | Battery charging resistor | VBRS in PWR_CR3= 0 | - | 5 | - | kΩ |
| | | VBRS in PWR_CR3= 1 | - | 1.5 | - | |

## 6.3.28 Temperature and $V_{BAT}$ monitoring characteristics for tamper detection

**Table 86. Temperature and $V_{BAT}$ monitoring characteristics for temper detection**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $TEMP_{high}$ | High temperature monitoring | 105 | 116 | 126 | °C |
| $TEMP_{low}$ | Low temperature monitoring | -42 | -31 | -20 | |
| $V_{BAThigh}$(1) | High supply monitoring | 3.47 | 3.59 | 3.73 | V |
| $V_{BATlow}$(1) | Low supply monitoring | 1.3 | 1.34 | 1.43 | |

1. Monitored supply is $V_{SW}$ (i.e. $V_{DD}$ if $V_{DD}$ is present, $V_{BAT}$ otherwise)

### 6.3.29 $V_{DDCORE}$ monitoring characteristics

**Table 87. $V_{DDCORE}$ monitoring characteristics**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $t_{S_vddcore}$(1) | ADC sampling time when reading $V_{DDCORE}$ input | 100 | - | - | ns |

1. Guaranteed by design.

### 6.3.30 Voltage booster for analog switch

**Table 88. Voltage booster for analog switch characteristics**

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $V_{DD}$ | Supply voltage | - | 1.71 | - | 3.6 | V |
| $t_{SU(BOOST)}$ | Booster startup time | - | - | - | 50 | µs |
| $I_{DD(BOOST)}$ | Booster consumption | 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | - | 125 | µA |
| | | 2.7 V < $V_{DD}$ < 3.6 V | - | - | 250 | |

### 6.3.31 Compensation cell

**Table 89. Compensation cell characteristics**

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $I_{COMPCELL}$ | $V_{DD}$ current consumption during code calculation | 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | - | 3.5 | mA |
| | | 2.7 V < $V_{DD}$ < 3.6 V | - | - | 10 | |
| $T_{READY}$ | Time needed for code calculation | 1.71 V ≤ $V_{DD}$ ≤ 2.7 V | - | - | 300 | µs |
| | | 2.7 V < $V_{DD}$ < 3.6 V | - | - | 250 | |

### 6.3.32 Digital filter for sigma-delta modulators (DFSDM) characteristics

Unless otherwise specified, the parameters given in *Table 90* for DFSDM are derived from tests performed under the ambient temperature, $f_{pclkx}$ frequency and $V_{DD}$ supply voltage summarized in *Table 13: General operating conditions*, with the following configuration:

- Output speed is set to OSPEEDRy[1:0] = 10
- Capacitive load C = 30 pF
- Measurement points are done at CMOS levels: 0.5×$V_{DD}$

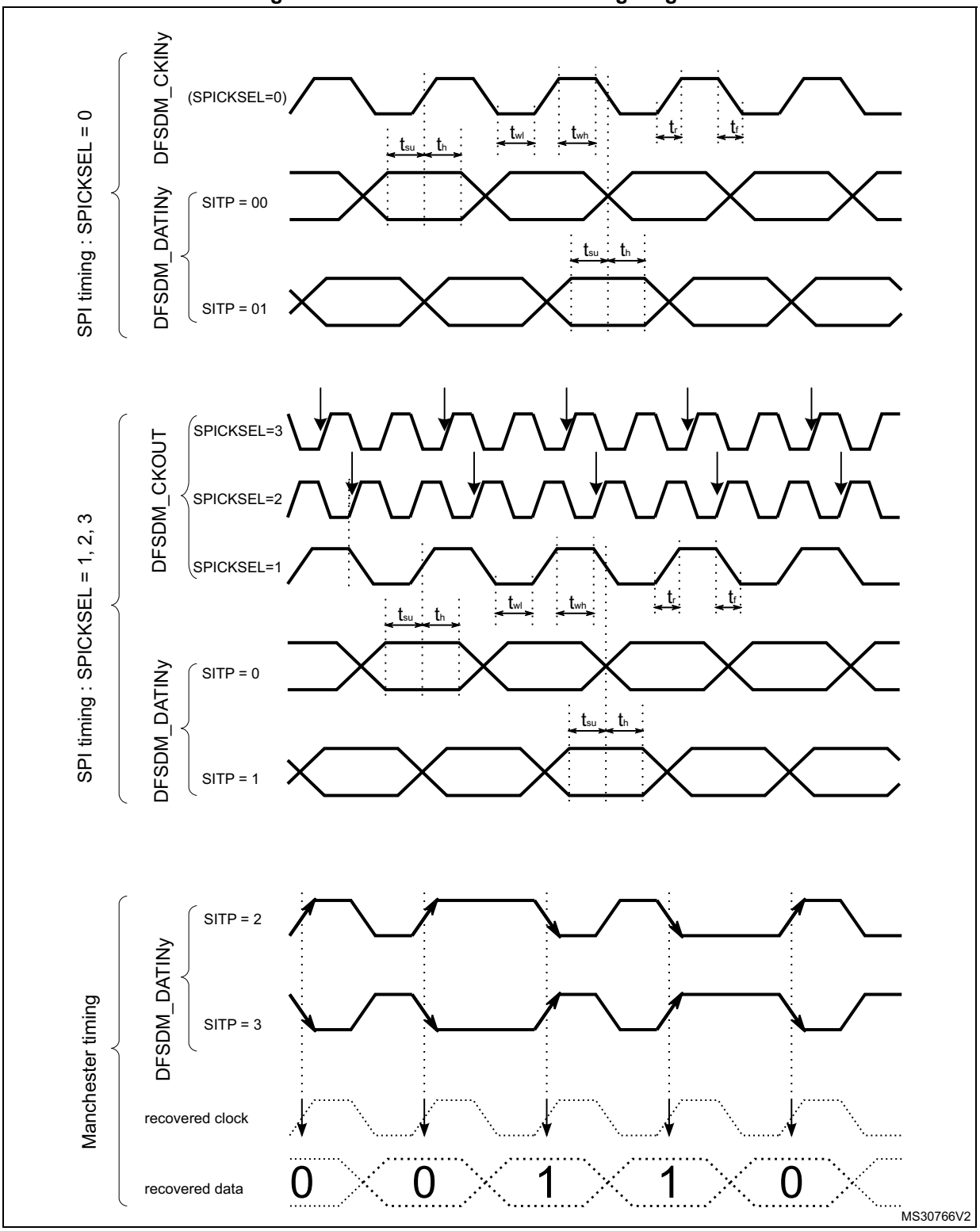
Refer to *Section 6.3.17: I/O port characteristics* for more details on the input/output alternate function characteristics (DFSDMx_CKINx, DFSDMx_DATINx, DFSDMx_CKOUT for DFSDMx).

**Table 90. DFSDM measured timing**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $f_{DFSDMCLK}$ | DFSDM clock | 1.71 V < $V_{DD}$ < 3.6 V | - | - | $f_{SYSCLK}$ | MHz |
| $f_{CKIN}$ ($1/T_{CKIN}$) | Input clock frequency | SPI mode (SITP[1:0]=0,1), External clock mode (SPICKSEL[1:0]=0), 1.71 V < $V_{DD}$ < 3.6 V | - | - | 20 ($f_{DFSDMCLK}$/4) | |
| | | SPI mode (SITP[1:0]=0,1), External clock mode (SPICKSEL[1:0]=0), 2.7 < $V_{DD}$ < 3.6 V | - | - | 20 ($f_{DFSDMCLK}$/4) | |
| | | SPI mode (SITP[1:0]=0,1), Internal clock mode (SPICKSEL[1:0]≠0), 1.71 < $V_{DD}$ < 3.6 V | - | - | 20 ($f_{DFSDMCLK}$/4) | |
| | | SPI mode (SITP[1:0]=0,1), Internal clock mode (SPICKSEL[1:0]≠0), 2.7 < $V_{DD}$ < 3.6 V | - | - | 20 ($f_{DFSDMCLK}$/4) | |
| $f_{CKOUT}$ | Output clock frequency | 1.71 < $V_{DD}$ < 3.6 V | - | - | 20 | |
| $DuCy_{CKOUT}$ | Output clock frequency duty cycle | 1.71 < $V_{DD}$ < 3.6 V | 45 | 50 | 55 | % |
| $t_{wh(CKIN)}$ $t_{wl(CKIN)}$ | Input clock high and low time | SPI mode (SITP[1:0]=0,1), External clock mode (SPICKSEL[1:0]=0), 1.71 < $V_{DD}$ < 3.6 V | $T_{CKIN}$/2 - 0.5 | $T_{CKIN}$/2 | - | ns |
| $t_{su}$ | Data input setup time | SPI mode (SITP[1:0]=0,1), External clock mode (SPICKSEL[1:0]=0), 1.71 < $V_{DD}$ < 3.6 V | 1 | - | - | |
| $t_h$ | Data input hold time | SPI mode (SITP[1:0]=0,1), External clock mode (SPICKSEL[1:0]=0), 1.71 < $V_{DD}$ < 3.6 V | 0.5 | - | - | |
| $T_{Manchester}$ | Manchester data period (recovered clock period) | Manchester mode (SITP[1:0]=2,3), Internal clock mode (SPICKSEL[1:0]¹0), 1.71 < $V_{DD}$ < 3.6 V | (CKOUTDIV+1) ×$T_{DFSDMCLK}$(1) | - | (2×CKOUTDIV) × $T_{DFSDMCLK}$(1) | |

1. See DFSDM section in RM0442 reference manual for definition of CKOUTDIV.

**Figure 42. Channel transceiver timing diagrams**



### 6.3.33 Camera interface (DCMI) characteristics

Unless otherwise specified, the parameters given in *Table 91* for DCMI are derived from tests performed under the ambient temperature, $F_{mcu_ck}$ frequency and $V_{DD}$ supply voltage summarized in *Table 13: General operating conditions*, with the following configuration:

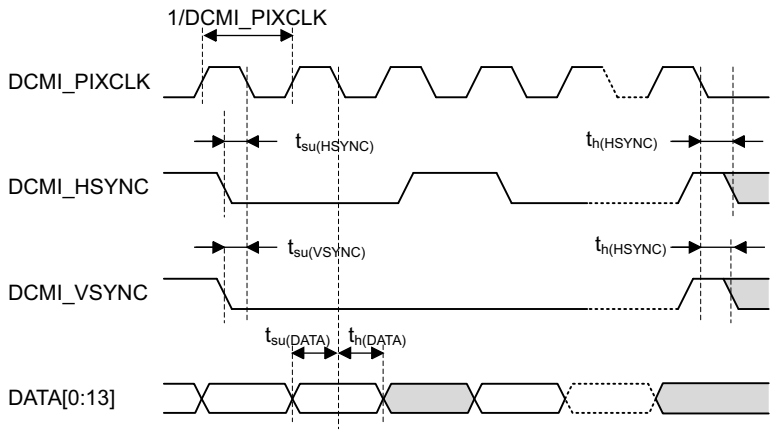
- DCMI_PIXCLK polarity: falling
- DCMI_VSYNC and DCMI_HSYNC polarity: high
- Data formats: 14 bits
- Capacitive load C = 30 pF
- Measurement points are done at CMOS levels: $0.5 \times V_{DD}$

**Table 91. DCMI characteristics(1)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| - | Frequency ratio DCMI_PIXCLK/$F_{mcu_ck}$ | - | 0.4 | - |
| DCMI_PIXCLK | Pixel clock input | - | 80 | MHz |
| $D_{Pixel}$ | Pixel clock input duty cycle | 30 | 70 | % |
| $t_{su(DATA)}$ | Data input setup time | 2 | - | ns |
| $t_{h(DATA)}$ | Data input hold time | 0.5 | - | |
| $t_{su(HSYNC)}$ $t_{su(VSYNC)}$ | DCMI_HSYNC/DCMI_VSYNC input setup time | 2 | - | |
| $t_{h(HSYNC)}$ $t_{h(VSYNC)}$ | DCMI_HSYNC/DCMI_VSYNC input hold time | 1 | - | |

1. Guaranteed by characterization results.

**Figure 43. DCMI timing diagram**



### 6.3.34 LCD-TFT controller (LTDC) characteristics

Unless otherwise specified, the parameters given in *Table 92* for LCD-TFT are derived from tests performed under the ambient temperature, $F_{pclk4}$ frequency and $V_{DD}$ supply voltage summarized in *Table 13: General operating conditions*, with the following configuration:

- LCD_CLK polarity: high
- LCD_DE polarity: low
- LCD_VSYNC and LCD_HSYNC polarity: high
- Pixel formats: 24 bits
- Output speed is set to OSPEEDRy[1:0] = 11
- Capacitive load C = 30 pF
- Measurement points are done at CMOS levels: $0.5 \times V_{DD}$
- I/O compensation cell enabled

**Table 92. LTDC characteristics (1)**

| Symbol | Parameter | Conditions | Min | Max | Unit |
|---|---|---|---|---|---|
| $f_{CLK}$ | LTDC clock output frequency | 2.7 V < $V_{DD}$ < 3.6 V OSPEEDR[1:0] = 11, 10 | - | 90 | MHz |
| | | 1.71 V < $V_{DD}$ < 3.6 V OSPEEDR[1:0] = 11 | - | 45 | |
| | | 1.71 V < $V_{DD}$ < 3.6 V OSPEEDR[1:0] = 10 | - | 38 | |
| $D_{CLK}$ | LTDC clock output duty cycle | - | 45 | 55 | % |
| $t_{w(CLKH)}$, $t_{w(CLKL)}$ | Clock High time, low time | - | $t_{w(CLK)}/2$ - 0.5 | $t_{w(CLK)}/2$ + 0.5 | ns |
| $t_{v(DATA)}$ | Data output valid time | OSPEEDR[1:0] = 11 | - | 3 | |
| | | OSPEEDR[1:0] = 10 | - | 4 | |
| $t_{h(DATA)}$ | Data output hold time | - | 0 | - | |
| $t_{v(HSYNC)}$, $t_{v(VSYNC)}$, $t_{v(DE)}$ | HSYNC/VSYNC/DE output valid time | OSPEEDR[1:0] = 11 | - | 2.5 | |
| | | OSPEEDR[1:0] = 10 | - | 3.5 | |
| $t_{h(HSYNC)}$, $t_{h(VSYNC)}$, $t_{h(DE)}$ | HSYNC/VSYNC/DE output hold time | - | 0 | - | |

1. Guaranteed by characterization results.

**Figure 44. LCD-TFT horizontal timing diagram**

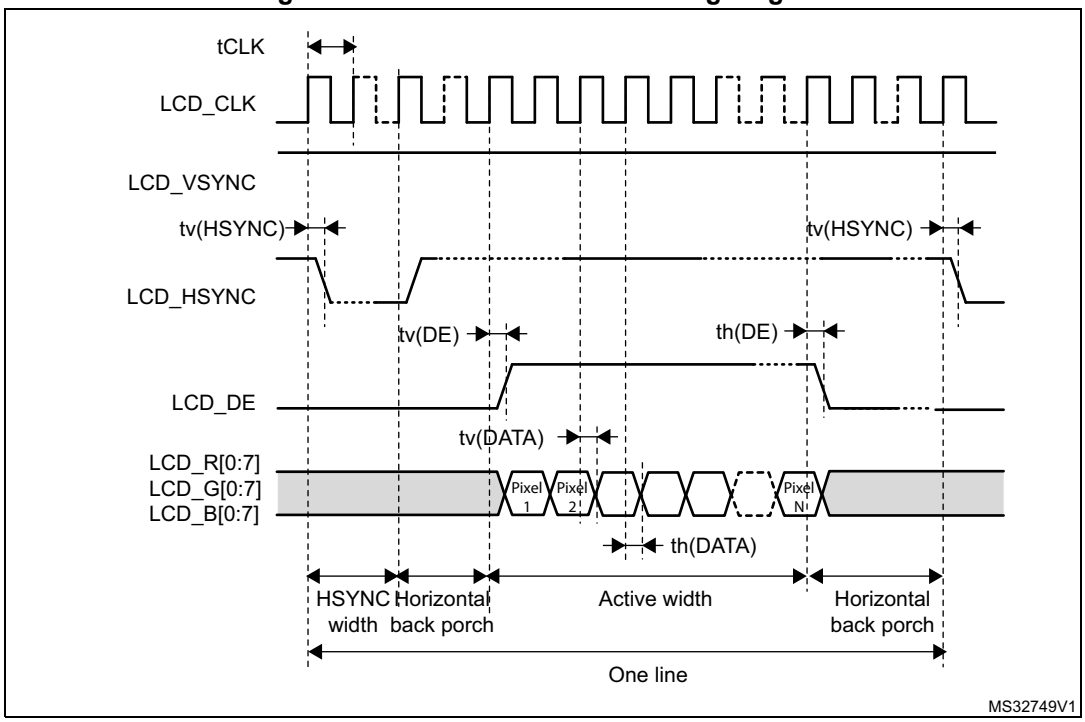
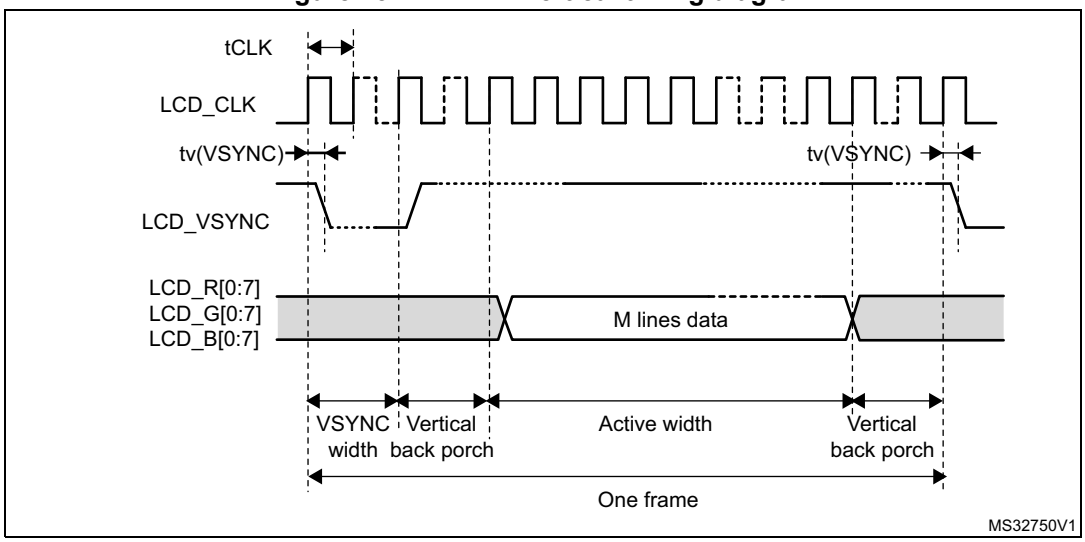



**Figure 45. LCD-TFT vertical timing diagram**



### 6.3.35 Timer characteristics

The parameters given in *Table 93* are guaranteed by design.

Refer to *Section 6.3.17: I/O port characteristics* for details on the input/output alternate function characteristics (output compare, input capture, external clock, PWM output).

**Table 93. TIMx characteristics(1)(2)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{res(TIM)}$ | Timer resolution time | 1 | - | $t_{TIMxCLK}$ |
| $f_{TIMxCLK}$ | Timer kernel clock | 0 | 209 | MHz |
| $f_{EXT}$ | Timer external clock frequency on CH1 to CH4 | 0 | $f_{TIMxCLK}/2$ | |
| $Res_{TIM}$ | Timer resolution | - | 16/32 | bit |
| $t_{MAX_COUNT}$ | Maximum possible count with 16-bit counters | - | 65536 | $t_{TIMxCLK}$ |
| | Maximum possible count with 32-bit counter (TIM2, TIM5) | | 65536 × 65536 | |

1. TIMx is used as a general term to refer to the TIM1 to TIM17 timers.
2. Guaranteed by design.

**Table 94. LPTIMx characteristics(1)(2)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{res(TIM)}$ | Timer resolution time | 1 | - | $t_{TIMxCLK}$ |
| $f_{LPTIMxCLK}$ | Timer kernel clock | 0 | 104.5 | MHz |
| $f_{EXT}$ | Timer external clock frequency on Input1 and Input2 | 0 | $f_{LPTIMxCLK}/2$ | |
| $Res_{TIM}$ | Timer resolution | - | 16 | bit |
| $t_{MAX_COUNT}$ | Maximum possible count | - | 65536 | $t_{TIMxCLK}$ |

1. LPTIMx is used as a general term to refer to the LPTIM1 to LPTIM5 timers.
2. Guaranteed by design.

### 6.3.36 Communications interfaces

#### I2C interface characteristics

The I2C interface meets the timings requirements of the $I^2C$-bus specification for:

- Standard-mode (Sm): with a bit rate up to 100 kbit/s
- Fast-mode (Fm): with a bit rate up to 400 kbit/s.
- Fast-mode Plus (Fm+): with a bit rate up to 1 Mbit/s.

The $I^2C$ timings requirements are guaranteed by design when the I2C peripheral is properly configured and when the i2c_ker_ck frequency is greater than the minimum shown in the table below:

**Table 95. Minimum i2c_ker_ck frequency in all I2C modes**

| Symbol | Parameter | Condition | | Min | Unit |
|---|---|---|---|---|---|
| f(I2CCLK) | I2CCLK frequency | Standard-mode | - | 2 | MHz |
| | | Fast-mode | Analog filter ON DNF=0 | 8 | |
| | | | Analog filter OFF DNF=1 | 9 | |
| | | Fast-mode Plus | Analog filter ON DNF=0 | 19 | |
| | | | Analog filter OFF DNF=1 | 16 | |

The SDA and SCL I/O requirements are met with the following restrictions:

- The SDA and SCL I/O pins are not “true” open-drain. When configured as open-drain, the PMOS connected between the I/O pin and $V_{DD}$ is disabled, but is still present.
- The 20 mA output drive requirement in Fast-mode Plus is not supported. This limits the maximum load $C_{load}$ supported in Fm+, which is given by these formulas:

$t_{r(SDA/SCL)} = 0.8473 \times R_p \times C_{load}$

$R_{p(min)} = (V_{DD}-V_{OL(max)})/I_{OL(max)}$

Where $R_p$ is the I2C lines pull-up. Refer to *Section 6.3.17: I/O port characteristics* for the I2C I/Os characteristics.

All I2C SDA and SCL I/Os embed an analog filter. Refer to *Table 96* for the analog filter characteristics:

**Table 96. I2C analog filter characteristics(1)**

| Symbol | Parameter | Min | Max | Unit |
|---|---|---|---|---|
| $t_{AF}$ | Maximum pulse width of spikes that are suppressed by the analog filter | 40(2) | 260(3) | ns |

1. Guaranteed by design.
2. Spikes with widths below $t_{AF(min)}$ are filtered.
3. Spikes with widths above $t_{AF(max)}$ are not filtered.

The I2C pins can be set in FM+ mode in SYSCFG_PMCR register.

Unless otherwise specified, the parameters given in Table 55 are derived from tests performed under the ambient temperature and $V_{DD}$ supply voltage conditions summarized in *Table 13: General operating conditions*.

**Table 97. I2C FM+ pin characteristics**

| Symbol | Parameter | Conditions | Min | Max | Unit |
|---|---|---|---|---|---|
| $F_{max}$(1) | Maximum frequency | C = 50 pF<br>1.71 ≤ $V_{DD}$ ≤ 3.6 V | - | 1 | MHz |
| $T_f$(2) | Output high to low level fall time | | - | 5 | ns |

1. The maximum frequency is defined with the following conditions:
   - (Tr + Tf) ≤ ⅔T
   - 45% < duty cycle < 55%.
2. The fall time is defined between 70% and 30% of the output waveform accordingl to $I^2C$ specification NXP UM10204 rev- Oct 2012.

## SPI interface characteristics

Unless otherwise specified, the parameters given in *Table 98* for the SPI interface are derived from tests performed under the ambient temperature, $f_{pclkx}$ frequency and $V_{DD}$ supply voltage conditions summarized in *Table 13: General operating conditions*, with the following configuration:

- Output speed is set to OSPEEDRy[1:0] = 11
- Capacitive load C = 30 pF
- Measurement points are done at CMOS levels: 0.5×$V_{DD}$
- I/O compensation cell enabled
- HSLV activated when $V_{DD}$ ≤ 2.7 V

Refer to *Section 6.3.17: I/O port characteristics* for more details on the input/output alternate function characteristics (NSS, SCK, MOSI, MISO for SPI).

**Table 98. SPI dynamic characteristics(1)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $f_{SCK}$ | SPI clock frequency | Master mode<br>1.71 V ≤ $V_{DD}$ ≤ 3.6 V<br>SPI1 | - | - | 70 | MHz |
| | | Master mode<br>2.7 V ≤ $V_{DD}$ ≤ 3.6 V<br>SPI1 | | | 80 | |
| | | Master mode<br>1.71 V ≤ $V_{DD}$ ≤ 3.6 V<br>SPI2, SPI3 | | | 80 | |
| | | Master mode<br>2.7 V ≤ $V_{DD}$ ≤ 3.6 V<br>SPI2, SPI3 | | | 100 | |
| | | Master mode<br>1.71 V ≤ $V_{DD}$ ≤ 3.6 V<br>SPI4, SPI5, SPI6 | | | 66 | |
| | | Slave receiver mode<br>1.71 V ≤ $V_{DD}$ ≤ 3.6 V<br>SPI1, SPI2, SPI3 | | | 100 | |
| | | Slave receiver mode<br>1.71 V ≤ $V_{DD}$ ≤ 3.6 V<br>SPI4, SPI5, SPI6 | | | 66 | |
| | | Slave mode transmitter/full duplex<br>2.7 V ≤ $V_{DD}$ ≤ 3.6 V | | | 38(2) | |
| | | Slave mode transmitter/full duplex<br>1.71 V ≤ $V_{DD}$ ≤ 3.6 V | | | 35(2) | |
| $t_{su(NSS)}$ | NSS setup time | Slave mode | 2 | - | - | ns |
| $t_{h(NSS)}$ | NSS hold time | | 1 | - | - | |
| $t_{w(SCKH)}$, $t_{w(SCKL)}$ | SCK high and low time | Master mode | $T_{pclk}$ - 1 | $T_{pclk}$ | $T_{pclk}$ + 1 | |

**Table 98. SPI dynamic characteristics(1) (continued)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $t_{su(MI)}$ | Data input setup time | Master mode | 1 | - | - | ns |
| $t_{su(SI)}$ | | Slave mode | 2 | - | - | |
| $t_{h(MI)}$ | Data input hold time | Master mode | 3 | - | - | |
| $t_{h(SI)}$ | | Slave mode | 1 | - | - | |
| $t_{a(SO)}$ | Data output access time | Slave mode | 9 | 11 | 16 | |
| $t_{dis(SO)}$ | Data output disable time | Slave mode | 3 | 5 | 7.5 | |
| $t_{v(SO)}$ | Data output valid time | Slave mode<br>2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 11 | 13 | |
| | | Slave mode<br>1.71 V ≤ $V_{DD}$ ≤ 3.6 V | - | 11 | 14 | |
| $t_{v(MO)}$ | | Master mode | - | 1.5 | 2.5 | |
| $t_{h(SO)}$ | Data output hold time | Slave mode<br>1.71 V ≤ $V_{DD}$ ≤ 3.6 V | 8 | - | - | |
| $t_{h(MO)}$ | | Master mode | 1 | - | - | |

1. Guaranteed by characterization results.
2. Maximum frequency in slave transmitter mode is determined by the sum of $t_{v(SO)}$ and $t_{su(MI)}$ which has to fit into SCK low or high phase preceding the SCK sampling edge. This value can be achieved when the SPI communicates with a master having $t_{su(MI)}$ = 0 while Duty(SCK) = 50%.

**Figure 46. SPI timing diagram - slave mode and CPHA = 0**

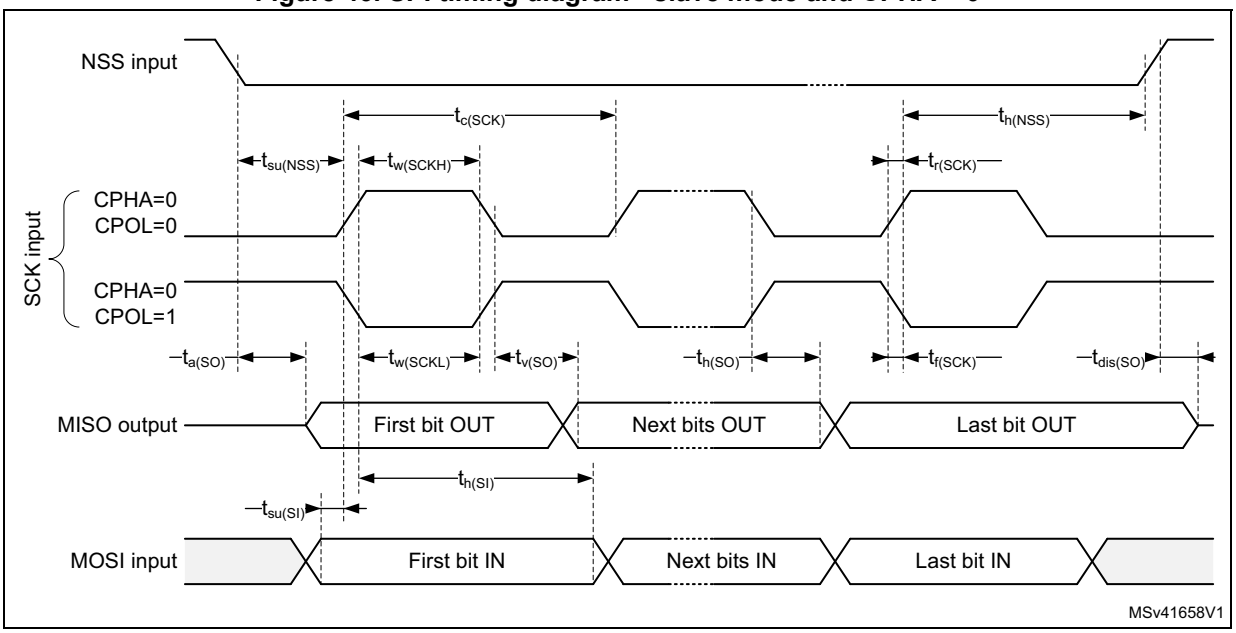
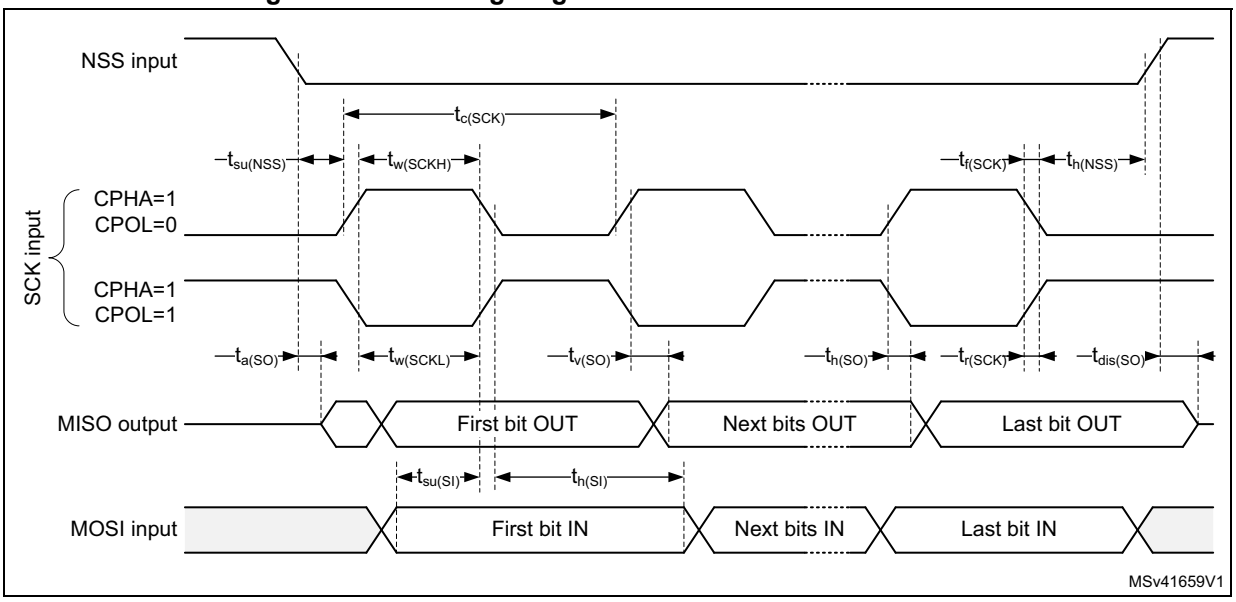
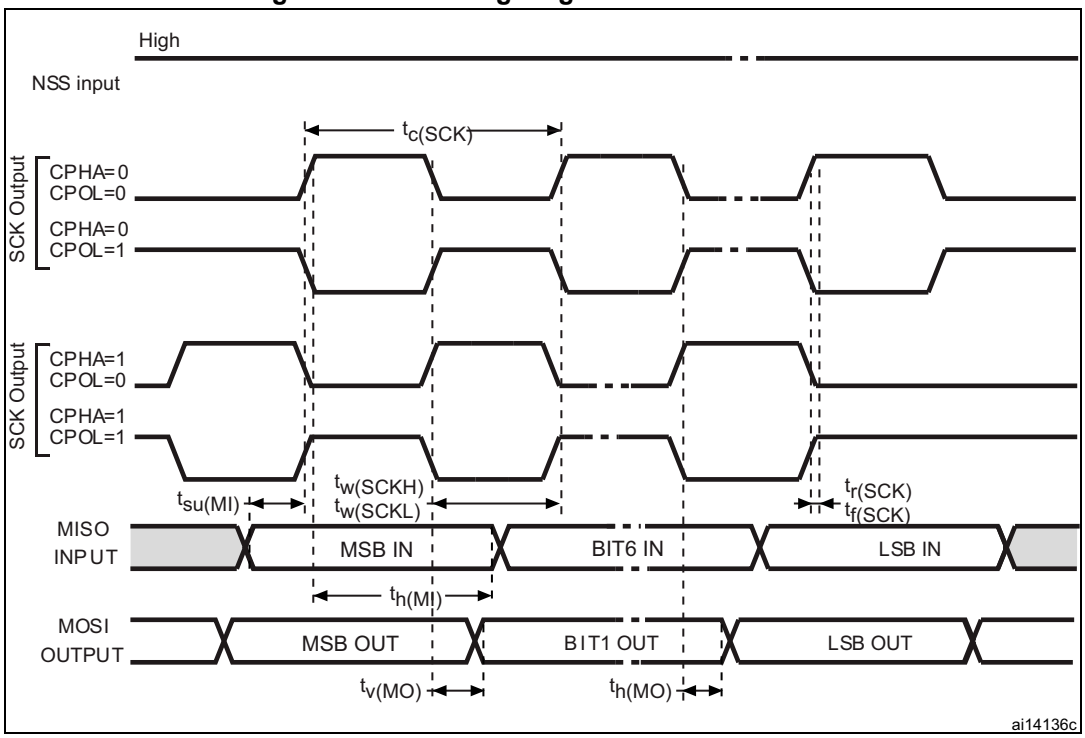


**Figure 47. SPI timing diagram - slave mode and CPHA = 1(1)**




1. Measurement points are done at $0.5 \times V_{DD}$ and with external $C_L$ = 30 pF.

**Figure 48. SPI timing diagram - master mode(1)**




1. Measurement points are done at $0.5 \times V_{DD}$ and with external $C_L$ = 30 pF.

## I2S interface characteristics

Unless otherwise specified, the parameters given in *Table 99* for the I2S interface are derived from tests performed under the ambient temperature, $f_{pclkx}$ frequency and $V_{DD}$

supply voltage conditions summarized in *Table 13: General operating conditions*, with the following configuration:

- Output speed is set to OSPEEDRy[1:0] = 10
- Capacitive load C = 30 pF
- Measurement points are done at CMOS levels: $0.5 \times V_{DD}$
- I/O compensation cell enabled

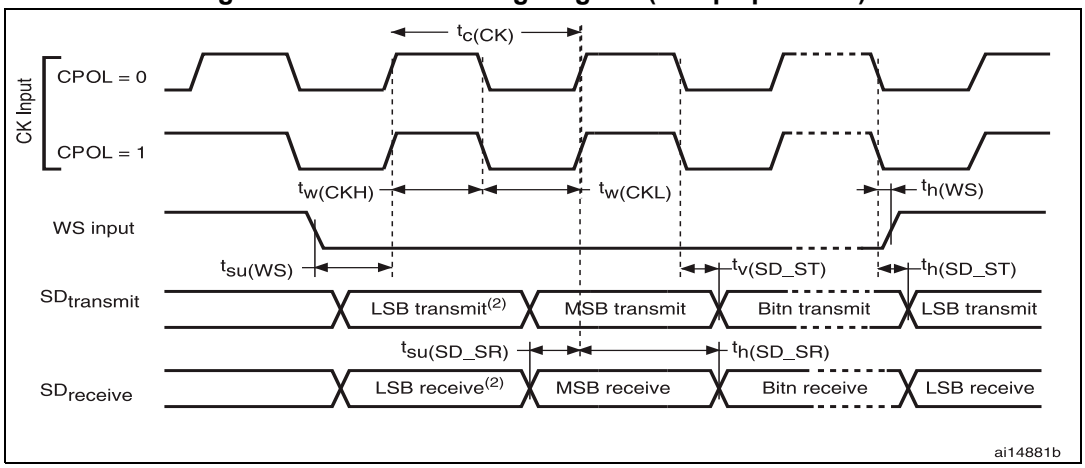
Refer to *Section 6.3.17: I/O port characteristics* for more details on the input/output alternate function characteristics (CK, SD, WS).

**Table 99. I2S dynamic characteristics(1)**

| Symbol | Parameter | Conditions | Min | Max | Unit |
|---|---|---|---|---|---|
| $f_{MCK}$ | I2S main clock output | - | 256×8K | 256×Fs | MHz |
| $f_{CK}$ | I2S clock frequency | Master data | - | 64×Fs | MHz |
| | | Slave data | - | 64×Fs | |
| $t_{v(WS)}$ | WS valid time | Master mode | - | 6.5 | ns |
| $t_{h(WS)}$ | WS hold time | Master mode | 0.5 | - | |
| $t_{su(WS)}$ | WS setup time | Slave mode | 1 | - | |
| $t_{h(WS)}$ | WS hold time | Slave mode | 0 | - | |
| $t_{su(SD_MR)}$ | Data input setup time | Master receiver | 2 | - | |
| $t_{su(SD_SR)}$ | | Slave receiver | 1.5 | - | |
| $t_{h(SD_MR)}$ | Data input hold time | Master receiver | 2 | - | |
| $t_{h(SD_SR)}$ | | Slave receiver | 0.5 | - | |
| $t_{v(SD_ST)}$ | Data output valid time | Slave transmitter (after enable edge) | - | 15 | |
| $t_{v(SD_MT)}$ | | Master transmitter (after enable edge) | - | 1 | |
| $t_{h(SD_ST)}$ | Data output hold time | Slave transmitter (after enable edge) | 8.5 | - | |
| $t_{h(SD_MT)}$ | | Master transmitter (after enable edge) | 0 | - | |

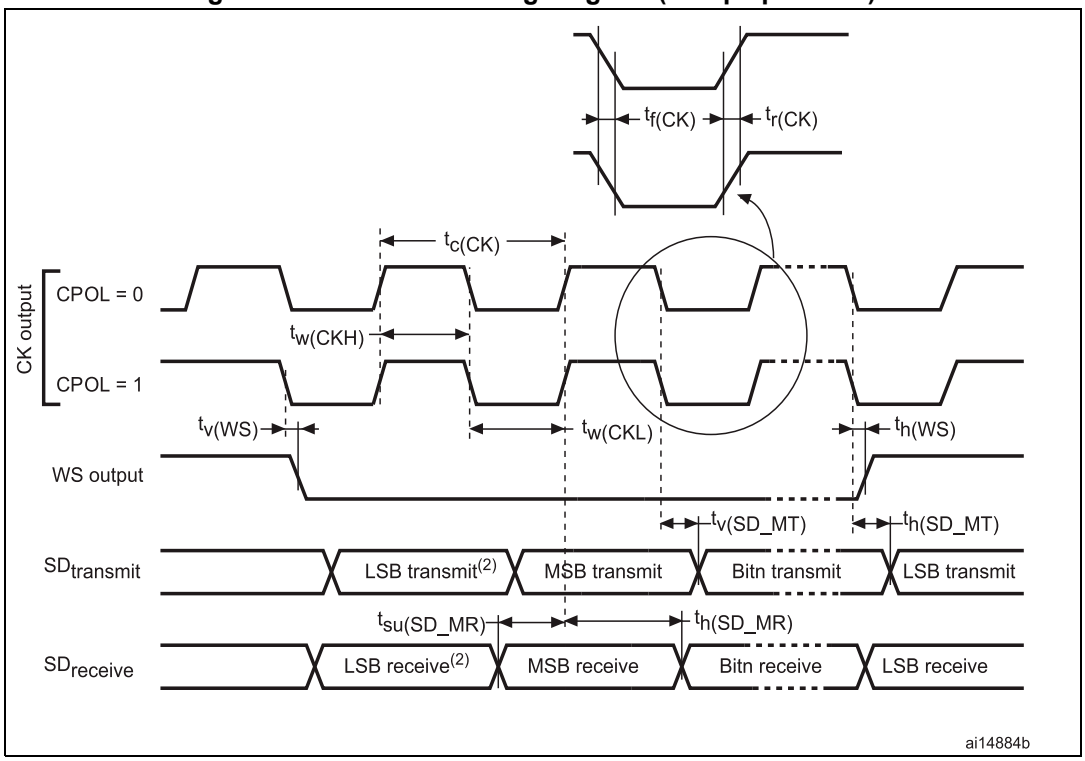
1. Guaranteed by characterization results.

**Figure 49. I2S slave timing diagram (Philips protocol)(1)**




1. LSB transmit/receive of the previously transmitted byte. No LSB transmit/receive is sent before the first byte.

**Figure 50. I2S master timing diagram (Philips protocol)(1)**




1. LSB transmit/receive of the previously transmitted byte. No LSB transmit/receive is sent before the first byte.

## SAI characteristics

Unless otherwise specified, the parameters given in *Table 100* for SAI are derived from tests performed under the ambient temperature, $F_{pclk2}$ frequency and $V_{DD}$ supply voltage

conditions summarized in *Table 13: General operating conditions*, with the following configuration:

- Output speed is set to OSPEEDRy[1:0] = 10
- Capacitive load C = 30 pF
- Measurement points are performed at CMOS levels: $0.5 \times V_{DD}$

Refer to *Section 6.3.17: I/O port characteristics* for more details on the input/output alternate function characteristics (SCK,SD,WS).

**Table 100. SAI characteristics(1)**

| Symbol | Parameter | Conditions | Min | Max | Unit |
|---|---|---|---|---|---|
| $f_{MCK}$ | SAI Main clock output | - | - | 50 | MHz |
| $F_{CK}$ | SAI bit clock frequency(2) | Master transmitter 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 45 | MHz |
| | | Master transmitter 1.71 V ≤ $V_{DD}$ ≤ 3.6 V | - | 27 | |
| | | Master receiver 1.71 V ≤ $V_{DD}$ ≤ 3.6 V | - | 27 | |
| | | Slave transmitter 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 45 | |
| | | Slave transmitter 1.71 V ≤ $V_{DD}$ ≤ 3.6 V | - | 31 | |
| | | Slave receiver 1.71 ≤ $V_{DD}$ ≤ 3.6 V | - | 50 | |
| $t_{v(FS)}$ | FS valid time | Master mode 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 11 | ns |
| | | Master mode 1.71 V ≤ $V_{DD}$ ≤ 3.6 V | - | 18 | |
| $t_{su(FS)}$ | FS setup time | Slave mode | 7 | - | |
| $t_{h(FS)}$ | FS hold time | Master mode | 2 | - | |
| | | Slave mode | 2.5 | - | |
| $t_{su(SD_A_MR)}$ | Data input setup time | Master receiver | 2 | - | |
| $t_{su(SD_B_SR)}$ | | Slave receiver | 1.5 | - | |
| $t_{h(SD_A_MR)}$ | Data input hold time | Master receiver | 3 | - | |
| $t_{h(SD_B_SR)}$ | | Slave receiver | 0.5 | - | |

**Table 100. SAI characteristics(1) (continued)**

| Symbol | Parameter | Conditions | Min | Max | Unit |
|---|---|---|---|---|---|
| $t_{v(SD_B_ST)}$ | Data output valid time | Slave transmitter (after enable edge) 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 11 | ns |
| | | Slave transmitter (after enable edge) 1.71 V ≤ $V_{DD}$ ≤ 3.6 V | - | 16 | |
| $t_{h(SD_B_ST)}$ | Data output hold time | Slave transmitter (after enable edge) | 8.5 | - | |
| $t_{v(SD_A_MT)}$ | Data output valid time | Master transmitter (after enable edge) 2.7 V ≤ $V_{DD}$ ≤ 3.6 V | - | 10 | |
| | | Master transmitter (after enable edge) 1.71 V ≤ $V_{DD}$ ≤ 3.6 V | - | 18 | |
| $t_{h(SD_A_MT)}$ | Data output hold time | Master transmitter (after enable edge) | 7 | - | |

1. Guaranteed by characterization results.
2. APB clock frequency must be at least twice SAI clock frequency.

**Figure 51. SAI master timing waveforms**

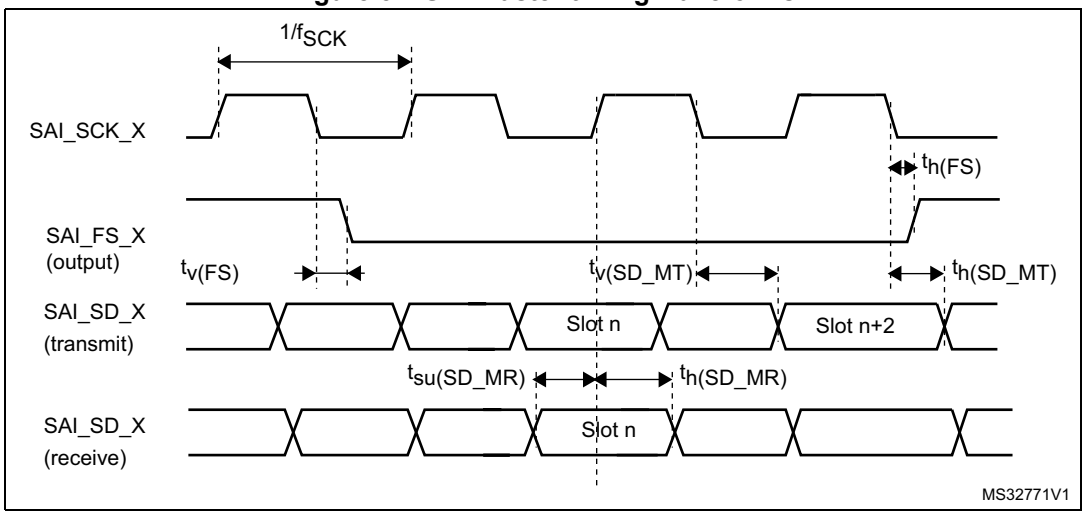
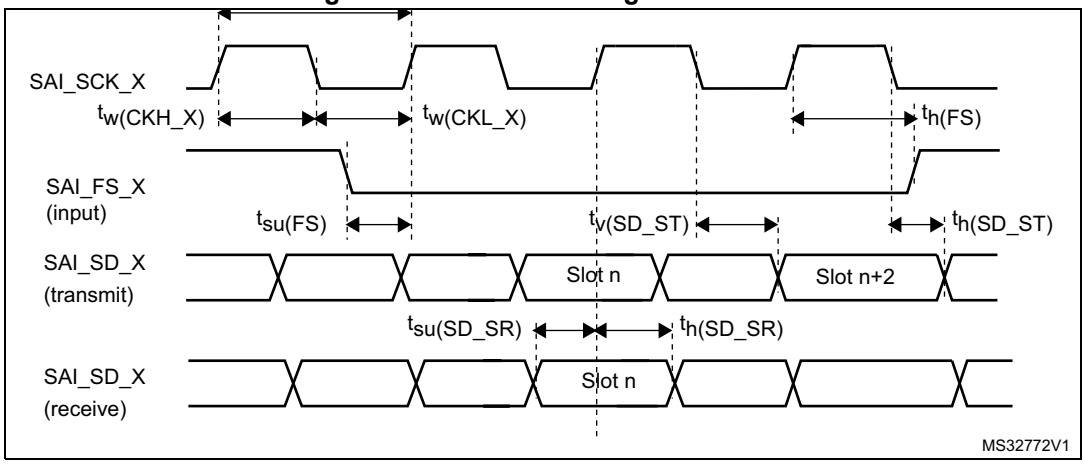



**Figure 52. SAI slave timing waveforms**



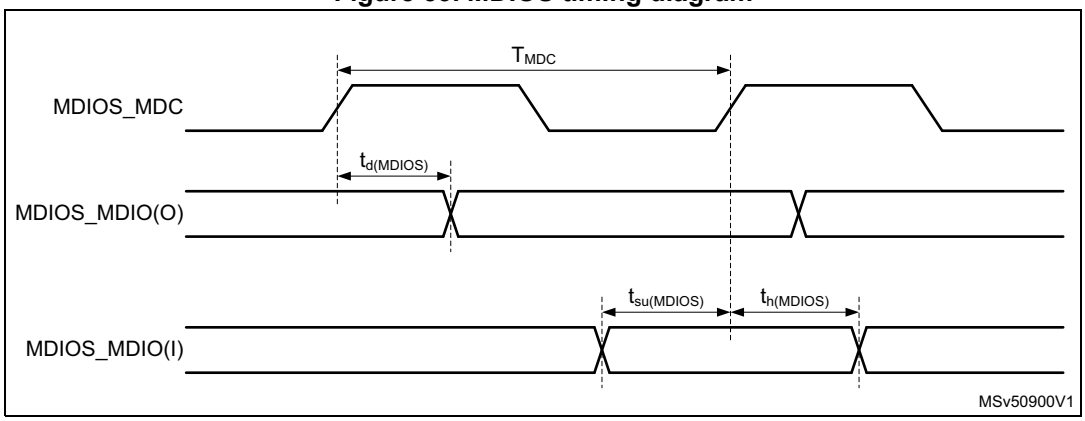
## MDIOS characteristics

**Table 101. MDIOS timing parameters**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $F_{MDC}$ | Management data clock | - | - | 30 | MHz |
| $t_{d(MDIOS)}$ | Management data input/output **output valid time** | 6.5 | 8 | 19 | ns |
| $t_{su(MDIOS)}$ | Management data input/output **setup time** | 1 | - | - | |
| $t_{h(MDIOS)}$ | Management data input/output **hold time** | 0.5 | - | - | |

The MDIOS controller is mapped on APB1 domain. The frequency of the APB bus should at least 1.5 times the MDC frequency: $F_{pclk1} \geq 1.5 * F_{MDC}$.

**Figure 53. MDIOS timing diagram**




## SD/SDIO MMC card host interface (SDMMC) characteristics

Unless otherwise specified, the parameters given in *Table 102* for the SDIO/MMC interface are derived from tests performed under the ambient temperature, $F_{hclk6}$ frequency and $V_{DD}$ supply voltage conditions summarized in *Table 13: General operating conditions*, with the following configuration:

- Output speed is set to OSPEEDRy[1:0] = 11
- Capacitive load C = 30 pF
- Measurement points are done at CMOS levels: $0.5 \times V_{DD}$
- I/O compensation cell enabled
- HSLV activated when $V_{DD} \leq 2.7$ V
- Delay block disabled

Refer to *Section 6.3.17: I/O port characteristics* for more details on the input/output characteristics.

**Table 102. Dynamic characteristics: SD / MMC / *e*•MMC characteristics, $V_{DD}$ = 2.7 V to 3.6 V(1)(2)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $f_{PP}$ | Clock frequency in data transfer mode | - | 0 | - | 130 | MHz |
| - | SDIO_CK/$f_{pclk2}$ frequency ratio | - | - | - | 8/3 | - |
| $t_{W(CKL)}$ | Clock low time | $f_{PP}$ = 52 MHz | 8.5 | 9.5 | - | ns |
| $t_{W(CKH)}$ | Clock high time | | 8.5 | 9.5 | - | |
| CMD, D inputs (referenced to CK) in MMC and SD HS/SDR(3)/DDR(3) mode | | | | | | |
| $t_{ISU}$ | Input setup time HS | - | 1.5 | - | - | ns |
| $t_{IH}$ | Input hold time HS | | 1.5 | - | - | |
| $t_{IDW}$(4) | Input valid window (variable window) | | 2.5 | - | - | |
| CMD, D outputs (referenced to CK) in MMC and SD HS/SDR(3)/DDR(3) mode | | | | | | |
| $t_{OV}$ | Output valid time HS | - | - | 5 | 6.5 | ns |
| $t_{OH}$ | Output hold time HS | | 2.5 | - | - | |
| CMD, D inputs (referenced to CK) in SD default mode | | | | | | |
| $t_{ISUD}$ | Input setup time SD | - | 1.5 | - | - | ns |
| $t_{IHD}$ | Input hold time SD | | 1.5 | - | - | |
| CMD, D outputs (referenced to CK) in SD default mode | | | | | | |
| $t_{OVD}$ | Output valid default time SD | - | - | 0.5 | 1.5 | ns |
| $t_{OHD}$ | Output hold default time SD | | 0 | - | - | |

1. Guaranteed by characterization results.
2. Above 100 MHz, $C_L$ = 20 pF.
3. For SD 1.8 V support, an external voltage converter is required.
4. The minimum window of time where the data needs to be stable for proper sampling in tuning mode.

**Table 103. Dynamic characteristics: SD / MMC / *e*•MMC characteristics $V_{DD}$ = 1.71 V to 1.9 V(1)(2)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $f_{PP}$ | Clock frequency in data transfer mode | - | 0 | - | 105 | MHz |
| - | SDIO_CK/$f_{pclk2}$ frequency ratio | - | - | - | 8/3 | - |
| $t_{W(CKL)}$ | Clock low time | $f_{PP}$ = 52 MHz | 8.5 | 9.5 | - | ns |
| $t_{W(CKH)}$ | Clock high time | | 8.5 | 9.5 | - | |
| CMD, D inputs (referenced to CK) in *e*•MMC mode | | | | | | |
| $t_{ISU}$ | Input setup time HS | - | 1.5 | - | - | ns |
| $t_{IH}$ | Input hold time HS | | 2.5 | - | - | |
| $t_{IDW}$(3) | Input valid window (variable window) | | 3 | - | - | |
| CMD, D outputs (referenced to CK) in *e*•MMC mode | | | | | | |

**Table 103. Dynamic characteristics: SD / MMC / *e*•MMC characteristics $V_{DD}$ = 1.71 V to 1.9 V(1)(2) (continued)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $t_{OV}$ | Output valid time HS | - | - | 5 | 6 | ns |
| $t_{OH}$ | Output hold time HS | | 4 | - | - | |

1. Guaranteed by characterization results.
2. $C_L$ = 20 pF.
3. The minimum window of time where the data needs to be stable for proper sampling in tuning mode.

**Figure 54. SDIO high-speed mode**

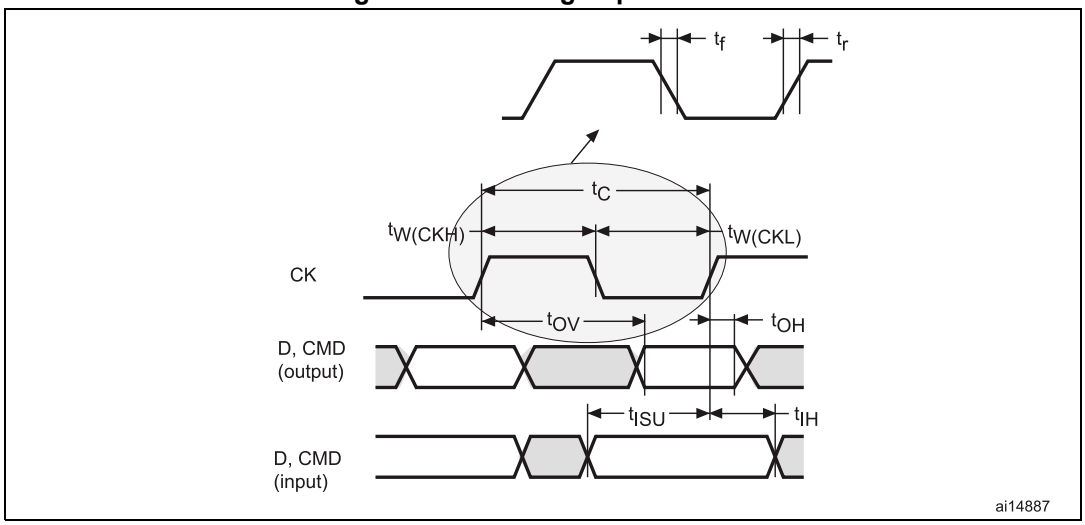



**Figure 55. SD default mode**

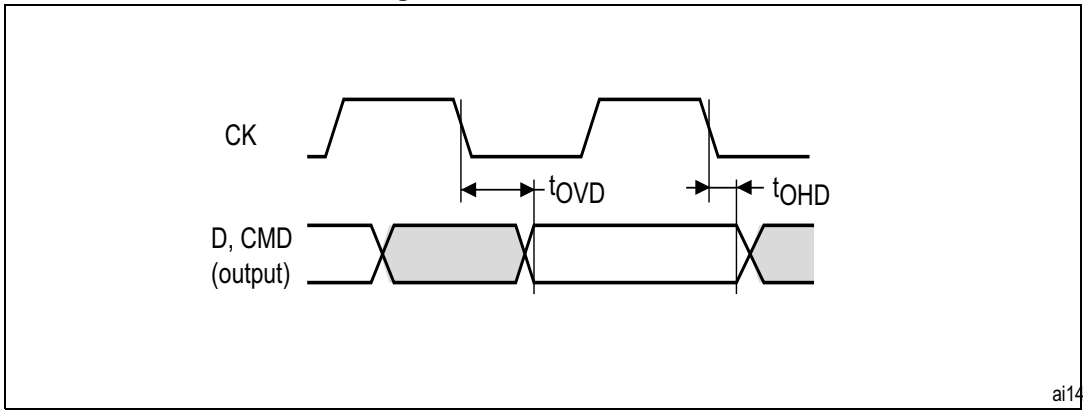
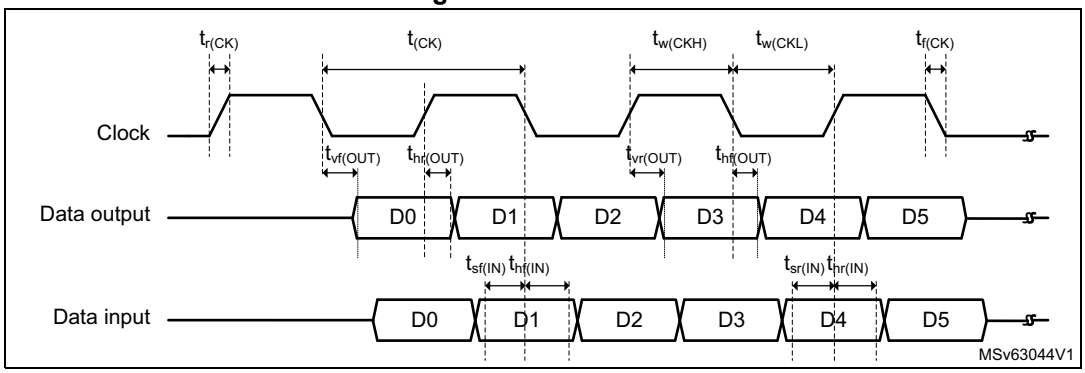


**Figure 56. DDR mode**




## FDCAN (controller area network) interface

Refer to *Section 6.3.17: I/O port characteristics* for more details on the input/output alternate function characteristics (FDCANx_TX and FDCANx_RX).

## USB OTG_FS characteristics

The USB interface is fully compliant with the USB specification version 2.0 and is USB-IF certified (for Full-speed device operation).

**Table 104. USB OTG_FS electrical characteristics**

| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $V_{DD33USB}$ | USB transceiver operating voltage | - | 3.0(1) | - | 3.6 | V |
| $R_{PUI}$ | Embedded USB_DP pull-up value during idle | - | 900 | 1250 | 1600 | Ω |
| $R_{PUR}$ | Embedded USB_DP pull-up value during reception | - | 1400 | 2300 | 3200 | |
| $Z_{DRV}$ | Output driver impedance(2) | Driver high and low | 28 | 36 | 44 | |

1. The USB functionality is ensured down to 2.7 V but not the full USB electrical characteristics which are degraded in the 2.7 to 3.0 V voltage range.
2. No external termination series resistors are required on USB_DP (D+) and USB_DM (D-); the matching impedance is already included in the embedded driver.

## Ethernet (ETH) characteristics

Unless otherwise specified, the parameters given in *Table 105*, *Table 106*, *Table 107*, *Table 108* and *Table 109* for MDIO/SMA, RMII, GMII, RGMII and MII are derived from tests performed under the ambient temperature, $F_{axiss_ck}$ frequency summarized in *Table 13: General operating conditions*, with the following configuration:

- Output speed is set to OSPEEDRy[1:0] = 10
- Capacitive load C = 20 pF
- Measurement points are done at CMOS levels: $0.5 \times V_{DD}$.

Refer to *Section 6.3.17: I/O port characteristics* for more details on the input/output characteristics.

*Table 105* gives the list of Ethernet MAC timings for the MDIO/SMA and *Figure 57* shows the corresponding timing diagram.

**Table 105. Dynamics characteristics: Ethernet MAC timings for MDIO/SMA(1)**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $t_{MDC}$ | MDC cycle time(2.5 MHz) | 399 | 400 | 401 | ns |
| $T_{d(MDIO)}$ | Write data valid time | 0.5 | 1 | 3 | |
| $t_{su(MDIO)}$ | Read data setup time | 13.5 | - | - | |
| $t_{h(MDIO)}$ | Read data hold time | 0 | - | - | |

1. Guaranteed by characterization results.

**Figure 57. Ethernet MDIO/SMA timing diagram**

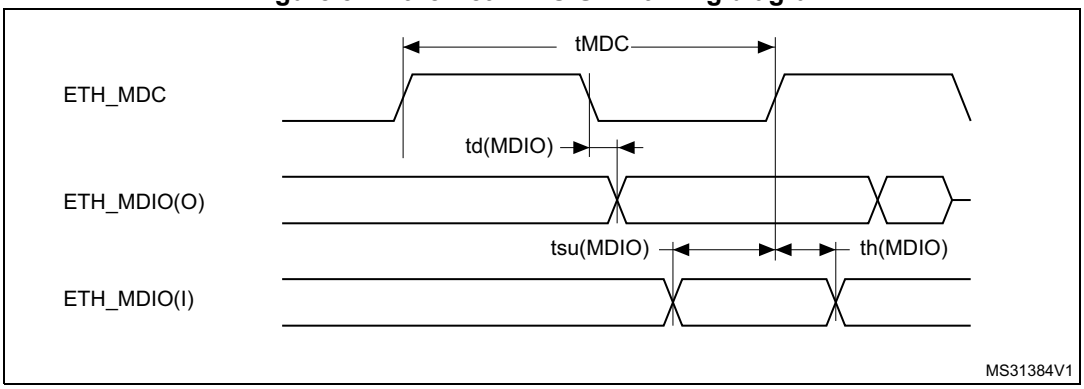



*Table 106* gives the list of Ethernet MAC timings for the RMII and *Figure 58* shows the corresponding timing diagram.

**Table 106. Dynamics characteristics: Ethernet MAC timings for RMII(1)**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $t_{su(RXD)}$ | Receive data setup time | 2 | - | - | ns |
| $t_{ih(RXD)}$ | Receive data hold time | 1.5 | - | - | |
| $t_{su(CRS)}$ | Carrier sense setup time | 1.5 | - | - | |
| $t_{ih(CRS)}$ | Carrier sense hold time | 1.5 | - | - | |
| $t_{d(TXEN)}$ | Transmit enable valid delay time | 5.5 | 6.5 | 9.5 | |
| $t_{d(TXD)}$ | Transmit data valid delay time | 6 | 6.5 | 10 | |

1. Guaranteed by characterization results.

**Figure 58. Ethernet RMII timing diagram**

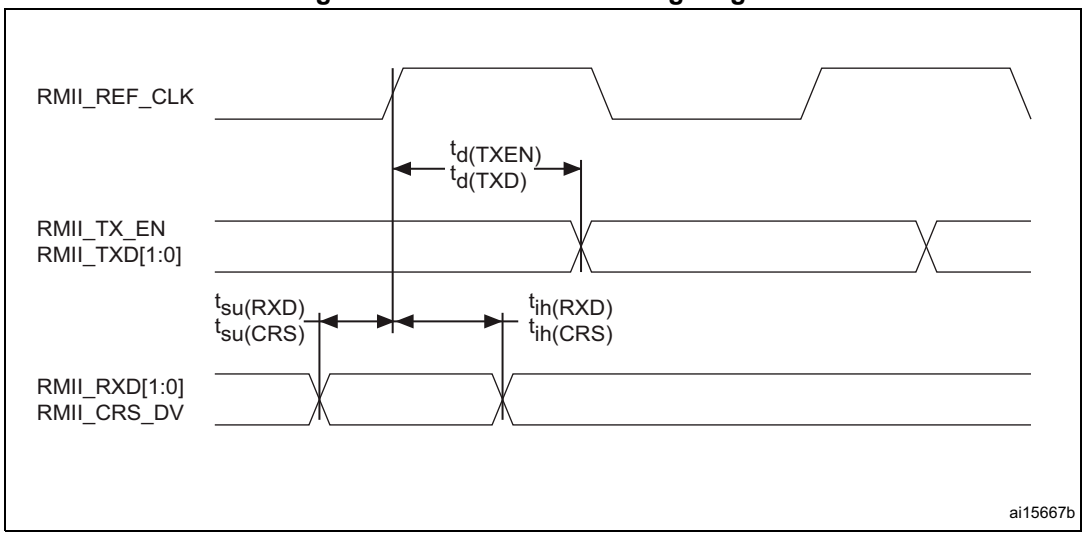



*Table 107* gives the list of Ethernet MAC timings for MII and *Figure 59* shows the corresponding timing diagram.

**Table 107. Dynamics characteristics: Ethernet MAC timings for MII(1)**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $t_{su(RXD)}$ | Receive data setup time | 2 | - | - | ns |
| $t_{ih(RXD)}$ | Receive data hold time | 1 | - | - | |
| $t_{su(DV)}$ | Data valid setup time | 1 | - | - | |
| $t_{ih(DV)}$ | Data valid hold time | 0.5 | - | - | |
| $t_{su(ER)}$ | Error setup time | 1 | - | - | |
| $t_{ih(ER)}$ | Error hold time | 0.5 | - | - | |
| $t_{d(TXEN)}$ | Transmit enable valid delay time | 6 | 7.5 | 10.5 | |
| $t_{d(TXD)}$ | Transmit data valid delay time | 7 | 8 | 11 | |

1. Guaranteed by characterization results.

**Figure 59. Ethernet MII timing diagram**

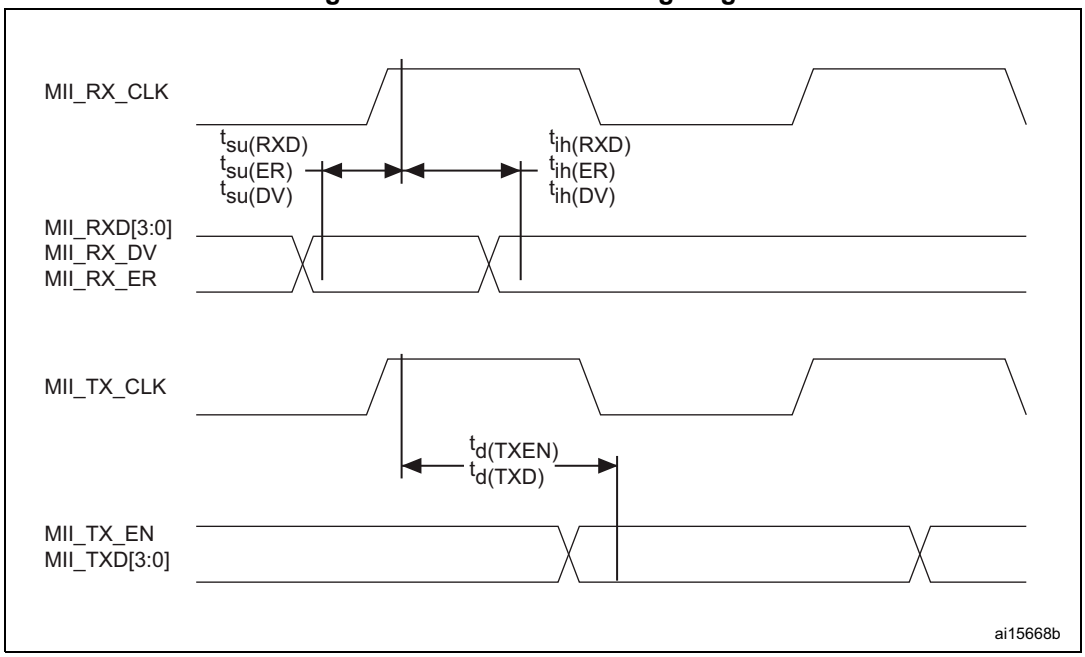



**Table 108. Dynamics characteristics: Ethernet MAC signals for GMII (1)**

| Symbol | Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $t_{su(RXD)}$ | Receive data setup time | 1 | - | - | ns |
| $t_{ih(RXD)}$ | Receive data hold time | 0.5 | - | - | |
| $t_{su(DV)}$ | Data valid setup time | 1 | - | - | |
| $t_{ih(DV)}$ | Data valid hold time | 0.5 | - | - | |
| $t_{su(ER)}$ | Error setup time | 1 | - | - | |
| $t_{ih(ER)}$ | Error hold time | 0.5 | - | - | |
| $t_{d(TXEN)}$ | Transmit enable valid delay time | 1 | 1.5 | 2 | |
| $t_{d(TXD)}$ | Transmit data valid delay time | 1 | 2 | 3 | |

1. Guaranteed by characterization results.

**Figure 60. Ethernet GMII timing diagram**

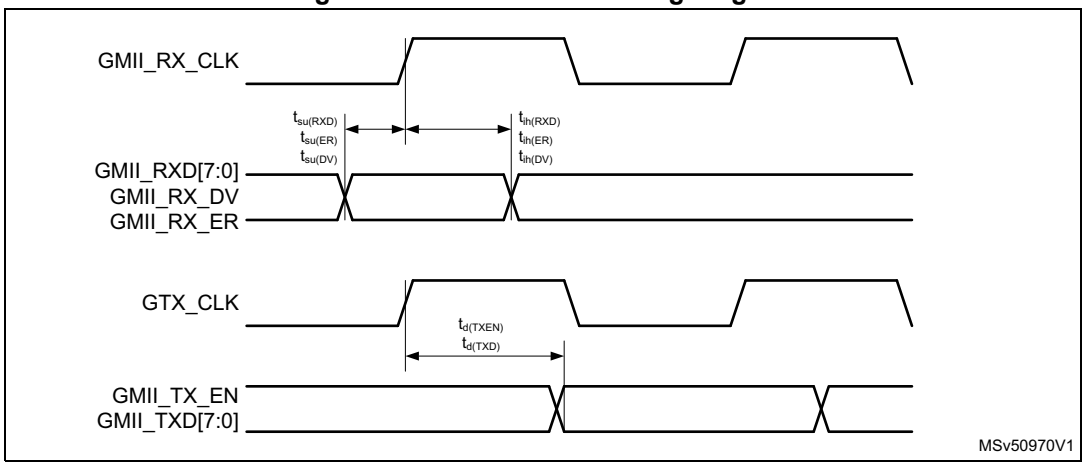
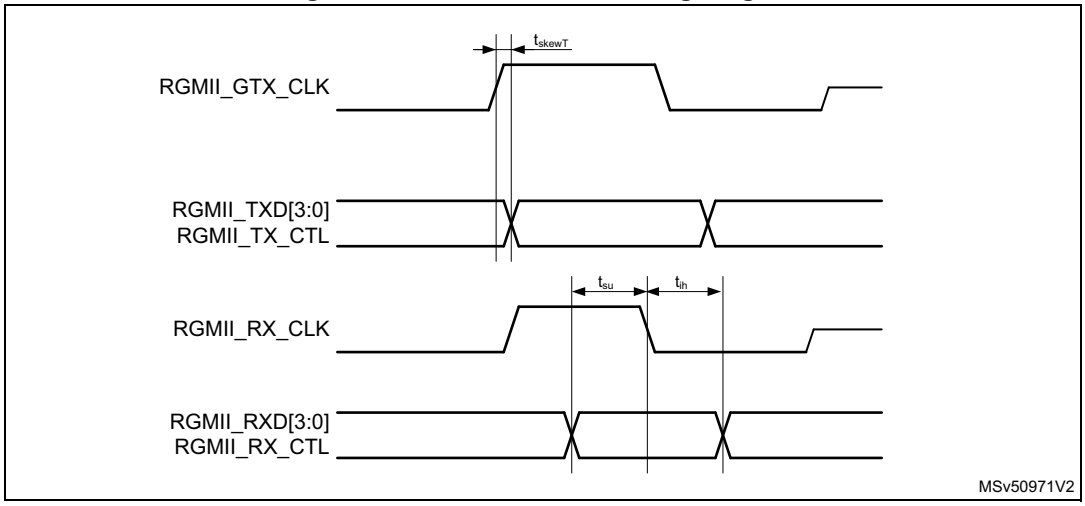



**Table 109. Dynamics characteristics: Ethernet MAC signals for RGMII (1)**

| Symbol | Rating | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $t_{su(RXD)}$ | Receive data setup time | 1.12(2) | - | - | ns |
| $t_{ih(RXD)}$ | Receive data hold time | 0.83(2) | - | - | |
| $t_{su(RX_CTL)}$ | Receive control valid setup time | 1.12(2) | - | - | |
| $t_{ih(RX_CTL)}$ | Receive control valid hold time | 0.83(2) | - | - | |
| $T_{skewT(TX_CTL)}$ | Transmit control valid delay time | -0.25 | 0.25 | 0.5 | |
| $T_{skewT(TXD)}$ | Transmit data valid delay time | -0.25 | 0.25 | 0.5 | |

1. Guaranteed by characterization results.
2. Guaranteed by design.

**Figure 61. Ethernet RGMII timing diagram**



### 6.3.37 USART interface characteristics

Unless otherwise specified, the parameters given in *Table 110* for USART are derived from tests performed under the ambient temperature, $f_{HCLK}$ frequency and $V_{DD}$ supply voltage conditions summarized in *Table 110*, with the following configuration:

- Output speed is set to OSPEEDRy[1:0] = 10
- Capacitive load C = 30 pF
- Measurement points are done at CMOS levels: $0.5 \times V_{DD}$

Refer to *Section 6.3.17: I/O port characteristics* for more details on the input/output alternate function characteristics (NSS, CK, TX, RX for USART).

**Table 110. USART characteristics(1)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $f_{CK}$ | USART clock frequency | Master mode USART2,3,6 | - | - | 12.5 | MHz |
| | | Master mode USART1 | | | 16.5 | |
| | | Slave mode | - | - | 27 | |
| $t_{su(NSS)}$ | NSS setup time | Slave mode | $t_{ker}+2$ | - | - | ns |
| $t_{h(NSS)}$ | NSS hold time | Slave mode | 2 | - | - | ns |
| $t_{w(CKH)}$, $t_{w(CKL)}$ | CK high and low time | Master mode | $1/f_{CK}/2 - 1$ | 1/fck/2 | $1/f_{CK}/2 + 1$ | ns |
| $t_{su(RX)}$ | Data input setup time | Master mode | $t_{ker}+3$ | - | - | ns |
| | | Slave mode | 2 | - | - | |
| $t_{hRX)}$ | Data input hold time | Master mode | 1 | - | - | ns |
| | | Slave mode | 1 | - | - | |
| $t_{v(TX)}$ | Data output valid time | Slave mode | - | 10 | 18 | ns |
| | | Master mode | - | 0.5 | 1 | |
| th(TX) | Data output hold time | Slave mode | 8 | - | - | ns |
| | | Master mode | 0 | - | - | |

1. 1.Guaranteed by characterization results.

### 6.3.38 USB High-Speed PHY characteristics

**Table 111. USB High-Speed PHY characteristics(1)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $R_{REF}$ | Reference resistor on USB_RREF pin | - | 2.97 | 3.00 | 3.03 | kΩ |

**Table 111. USB High-Speed PHY characteristics(1) (continued)**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $I_{DDA1V1_REG(PHY)}$ | High-Speed TX(2) | One USB port | - | 1.4 | - | mA |
| | | Two USB ports | - | 2.4 | - | |
| | High-Speed RX(3) / Idle | One USB port | - | 5.4 | - | |
| | | Two USB ports | - | 10.4 | - | |
| | Ful-Speed and Low-Speed mode (Suspend, TX or RX) | | - | 0 | - | |
| $I_{DDA1V8_REG(PHY)}$ | High-Speed TX(2) | One USB port | - | 25.5 | - | mA |
| | | Two USB ports | - | 50.5 | - | |
| | High-Speed RX(3) / Idle | One USB port | - | 2.5 | - | |
| | | Two USB ports | - | 5.5 | - | |
| | Ful-Speed and Low-Speed mode (Suspend, TX or RX) | | - | 0 | - | |
| $I_{DDA3V3_USBHS(PHY)}$ | High-Speed TX(2) | One USB port | - | 5 | - | mA |
| | | Two USB ports | - | 7 | - | |
| | High-Speed RX(3) / Idle | One USB port | - | 6 | - | |
| | | Two USB ports | - | 10 | - | |
| | Full-Speed Suspend (host mode) | One USB port | - | 0 | - | |
| | | Two USB ports | - | 0 | - | |
| | Full-Speed Suspend (peripheral mode) | One USB port | - | 0.2 | - | |
| | | Two USB ports | - | 0.4 | - | |
| | Full-Speed TX(2) | One USB port | - | 6.5 | - | |
| | | Two USB ports | - | 10.5 | - | |
| | Full-Speed RX(3) | One USB port | - | 6.5 | - | |
| | | Two USB ports | - | 11.5 | - | |
| | Low-Speed TX(2) | One USB port | - | 7 | - | |
| | | Two USB ports | - | 11.5 | - | |
| | Low-Speed RX(3) | One USB port | - | 4.3 | - | |
| | | Two USB ports | - | 6.1 | - | |

1. Guaranteed by design unless otherwise specified.
2. USB link 100% of the time in transmission
3. USB link 100% of the time in reception

### 6.3.39 JTAG/SWD interface characteristics

Unless otherwise specified, the parameters given in *Table 112* and *Table 113* for JTAG/SWD are derived from tests performed under the ambient temperature, $f_{rcc_c_ck}$ frequency and

$V_{DD}$ supply voltage summarized in *Table 13: General operating conditions*, with the following configuration:

- Output speed is set to OSPEEDRy[1:0] = 0x10
- Capacitive load C = 30 pF
- Measurement points are done at CMOS levels: $0.5 \times V_{DD}$

Refer to *Section 6.3.17: I/O port characteristics* for more details on the input/output characteristics.

**Table 112. Dynamics characteristics: JTAG characteristics**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $F_{pp}$ | $T_{CK}$ clock frequency | 2.7 V < $V_{DD}$ < 3.6 V | - | - | 35 | MHz |
| $1/t_{c(TCK)}$ | | 1.71 V < $V_{DD}$ < 3.6 V | - | - | 27 | |
| $ti_{su(TMS)}$ | TMS input setup time | - | 2.5 | - | - | ns |
| $ti_{h(TMS)}$ | TMS input hold time | - | 1 | - | - | |
| $ti_{su(TDI)}$ | TDI input setup time | - | 2 | - | - | |
| $ti_{h(TDI)}$ | TDI input hold time | - | 1 | - | - | |
| $t_{ov\ (TDO)}$ | TDO output valid time | 2.7 V < $V_{DD}$ < 3.6 V | - | 8 | 14 | |
| | | 1.71 V < $V_{DD}$< 3.6 V | - | 8 | 18 | |
| $t_{oh(TDO)}$ | TDO output hold time | - | 7 | - | - | |

**Table 113. Dynamics characteristics: SWD characteristics**

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $F_{pp}$ | SWCLK clock frequency | 2.7 V < $V_{DD}$ < 3.6 V | - | - | 71 | MHz |
| $1/t_{c(SWCLK)}$ | | 1.71 V < $V_{DD}$ < 3.6 V | - | - | 55 | |
| $ti_{su(SWDIO)}$ | SWDIO input setup time | - | 2.5 | - | - | ns |
| $ti_{h(SWDIO)}$ | SWDIO input hold time | - | 1 | - | - | |
| $t_{ov\ (SWDIO)}$ | SWDIO output valid time | 2.7 V < $V_{DD}$ < 3.6 V | - | 8.5 | 14 | |
| | | 1.71 V < $V_{DD}$ < 3.6 V | - | 8.5 | 18 | |
| $t_{oh(SWDIO)}$ | SWDIO output hold time | - | 8 | - | - | |

**Figure 62. JTAG timing diagram**

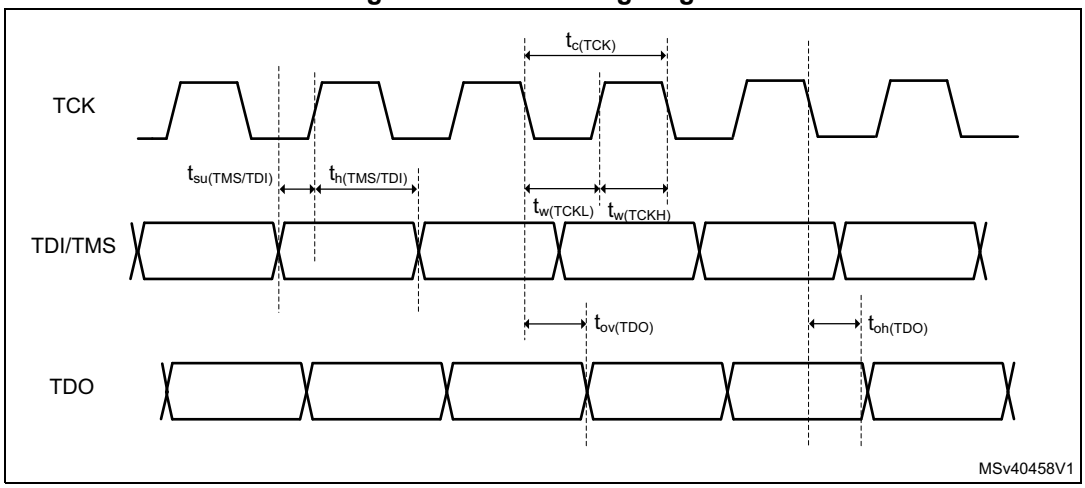
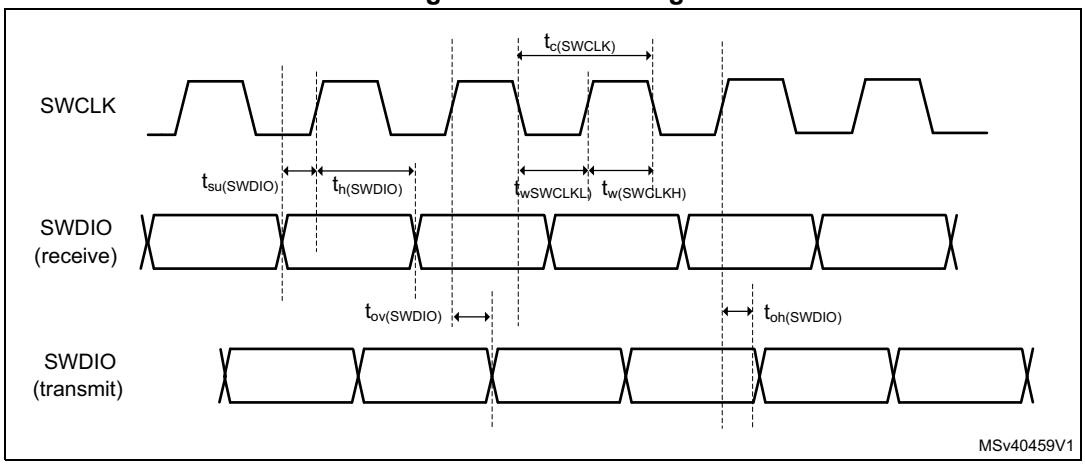



**Figure 63. SWD timing**



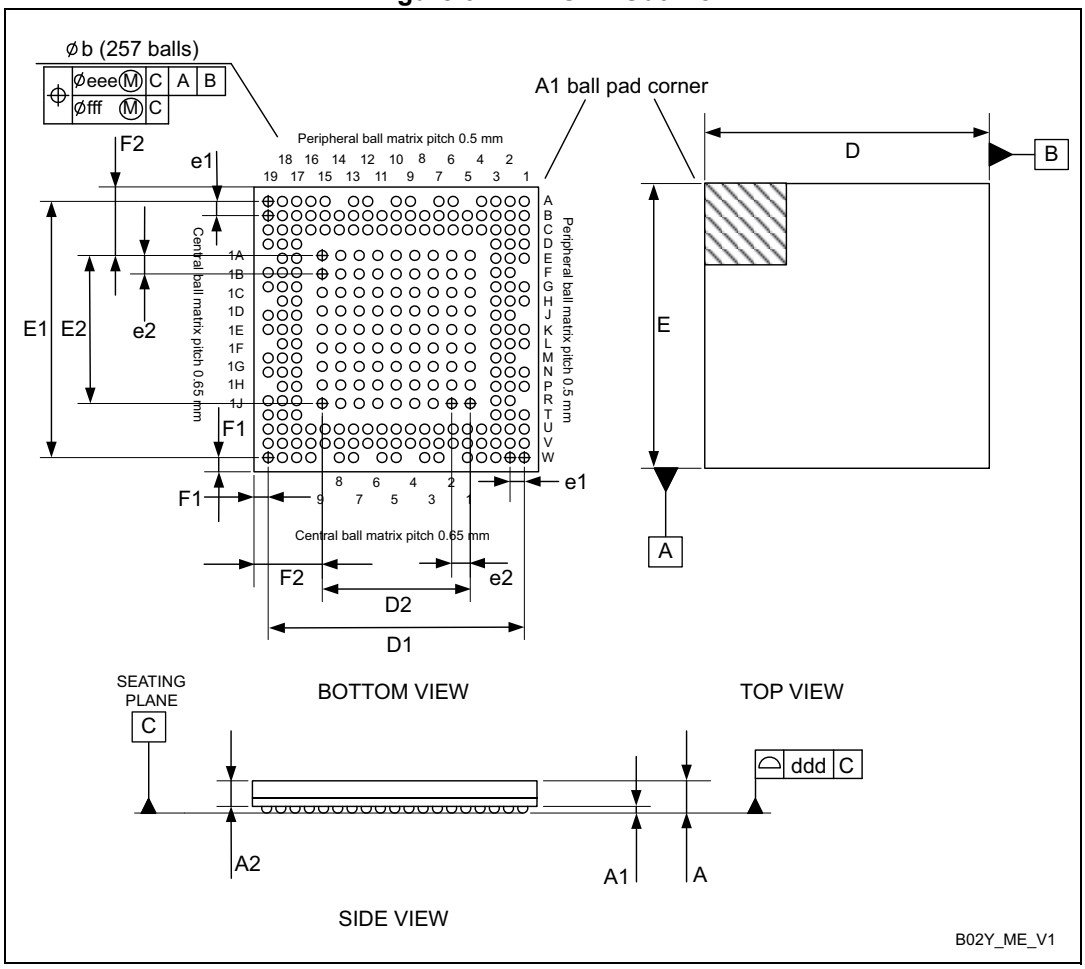
# 7 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK is an ST trademark.

## 7.1 TFBGA257 package information

This TFBGA is a 257 balls, 10x10 mm, 0.5/0.65 mm pitch, low profile fine pitch ball grid array package

**Figure 64. TFBGA - Outline**



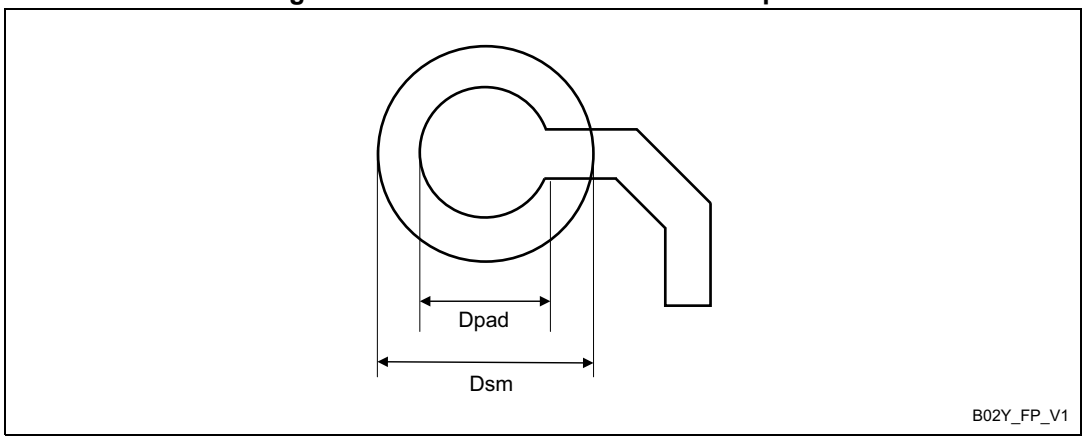

1. Drawing is not to scale.

**Table 114. TFBGA - Mechanical data**

| Symbol | millimeters | | | inches[1] | | |
|---|---|---|---|---|---|---|
| | Min | Typ | Max | Min | Typ | Max |
| A | - | - | 1.200 | - | - | 0.0472 |
| A1[2] | 0.150 | - | - | 0.0059 | - | - |
| A2 | - | 0.810 | - | - | 0.0319 | - |
| b[3] | 0.300 | 0.350 | 0.400 | 0.0118 | 0.0138 | 0.0157 |
| D | 9.850 | 10.000 | 10.150 | 0.3878 | 0.3937 | 0.3996 |
| D1 | - | 9.000 | - | - | 0.3543 | - |
| E | 9.850 | 10.000 | 10.150 | 0.3878 | 0.3937 | 0.3996 |
| E1 | - | 9.000 | - | - | 0.3543 | - |
| D2 | - | 5.200 | - | - | 0.2047 | - |
| E2 | - | 5.200 | - | - | 0.2047 | - |
| e1 | - | 0.500 | - | - | 0.0197 | - |
| e2 | - | 0.650 | - | - | 0.0256 | - |
| F1 | - | 0.500 | - | - | 0.0197 | - |
| F2 | - | 2.400 | - | - | 0.0945 | - |
| ddd | - | - | 0.100 | - | - | 0.0039 |
| eee[4] | - | - | 0.150 | - | - | 0.0059 |
| fff[5] | - | - | 0.050 | - | - | 0.0020 |

1. Values in inches are converted from mm and rounded to 4 decimal digits.
2. - The terminal A1 corner must be identified on the top surface by using a corner chamfer, ink or metalized markings, or other feature of package body or integral heat slug.
   - A distinguishing feature is allowable on the bottom surface of the package to identify the terminal A1 corner. Exact shape of each corner is optional.
3. Initial ball equal 0.300 mm.
4. The tolerance of position that controls the location of the pattern of balls with respect to datums A and B. For each ball there is a cylindrical tolerance zone eee perpendicular to datum C and located on true position with respect to datums A and B as defined by e. The axis perpendicular to datum C of each ball must lie within this tolerance zone.
5. The tolerance of position that controls the location of the balls within the matrix with respect to each other. For each ball there is a cylindrical tolerance zone fff perpendicular to datum C and located on true position as defined by e. The axis perpendicular to datum C of each ball must lie within this tolerance zone. Each tolerance zone fff in the array is contained entirely in the respective zone eee above The axis of each ball must lie simultaneously in both tolerance zones.

**Figure 65. TFBGA - Recommended footprint**




1. Dimensions are expressed in millimeters.

**Table 115. TFBGA - Recommended PCB design rules (0.5/0.65 mm pitch, BGA)**

| Dimension | Recommended values |
|---|---|
| Pitch | 0.5/0.65 mm |
| Dpad | 0.230 mm |
| Dsm | 0.390 mm typ. |
| Stencil opening | 0.230 mm |
| Stencil thickness | 0.125 mm to 0.100 mm |

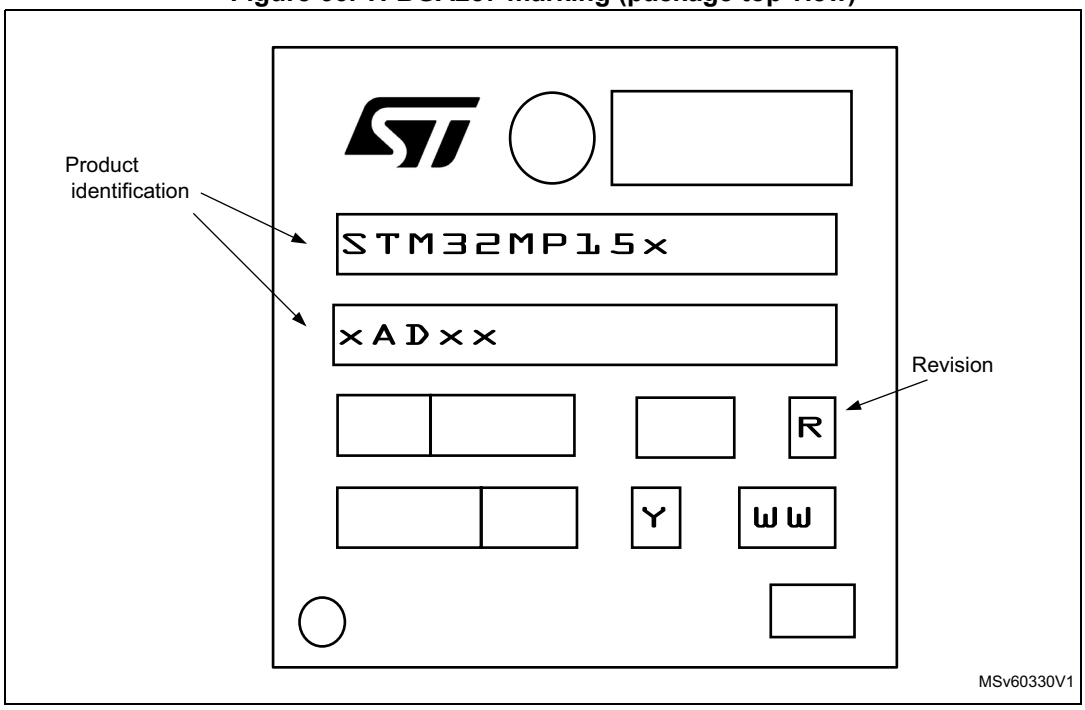
### Device marking

The following figure gives an example of topside marking orientation versus ball A1 identifier location.

The printed markings may differ depending on the supply chain.

Other optional marking or inset/upset marks, which identify the parts throughout supply chain operations, are not indicated below.

**Figure 66. TFBGA257 marking (package top view)**

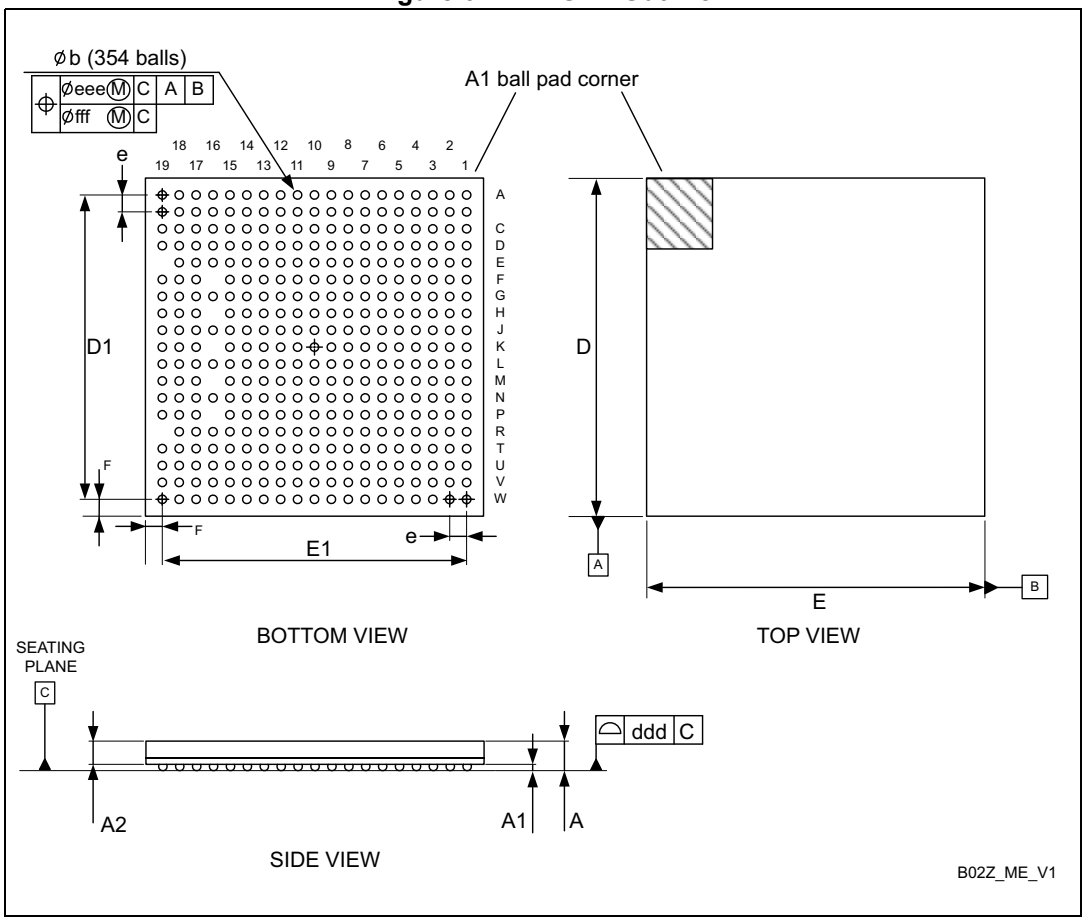



1. Parts marked as ES or E or accompanied by an Engineering Sample notification letter are not yet qualified and therefore not approved for use in production. ST is not responsible for any consequences resulting from such use. In no event will ST be liable for the customer using any of these engineering samples in production. ST's Quality department must be contacted prior to any decision to use these engineering samples to run a qualification activity.

## 7.2 LFBGA354 package information

This LFBGA is a 354 balls, 16x16 mm, 0.8 mm pitch, low profile fine pitch ball grid array package

**Figure 67. LFBGA - Outline**




1. Drawing is not to scale.
2. The tolerance of position that controls the location of the balls within the matrix with respect to each other. For each ball there is a cylindrical tolerance zone fff perpendicular to datum C and located on true position as defined by e. The axis perpendicular to datum C of each ball must lie within this tolerance zone. Each tolerance zone fff in the array is contained entirely in the respective zone eee above. The axis of each ball must lie simultaneously in both tolerance zones.

**Table 116. LFBGA - Mechanical data**

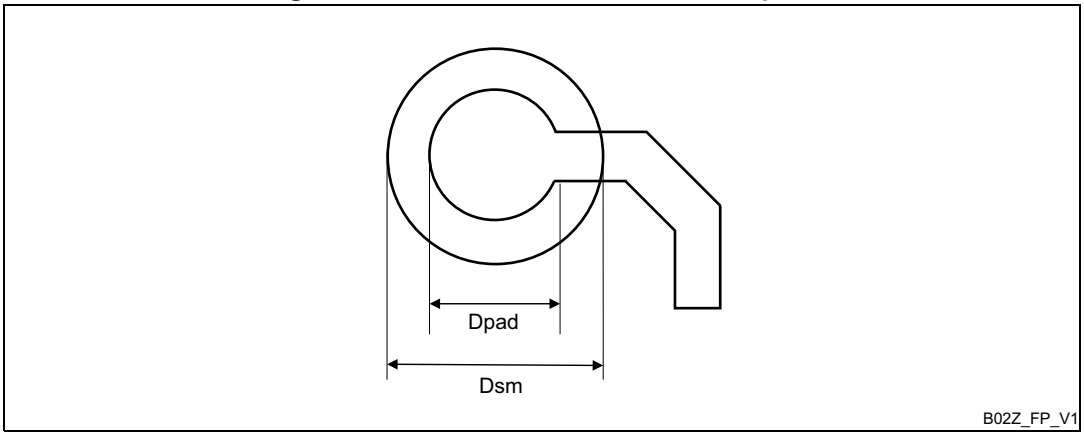
| Symbol | millimeters | | | inches[1] | | |
|---|---|---|---|---|---|---|
| | Min | Typ | Max | Min | Typ | Max |
| A[2] | - | - | 1.290 | - | - | 0.0508 |
| A1[3] | 0.250 | - | - | 0.0098 | - | - |
| A2 | - | 0.900 | - | - | 0.0354 | - |
| b[4] | 0.350 | 0.400 | 0.450 | 0.0138 | 0.0157 | 0.0177 |
| D | 15.850 | 16.000 | 16.150 | 0.6240 | 0.6299 | 0.6358 |

**Table 116. LFBGA - Mechanical data (continued)**

| Symbol | millimeters | | | inches[1] | | |
|---|---|---|---|---|---|---|
| | Min | Typ | Max | Min | Typ | Max |
| D1 | - | 14.400 | - | - | 0.5669 | - |
| E | 15.850 | 16.000 | 16.150 | 0.6240 | 0.6299 | 0.6358 |
| E1 | - | 14.400 | - | - | 0.5669 | - |
| e | - | 0.800 | - | - | 0.0315 | - |
| F | - | 0.800 | - | - | 0.0315 | - |
| ddd | - | - | 0.100 | - | - | 0.0039 |
| eee[5] | - | - | 0.150 | - | - | 0.0059 |
| fff[6] | - | - | 0.080 | - | - | 0.0031 |

1. Values in inches are converted from mm and rounded to 4 decimal digits.
2. LFBGA stands for Low profile Fine pitch Ball Grid Array package.
   Low profile: 1.20mm < A ≤ 1.70mm / Fine pitch: e < 1.00mm pitch. The total profile height (Dim A) is measured from the seating plane to the top of the component The maximum total package height is calculated by the RSS method (Root Sum Square).
   A Max = A1 Typ + A2 Typ + A4 Typ + $\sqrt{(A1^2 + A2^2 + A4^2}$ tolerance values).
3. The terminal A1 corner must be identified on the top surface by using a corner chamfer, ink or metalized markings, or other feature of package body or integral heat slug.
   A distinguishing feature is allowable on the bottom surface of the package to identify the terminal A1 corner. Exact shape of each corner is optional.
4. Initial ball equal 0.400 mm.
5. The tolerance of position that controls the location of the pattern of balls with respect to datums A and B. For each ball there is a cylindrical tolerance zone eee perpendicular to datum C and located on true position with respect to datums A and B as defined by e. The axis perpendicular to datum C of each ball must lie within this tolerance zone.
6. The tolerance of position that controls the location of the balls within the matrix with respect to each other. For each ball there is a cylindrical tolerance zone fff perpendicular to datum C and located on true position as defined by e. The axis perpendicular to datum C of each ball must lie within this tolerance zone.
   Each tolerance zone fff in the array is contained entirely in the respective zone eee above The axis of each ball must lie simultaneously in both tolerance zones.

**Figure 68. LFBGA - Recommended footprint**




1. Dimensions are expressed in millimeters.

**Table 117. LFBGA - Recommended PCB design rules (0.8 mm pitch, BGA)**

| Dimension | Recommended values |
|---|---|
| Pitch | 0.8 mm |
| Dpad | 0.320 mm |
| Dsm | 0.520 mm typ. |
| Stencil opening | 0.320 mm |
| Stencil thickness | 0.125 mm to 0.100 mm |

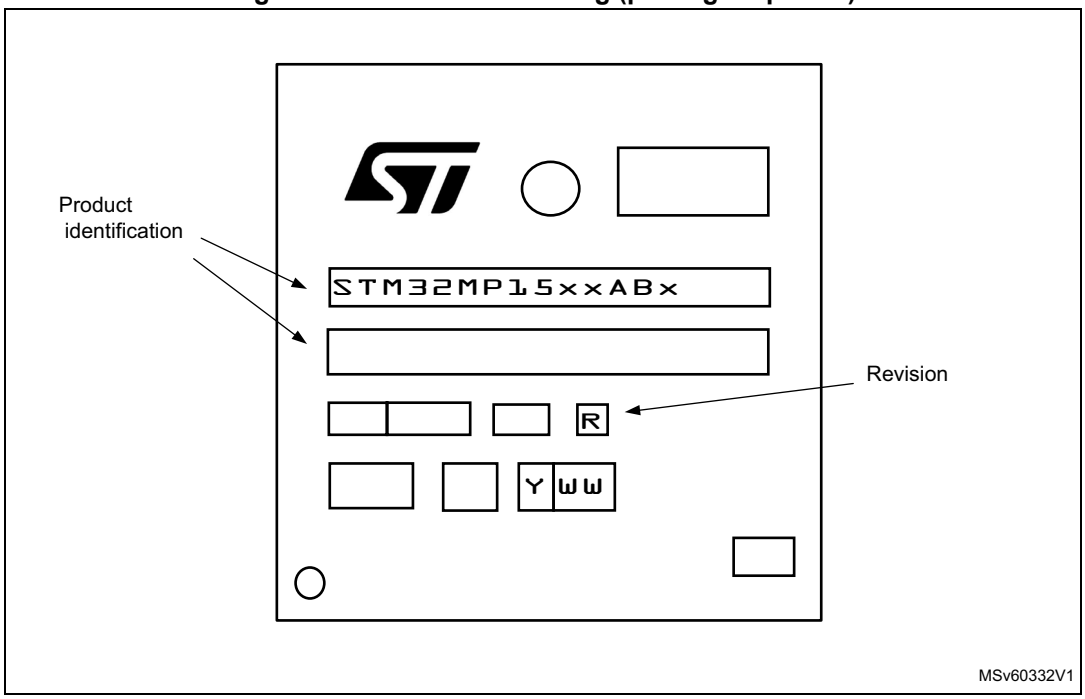
## Device marking

The following figure gives an example of topside marking orientation versus ball A1 identifier location.

The printed markings may differ depending on the supply chain.

Other optional marking or inset/upset marks, which identify the parts throughout supply chain operations, are not indicated below.

**Figure 69. LFBGA354 marking (package top view)**

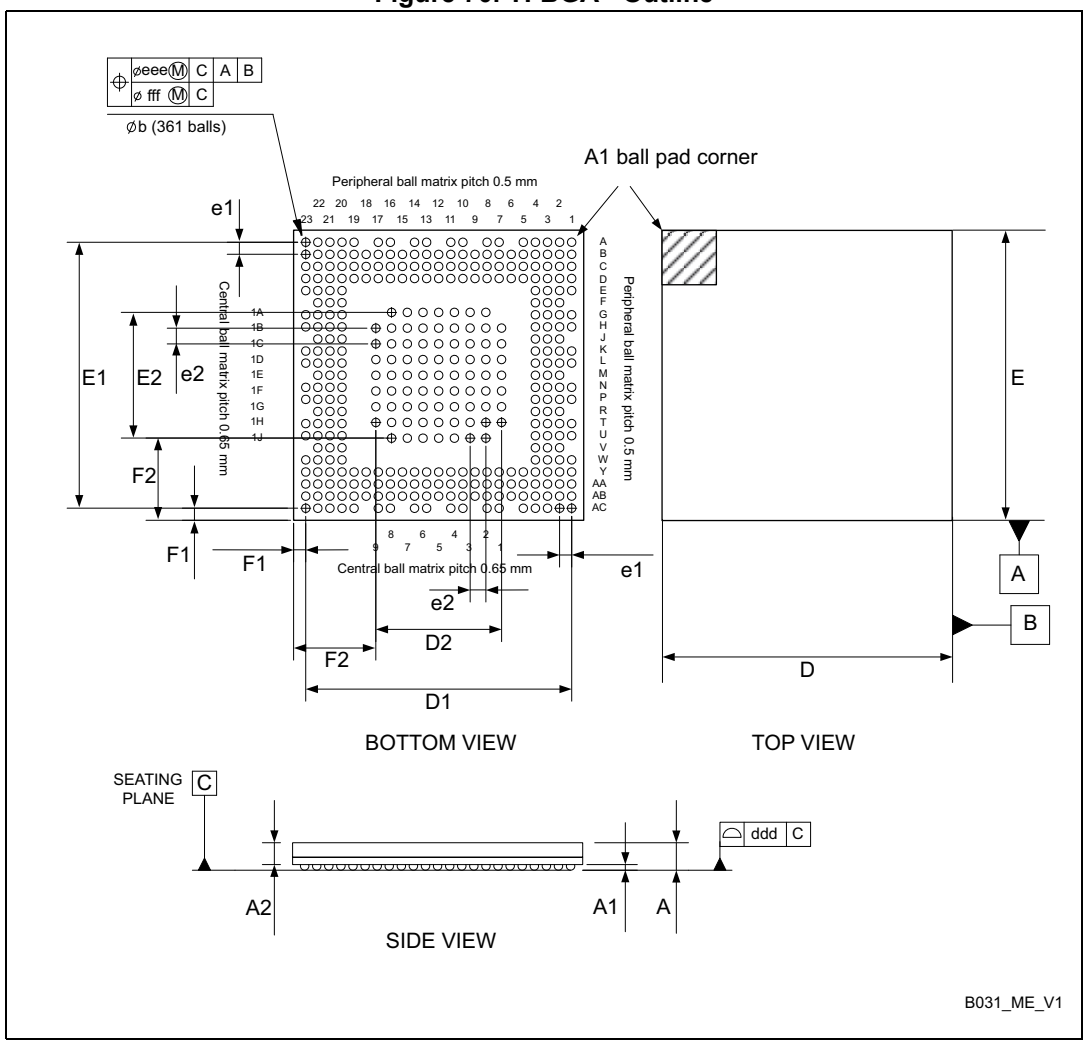



1. Parts marked as ES or E or accompanied by an Engineering Sample notification letter are not yet qualified and therefore not approved for use in production. ST is not responsible for any consequences resulting from such use. In no event will ST be liable for the customer using any of these engineering samples in production. ST's Quality department must be contacted prior to any decision to use these engineering samples to run a qualification activity.

## 7.3 TFBA361 package information

This TFBGA is a 361 ball, 12x12 mm, 0.5/0.65 mm pitch, thin profile fine pitch ball grid array package.

**Figure 70. TFBGA - Outline**




1. Drawing is not to scale.
2. The terminal A1 corner must be identified on the top surface by using a corner chamfer, ink or metalized markings, or other feature of package body or integral heat slug. A distinguishing feature is allowable on the bottom surface of the package to identify the terminal A1 corner. Exact shape of each corner is optional.

**Table 118. TFBGA - Mechanical data**

| Symbol | millimeters | | | inches[1] | | |
|---|---|---|---|---|---|---|
| | Min | Typ | Max | Min | Typ | Max |
| A[2] | - | - | 1.200 | - | - | 0.0472 |
| A1 | 0.150 | - | - | 0.0059 | - | - |
| A2 | - | 0.810 | - | - | 0.0319 | - |
| b[3] | 0.300 | 0.350 | 0.400 | 0.0118 | 0.0138 | 0.0157 |
| D | 11.850 | 12.000 | 12.150 | 0.4665 | 0.4724 | 0.4783 |
| D1 | - | 11.000 | - | - | 0.4331 | - |
| E | 11.850 | 12.000 | 12.150 | 0.4665 | 0.4724 | 0.4783 |
| E1 | - | 11.000 | - | - | 0.4331 | - |
| D2 | - | 5.200 | - | - | 0.2047 | - |
| E2 | - | 5.200 | - | - | 0.2047 | - |
| e1 | - | 0.500 | - | - | 0.0197 | - |
| e2 | - | 0.650 | - | - | 0.0256 | - |
| F1 | - | 0.500 | - | - | 0.0197 | - |
| F2 | - | 3.400 | - | - | 0.1339 | - |
| ddd | - | - | 0.080 | - | - | 0.0031 |
| eee[4] | - | - | 0.150 | - | - | 0.0059 |
| fff[5] | - | - | 0.080 | - | - | 0.0031 |

1. Values in inches are converted from mm and rounded to 4 decimal digits.
2. TFBGA stands for Thin Profile Fine Pitch Ball Grid Array. The total profile height (dim A) is measured from the seating plane to the top of the component.
3. Initial ball equal to 0.300 mm.
4. The tolerance of position that controls the location of the pattern of balls with respect to datums A and B. For each ball there is a cylindrical tolerance zone eee perpendicular to datum C and located on true position with respect to datums A and B as defined by e. The axis perpendicular to datum C of each ball must lie within this tolerance zone.
5. The tolerance of position that controls the location of the balls within the matrix with respect to each other. For each ball there is a cylindrical tolerance zone fff perpendicular to datum C and located on true position as defined by e. The axis perpendicular to datum C of each ball must lie within this tolerance zone. Each tolerance zone fff in the array is contained entirely in the respective zone eee above The axis of each ball must lie simultaneously in both tolerance zones.

**Figure 71. TFBGA - Recommended footprint**

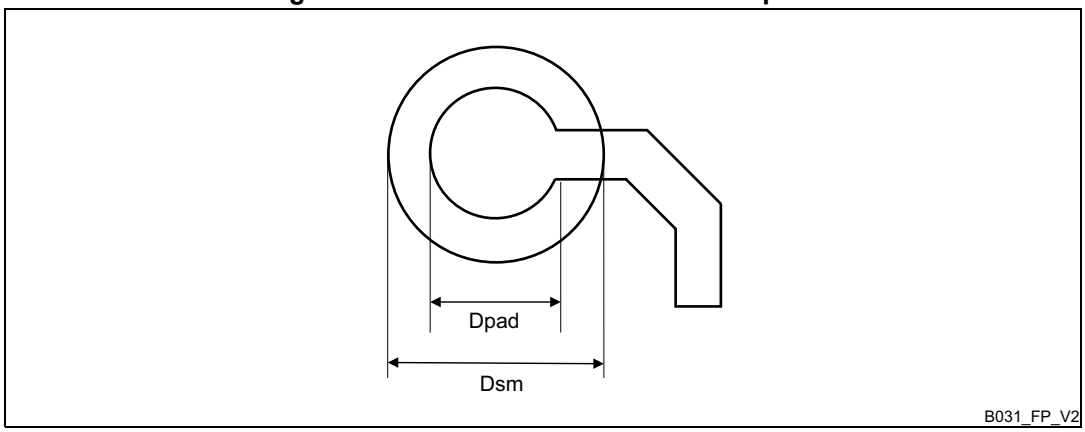



**Table 119. TFBGA - Recommended PCB design rules (0.5/0.65 mm pitch BGA)**

| Dimension | Recommended values |
|---|---|
| Pitch | 0.5/0.65 mm |
| Dpad | 0.230 mm |
| Dsm | 0.390 mm typ. |
| Stencil opening | 0.230 mm |
| Stencil thickness | 0.125 mm to 0.100 mm |

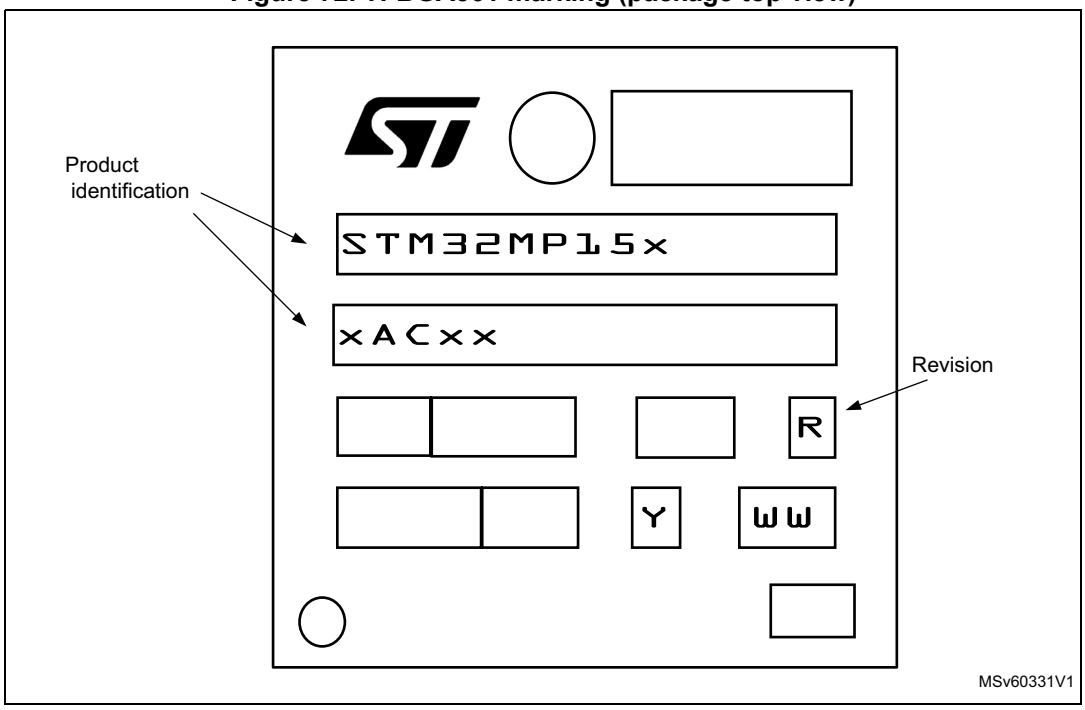
### Device marking

The following figure gives an example of topside marking orientation versus ball A1 identifier location.

The printed markings may differ depending on the supply chain.

Other optional marking or inset/upset marks, which identify the parts throughout supply chain operations, are not indicated below.

**Figure 72. TFBGA361 marking (package top view)**

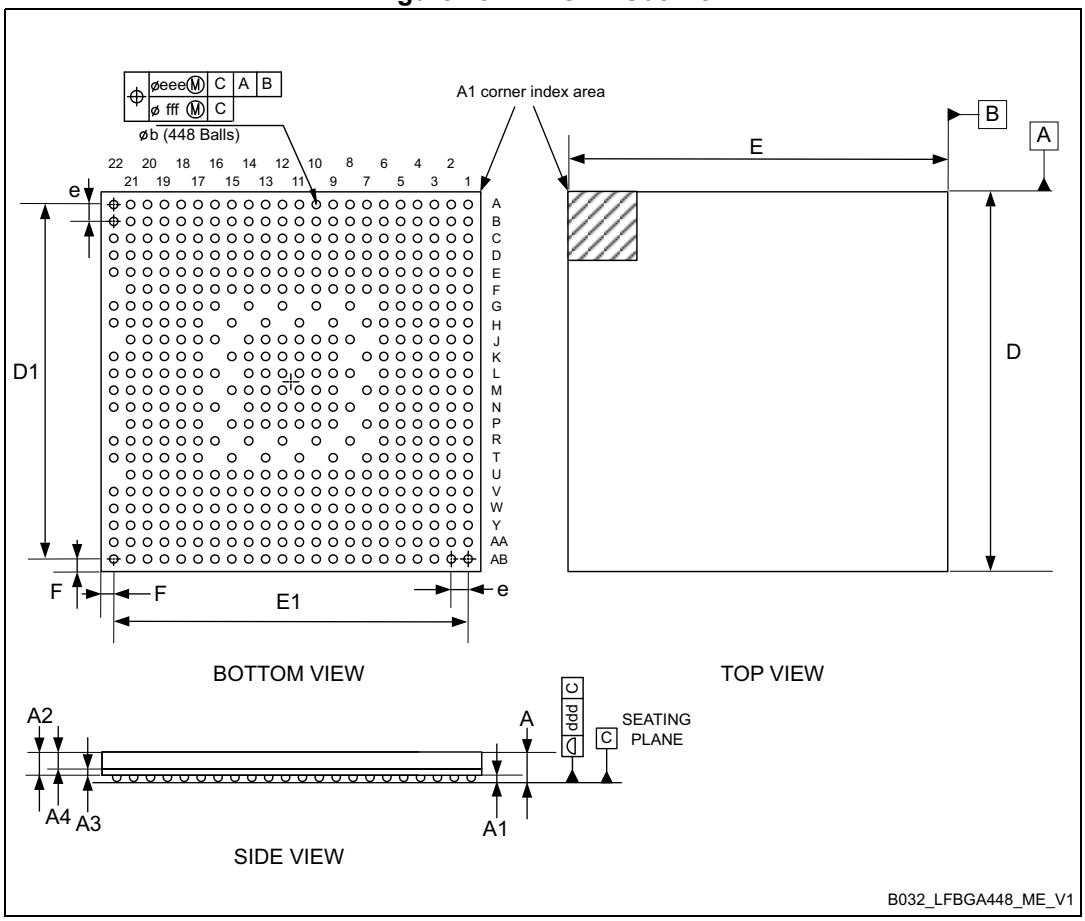



1. Parts marked as ES or E or accompanied by an Engineering Sample notification letter are not yet qualified and therefore not approved for use in production. ST is not responsible for any consequences resulting from such use. In no event will ST be liable for the customer using any of these engineering samples in production. ST's Quality department must be contacted prior to any decision to use these engineering samples to run a qualification activity.

## 7.4 LFBGA448 package information

This LFBGA is a 448 balls, 18x18 mm, 0.8 mm pitch, low profile fine pitch ball grid array package.

**Figure 73. LFBGA - Outline**




1. Drawing is not to scale.
2. The tolerance of position that controls the location of the balls within the matrix with respect to each other. For each ball there is a cylindrical tolerance zone fff perpendicular to datum C and located on true position as defined by e. The axis perpendicular to datum C of each ball must lie within this tolerance zone. Each tolerance zone fff in the array is contained entirely in the respective zone eee above. The axis of each ball must lie simultaneously in both tolerance zones.

**Table 120. LFBGA - Mechanical data**

| Symbol | millimeters | | | inches[1] | | |
|---|---|---|---|---|---|---|
| | Min | Typ | Max | Min | Typ | Max |
| A | - | - | 1.270 | - | - | 0.0500 |
| A1 | 0.250 | 0.290 | 0.330 | 0.0098 | 0.0114 | 0.0130 |
| A2 | 0.790 | 0.880 | 0.970 | 0.0311 | 0.0346 | 0.0382 |
| A3 | 0.240 | 0.28 | 0.320 | 0.0094 | 0.0110 | 0.0126 |
| A4 | 0.550 | 0.600 | 0.650 | 0.0217 | 0.0236 | 0.0256 |

**Table 120. LFBGA - Mechanical data (continued)**

| Symbol | millimeters | | | inches[1] | | |
|---|---|---|---|---|---|---|
| | Min | Typ | Max | Min | Typ | Max |
| b[2] | 0.350 | 0.400 | 0.450 | 0.0138 | 0.0157 | 0.0177 |
| D | 17.900 | 18.000 | 18.100 | 0.7047 | 0.7087 | 0.7126 |
| D1 | - | 16.800 | - | - | 0.6614 | - |
| E | 17.900 | 18.000 | 18.100 | 0.7047 | 0.7087 | 0.7126 |
| E1 | - | 16.800 | - | - | 0.6614 | - |
| e | - | 0.800 | - | - | 0.0315 | - |
| F | - | 0.600 | - | - | 0.0236 | - |
| ddd | - | 0.120 | - | - | 0.0047 | - |
| eee[3] | - | 0.150 | - | - | 0.0059 | - |
| fff[4] | - | 0.080 | - | - | 0.0031 | - |

1. Values in inches are converted from mm and rounded to 4 decimal digits.
2. Low profile: 1.20 mm < A ≤ 1.70 mm / Fine pitch: e < 1.00 mm pitch.
   The total profile height (Dim.A) is measured from the seating plane “C” to the top of the component. The maximum total package height is calculated by the RSS method (Root Sum Square).
   A Max = A1 Typ + A2 Typ + A4 Typ + $\sqrt{(A1^2 + A2^2 + A4^2}$ tolerance values).
3. The typical ball diameter before mounting is 0.40 mm
4. The tolerance of position that controls the location of the pattern of balls with respect to datums A and B. For each ball there is a cylindrical tolerance zone eee perpendicular to datum C and located on true position with respect to datums A and B as defined by e. The axis perpendicular to datum C of each ball must lie within this tolerance zone.

**Figure 74. LFBGA - Recommended footprint**

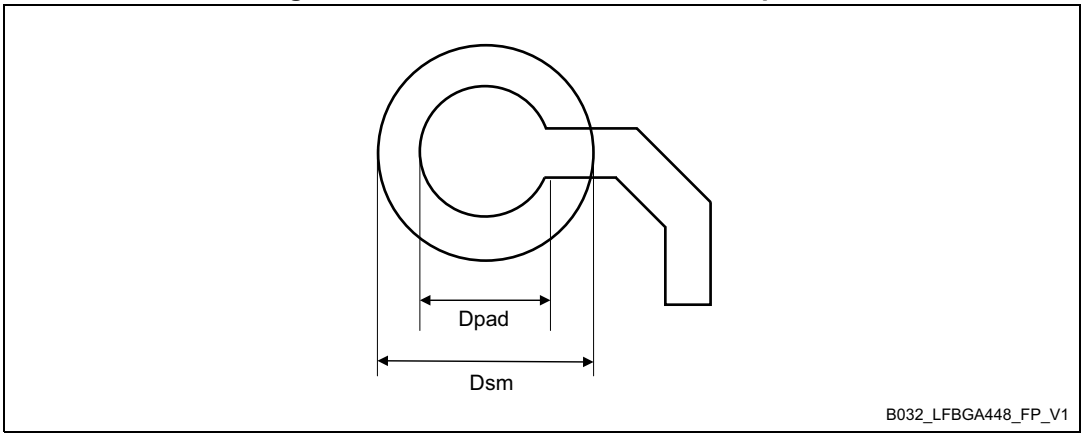



**Table 121. LFBGA - Recommended PCB design rules (0.8 mm pitch, BGA)**

| Dimension | Recommended values |
|---|---|
| Pitch | 0.8 mm |
| Dpad | 0.320 mm |
| Dsm | 0.520 mm typ. |

**Table 121. LFBGA - Recommended PCB design rules (0.8 mm pitch, BGA) (continued)**

| Dimension | Recommended values |
|---|---|
| Stencil opening | 0.320 mm |
| Stencil thickness | 0.125 mm to 0.100 mm |

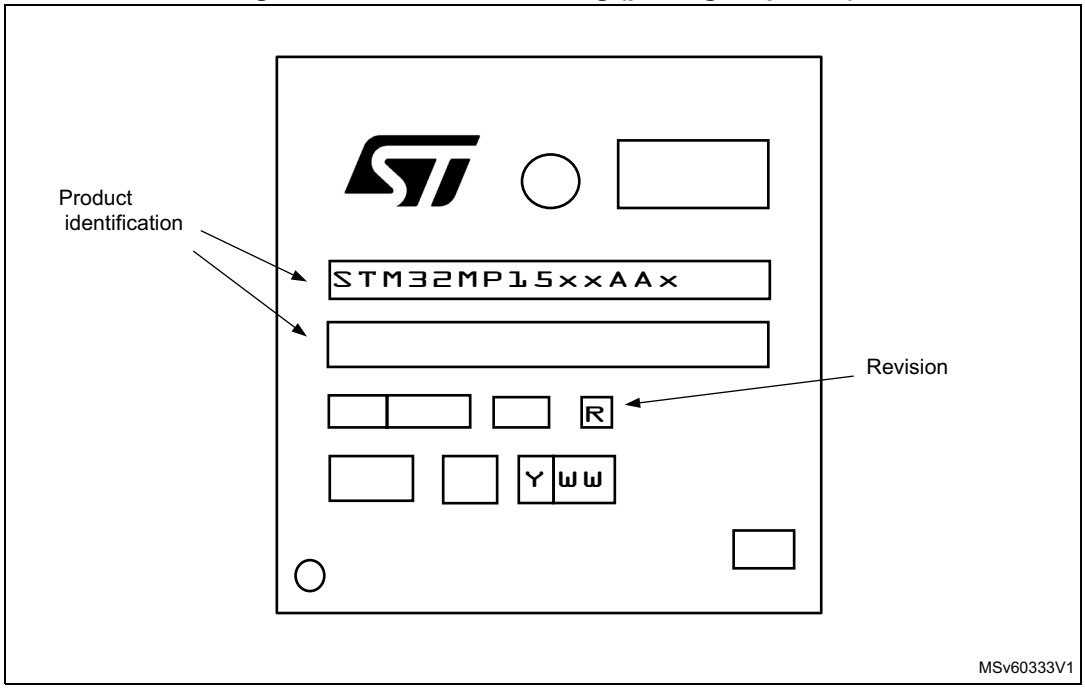
## Device marking

The following figure gives an example of topside marking orientation versus ball A1 identifier location.

The printed markings may differ depending on the supply chain.

Other optional marking or inset/upset marks, which identify the parts throughout supply chain operations, are not indicated below.

**Figure 75. LFBGA448 marking (package top view)**




1. Parts marked as ES or E or accompanied by an Engineering Sample notification letter are not yet qualified and therefore not approved for use in production. ST is not responsible for any consequences resulting from such use. In no event will ST be liable for the customer using any of these engineering samples in production. ST's Quality department must be contacted prior to any decision to use these engineering samples to run a qualification activity.

## 7.5 Thermal characteristics

Package thermal characteristics in *Table 122* are specified with conditions as per JEDEC JESD51-6, JESD51-8, JESD51-9, and JESD51-12. These typical values will vary in function of board thermal characteristics and other components on the board.

$\Theta_{JA}$ : Thermal resistance junction-ambient.
$\Theta_{JB}$: Thermal resistance junction-board.
$\Theta_{JC}$: Thermal resistance junction-top-case.
Θjb: Thermal parameter junction-board.
Ψjt: Thermal parameter junction-top-case.
Motherboard type: four layers, JEDEC 2S2P

**Table 122. Thermal characteristics**

| Symbol | Parameter | Value | | Unit |
|---|---|---|---|---|
| | | Natural convection | 1m/s (200 ft/mn) | |
| $\Theta_{JA}$(1) | TFBGA257 - 257-ball 10x10 mm 0.50/0.65 mm pitch | 36.079 | 31.79 | °C/W |
| | TFBGA361 - 361-ball 12x12 mm 0.50/0.65 mm pitch | 35.151 | 30.953 | |
| | LFBGA354 - 354-ball 16x16 mm 0.80 mm pitch | 34.145 | 30.121 | |
| | LFBGA448 - 448-ball 18x18 mm 0.80 mm pitch | 28.545 | 24.797 | |
| $\Theta_{JB}$(2) | TFBGA257 - 257-ball 10x10 mm 0.50/0.65 mm pitch | 19.487 | | °C/W |
| | TFBGA361 - 361-ball 12x12 mm 0.50/0.65 mm pitch | 20.555 | | |
| | LFBGA354 - 354-ball 16x16 mm 0.80 mm pitch | 22.038 | | |
| | LFBGA448 - 448-ball 18x18 mm 0.80 mm pitch | 17.409 | | |
| $\Theta_{JC}$(3) | TFBGA257 - 257-ball 10x10 mm 0.50/0.65 mm pitch | 10.768 | | °C/W |
| | TFBGA361 - 361-ball 12x12 mm 0.50/0.65 mm pitch | 10.049 | | |
| | LFBGA354 - 354-ball 16x16 mm 0.80 mm pitch | 9.675 | | |
| | TLFBGA448 - 448-ball 18x18 mm 0.80 mm pitch | 8.439 | | |
| Ψjb (4) | TFBGA257 - 257-ball 10x10 mm 0.50/0.65 mm pitch | 18.949 | 18.332 | °C/W |
| | TFBGA361 - 361-ball 12x12 mm 0.50/0.65 mm pitch | 20.002 | 19.398 | |
| | LFBGA354 - 354-ball 16x16 mm 0.80 mm pitch | 21.456 | 20.894 | |
| | LFBGA448 - 448-ball 18x18 mm 0.80 mm pitch | 16.946 | 16.574 | |
| Ψjt (5) | TFBGA257 - 257-ball 10x10 mm 0.50/0.65 mm pitch | 0.383 | 0.812 | °C/W |
| | TFBGA361 - 361-ball 12x12 mm 0.50/0.65 mm pitch | 0.354 | 0.735 | |
| | LFBGA354 - 354-ball 16x16 mm 0.80 mm pitch | 0.339 | 0.658 | |
| | LFBGA448 - 448-ball 18x18 mm 0.80 mm pitch | 0.297 | 0.542 | |

1. Per JEDEC JESD51-9
2. Per JEDEC JESD51-8
3. Per JEDEC JESD51-12 best practice guidelines
4. Per JEDEC JESD51-12.
5. Per JEDEC JESD51-12.

### 7.5.1 Reference documents

JESD51-6 Integrated Circuit Thermal Test Method Environmental Conditions - Forced Convection (Moving Air). Available from www.jedec.org.

JESD51-8 Integrated Circuit Thermal Test Method Environmental Conditions —Junction-to-Board. Available from www.jedec.org.

JESD51-9 Test Boards for Area Array Surface. Mount Package Thermal. Measurements. Available from www.jedec.org.

JESD51-12 Guidelines for Reporting and Using Electronic Package Thermal Information. Available from www.jedec.org.

# 8 Ordering information

**Table 123. STM32MP153C/F ordering information scheme**

Example: STM32 MP 153 F AA 1 T

Device family

STM32 = Arm-based 32-bit processor

Product type

MP = MPU product

Device subfamily

153 = STM32MP153 Line

Security option

C = Secure boot, cryptography hardware, 650 MHz
F = Secure boot, cryptography hardware, 800 MHz

Package and pin count

AD = TFBGA257 10x10, 257 balls pitch 0.5 mm

AB = LFBGA354 16x16, 354 balls pitch 0.8 mm

AC = TFBGA361 12x12, 361 balls pitch 0.5 mm

AA = LFBGA448 18x18, 448 balls pitch 0.8 mm

Junction temperature range

1 = -20 °C < $T_J$ < +105 °C

3 = -40 °C < $T_J$ < +125 °C

Packing

T = tape and reel

No character = tray or tube

For a list of available options (speed, package, etc.) or for further information on any aspect of this device, please contact your nearest ST sales office.

# 9 Revision history

**Table 124. Document revision history**

| Date | Revision | Changes |
|---|---|---|
| 08-Feb-2019 | 1 | Initial release. |
| 01-Aug-2019 | 2 | Updated ADC characteristics on cover page.<br>Updated *Table 1: STM32MP153C/F features and peripheral counts*<br>Updated *Section 3.7.1: Power supply scheme*.<br>Updated *Table 7: STM32MP153C/F pin and ball definitions*.<br>Updated *Table 8: Alternate function AF0 to AF7*.<br>Updated *Table 10: Voltage characteristics*.<br>Updated *Table 13: General operating conditions*.<br>Updated *Table 14: Operating conditions at power-up / power-down*.<br>Updated *Table 15: Embedded reset and power control block characteristics*.<br>Updated *Figure 13: VDDCORE rise time from reset*.<br>Updated *Table 15: Embedded reset and power control block characteristics*.<br>Updated *Table 16: Embedded reference voltage*.<br>Updated *Table 18: REG1V1 embedded regulator (USB_PHY) characteristics*.<br>Updated *Table 19: REG1V8 embedded regulator (USB) characteristics*.<br>Updated *Table 20: Current consumption (IDDCORE) in Run mode*.<br>Updated *Table 21: Current consumption (IDD) in Run mode*.<br>Updated *Table 22: Current consumption in Stop mode*.<br>Updated *Table 23: Current consumption in LPLV-Stop mode*.<br>Updated *Table 25: Current consumption in VBAT mode*.<br>Updated *Table 28: High-speed external user clock characteristics (digital bypass)*.<br>Updated *Table 29: High-speed external user clock characteristics (analog bypass)*.<br>Added *Table 30: Low-speed external user clock characteristics (analog bypass)*.<br>Added *Figure 17: Low-speed external clock source AC timing diagram (analog bypass)*.<br>Updated *Table 32: 8-48 MHz HSE oscillator characteristics*.<br>Updated *Figure 19: Typical application with a 24 MHz crystal*.<br>Updated *Figure 20: Typical application with a 32.768 kHz crystal*. |

**Table 124. Document revision history**

| Date | Revision | Changes |
|---|---|---|
| 01-Aug-2019 | 2 (continued) | Updated *Table 35: HSI oscillator characteristics*.<br>Updated *Table 36: CSI oscillator characteristics*.<br>Updated *Table 37: LSI oscillator characteristics*.<br>Updated *Table 38: PLL1_1600, PLL2_1600 characteristics*.<br>Updated *Table 35: HSI oscillator characteristics*.<br>Updated *Table 36: CSI oscillator characteristics*.<br>Updated *Table 37: LSI oscillator characteristics*.<br>Updated *Table 38: PLL1_1600, PLL2_1600 characteristics*.<br>Updated *Table 39: PLL3_800, PLL4_800 characteristics*.<br>Updated *Table 40: USB_PLL characteristics*.<br>Updated *Table 46: EMI characteristics*.<br>Updated *Table 47: ESD absolute maximum ratings*.<br>Updated *Section : Static latchup*<br>Updated *Table 49: I/O current injection susceptibility*.<br>Updated *Table 50: I/O static characteristics*.<br>Updated *Table 51: Output voltage characteristics for all I/Os except PC13, PC14, PC15 and PI8*.<br>Added *Table 52: Output voltage characteristics for PC13, PC14, PC15 and PI8*.<br>Updated *Table 53: Output timing characteristics (HSLV OFF)*.<br>Added *Figure 23: VIL/VIH for FT I/Os*.<br>Updated *Table 74: ADC characteristics*.<br>Updated *Table 75: Minimum sampling time versus RAIN with 47 pF PCB capacitor up to 125 °C and VDDA = 1.6 V*.<br>Updated *Table 78: DAC characteristics*.<br>Updated *Table 83: DTS characteristics*.<br>Updated *Table 84: $V_{BAT}$ ADC monitoring characteristics*.<br>Updated *Table 86: Temperature and VBAT monitoring characteristics for temper detection*.<br>Added *Section 6.3.31: Compensation cell*.<br>Updated *Table 96: I2C analog filter characteristics*.<br>Added *Section 6.3.38: USB High-Speed PHY characteristics*.<br>Added *Section 7.5: Thermal characteristics*. |
| 04-Feb-2020 | 3 | Introduced STM32MP153F corresponding to the 800 MHz upgrade of the microprocessor, in all the document.<br>Updated *Table 1: STM32MP153C/F features and peripheral counts*.<br>Updated *Figure 1: STM32MP153C/F block diagram*.<br>Updated *Table 4: Timer feature comparison*. |

**Table 124. Document revision history**

| Date | Revision | Changes |
|---|---|---|
| 04-Feb-2020 | 3 (continued) | Updated *Table 7: STM32MP153C/F pin and ball definitions*.<br>Updated *Table 8: Alternate function AF0 to AF7*.<br>Updated *Table 9: Alternate function AF8 to AF15*.<br>Updated *Table 10: Voltage characteristics*.<br>Updated *Table 12: Thermal characteristics*.<br>Updated *Table 13: General operating conditions*.<br>Updated *Table 20: Current consumption (IDDCORE) in Run mode*.<br>Updated *Table 38: PLL1_1600, PLL2_1600 characteristics*.<br>Updated *Section 6.3.12: PLL spread spectrum clock generation (SSCG) characteristics*.<br>Updated *Table 45: EMS characteristics*.<br>Updated *Table 46: EMI characteristics*.<br>Updated *Table 74: ADC characteristics*.<br>Updated *Table 78: DAC characteristics*.<br>Updated *Table 79: DAC accuracy*.<br>Updated *Table 80: VREFBUF characteristics*.<br>Updated *Table 109: Dynamics characteristics: Ethernet MAC signals for RGMII*.<br>Updated *Figure 61: Ethernet RGMII timing diagram*.<br>Updated *Table 111: USB High-Speed PHY characteristics*.<br>Updated *Table 112: Dynamics characteristics: JTAG characteristics*.<br>Updated *Table 113: Dynamics characteristics: SWD characteristics*.<br>Updated *Table 123: STM32MP153C/F ordering information scheme*. |

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Телефон: 8 (812) 309-75-97 (многоканальный)
Факс: 8 (812) 320-03-32
Электронная почта: ocean@oceanchips.ru
Web: http://oceanchips.ru/
Адрес: 198099, г. Санкт-Петербург, ул. Калинина, д. 2, корп. 4, лит. А